

POLY SWITCH CIRCUIT PROTECTION PRODUCTS CATALOG

2016

- Hybrid Protection
 - Overtemperature Protection
 - Overvoltage Protection
 - Overcurrent Protection
-



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LITTELFUSE POLYSWITCH CIRCUIT PROTECTION



Littelfuse is the global leader in circuit protection solutions. We are the only company to offer all of the pertinent circuit protection technologies, with products that can be used in virtually everything that uses electrical energy. Complementing our wide portfolio of circuit protection products is a global network of design and technical support expertise. We offer decades of design experience to help you address application challenges and achieve regulatory compliance.

Littelfuse PolySwitch® circuit protection devices help to make your world safer and your electronics more reliable. Our products can be found in your cellphone, tablet, car, home appliances, LED lighting fixtures and a myriad of other everyday applications.

Overcurrent Protection

- **PolySwitch devices** — PolySwitch PPTC devices provide resettable circuit protection. Device types include: Automotive, Radial-leaded, Strap Battery and Surface-mount Devices (SMDs)

Overvoltage Protection

- **Gas Discharge Tubes (GDTs)** — Low-capacitance GDT devices help protect applications such as telecom and appliances damage from potentially harmful surge events

ESD (Electrostatic Discharge) Protection

- **Polymer ESD (PESD) devices** — Help provide protection for today's highest-speed interface applications (USB, HDMI, DisplayPort, etc.).
- **ChipSESD devices** — Bi-directional, silicon-based devices in 0201 and 0402 sizes are easier to install and re-work than traditional semiconductor-packaged ESD devices

Hybrid Protection

- **PolyZen devices** — Each PolyZen device integrates a precision Zener diode and a PolySwitch PPTC device. Devices are offered in “LS”, “YC” and “YM” options to help protect a broad range of applications requiring overcurrent/overvoltage protection
- **2Pro devices** — Combining an MOV and PPTC in a single device helps provide space-efficient protection against overvoltage/overcurrent events. The 2Pro AC device family provides AC-line protection and can offer better space and reliability benefits than discrete solutions

Thermal Protection

- **Metal Hybrid PPTC (MHP) devices** — Combining the best attributes of a PPTC and bimetal breaker in one device helps protect lithium battery applications.

To date, billions of Littelfuse PolySwitch Circuit Protection devices are being used to help protect a wide range of electronic products in computer, battery and portable electronics, consumer, automotive, industrial, home appliance, HVAC, and telecommunications applications. Our products help manufacturers meet strict regulatory standards while diminishing warranty returns.

Littelfuse PolySwitch Circuit Protection offers a dedicated engineering sales force along with worldwide manufacturing and design centers. Our history in circuit protection, combined with local engineering support, enables us to think globally – and act locally – to meet our customers' needs.

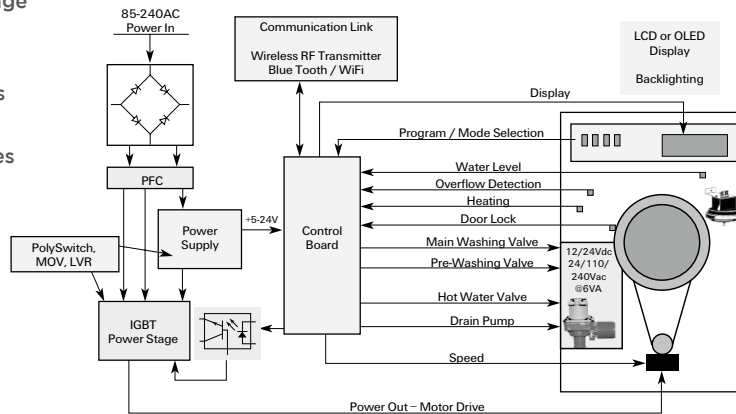
Application Summaries

Appliances

Washing Machines

A number of circuit protection devices can be used to help provide overtemperature, overcurrent and overvoltage protection for the small electric motors, LED displays and control electronics found in home appliances.

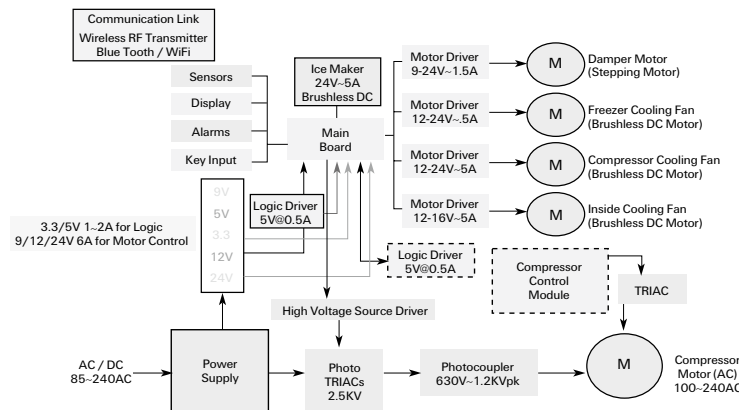
- PolySwitch Line-voltage radial-leaded devices
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- ESD devices
- GDTs



Refrigerators / Freezers

Our circuit protection devices help protect the small electric motors and fans, controllers, touchpads, displays and interface circuitry required by sophisticated appliances.

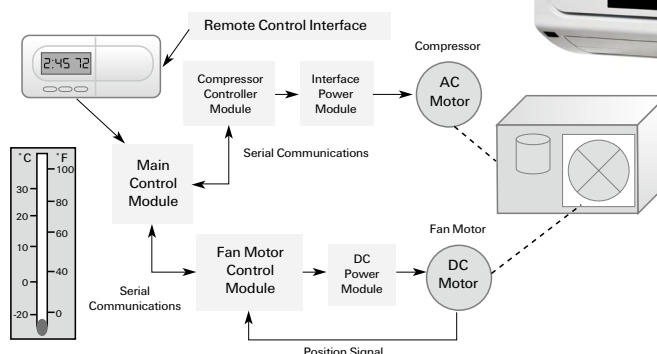
- PolySwitch Line-voltage radial-leaded devices
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- ESD devices



Air Conditioning Units

Resettable PolySwitch devices, ESD devices and chip fuses help provide coordinated overcurrent and overvoltage protection for the small electric motors, fans, displays and interface circuits used in modern HVAC equipment.

- PolySwitch Line-voltage radial-leaded devices
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- ESD devices



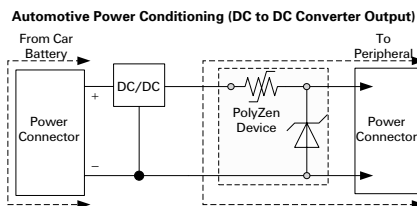
Application Summaries

Automotive

Automotive Electronics

PolyZen devices help protect automotive electronics and peripherals and/or portable electronics that can be charged in the vehicle from damage caused by inductive voltage spikes, voltage transients and reverse polarity. Providing coordinated overcurrent, overvoltage and reverse polarity protection, the PolySwitch device protects like a Zener diode but is capable of withstanding the high-power fault conditions that can occur in automotive applications.

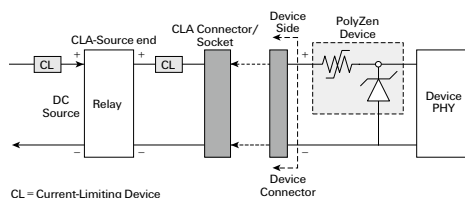
- PolyZen devices



DC Cigarette Lighters and Power Plug Adapters

Charger circuits for mobile phones, iPods, after-market hands-free devices, or other rechargeable battery operated equipment, use connectors to plug into automobile cigarette lighter or power outlets. These assemblies must operate over a wide range of temperatures, charging conditions and in harsh automotive environments.

Typically, overcurrent protection, such as a PolySwitch polymer positive temperature coefficient (PPTC) device, and overvoltage protection are coordinated at the input to the charger to help meet the stringent electrical requirement. A single PolyZen device or PolyZen-AS device can be used to help protect against damage caused by overcurrent, overvoltage, or reverse polarity faults.



- PolySwitch automotive devices
- PolyZen devices



Liquid Crystal Display Backlight Heaters

There are an increasing number of displays – such as navigation systems, instrumentation displays, video and TV screens – being designed into automobiles. A temperature-sensing PolySwitch PPTC current-limiting device can be employed to help prevent thermal runaway due to a failure in the control circuitry. In most cases, the circuit will be powered off on a regular basis (i.e., when the ignition is turned off) and a resettable PolySwitch device may be desired. In other cases, a single-use RTP (Reflowable Thermal Protector) device or single-use fuse may be preferred.

- PolySwitch automotive devices



Driver-Side Door Console

The switch console on the driver-side door allows the driver to control multiple functions, including power windows, side mirrors and power door locks. Small Surface-mount PolySwitch devices help protect low current membrane switches and PCB traces against damage caused by overheating in the event of an overcurrent or short circuit condition. A variety of designs include PolySwitch devices that help protect PCB traces leading to high-current power window motors, as well as low-current delicate carbon membrane microswitches, transistors in LED backlighting circuits and small traces of the side mirror control circuits.

- PolySwitch automotive devices



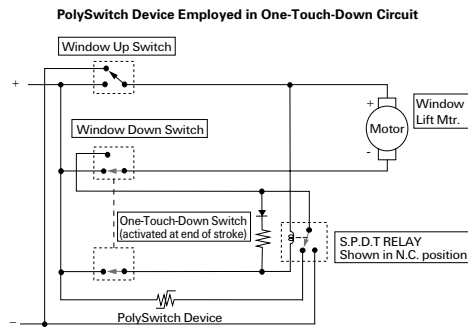
Application Summaries

Automotive

One-Touch-Down Circuits for Power Windows and Power Sunroofs

Lower cost one-touch-down circuits can employ a PolySwitch PPTC device to function both as a sense component and a switch component. This functionality allows a PolySwitch device to replace a number of other devices, such as the sense resistor, comparator, driver and control circuitry used in traditional power window and sunroof circuits. As a result, designers can help to achieve net cost savings through reduced component count and reduction in wire size.

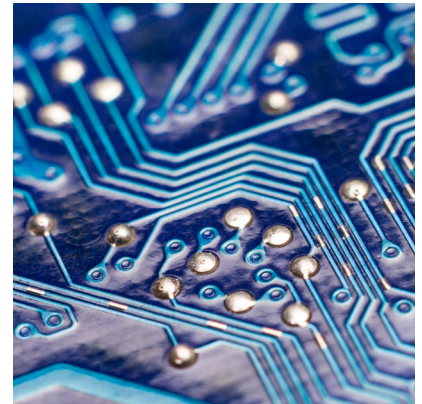
- PolySwitch automotive devices



Printed Circuit Board Traces

The width of the copper traces must be reduced to provide more space for the tighter-packed and smaller printed circuit boards. These “Black Box” control modules handle a large number of high-powered accessories such as power windows, power seat adjusters, remotely controlled door locks, and radio & GPS antennae. PolySwitch resettable devices can be used to help protect these delicate printed circuit board traces against damage caused by overcurrent conditions.

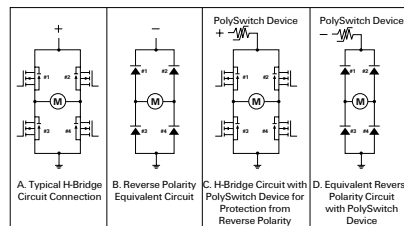
- PolySwitch automotive devices



H-Bridge Circuits

Automotive FET switched H-bridges must be protected from reverse polarity power sources. This may occur when jumper cables are connected to the wrong polarity of a dead or excessively discharged battery or when a new battery is installed backwards. Without protection, excessive heating can lead to failures in electronic modules or inadvertent activation of vehicle loads such as solenoids and motors, which can lead to unsafe conditions.

- PolySwitch automotive devices



Automotive Control Application and Multimedia Busses

Connecting lifestyles from the home to the vehicle has become a reality in the automotive industry. MOST, Flexray, IEEE1394 and other networks now co-exist with CAN and LIN. Their main goal is to facilitate equipment interfacing and information sharing for embedded equipment, while also enabling after-market electronic equipment such as Portable Navigation (PNDs), smart phones, DVD players, etc. In a hot-pluggable automotive environment, where the consumer is connecting and disconnecting peripherals on a powered port, the potential for short-circuit damage is clearly present. PolySwitch devices and ESD protection devices can be used to help protect the connected equipment.

- PolySwitch automotive devices
- ESD devices



Application Summaries

Automotive

Navigation and Infotainment Systems

Infotainment and navigation systems are packed with electronics and connectivity elements. Circuit protection devices help protect a wide variety of functions such as powered antennae, CAN-bus, touch screen, USB ports, HDMI ports, RF tuners, I/O lines, HDD, etc. Overcurrent and overvoltage protection devices help prevent system breakdown and enhance design safety.

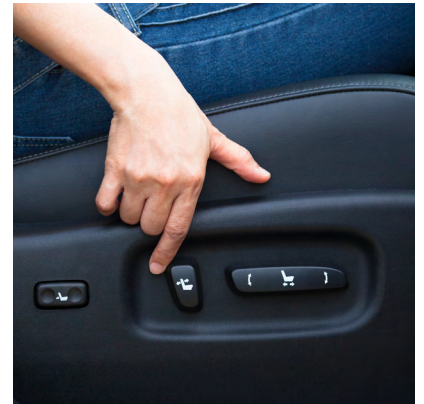
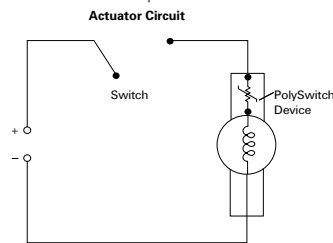
- PolySwitch automotive devices
- ESD devices
- PolyZen device



Automotive Actuators and Medium-Size DC Motors

Automotive electric motors can overheat and cause damage to internal temperature sensitive components. To help protect these components, custom and semi-custom PolySwitch devices can be designed to meet specific customer thermal protection needs. Installing a PolySwitch device in close proximity to the motor or solenoid offers the added benefit by limiting current due to excessive heat.

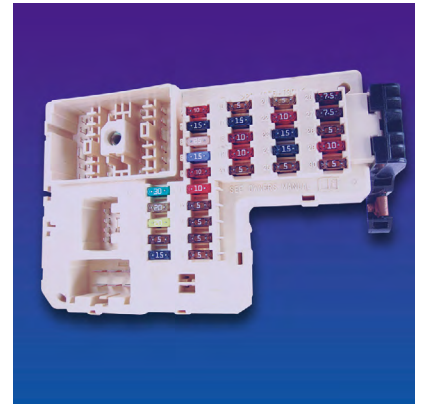
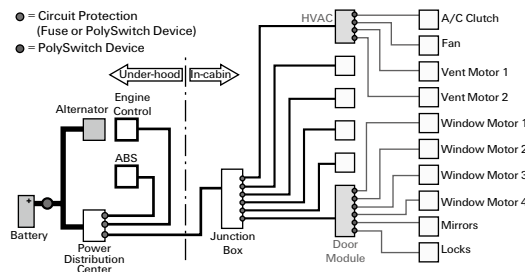
- PolySwitch automotive devices



Automobile Harnesses

The wiring harness architectures of light and heavy vehicles have undergone considerable change due to increased electrical and electronic content. PolySwitch PPTC resettable circuit protection devices, which do not require driver accessibility, can be embedded in distributed electronic control modules and power controlling switches throughout the vehicle. This approach of creating separate circuits helps to enable fault isolation as well as the downsizing of wire gauges and PCB traces.

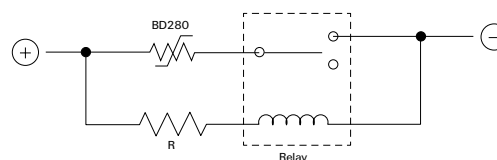
- PolySwitch automotive devices



Automobile Relays

Relay contacts can pit during high current interrupt events. A PolySwitch PPTC device helps reduce current prior to contact switching events. This circuit design becomes a tuned system that uses the normally open contacts and works in coordination with relay inertia. During an overload condition, the relay energizes and latches in the off state. Once the power is cycled and/or the load is removed, the relay de-energizes and the circuit immediately resets and is able to deliver full power. The use of a PolySwitch device in this circuit can help achieve vehicle power outlet protection, but it can also be used to help protect isolated trailer lighting circuits.

- PolySwitch devices



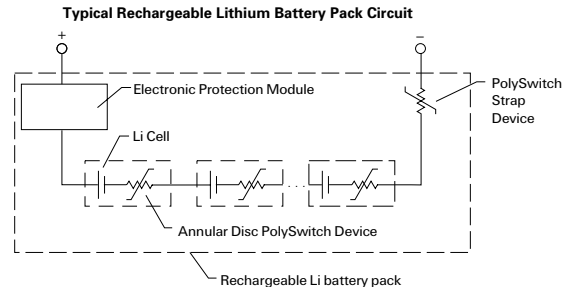
Application Summaries

Batteries

Lithium Cells and Battery Packs

External shorts, runaway charging conditions, or abusive charging can cause considerable damage to primary and secondary lithium (Li) cells. PolySwitch disc and strap circuit protection devices can help protect rechargeable lithium batteries used in notebook computers and cellular phones, as well as other portable electronic applications.

- PolySwitch strap devices
- PolySwitch disc devices

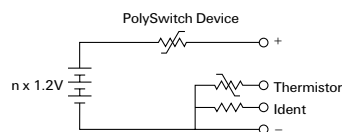


Rechargeable Battery Packs

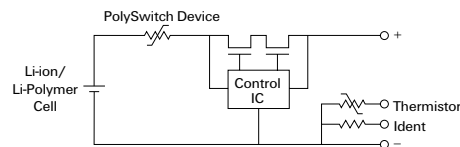
Due to external shorts, runaway charging conditions, or abusive charging, considerable damage can be sustained in both battery cells and pack surroundings. The most common applications for PolySwitch devices are for helping to protect lithium-ion (Li-ion) battery packs used in cellular phones, digital cameras and laptop/notebook computers, or for helping to protect nickel-cadmium (NiCd) and nickel-metal-hydride (NiMH) battery packs used in other portable electronic applications.

- PolySwitch strap devices

NiMH/NiCd Battery Pack Circuit Diagram



Single Cell Li-ion/Li-Polymer Battery Pack Circuit Diagram

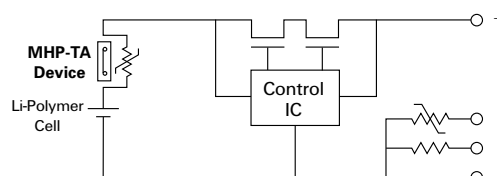


Rechargeable Lithium Polymer Cells

Tablets, ultra-thin notebook PCs and other small portable electronics use high-capacity lithium polymer and prismatic cells that require overtemperature protection to help prevent the cells from overheating. The combination of thin form factors, high cell capacities and high battery discharge rates typical of these applications create a unique set of circuit protection requirements, which are low thermal cut-off temperatures ($<90^{\circ}C$), high hold current ratings ($>6A$) and compact size.

The MHP-TA series of MHP (Metal Hybrid PPTC) devices addresses these design concerns by offering two levels of current carrying capacity (6A or 15A hold current at $25^{\circ}C$) as well as an ultra-thin package (L:5.8mm x W: 3.85mm x H: 1.15mm).

- MHP devices



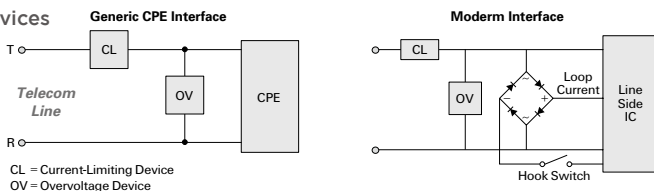
Application Summaries

Communications

Customer Premise Equipment

To protect subscribers against damage caused by faults entering from outside wiring, customer premise equipment (CPE) is designed with power cross and lightning protection components. The following are recommended circuit protection solutions based on regional requirements.

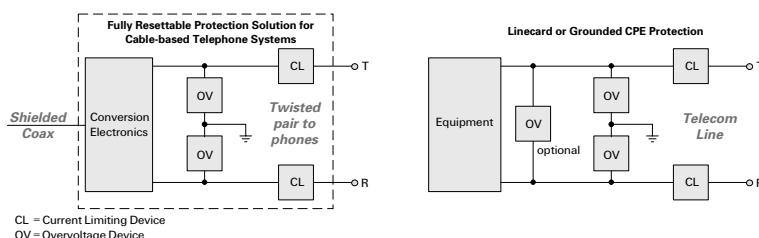
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- PolySwitch telecom devices
- GDTs
- 2Pro devices



Short-haul/Intrabuilding Protection Requirements

Communications equipment that is not directly connected to the PSTN is subjected to lower level hazards. Here are a few circuit protection recommendations for LAN, WLL, VoIP and other intrabuilding applications.

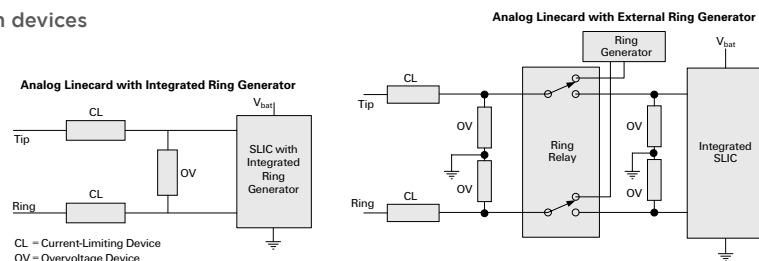
- PolySwitch telecom devices
- GDTs



Analog Linecards

Central office linecards are subject to transient overcurrent and overvoltage faults, which may be generated from nearby power cross, power induction and lightning events. Circuit protection recommendations based on regional agency specifications are provided below.

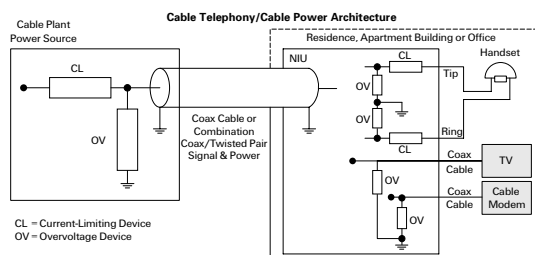
- PolySwitch telecom devices
- GDTs



Cable Telephony/Cable Power Passing Taps

Cable telephony electronics that are powered via twisted pair or coaxial cable are susceptible to power faults passed through the cable plant. The circuit protection solutions listed below can help decrease the risk of these faults in power passing taps.

- PolySwitch telecom devices
- GDTs



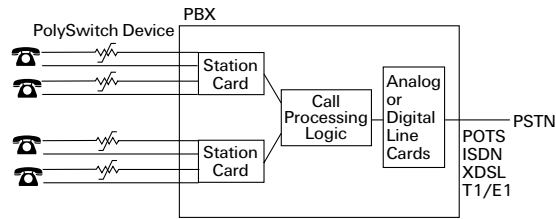
Application Summaries

Communications

PBX and Key Telephone Systems

Below are circuit protection device recommendations to help protect PBX and key telephone systems against damage caused by power faults and short circuits.

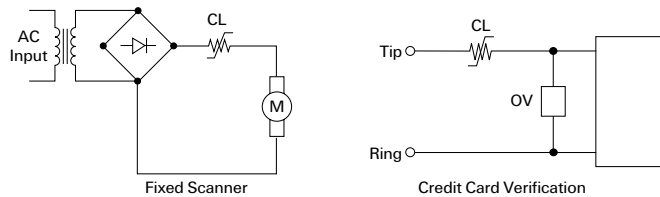
- PolySwitch telecom devices
- GDTs



POS Equipment

Equipment connected to telephone lines can be subject to power cross, induction, and lightning surge hazards. We recommend the devices below to help protect scanner motors and ditherers against damage caused by jams and stalls.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- PolySwitch telecom devices
- 2Pro devices



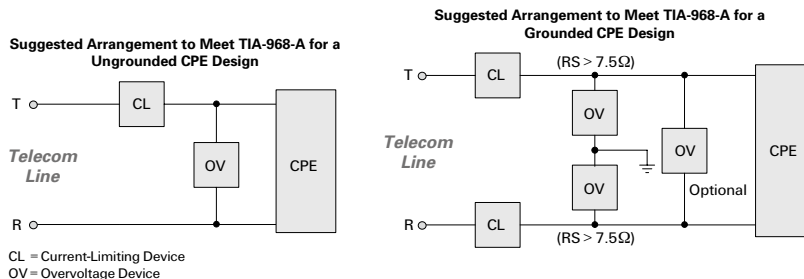
CL = Current-Limiting Device
OV = Overvoltage Device



UL60950 and TIA-968-A (formerly FCC part 68) Requirements

The UL60950 and TIA-968-A cover standards electrical hazards from which customer premise equipment (CPE) in North America must be protected. Below are resettable circuit protection recommendations.

- PolySwitch telecom devices
- 2Pro devices
- GDTs



CL = Current-Limiting Device
OV = Overvoltage Device



Application Summaries

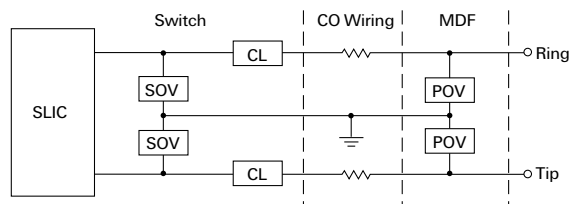
Communications

GR-1089: Public Switched Telephone Network Equipment

GR-1089 describes the electrical hazards which public switched telephone network (PSTN) equipment in North America should be protected against. The figure below shows several recommended resettable circuit protection solutions for a simplified model of the central office end of a subscriber loop system.

- PolySwitch telecom devices
- GDTs

Simplified Model of Central Office End of Subscriber Loop



CL = Current-Limiting Device
CO = Central Office
MDF = Main Distribution Frame
POV = Primary Overvoltage Protection Device
SLIC = Subscriber Line Interface Card
SOV = Secondary Overvoltage Protection Device

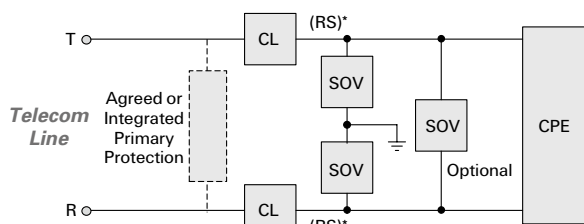


GR-1089-CORE, Issue 5: Public Switched Telephone Network Equipment

According to the GR-1089-CORE, Issue 5 standard, to help prevent damage to telecom equipment, circuits connected to outside lines generally need protection from lightning and power fault events. The equipment must be able to withstand the surges that the primary protector lets through. For this reason, secondary, and even tertiary, protection is included to help limit the potential damage of the surge let through. To be effective, the secondary protection must coordinate with the primary protection.

Littelfuse offers a broad line of overcurrent and overvoltage devices that can help Public Switched Telephone Networks equipment conserve valuable board space and meet emerging safety and performance standards.

- PolySwitch telecom devices
- GDTs



CL = Current-Limiting Device
SOV = Secondary Overvoltage Device
* RS is equal to the total coordinating resistance of the application

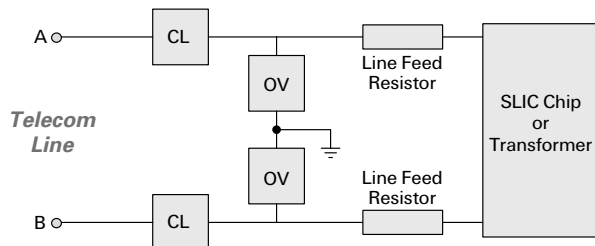


ITU-T Recommendations

The ITU-T standard lists several recommendations for central office (K.20), customer premise (K.21) and access network (K.45) equipment. Below is an overview of our device recommendations, including resettable circuit protection solutions.

- PolySwitch telecom devices
- GDTs

Typical Protection System for Network Equipment



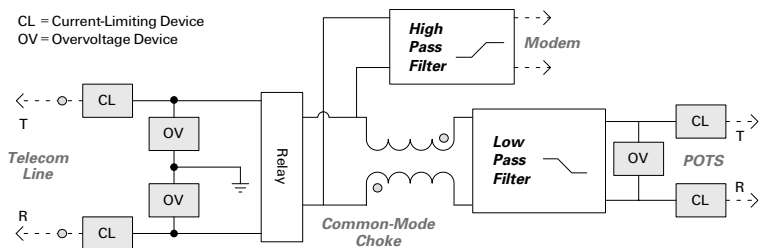
CL = Current-Limiting Device
OV = Overvoltage Device



DSL Equipment

DSL equipment, such as splitters, must be protected against damage caused by both external and intrabuilding faults. Recommendations for resettable protection solutions are provided here, based on regional requirements.

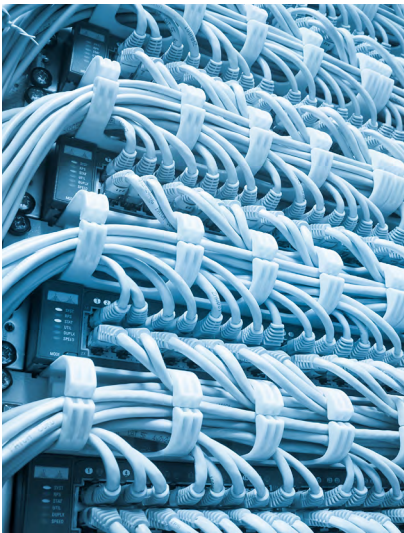
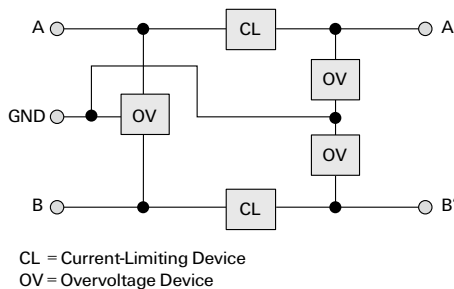
- PolySwitch telecom devices
- GDTs



Main Distribution Frame (MDF) Modules

Telecom systems, such as MDF modules, typically have multi-stage circuit protection. Primary protection is used closest to the “outside world” where the highest surge withstand capability is typically needed. Secondary protection is needed to help protect against damage caused by hazardous power cross and lightning faults until the primary protection component activates. The following devices are recommended for helping to protect these systems.

- PolySwitch telecom devices
- GDTs



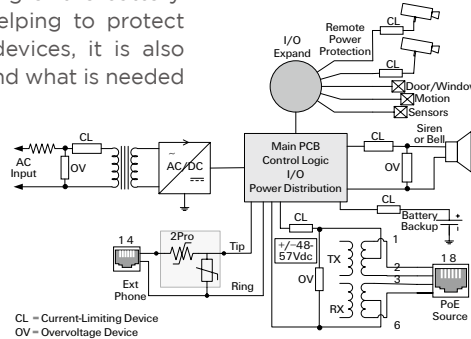
Application Summaries

Industrial

Security and Fire Alarm Systems

Security and fire alarm systems have a need for circuit protection, due to fault conditions experienced by these applications as well as safety requirements. Possible faults include short circuits in the sensor lines or overheating of the battery. The devices below are recommended for helping to protect these systems. When choosing protection devices, it is also important to consider the different currents and what is needed to meet the requirements of UL864.

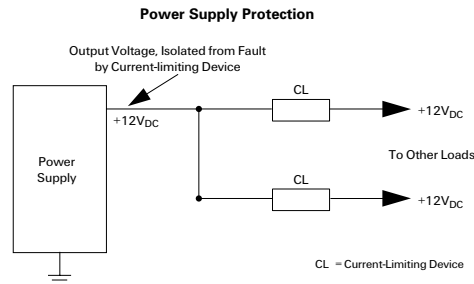
- PolySwitch Radial-leaded devices
- PolySwitch telecom devices
- GDTs
- ESD devices
- 2Pro devices



Test and Measurement Equipment

Power supplies, communication ports, test probes, and battery packs are all vulnerable to overcurrent faults and electrostatic discharge (ESD). Incorrect termination of outputs may lead to system damage.

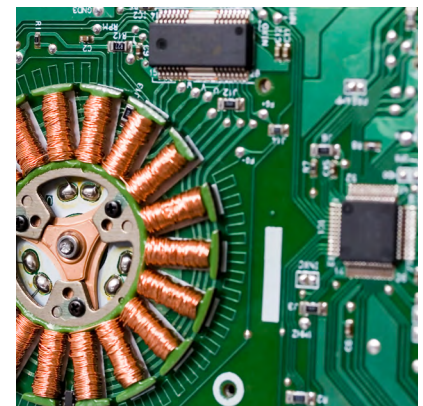
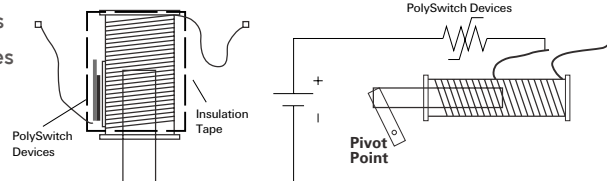
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- PolySwitch telecom devices
- ESD devices
- PolyZen devices



Solenoids

Solenoids are used in various PC and peripheral applications such as printer feed trays and CD/CD-RW/DVD tray mechanisms. A PolySwitch device can be used to help protect the coil assembly of the solenoid when a sensor fails or if the armature fails to retract, thus causing the coil temperature to increase and burn out the coil wire.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



Electromagnetic Loads

Electromagnetic loads can be susceptible to many problems. Incorrect use of solenoids, valves and motors can potentially lead to device failure and circuit damage. The devices below are recommended as circuit protection solutions for these applications.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



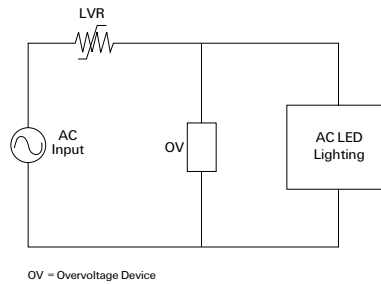
Application Summaries

Lighting

Protection for AC LEDs

Lighting fixtures powered by AC power can be put at risk from high voltage or power transients due to lightning strikes, load switching transients and their associated surge currents. We recommend the following circuit protection devices to help protect AC LEDs.

- PolySwitch Line-voltage-rated
- PolySwitch Surface-mount devices
- 2Pro devices

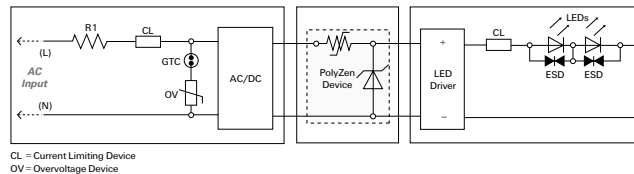


Protection for DC Solid State Lighting (SSL)/LED Lighting

LED driver integrated circuits (ICs) used in many LED applications require a protected DC input to provide a regulated-current output to the LED. Listed below are devices that help protect these lighting applications.

A PolySwitch device placed in series with the LED driver IC and combined with a parallel voltage-limiting device, such as a Zener or transient suppression diode, can help provide effective protection against damage caused by faulty DC input voltages. A PolyZen device with an integrated PolySwitch PPTC device and Zener diode help provide both protection capabilities in one package.

- PolyZen devices
- PolySwitch Radial-leaded devices
- GDTs
- ESD devices



CFL Electronic Ballasts

There are two types of ballasts in compact fluorescent lamps (CFLs): electronic ballasts and magnetic ballasts. The electronic ballasts help prevent the fluorescent light from flickering when turning on. The electronic ballasts are more delicate and can be at risk from high-voltage or power transients due to lightning strikes, load switching transients and their associated surge currents.

A PolySwitch device helps provide effective protection for the electronic components inside the ballast against damage caused by faulty transients. Littelfuse Circuit Protection's 2Pro device and surface-mount fuses also help to provide effective protection in CFL ballasts.

- 2Pro devices



Street Lighting Electronic Ballasts

Lighting ballasts for street lighting can be at risk from high-voltage or power transients due to lightning strikes, load switching transients and their associated surge currents.

A PolySwitch device in series with the LED driver IC, and combined with a parallel voltage limiting device such as metal oxide varistors, can help provide effective protection against damage caused by faulty transients. Our recommended devices for street lighting also include the following:

- PolySwitch Telecom devices
- GDTs



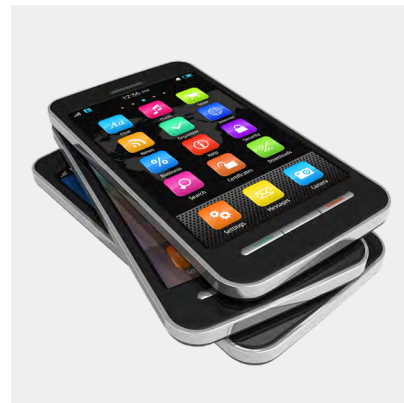
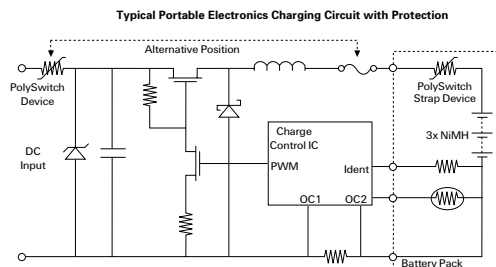
Application Summaries

Consumer Device Ports

Portable Electronics Input Ports

The use of an incorrect or faulty adapter/charger can irreparably damage unprotected portable electronics equipment. Typical applications include cell phones, digital cameras, and tablets. The devices listed below are recommended for these applications.

- PolySwitch Surface-mount devices
- PolyZen devices

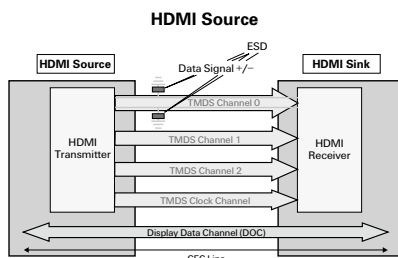


HDMI: LCD & Plasma Displays, HDTVs, Set-top Boxes, DVD Players

High definition multimedia interface (HDMI) applications, such as LCD displays, plasma displays, high-definition television set-top boxes and DVD players, are susceptible to electrostatic discharge (ESD devices). To help protect the high-speed TMDS lines against damage caused by our ESD or SESD protection devices can be used two-per-line in HDMI designs.

- PolySwitch Surface-mount devices
- ESD devices
- PolyZen devices

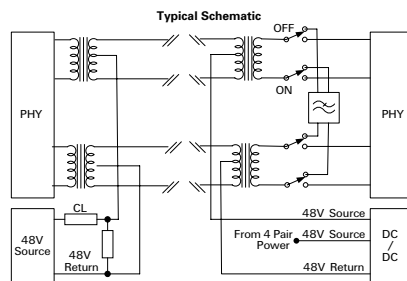
Note: HDMI 1.3 reference layout, whitepaper and testing results available upon request.



IEEE 802.3 Ethernet LAN (Powered Ethernet)

The auxiliary unit interface (AUI) consists of signal circuits, power and ground. Per the IEEE 802.3 standard, the Voltage Plus circuit is capable of operating at 12-15VDC for currents up to 500mA. In addition, per section 7.5.2.5, the source shall provide protection for this circuit against damage caused by an overload condition. Powering IP devices such as IP phones over the Ethernet cable introduces the potential for a short circuit and/or FET failure, causing service interruption. Devices recommended for circuit protection are:

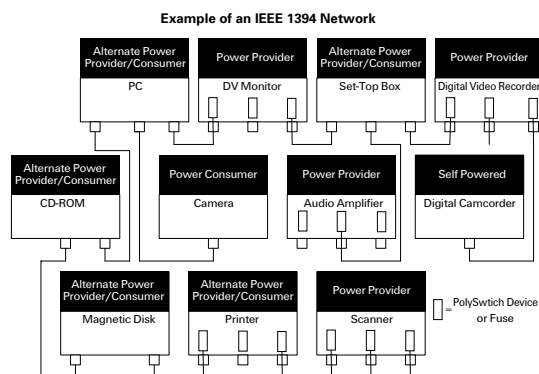
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



IEEE 1394: FireWire, i.Link

The IEEE 1394's complex power architecture provides up to 1.5A at voltages of 8-33V. PolySwitch devices help provide short-circuit protection in this high-power, hot-plugging environment.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



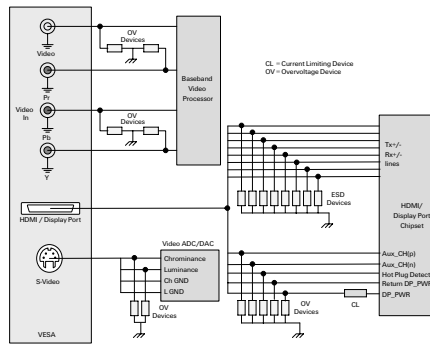
Application Summaries

Consumer Device Ports

Video Ports: VESA, DDC, DVI, HDMI, DisplayPort

PolySwitch devices help protect video ports on PCI video cards and motherboard video ports from faults on the 5V interface line in Display Data Channel (DDC) circuits. These ports are designed for Energy Star compliance. PolySwitch devices suitable for these applications include:

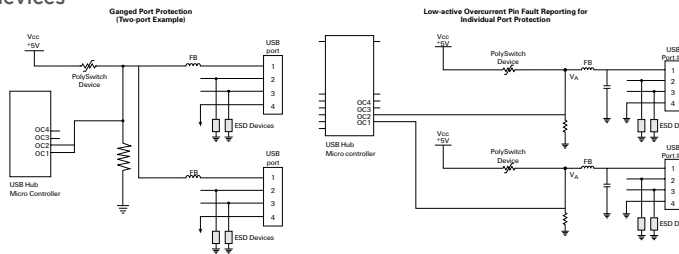
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- PolyZen devices
- ESD devices



Universal Serial Bus (USB)

PolySwitch devices help provide short-circuit protection in this hot-plugging environment for USB hosts, self-powered and bus-powered hubs. Recommended circuit protection devices are:

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- PolyZen devices
- ESD devices



Audio Input/Output Ports

ESD protection devices can help protect analog audio ports from electrostatic discharge (ESD) during installation, or any time the user disconnects the source from the receiver. Additionally, our PolySwitch surface-mount devices and surface-mount fuses can be used.

- ESD devices
- Surface-mount PolySwitch devices



Power Input

PolySwitch devices help protect against overcurrent and overtemperature fault conditions by limiting the flow of current in the DC input power port circuit. Surface-mount fuses and PolyZen devices are also recommended for this application.

- PolyZen devices
- Surface-mount PolySwitch devices



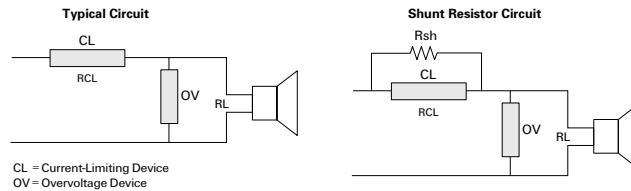
Application Summaries

Consumer Device Peripherals

Loudspeakers

High-powered amplifiers used with low-powered speakers may overdrive the speaker coils with excessive power during sustained high volumes. Low-powered amplifiers may be overdriven so that clipping occurs. This causes an upward frequency shift of power that can overload the tweeters. Digital recordings, with their ability to reproduce high-frequency material, place extra strain on tweeters. Littelfuse devices, including PolySwitch devices, can help the design engineer solve these problems.

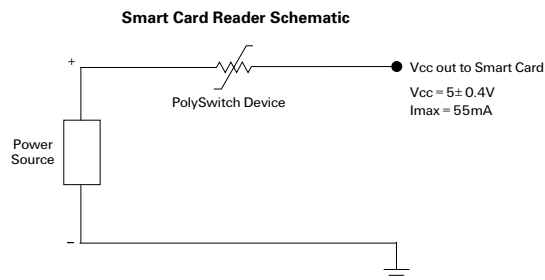
- PolySwitch Radial-leaded devices
- PolyZen devices



Smart Card Readers

Smart cards are powered from the readers' Vcc output. Defective cards or foreign objects placed into the reader can cause a short circuit and permanently damage the reader. The PolySwitch device can be used for circuit protection in smart card reader designs.

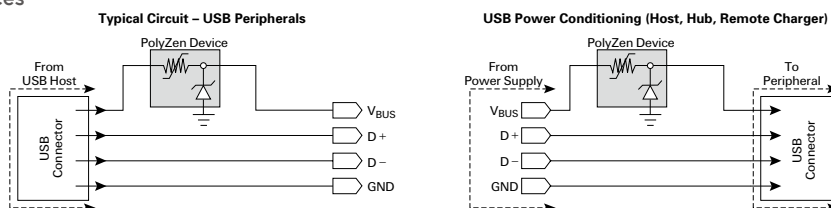
- PolySwitch Surface-mount devices



USB Peripherals

PolyZen devices can help protect against damage caused by overvoltage on USB peripherals and devices on the 5V computer bus. The component helps protect sensitive follow-on electronics — such as flash memory and other 6V capable silicon — from inductive voltage spikes, incorrect power supplies, dirty power and other voltage transients. The RoHS-compliant device offers massive power-handling in a 4mm package. PolyZen devices and ESD protection devices are also suitable for this application.

- PolySwitch Surface-mount devices
- PolyZen devices
- ESD devices



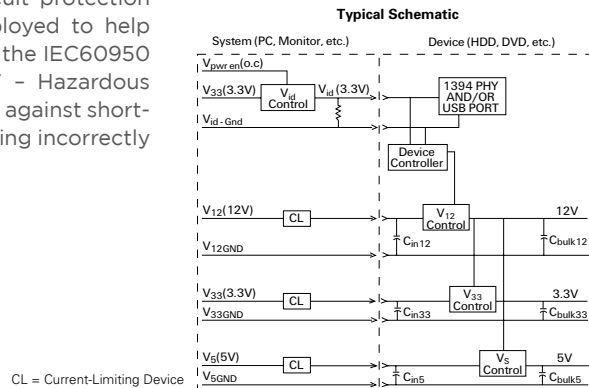
Application Summaries

Consumer Device Subsystems

Backplane and Redundant Array of Inexpensive Disks (RAID)

Power backplane applications allow for field-serviceable and field-replaceable cards and drives to maximize the “up-time” of products. During card or drive replacements, the power on the backplane is live. The circuit protection devices listed below can be employed to help minimize safety risks, comply with the IEC60950 safety requirement (clause 1.2.8.7 – Hazardous Energy Levels), and to help protect against short-circuit damage caused by cards being incorrectly inserted.

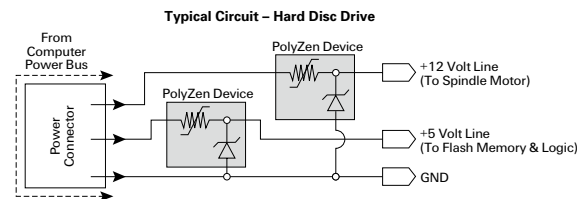
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



Hard Disk Drives (HDDs)

Integrated PolyZen devices can help protect devices on the 5V and 12V computer bus from overvoltage events and inductive voltage spikes resulting from a rapid change in current. The PolyZen device incorporates a stable Zener diode for precise voltage clamping and a resistively non-linear, polymer positive temperature coefficient (PPTC) layer that responds to either diode heating or overcurrent events by transitioning from a low to a high resistance state. This unique device helps manufacturers meet safety requirements and reduce warranty costs. In addition to the PolyZen device, the following circuit protection products are recommended for HDDs.

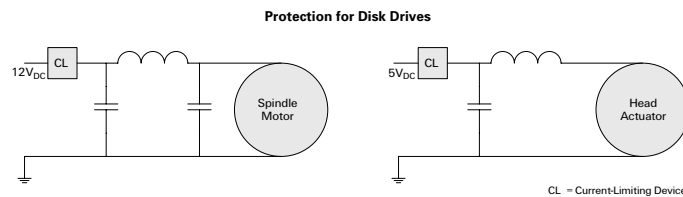
- PolySwitch Surface-mount devices
- PolyZen devices
- ESD devices



5V/12V Power Lines

The connection of a 12V line from the power supply instead of a 5V line can cause a high-current inrush that can damage the other components in the circuit. Reverse polarity can cause damage to the tantalum capacitors, causing the capacitor to fail in a short-circuit mode. Applications suitable for the circuit protection devices listed below include hard disk drives, CD-ROM, CD-RW, DVD and other storage devices.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- PolyZen devices



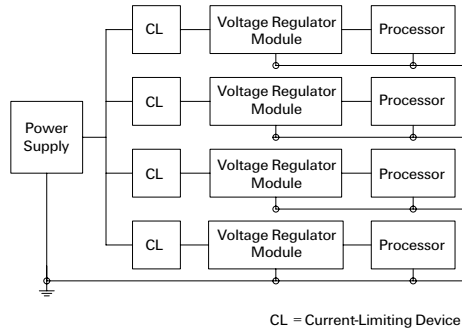
Application Summaries

Consumer Device Subsystems

Voltage Regulation Modules (VRMs)

Voltage regulation modules (VRMs) are used to supply power to central processing units. Due to load-change transients, processors can draw up to 13A. Also, during normal operation the current demand can change by as much as 7A as processor activity levels change. These high-current immediate demands can cause components to fail. The following Circuit Protection can help prevent the VRM from damaging the processor in the event of a VRM failure.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



Device Bays

The specifications for hot-swappable bays used in high-availability applications, such as servers and industrial computers, typically recommend overcurrent protection. An externally accessible port such as IEEE1394 or USB may also be used. The devices below are recommended for hot-swappable bay designs.

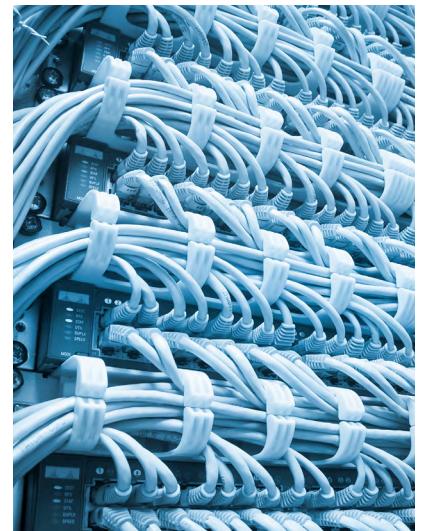
- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



Fibre Channel

A fault, such as a short circuit, that occurs during testing or hot-swapping a peripheral component interconnect (PCI) card can cause significant damage. Incorrect insertion of the gigabit interface converter (GBIC) or a foreign object placed into the connector can also cause permanent damage to the system. Protection on the PCI bus input is typically used as well as a secondary protector for the GBIC I/O. We recommend the following Littelfuse devices for this application.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices



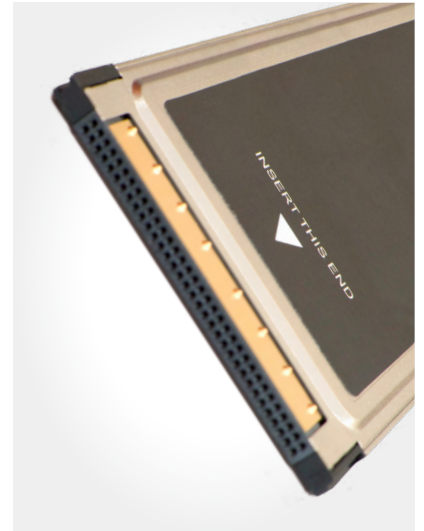
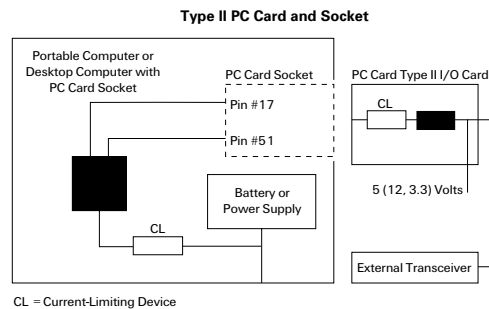
Application Summaries

Consumer Device Subsystems

PC Cards and Sockets

Short circuits from external sources are the primary hazards for PC cards. The devices below can help protect against large current inrushes that can damage the PC card or the PC card bus.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- ESD devices
- PolyZen devices



Motherboard Components

Since power-sensitive computer electronics such as flash memory can be exposed to voltages well in excess of the bus voltage, they require protection. Voltage spikes can result from a hot disconnect of a peripheral, an internal system shutdown or other internal power fluctuation. The integrated PolyZen device protects like a Zener diode while being capable of withstanding the high-power fault conditions that can occur in computer electronics. A coordinated protection scheme using the devices below is recommended as a solution in this application.

- PolySwitch Surface-mount devices
- ESD devices



Antennas

When used in antenna applications, PolySwitch devices can help limit the flow of dangerously high currents during fault conditions. As resettable polymer positive temperature coefficient (PPTC) devices, PolySwitch devices can reset back to normal operating mode once the fault condition is removed.

- PolySwitch Surface-mount devices



Application Summaries

Consumer Device Displays

LCD Monitors

Power for LCD monitors is supplied from the 5V and 12V buses. The LCD controller itself and the surrounding controller logic are powered from the 5V bus. The LCD inverter and the electronics on the board are powered from the 12V bus. Misconnections and mishandling of the monitors during assembly or while in use can cause large overloads and short circuits in the system, damaging expensive components. For this reason, the following Littelfuse Circuit Protection devices are recommended for LCD monitor applications.

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- ESD devices



Displays

PolySwitch resettable devices can be thermally linked to the LCD glass. They can protect the power module if the control circuitry fails to turn off the element and help prevent thermal runaway. The following devices are suitable for use in display applications:

- PolySwitch Radial-leaded devices
- PolySwitch Surface-mount devices
- ESD devices



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Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, automotive, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

Application Solution Guide

		Overcurrent Circuit Protection				Overvoltage Circuit Protection		Overtemperature Protection	Hybrid Protection
		PolySwitch Devices	PESD Devices	ChipSESD Devices	Gas Discharge Tubes	MHP-TAM Devices		2Pro Devices	PolyZen Devices
APPLIANCES	Buttons		•	•					
	Compressors	•							
	Displays	•	•	•					
	Motors	•							
	Power supplies	•			•			•	•
	Transformers	•						•	
	TRIACs	•							
AUTOMOTIVE	ABS systems	•				•			
	Glow Plug ECU								
	Diesel Motor Preheater								
	Antennae	•	•	•					
	Cigarette lighter accessories	•							•
	Connectors	•							
	Displays	•	•	•					
	Electronic control units	•	•	•		•			
	HVAC and climate control	•				•			•
	Infotainment and navigation systems	•	•	•					•
	Motors	•				•			
	Wire harness	•							
BATTERIES	Li-ion	•	•	•		•			
	Ni-Cd	•	•	•		•			
	Ni-MH	•	•	•		•			
BUSINESS AND RETAIL EQUIPMENT	Antennae		•	•					
	Audio Input / Output	•	•	•					
	Batteries	•							
	Buttons	•							
	Displays	•	•	•					
	Motherboard components	•							
	Ports	•	•	•					
	HDDS	•	•	•					•
	Power Input	•							•

Application Solution Guide

		Overcurrent Circuit Protection				Overvoltage Circuit Protection		Overtemperature Protection	Hybrid Protection
		PolySwitch Devices	PESD Devices	ChipSESD Devices	Gas Discharge Tubes	MHP-TAM Devices		2Pro Devices	PolyZen Devices
COMMUNICATIONS	Antennae		•	•	•				
	Audio Input / Output	•	•	•	•				•
	Batteries	•							
	Buttons	•	•	•					
	Displays	•	•	•					
	Fans	•							
	HDDs	•	•	•					•
	HPNA	•	•	•	•				
	Low-speed test ports	•	•	•	•			•	
	MoCA	•	•	•	•				
	Motherboard components	•							
	Networking over powerline	•	•	•	•			•	
	Ports	•	•	•	•			•	
	Power input	•			•			•	•
	Power over Ethernet	•	•	•	•			•	
ENERGY AND SOLAR	Batteries	•	•	•					
	Charge controllers	•	•	•	•			•	
	Combiner boxes	•			•				
	Inverters	•	•	•	•				
	Junction boxes		•	•					
	Disconnect Boxes	•	•	•	•				
HOME ENTERTAINMENT	Audio Input / Output	•			•				•
	Batteries	•	•	•		•			
	Buttons		•	•					
	Displays	•	•	•					
	HDDS	•	•	•					•
	Motors	•							
	PCB components	•							
	Ports	•	•	•	•				
	Power Input	•			•			•	•

Application Solution Guide

		Overcurrent Circuit Protection				Overvoltage Circuit Protection		Overtemperature Protection	Hybrid Protection
		PolySwitch Devices	PESD Devices	ChipSESD Devices	Gas Discharge Tubes	MHP-TAM Devices		2Pro Devices	PolyZen Devices
INDUSTRIAL	Buttons	•	•	•	•				
	Compressors	•				•			
	Displays	•	•	•					
	Electromagnetic loads	•							
	Motors	•							
	Power Input	•			•			•	•
	Transformers	•							
	UPS Backup	•		•		•			
LIGHTING	CFL electronic ballasts	•						•	
	LED ballasts	•						•	
	LED controllers	•						•	•
	LED drivers	•						•	•
	PN junction								
	Power input	•						•	•
	Power supplies	•						•	•
	TRIACs	•							
MOBILE DEVICES	Antennae		•	•					
	Audio Input / Output	•	•	•					•
	Batteries	•				•			
	Buttons	•	•	•					
	Displays	•	•	•					
	LEDs	•							
	Ports	•	•	•					
	Power Input	•							•
PERSONAL COMPUTERS	Antennae	•	•	•					
	Audio Input / Output	•	•	•					
	Batteries	•	•	•					
	Buttons	•	•	•					
	Displays	•	•	•					
	Motherboard components	•	•	•					
	Ports	•	•	•					
	Power Input	•							•

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POLYZEN DEVICES

Polymer Protected Zener Diode

PolyZen devices are polymer-enhanced, precision Zener diodes. They offer resettable protection against multi-Watt fault events without the need for multi-Watt heat sinks.

The Zener diode used for voltage clamping a PolyZen device was selected due to its relatively flat voltage vs. current response. This helps improve output voltage clamping, even when input voltage is high and diode currents are large.

An advanced feature of the PolyZen device is that the Zener diode is thermally coupled to a resistively non-linear, PPTC (polymer positive temperature coefficient) layer. This PPTC layer is fully integrated into the device and is electrically in series between V_{IN} and the diode clamped V_{OUT} .

This advanced PPTC layer responds to either extended diode heating or overcurrent events by transitioning from a low to high resistance state, also known as “tripping.” A tripped PPTC will limit current and generate voltage drop. It helps to protect both the Zener diode and the follow-on electronics and effectively increases the diode’s power handling capability.

The polymer-enhanced Zener diode helps protect sensitive portable electronics from damage caused by inductive voltage spikes, voltage transients, incorrect power supplies and reverse bias. These devices are particularly suitable for portable electronics and other low-power DC devices.



BENEFITS

- Stable Zener diode helps shield downstream electronics from overvoltage and reverse bias
- Trip events shut out overvoltage and reverse bias sources
- Analog nature of trip events helps minimize damage from upstream inductive spikes
- Minimal power dissipation requirements
- Single component placement

FEATURES

- Overvoltage transient suppression
- Stable V_Z vs. fault current
- Time delayed, overvoltage trip
- Time delayed, reverse bias trip
- Multi-Watt power handling capability
- Integrated device construction
- RoHS compliant
- Halogen free
(refers to: Br $\geq$ 900ppm, Cl $\geq$ 900ppm, Br+Cl $\geq$ 1500ppm)

APPLICATIONS

- DC power port protection in portable electronics
- DC power port protection for systems using barrel jacks for power input
- Internal overvoltage and transient suppression
- DC output voltage regulation
- Tablet PCs and portable electronics

PolyZen Devices
Polymer Protected Zener Diode

Figure PZ1 – Typical Application Block Diagram

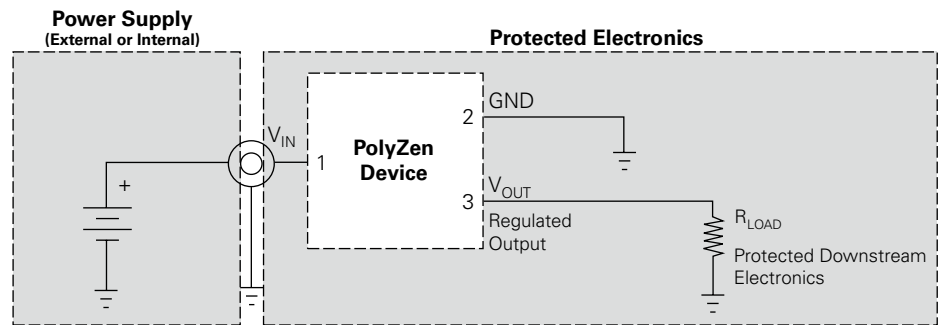


Table PZ1 – Electrical Characteristics

(Performance ratings @ 25°C unless otherwise specified)

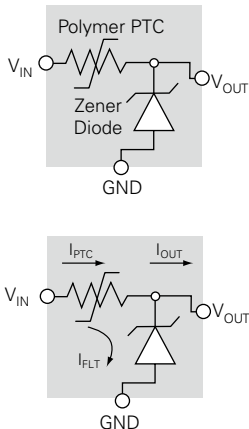
Part Number	V _Z (V)			I _{ZT} (A)	I _{HOLD} @ 20°C (A)	R _{Typ} (Ω)	R _{1MAX} (Ω)	V _{INT MAX}		I _{FLT MAX}	
	Min	Typ	Max					V _{INT MAX} (V)	Test Current (A)	I _{FLT MAX} (A)	Test Voltage (V)
ZEN056V130A24LS	5.45	5.60	5.75	0.10	1.30	0.12	0.16	24	3	+10/-40	+24/-16
ZEN059V130A24LS†	5.80	5.90	6.00	0.10	1.30	0.12	0.15	24	3	+6/-40	+24/-16
ZEN065V130A24LS	6.35	6.50	6.65	0.10	1.30	0.12	0.16	24	3	+6/-40	+24/-16
ZEN098V130A24LS	9.60	9.80	10.00	0.10	1.30	0.12	0.16	24	3	+3.5/-40	+24/-16
ZEN132V130A24LS	13.20	13.40	13.60	0.10	1.30	0.12	0.16	24	3	+2/-40	+24/-16
ZEN164V130A24LS	16.10	16.40	16.60	0.10	1.30	0.12	0.16	24	3	+1.25/-40	+24/-16
ZEN056V230A16LS	5.45	5.60	5.75	0.10	2.30	0.04	0.06	16	5	+5/-40	+16/-12
ZEN065V230A16LS	6.35	6.50	6.65	0.10	2.30	0.04	0.06	16	5	+3.5/-40	+16/-12
ZEN098V230A16LS	9.60	9.80	10.00	0.10	2.30	0.04	0.06	16	5	+3.5/-40	+16/-12
ZEN132V230A16LS	13.20	13.40	13.60	0.10	2.30	0.04	0.06	16	5	+2/-40	+20/-12
ZEN056V075A48LS	5.45	5.60	5.75	0.10	0.75	0.28	0.45	48	3	+10/-40	+48/-16
ZEN132V075A48LS	13.20	13.40	13.60	0.10	0.75	0.28	0.45	48	3	+2/-40	+48/-16
ZEN056V115A24LS	5.45	5.60	5.75	0.10	1.15	0.15	0.18	24	3	+10/-40	+24/-16
NEW ZEN056V130A16YM	5.35	5.60	5.85	0.10	1.30	0.110	0.160	14	3	+3/-40	+16/-12
NEW ZEN056V175A12YM	5.35	5.60	5.85	0.10	1.75	0.050	0.095	12	4	+3/-40	+12/-12
NEW ZEN132V130A16YM	13.20	13.40	13.80	0.10	1.30	0.110	0.160	14	3	+1/-40	+20/-12
NEW ZEN132V175A12YM	13.20	13.40	13.80	0.10	1.75	0.050	0.095	12	4	+1/-40	+20/-12
NEW ZEN056V130A24YC	5.35	5.60	5.85	0.10	1.30	0.110	0.170	24	3	+4/-40	+24/-16
NEW ZEN056V230A16YC	5.35	5.60	5.85	0.10	2.30	0.040	0.070	16	5	+3/-40	+16/-12
NEW ZEN056V260A16YC	5.35	5.60	5.85	0.10	2.60	0.040	0.055	16	5	+3/-40	+16/-12
NEW ZEN132V130A24YC	13.20	13.40	13.80	0.10	1.30	0.110	0.170	24	3	+1/-40	+24/-16
NEW ZEN132V230A16YC	13.20	13.40	13.80	0.10	2.30	0.040	0.070	16	5	+1/-40	+20/-12
NEW ZEN132V260A16YC	13.20	13.40	13.80	0.10	2.60	0.040	0.055	16	5	+1/-40	+20/-12

LS module height is 1.7mm typical. YM module height is 1.2mm typical. YC module height is 1.3mm typical.

† Typical operating current is 500µA @ 5.0V which meets USB suspend mode requirement.

Table PZ2 – Definition of Terms

V _Z	Zener clamping voltage measured at current I _{ZT} and 20°C.
I _{ZT}	Test current at which V _Z is measured.
I _{HOLD}	Maximum steady state current I _{PTC} that will not generate a trip event at the specified temperature. Ratings assume I _{FLT} = 0A
R _{Typ}	Typical resistance between V _{IN} and V _{OUT} pins when the device is at room temperature.
R _{1MAX}	The maximum resistance between V _{IN} and V _{OUT} pins, at room temperature, one hour after first trip or after reflow soldering.
I _{FLT}	Current flowing through the Zener diode.
I _{FLT MAX}	Maximum RMS fault current the Zener diode component of the device can withstand and remain resettable; testing is conducted at rated voltage with no load connected to V _{OUT} .
V _{INT MAX}	The voltage (V _{IN} - V _{OUT} "post trip") at which typical qualification devices (98% devices, 95% confidence) survived at least 100 trip cycles and 24 hours trip endurance when "tripped" at the specified voltage and current (I _{PTC}).
I _{PTC}	Current flowing through the PPTC portion of the circuit.
I _{OUT}	Current flowing out the V _{OUT} pin of the device.
Trip Event	A condition where the PPTC transitions to a high resistance state, thereby limiting I _{PTC} , and significantly increasing the voltage drop between V _{IN} and V _{OUT} .



PolyZen Devices

Polymer Protected Zener Diode

Figures PZ2-PZ9 – Typical Performance Curves for PolyZen Devices - LS Series

Figure PZ2

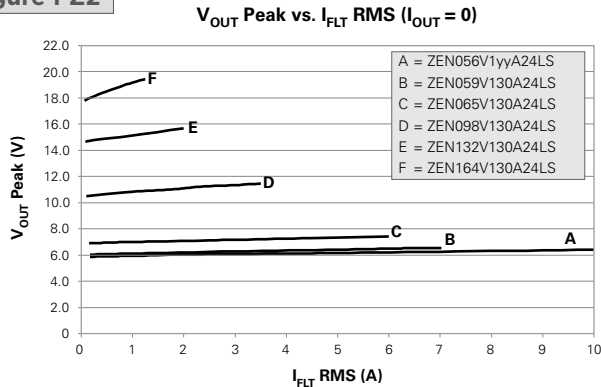


Figure PZ3

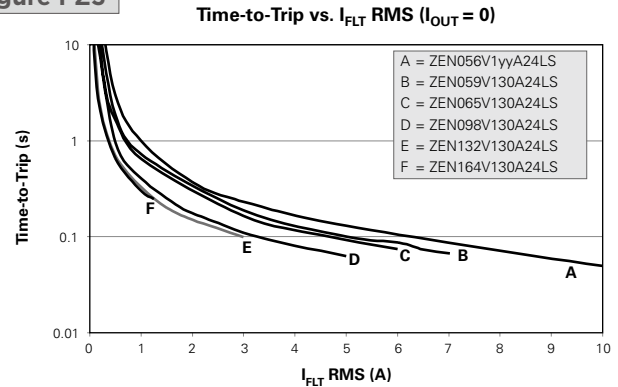


Figure PZ4

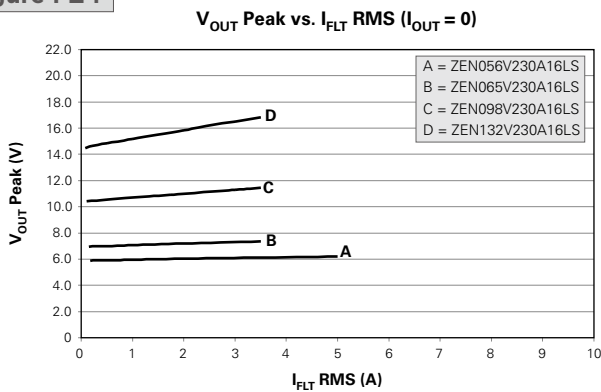


Figure PZ5

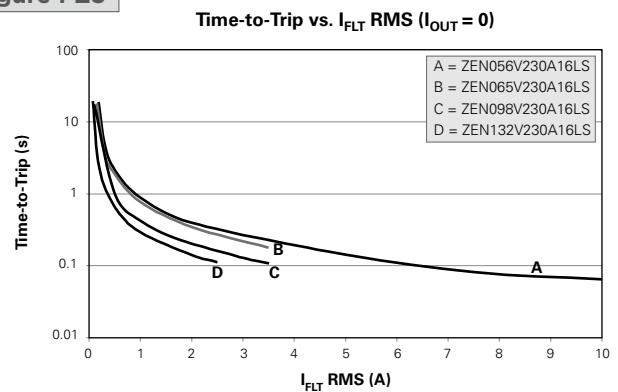


Figure PZ6

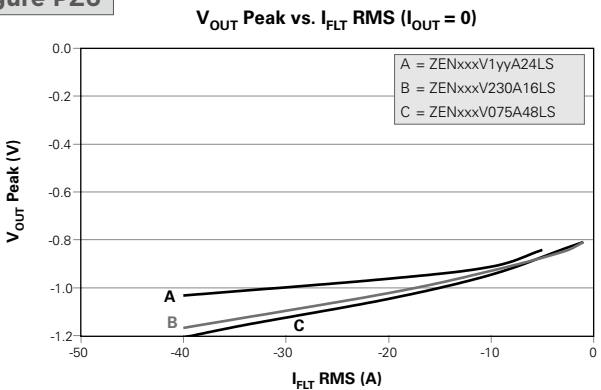


Figure PZ7

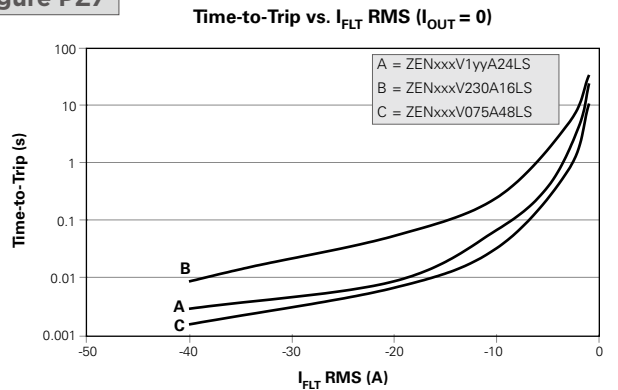


Figure PZ8

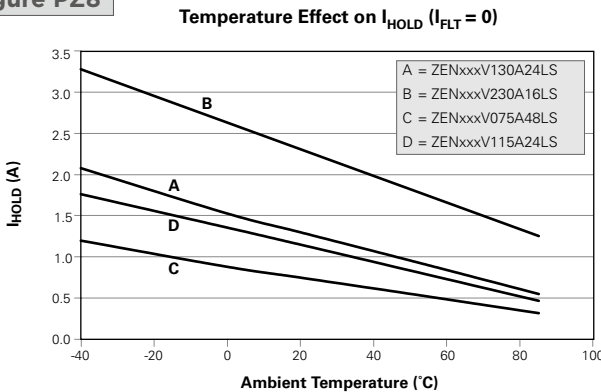
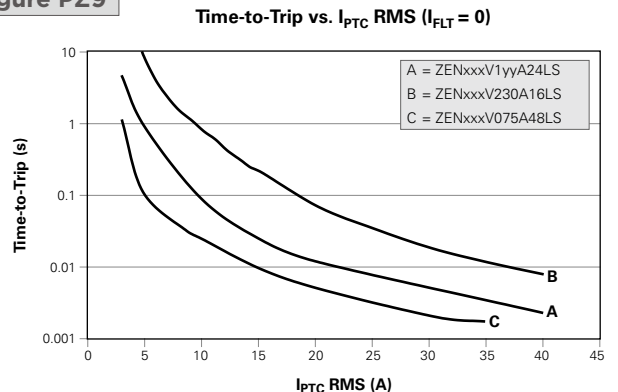


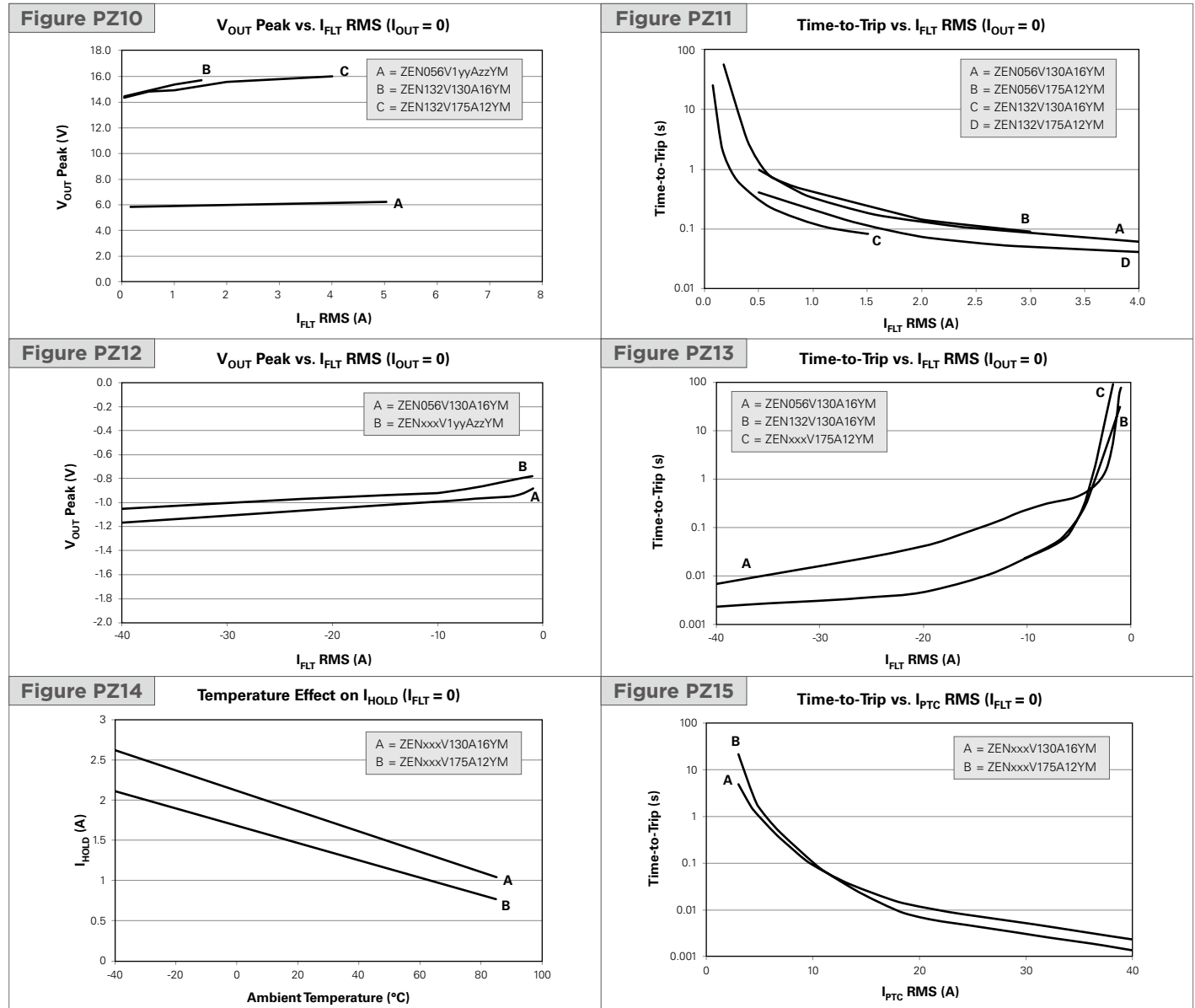
Figure PZ9



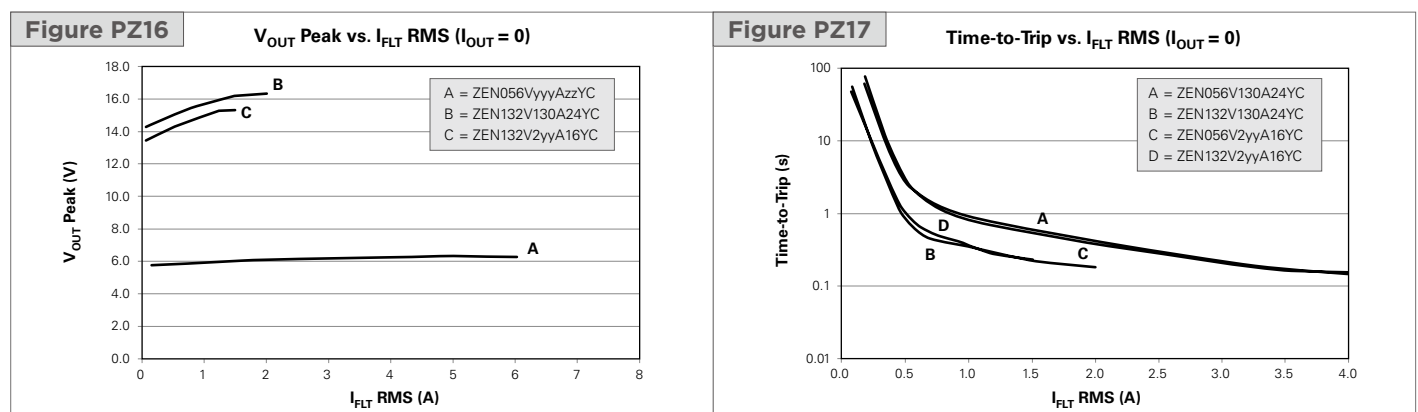
PolyZen Devices

Polymer Protected Zener Diode

Figures PZ10-PZ15 – Typical Performance Curves for PolyZen Devices -YM Series



Figures PZ16-PZ21 – Typical Performance Curves for PolyZen Devices -YC Series



PolyZen Devices

Polymer Protected Zener Diode

Figures PZ16-PZ21 — Typical Performance Curves for PolyZen Devices -YC Series (Cont'd)

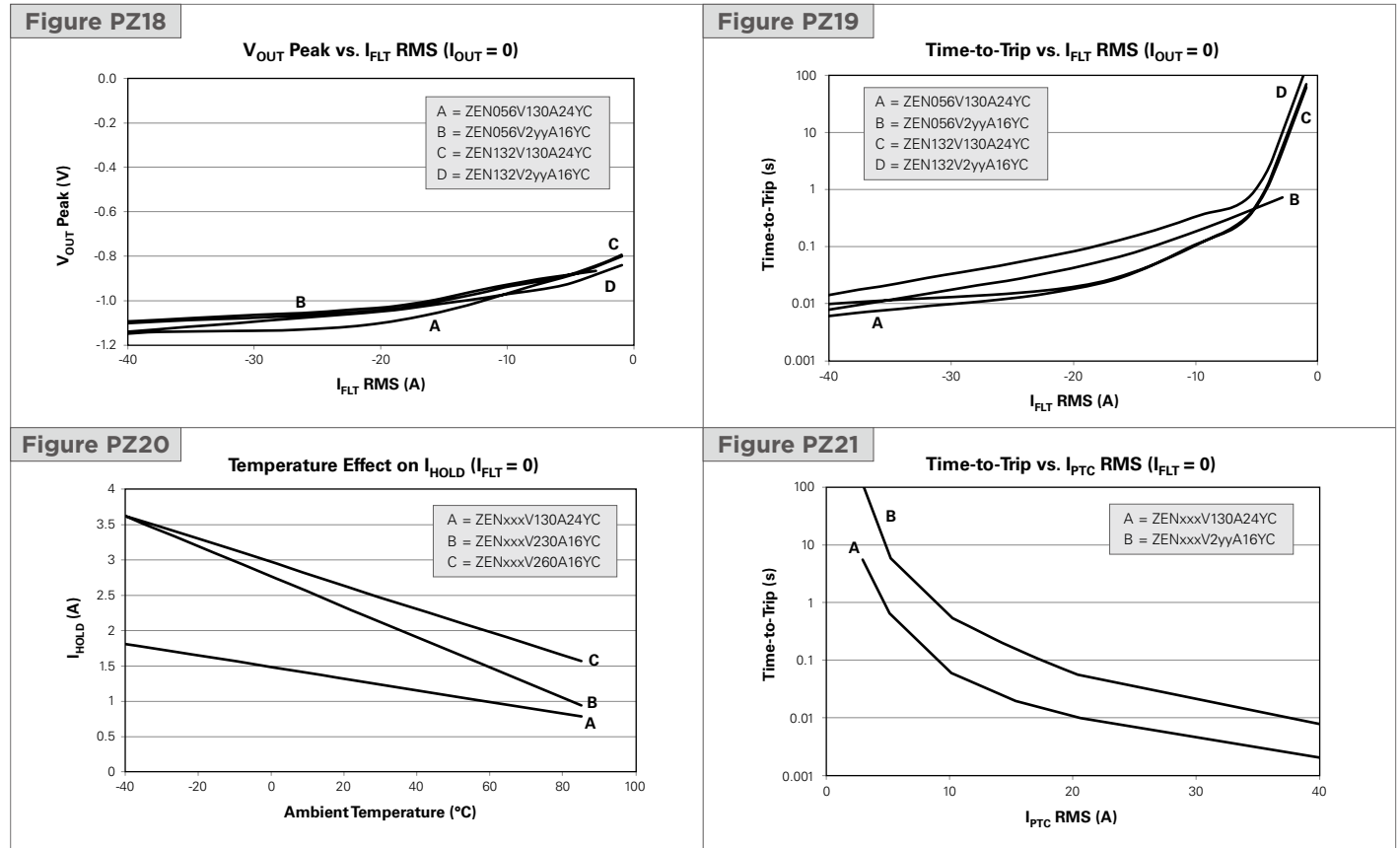


Table PZ3 — General Characteristics for PolyZen Devices

Operating temperature range	-40° to +85°C	
Storage temperature	-40° to +85°C	
ESD withstand	15kV	Human body model
Diode capacitance	4200pF	Typical @ 1MHz, 1V RMS
Construction	RoHS compliant	

Figures PZ22-PZ34 — Basic Operation Examples for PolyZen Devices - LS Series

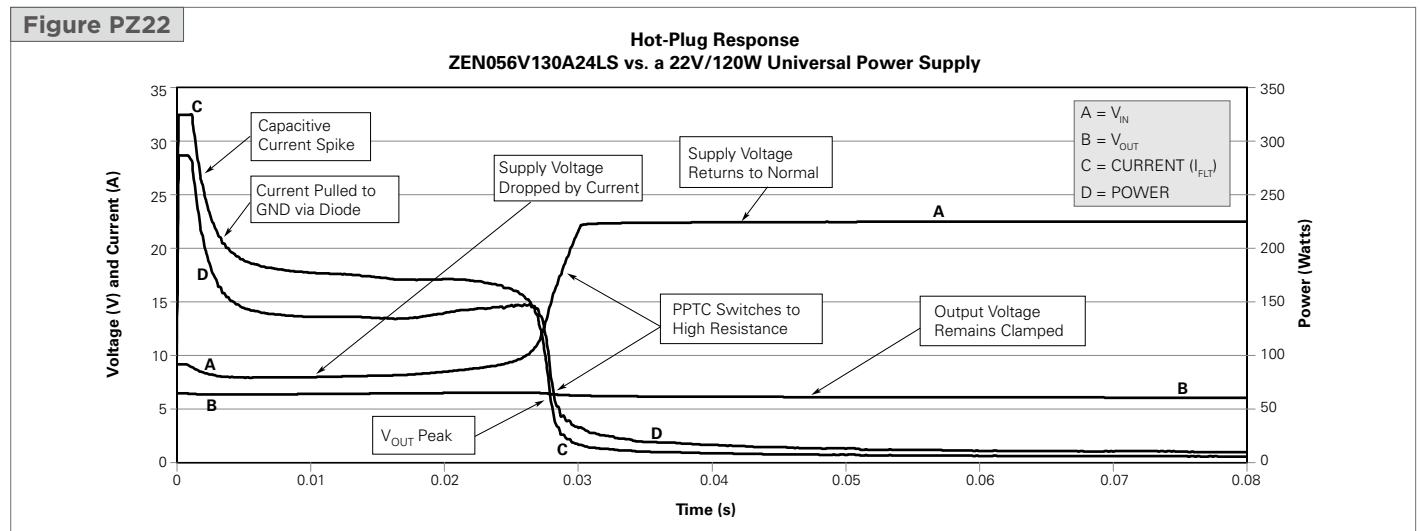


Figure PZ23

Typical Fault Response: ZEN056V1xxA24LS
20V, 3.5A Current Limited Source ($I_{OUT}=0$)

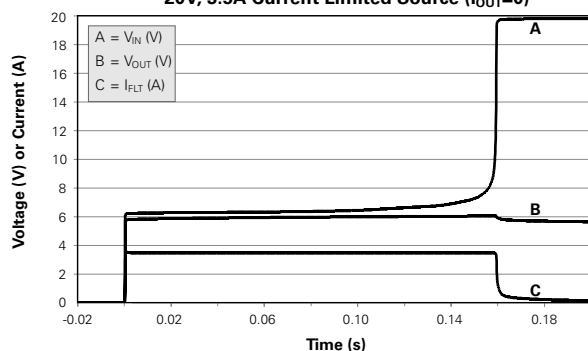


Figure PZ24

Typical Fault Response: ZEN059V130A24LS
24V, 6A Current Limited Source ($I_{OUT}=0$)

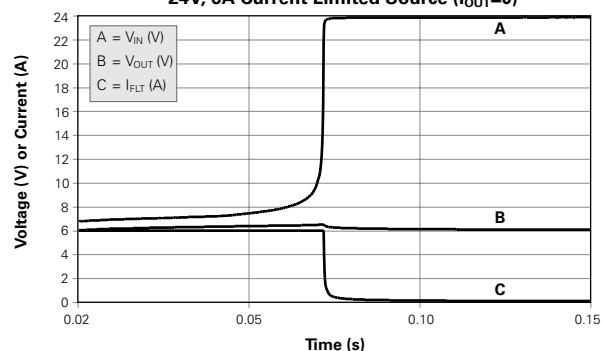


Figure PZ25

Typical Fault Response: ZEN065V130A24LS
24V, 5.0A Current Limited Source ($I_{OUT}=0$)

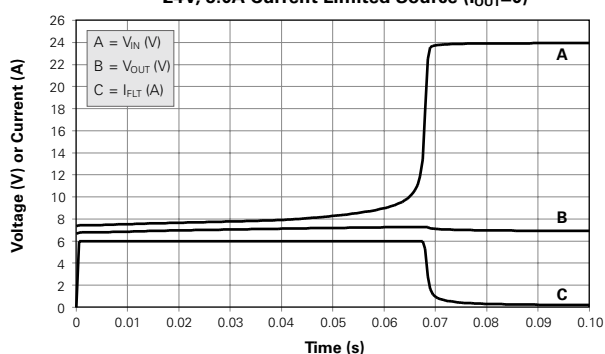


Figure PZ26

Typical Fault Response: ZEN098V130A24LS
24V, 3.5A Current Limited Source ($I_{OUT}=0$)

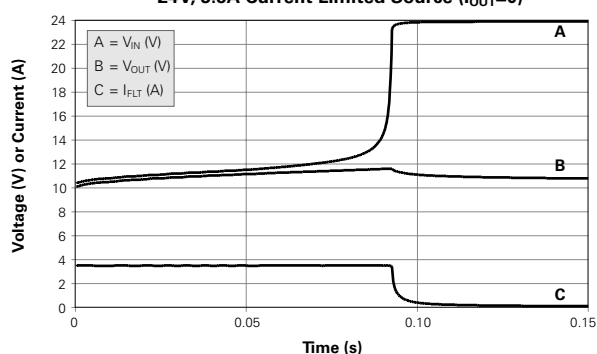


Figure PZ27

Typical Fault Response: ZEN132V130A24LS
24V, 2.0A Current Limited Source ($I_{OUT}=0$)

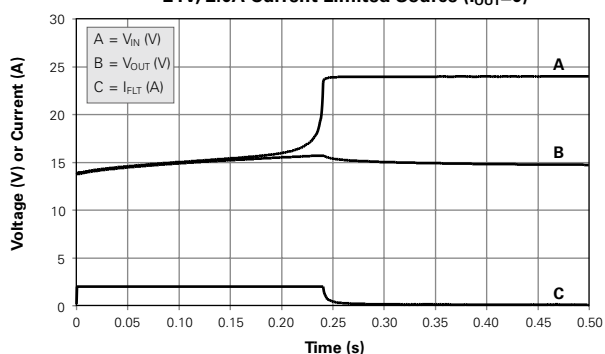


Figure PZ28

Typical Fault Response: ZEN164V130A24LS
24V, 1.0A Current Limited Source ($I_{OUT}=0$)

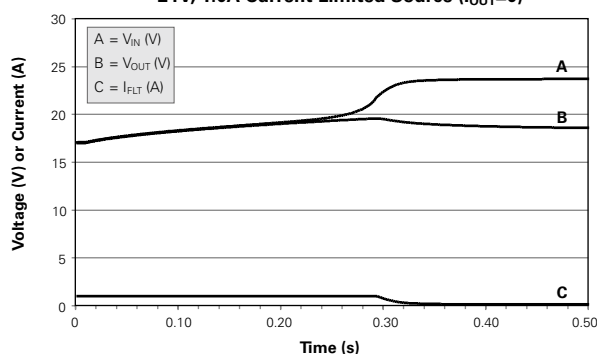


Figure PZ29

Typical Fault Response: ZEN056V230A16LS
16V, 5.0A Current Limited Source ($I_{OUT}=0$)

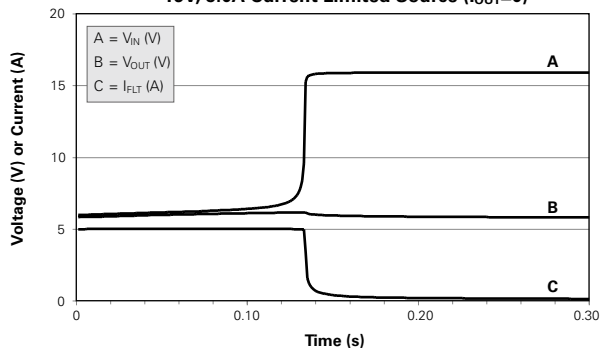
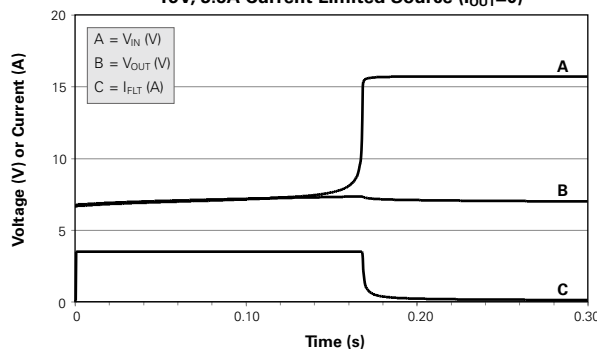
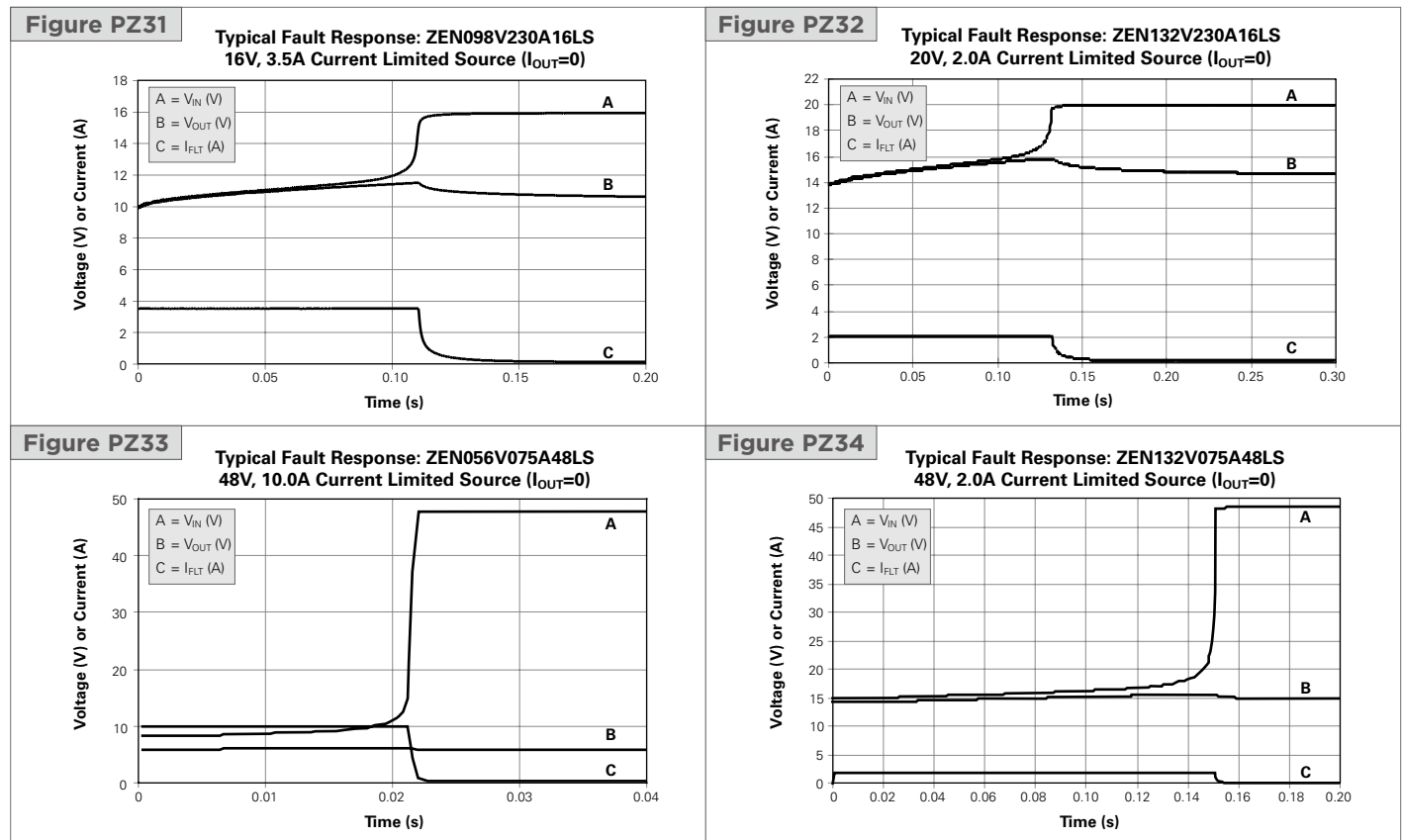


Figure PZ30

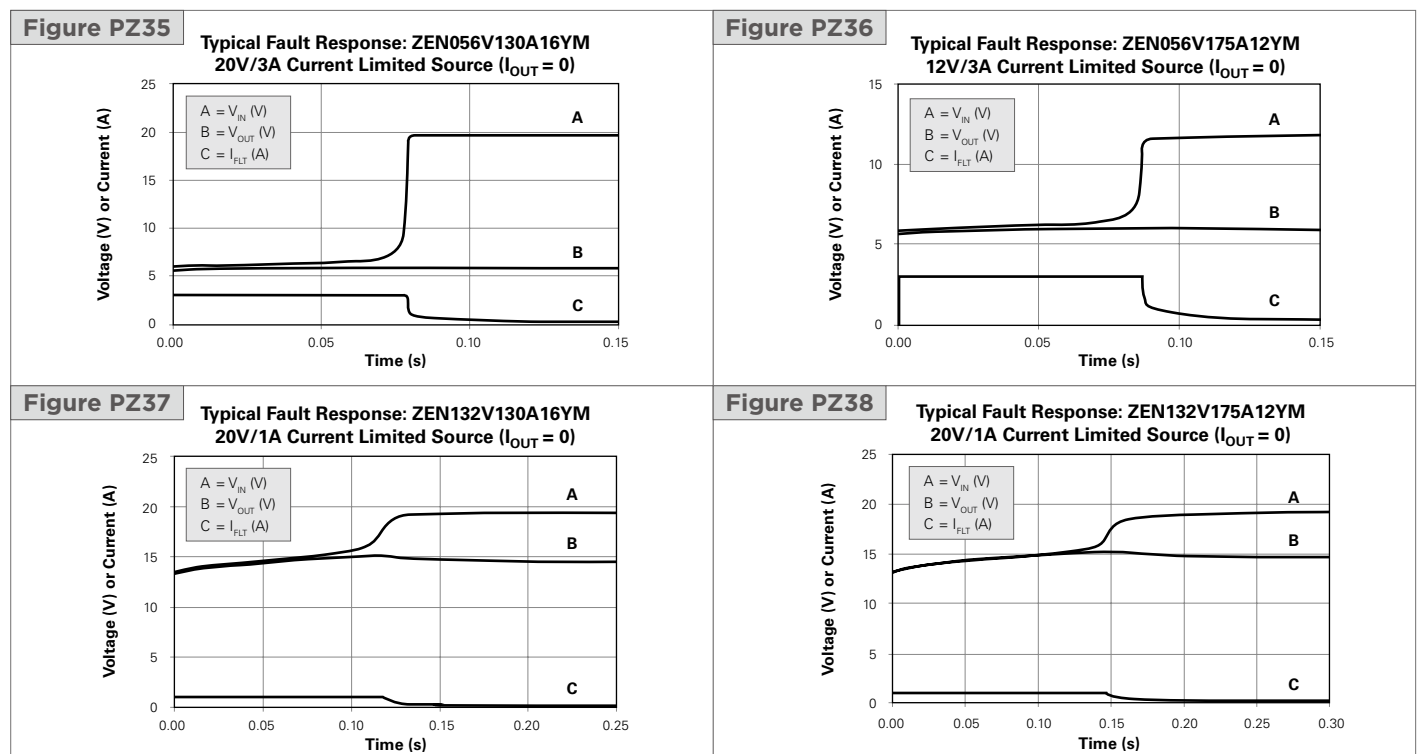
Typical Fault Response: ZEN065V230A16LS
16V, 3.5A Current Limited Source ($I_{OUT}=0$)



Figures PZ22-PZ34 — Basic Operation Examples for PolyZen Devices - LS Series (Cont'd)



Figures PZ35-PZ38 — Basic Operation Examples for PolyZen Devices - YM Series



Figures PZ39-PZ44 — Basic Operation Examples for PolyZen Devices -YC Series

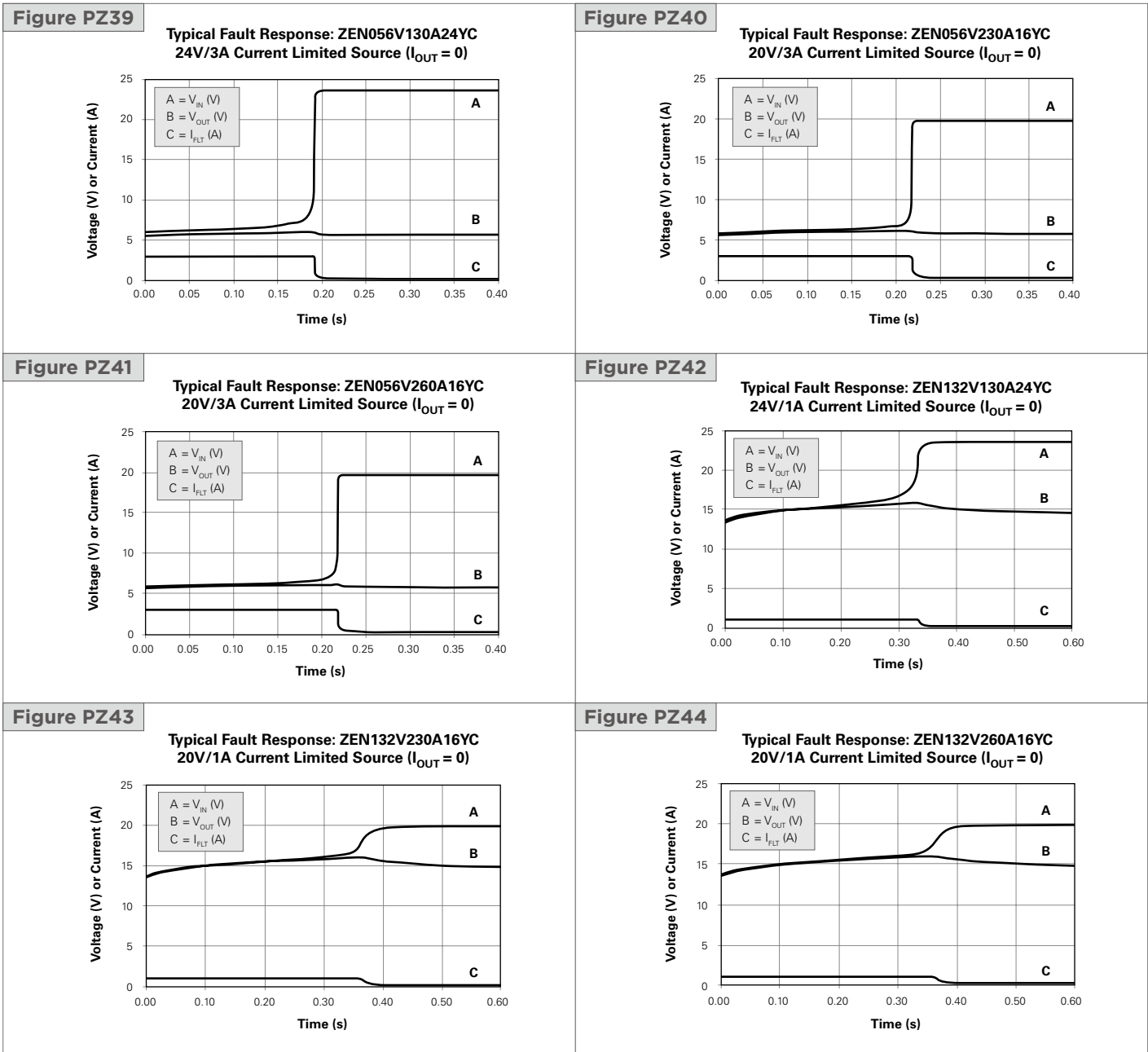


Table PZ4 - Packaging and Marking Information for PolyZen Devices

Part Number	Bag Quantity	Tape & Reel Quantity	Standard Package
ZENxxxVyyyAzzLS	—	3,000	15,000
ZENxxxVyyyAzzYM	—	3,000	30,000
ZENxxxVyyyAzzYC	—	4,000	20,000

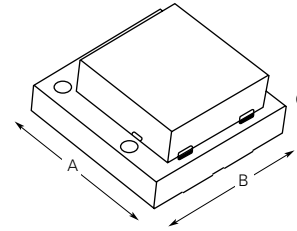
PolyZen Devices

Polymer Protected Zener Diode

Table PZ5 — Dimensions in Millimeters and Inches

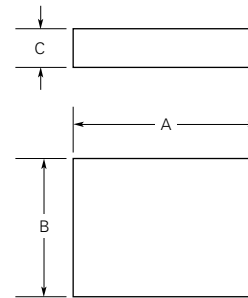
ZENxxxVyyyAzzLS Devices

	A		B		C	
	Min	Max	Min	Max	Min	Max
mm	3.85	4.15	3.85	4.15	1.40	2.00
in	(0.152)	(0.163)	(0.152)	(0.163)	(0.055)	(0.081)



ZENxxxVyyyAzzYM Devices

	A		B		C	
	Min	Max	Min	Max	Min	Max
mm	3.00	3.40	2.30	2.70	1.10	1.30
in	(0.118)	(0.134)	(0.091)	(0.106)	(0.043)	(0.051)



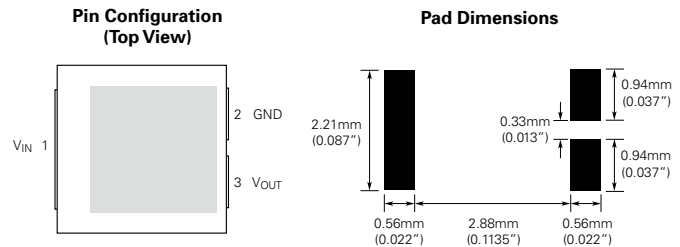
ZENxxxVyyyAzzYC Devices

	A		B		C	
	Min	Max	Min	Max	Min	Max
mm	4.80	5.20	3.80	4.20	1.20	1.40
in	(0.190)	(0.206)	(0.150)	(0.166)	(0.047)	(0.055)

Table PZ6 — Pad Layout and Configuration Information

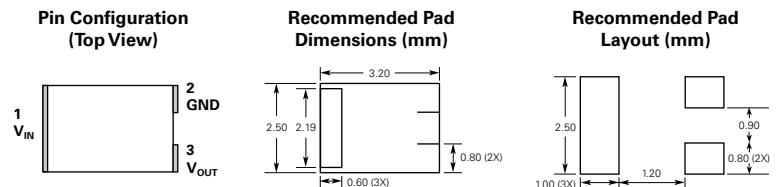
ZENxxxVyyyAzzLS Devices

Pin Number	Pin Name	Pin Function
1	V_{IN}	V_{IN} = Protected input to Zener diode
2	GND	GND = Ground
3	V_{OUT}	V_{OUT} = Zener regulated voltage output



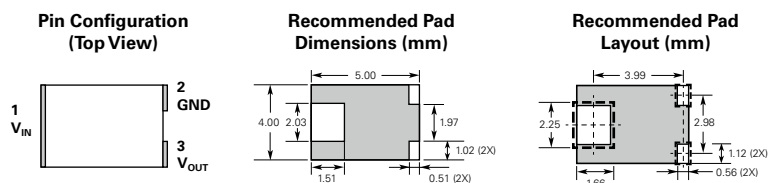
ZENxxxVyyyAzzYM Devices

Pin Number	Pin Name	Pin Function
1	V_{IN}	V_{IN} = Protected input to Zener diode
2	GND	GND = Ground
3	V_{OUT}	V_{OUT} = Zener regulated voltage output



ZENxxxVyyyAzzYC Devices

Pin Number	Pin Name	Pin Function
1	V_{IN}	V_{IN} = Protected input to Zener diode
2	GND	GND = Ground
3	V_{OUT}	V_{OUT} = Zener regulated voltage output

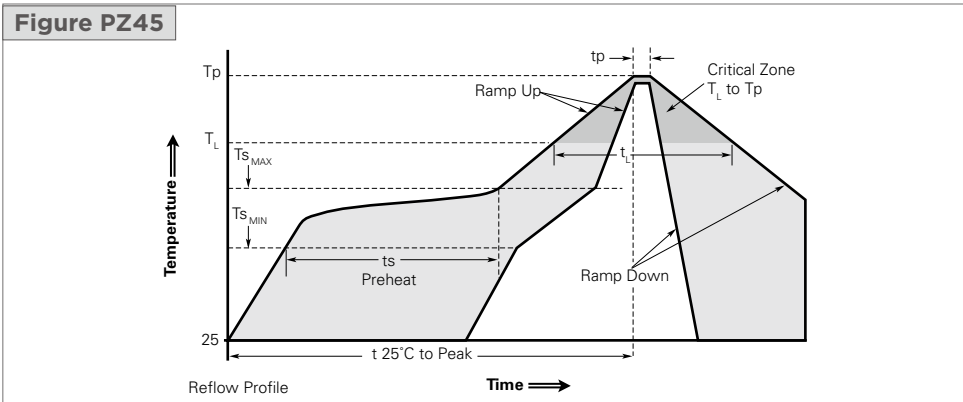


Solder Reflow and Rework Recommendation

Classification Reflow Profiles

Profile Feature	ZENxxxVyyyAzzLS Devices	
	ZENxxxVyyyAzzYM Devices	ZENxxxVyyyAzzYC Devices
	Pb-Free Assembly	Pb-Free Assembly
Average Ramp Up Rate (Ts _{MAX} to Tp) Preheat	3°C/ s Max	3°C/ s Max
• Temperature Min (Ts _{MIN})	150°C	150°C
• Temperature Max (Ts _{MAX})	200°C	200°C
• Time (ts Preheat)	60-180 s	60-180 s
Time Maintained Above:		
• Temperature (T _L)	217°C	217°C
• Time (t _L)	60-150 s	60-150 s
Peak/Classification Temperature (Tp)	260°C	250°C
Time within 5°C of Actual Peak Temperature		
Time (tp)	20-40 s	20-40 s
Average Ramp Down Rate (Tp to T _L)	6°C/ s Max	3°C/ s Max
Time 25°C to Peak Temperature	8 Minutes Max	8 Minutes Max

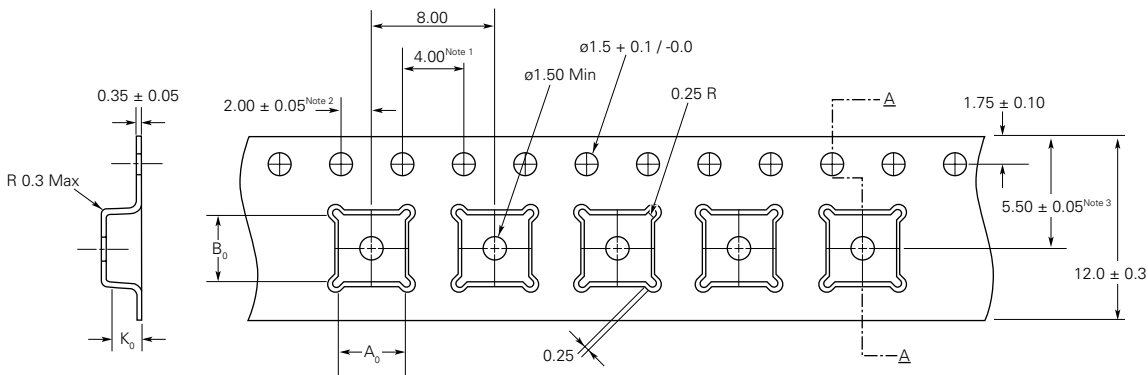
Note: All temperatures refer to top side of the package, measured on the package body surface.



Tape and Reel Specifications for PolyZen Devices in Millimeters

Figure PZ46 — EIA Referenced Taped Component Dimensions for ZENxxxVyyyAzzLS Devices in Millimeters (mm)

Description	ZENxxxVyyyAzzLS Devices
A ₀	4.35
B ₀	4.35
K ₀	2.30



- Notes:**
1. 10 sprocket hole pitch cumulative tolerance ±0.2
 2. Camber in compliance with EIA 481
 3. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole

PolyZen Devices

Polymer Protected Zener Diode

Figure PZ47 — Reel Dimensions for ZENxxxVyyyAzzLS Devices in Millimeters (mm)

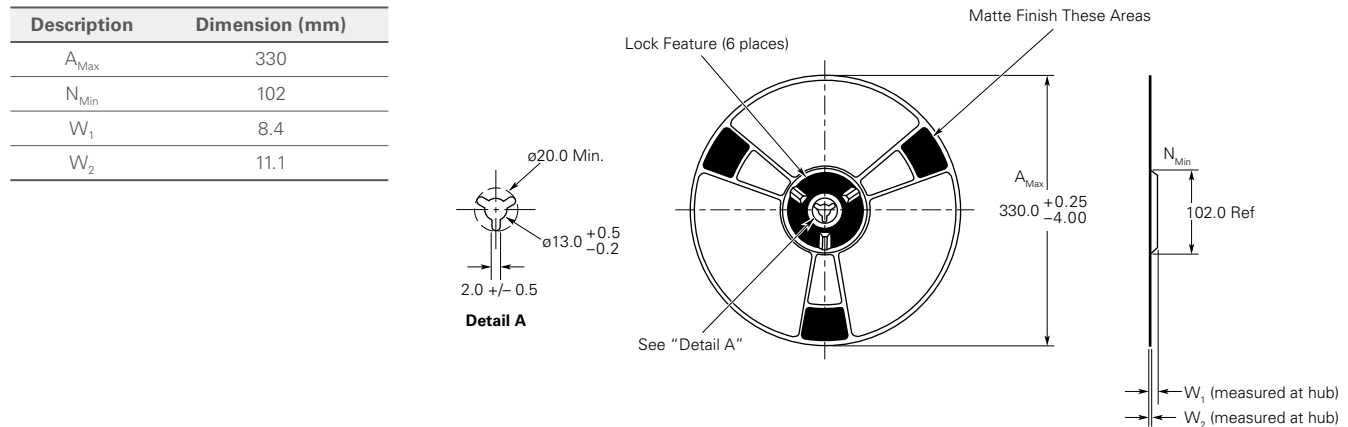


Figure PZ48 — EIA Referenced Taped Component Dimensions for ZENxxxVyyyAzzYM Devices in Millimeters (mm)

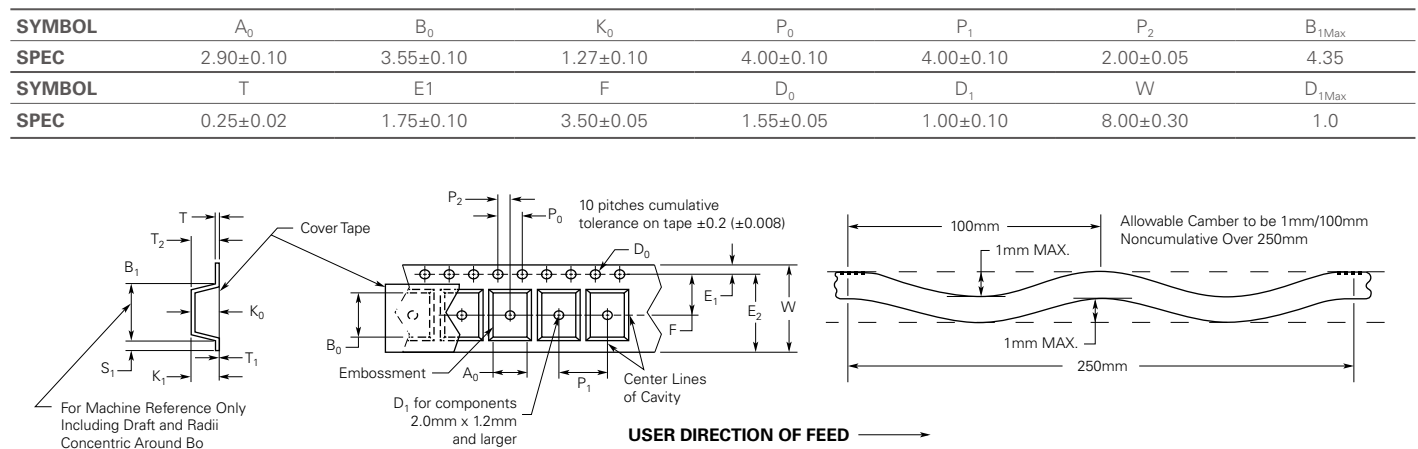
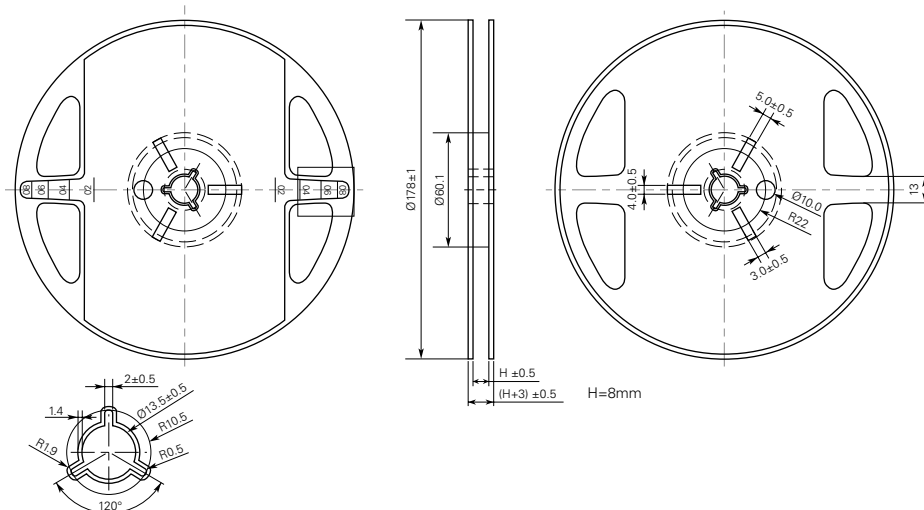


Figure PZ49 — Reel Dimensions for ZENxxxVyyyAzzYM Devices in Millimeters (mm)



PolyZen Devices

Polymer Protected Zener Diode

Figure PZ50 — EIA Referenced Taped Component Dimensions for ZENxxxVyyyAzzYC Devices in Millimeters (mm)

Item	Dimension	Tolerance
W	12.00	±0.10
P	8.00	±0.10
E	1.75	±0.10
F	5.50	±0.10
P ₂	2.00	±0.10
D	1.50	+0.10 -0.00
D ₁	1.50	±0.10
P ₀	4.00	±0.10
10P ₀	40.00	±0.20
A ₀	4.20	±0.10
B ₀	5.25	±0.10
K ₀	1.40	±0.10
t	0.24	±0.05

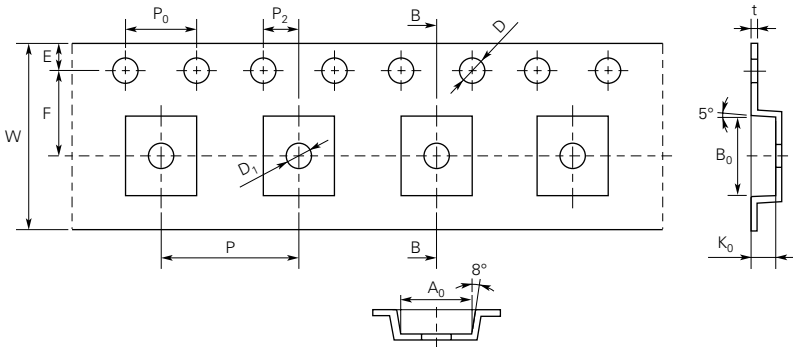
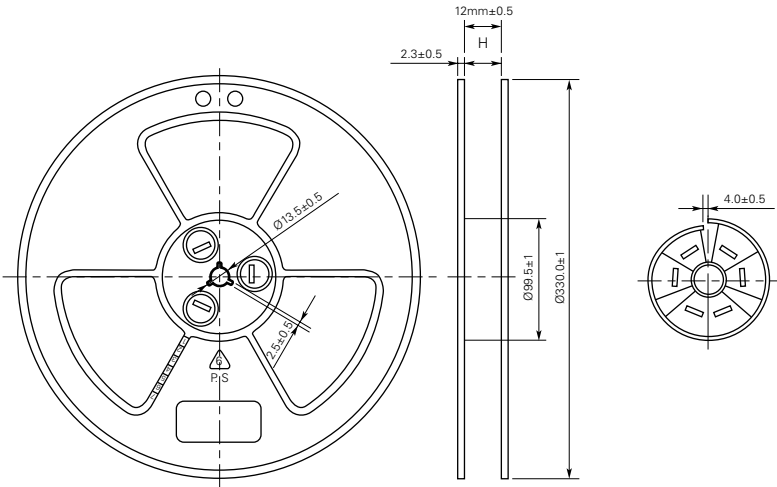
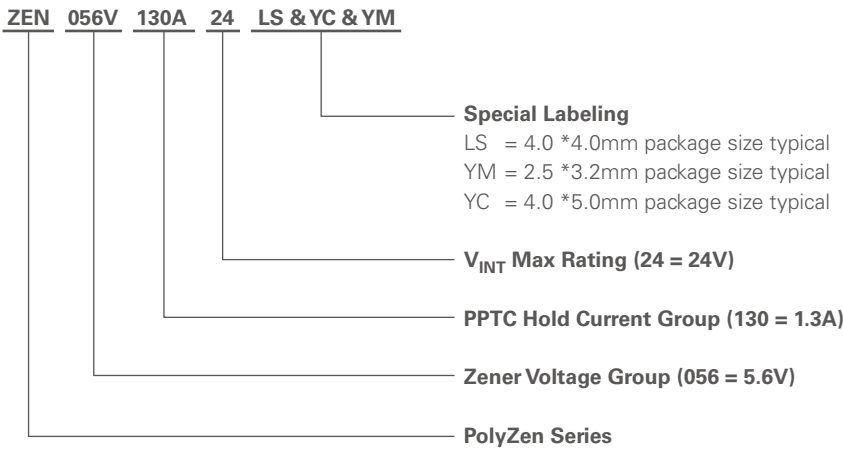


Figure PZ51 — Reel Dimensions for ZENxxxVyyyAzzYC Devices in Millimeters (mm)



Part Numbering System



PolyZen Devices

Polymer Protected Zener Diode

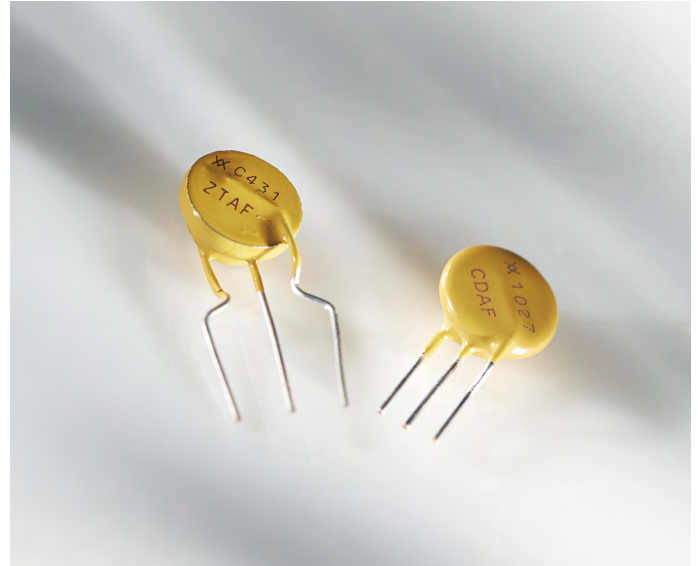
Notice:

Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, automotive, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

2PRO DEVICES

The 2Pro product is an integrated overcurrent/over-voltage protection device. The RoHS-compliant component incorporates PolySwitch PPTC (Polymeric Positive Temperature Coefficient) technology and MOV (Metal Oxide Varistor) technology in a single device to help reduce board space requirements and component count.

Damage to telephony communications equipment can be caused by various sources including lightning, electrostatic discharge (ESD), power contact and induction with AC lines. The 2Pro TM2P-10271 devices help provide current limiting during overcurrent events and voltage clamping during overvoltage events. After a fault condition is removed and power is cycled, 2Pro devices will reset so that the equipment remains operational.



The 2Pro device helps address the need for resettable circuit protection devices for use in cost-sensitive PSTN (Public Switched Telephone Network) and VoIP (Voice over Internet Protocol) telephony equipment. The widespread use of VoIP gateways in homes and enterprise environments as the primary means of voice delivery requires the utmost safety and reliability in equipment. 2Pro circuit protection devices help manufacturers comply with global safety standards, including UL 60950, TIA-968-A, IEC 60950 and ITU-T K.20/K.21. The UL 497A listed protector also helps provide ESD protection.

BENEFITS

- Single device helps reduce component count and footprint
- Helps reduce warranty returns
- Helps equipment comply with surge tests per: TIA-968-A, IEC 60950, ITU-T K.20/K.21
- Helps simplify UL 60950 testing
- Helps equipment comply with UL 60950

FEATURES

- RoHS compliant
- Halogen free (refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)
- Single overcurrent, overvoltage and ESD protection device
- Resettable overcurrent protection

APPLICATIONS

- Cordless telephones
- VoIP gateways
- Fax machines
- Data modems
- Set-top boxes
- Security systems
- MDF modules
- Analog and ISDN linecards

PolySwitch Resettable Devices

Radial-Leaded Devices

Table 2P1 — Electrical Characteristics

Overcurrent (terminals 1 – 2) — Performance ratings @ 20°C								
Part Number	I _{HOLD} (A)	I _{TRIP} (A)	Resistance† (Ω)			Time-to-Trip (s)†		
			R _{MIN}	R _{MAX}	R _{1 MAX*}	Typ	Max	
TM2P-10271	0.15	0.30	6.50	14.00	16.00	0.90	3.00	(@1A)
LVM2P-015R10431	0.15	0.30	6.50	14.00	16.00	0.90	3.00	(@1A)
LVM2P-035R14431	0.35	0.75	1.40	2.20	2.80	0.50	2.00	(@3A)
LVM2P-075R14431	0.75	1.50	0.37	0.80	1.00	0.90	1.20	(@7A)

Overvoltage (Terminals 2 – 3)					
Part Number	Varistor Voltage V @ 1mA		DC Resistance @ 100V (MΩ)	Maximum Clamping (V)	Rated Wattage (W)
	DC (V)	Tolerance			
TM2P-10271	260	+14% -7%	>10	455 (@25A)	0.25
LVM2P-015R10431	430	+10% -10%	>10	710 (@ 25A)	0.25
LVM2P-035R14431	430	+10% -10%	>10	710 (@ 50A)	0.60
LVM2P-075R14431	430	+10% -10%	>10	710 (@ 50A)	1.00

* Maximum device resistance at 20°C measured 1 hour post trip.
† Corresponds to operation below varistor voltages.

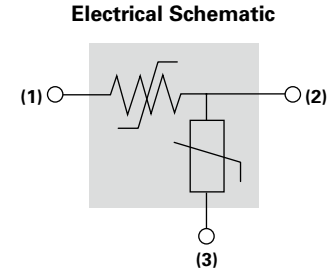
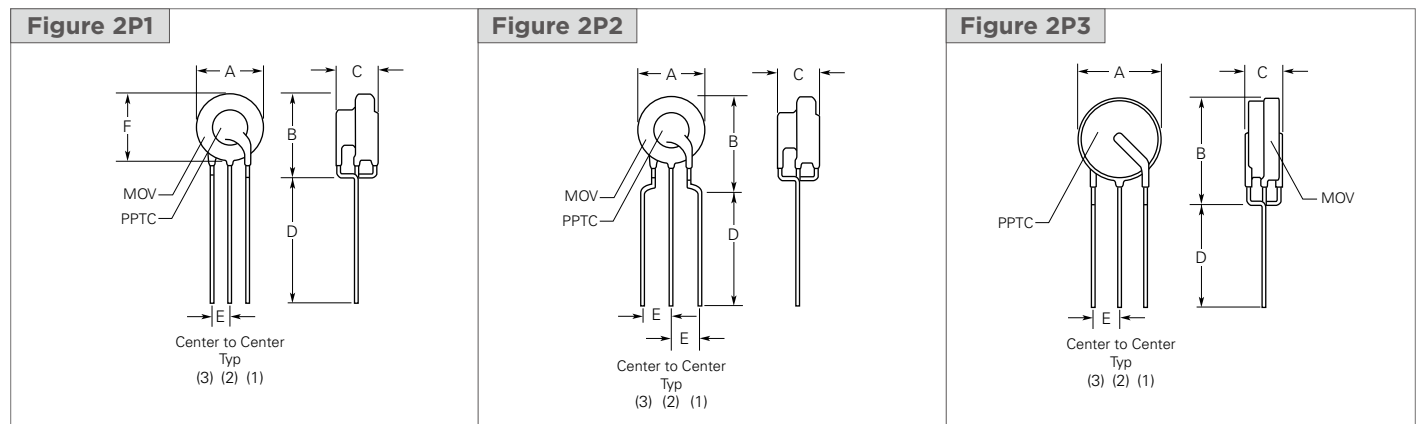


Table 2P2 — Dimensions in Millimeters and (Inches*)

Part	A		B		C		D		E	F		Figure
Number	Min	Max	Min	Max	Min	Max	Min	Max	Nom	Min	Max	
TM2P-10271												
mm	—	12.0	—	15.0	—	6.6	6.0	—	2.5	—	12.0	2P1
in*	—	(0.47)	—	(0.59)	—	(0.26)	(0.24)	—	(0.10)	—	(0.47)	
LVM2P-015R10431												
mm	—	12.0	—	17.0	—	7.4	8.5	11.5	5.1			2P2
in*	—	(0.47)	—	(0.67)	—	(0.29)	(0.34)	(0.45)	(0.20)			
LVM2P-035R14431												
mm	—	16.0	—	21.0	—	7.4	3.0	5.0	5.1			2P2
in*	—	(0.63)	—	(0.83)	—	(0.29)	(0.12)	(0.20)	(0.20)			
LVM2P-075R14431												
mm	—	16.0	—	21.0	—	7.4	3.0	5.0	2.5			2P3
in*	—	(0.63)	—	(0.83)	—	(0.29)	(0.12)	(0.20)	(0.10)			

* The dimensions in inches are rounded approximations.

Figures 2P1-2P3 — Dimension Figures



PolySwitch Resettable Devices
Radial-Leaded Devices

Figure 2P4 — Typical Time-to-Trip at 25°C

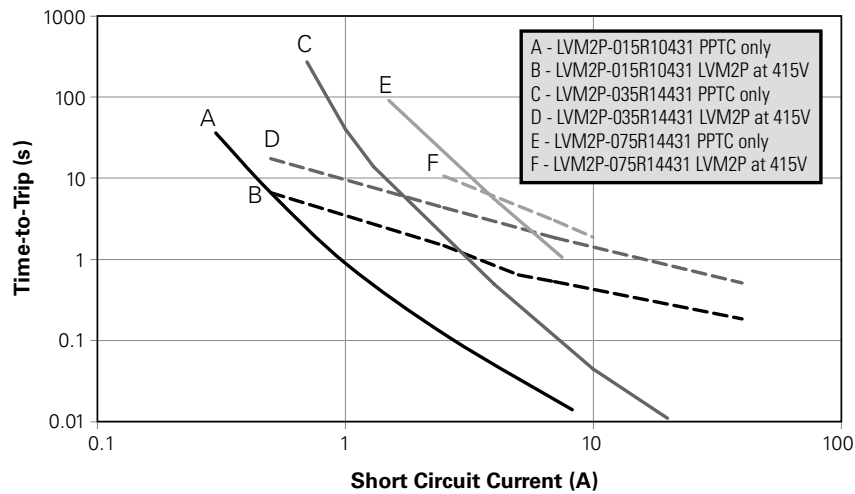


Table 2P3 — Physical Characteristics and Environmental Specifications

Physical Characteristics	
Lead Material	Tin-plated Copper, 0.33mm ² (22AWG), 0.64mm (0.025in)
Flammability	IEC 695-2-2 Needle Flame Test for 20s
Soldering Characteristics	ANSI Approved IPC/EIA/JEDEC J-STD-002, Category 3
Solder Heat Withstand	per IEC-STD 68-2-20, Test Tb, Method1A, Condition B, can withstand 10 Seconds at 260°C ± 5°C
Environmental Specifications	
Test	Conditions
Passive Aging	60°C, 1000 Hours / 85°C, 1000 Hours
Humidity Aging	85°C, 85% RH, 500 Hours
Active Aging	60°C, 90% RH, 60VDC Bias, 1000 Hours
Thermal Shock	125°C, -55°C (10 Times)
Solvent Resistance	MIL-STD-202, Method 215K

Note: Storage conditions: 40°C max, 70% RH max, devices should remain in original sealed bag prior to use.
Devices may not meet specified values if these storage conditions are exceeded.

PolySwitch Resettable Devices

Radial-Leaded Devices

Table 2P4 — Packaging and Marking Information

Part Number	Bag Quantity	Tape and Reel Quantity	Standard Package	Part Marking
TM2P-10271	250	—	3,000	1027 & Batch #
TM2P-10271-2	—	1,000	5,000	1027 & Batch #
LVM2P-015R10431	250	—	3,000	C431 & Batch #
LVM2P-035R14431	250	—	3,000	A431 & Batch #
LVM2P-075R14431	250	—	3,000	B431 & Batch #

Table 2P5 — Ordering Information

Bulk	250	pieces/bag
	3,000	pieces/box
Tape & Reel	1,000	pieces/reel
	5,000	pieces/box

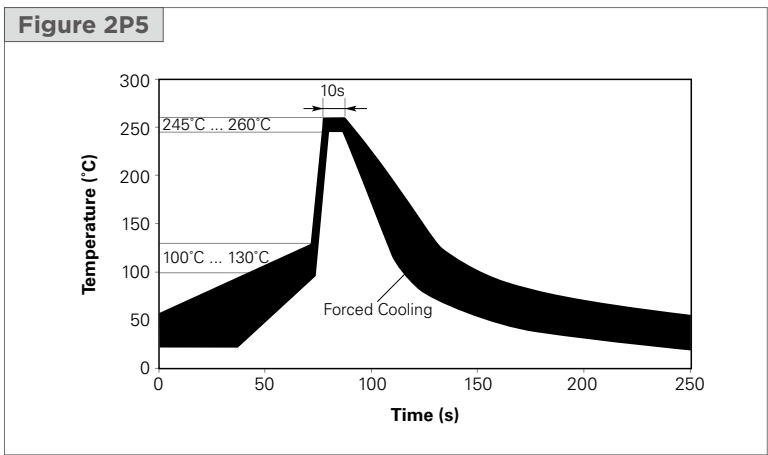
Wave Soldering and Rework Recommendations

Recommended Wave Soldering for Radial-leaded Devices

- Soldering temperature profile
(Temperature characteristic at component terminal with dual wave soldering)

Rework

- If a device is removed from the board, it should be discarded and replaced with a new device



PolySwitch Resettable Devices

Radial-Leaded Devices

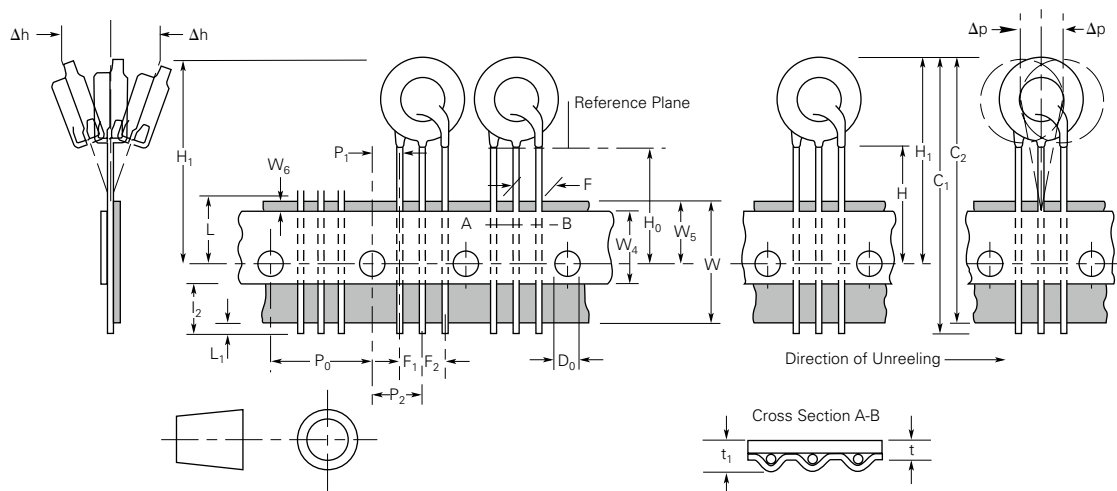
Table 2P6 — Tape and Reel Specifications in Millimeters (mm)

2Pro devices are available in tape and reel packaging per EIA 468-B standard.

Description	EIA Mark	IEC Mark	Dimension (mm)	Tolerance
Carrier Tape Width	W	W	18	-0.5/ +1.0
Hold Down Tape Width	W ₄	W ₀	5	Min
Top Distance Between Tape Edges	W ₆	W ₂	3	Max
Sprocket Hole Position	W ₅	W ₁	9	-0.5/ +0.75
Sprocket Hole Diameter	D ₀	D ₀	4	±0.2
Abcissa to Plane (Kinked Lead)*	H ₀	H ₀	16	-0.5/0.6
Abcissa to Top	H ₁	H ₁	32.2	Max
Overall Width with Lead Protrusion	—	C ₁	43.2	Max
Overall Width Without Lead Protrusion	—	C ₂	42.5	Max
Lead Protrusion	L ₁	I ₁	1.0	Max
Protrusion of Cut-out	L	L	11	Max
Protrusion Beyond Hold Down Tape	I ₂	I ₂	Not Specified	—
Sprocket Hole Pitch	P ₀	P ₀	12.7	±0.3
Pitch Tolerance	—	—	20 Consecutive	±1
Tape Thickness	t	t	0.9	Max
Tape Thickness with Splice*	t ₁	—	2.0	Max
Splice Sprocket Hole Alignment	—	—	0	±0.3
Body Lateral Deviation	h	h	0	±0.1
Body Tape Plane Deviation	p	p	0	±1.3
Ordinate to Component Center Lead	P ₂	P ₂	6.35	±0.7
Lead Spacing*	F ₁ , F ₂	F ₁ , F ₂	2.54	-0.1/+0.4
Reel Width	w ₂	w	56	Max
Reel Diameter	a	d	370	Max
Space Between Flanges	w ₁	—	51.2	Max
Arbor Hole Diameter	c	f	26	±12.0
Core Diameter	n	h	80	Max
Box	—	—	56/372/372	Max
Consecutive Missing Pieces*	—	—	3 Max	—
Empty Places Per Reel*	—	—	Not Specified	—

Note: *Differs from EIA specification.

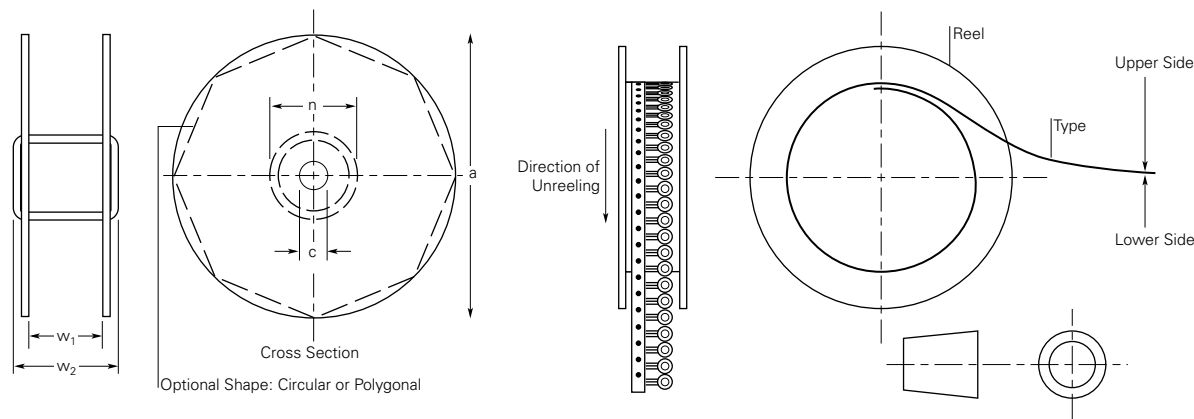
Figure 2P6 — EIA Referenced Taped Component Dimensions



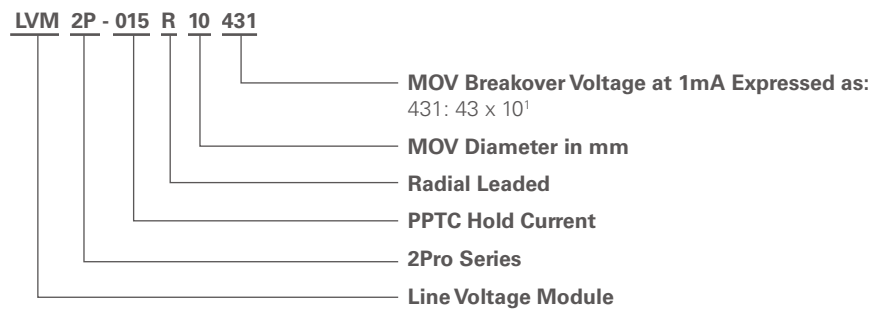
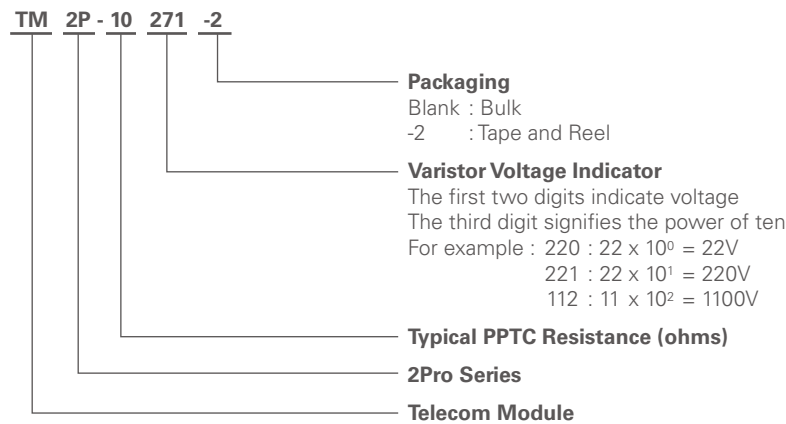
PolySwitch Resettable Devices

Radial-Leaded Devices

Figure 2P7 — EIA Referenced Reel Dimensions



Part Numbering System



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MHP-TAM DEVICES:

MHP with Thermal Activation

The rapidly expanding market for ultra-thin portable electronic devices, such as media tablets and ultra-thin PCs, has created demand for very thin, low-profile, lightweight and high-capacity Lithium Polymer (LiP) and prismatic cells.

A new MHP (Metal Hybrid PPTC) device, the MHP-TAM device, offers a 9V_{DC} rating and a higher current rating than typical battery strap devices. This helps them meet the battery safety requirements of higher-capacity LiP and prismatic batteries found in the latest tablet and ultra-thin computing products. Hybrid MHP technology connects a bimetal protector in parallel with a PPTC (polymeric positive temperature coefficient) device. The resulting MHP-TAM (Thermal Activation) series helps provide resettable overtemperature protection, while utilizing the PPTC device to act as a heater and to help keep the bimetal latched until the fault is removed.



BENEFITS

- Capable of handling the higher voltages and battery discharge rates found in high-capacity LiP and prismatic cell applications
- Helps provide resettable overtemperature protection in high-capacity LiP and prismatic cell applications

FEATURES

- 9V_{DC} rating
- Two levels of current carrying capacity:
 - Low current (nominal 6A hold current @25°C)
 - High current (nominal 15A hold current @25°C)
- Multiple activation temperature ratings (72°C, 77°C, 82°C, 85°C, 90°C)
- Compact size (L: 5.8mm x W: 3.85mm x H: 1.15mm) allows for ultra-thin battery pack designs

APPLICATIONS

Battery cell protection for high-capacity Lithium Polymer and prismatic cells used in:

- Notebook PCs
- Ultra-book
- Tablets
- Smart phones

MHP-TAM Devices
MHP with Thermal Activation

Table M1 — Electrical Characteristics for MHP-TAM15 Series

Model Number	Rating [°C]	Operation Temperature [°C]		Reset Temperature [°C]		Reference Resistance [mohms] 25°C	
	Nominal	Min	Max	Min	T	Typ	Max
MHP-TAM15-9-72	72	67	77	≥40	≥7	2.5	5
MHP-TAM15-9-77	77	72	82	≥40	≥10	2.5	5
MHP-TAM15-9-82	82	77	87	≥40	≥10	2.5	5
MHP-TAM15-9-85	85	80	90	≥40	≥10	2.5	5
MHP-TAM15-9-90	90	85	95	≥40	≥10	2.5	5

Maximum breaking current 5VDC / 80A (100 cycles)

Contact Rating 9VDC / 25A (6000 cycles)

Table M2 — Electrical Characteristics for MHP-TAM6 Series

Model Number	Rating [°C]	Operation Temperature [°C]		Reset Temperature [°C]		Reference Resistance [mohms] 25°C	
	Nominal	Min	Max	Min	T	Typ	Max
MHP-TAM6-9-72	72	67	77	≥40	Δ7	10	15
MHP-TAM6-9-77	77	72	82	≥40	≥10	10	15
MHP-TAM6-9-82	82	77	87	≥40	≥10	10	15
MHP-TAM6-9-85	85	80	90	≥40	≥10	10	15

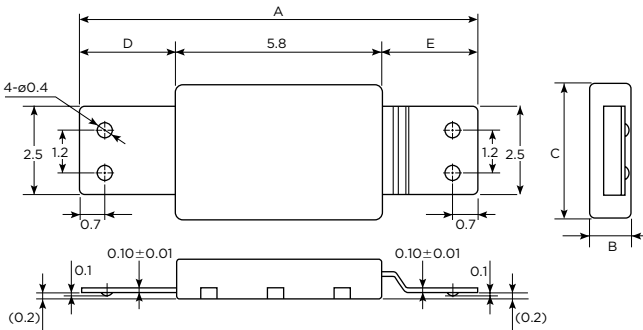
Maximum breaking current 5VDC / 40A (100 cycles).

Contact Rating 9VDC / 12A (6000 cycles).

T is the minimum temperature differential between the actual operation temperature of the device and the reset temperature

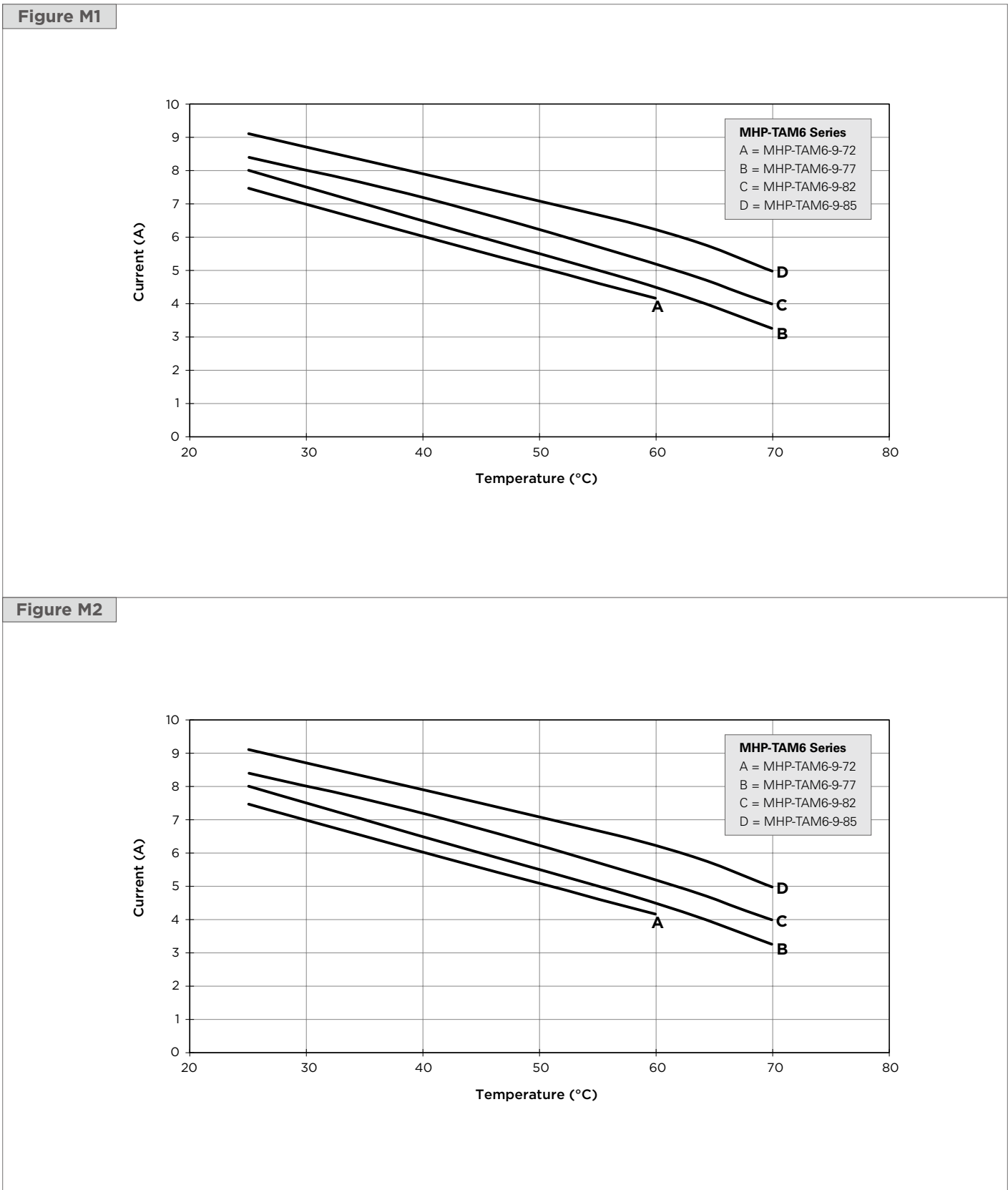
Table M3 — Dimensions in Millimeters and Mechanical Characteristics

	A		B	C		D		E	
	Min	Max	Max	Min	Max	Min	Max	Min	Max
mm:	10.9	11.4	1.15	3.75	3.85	2.6	2.8	2.6	2.8



MHP-TAM Devices
MHP with Thermal Activation

Figures M1-M2 — Hold Current vs. Temperature Curves (Typical)



MHP-TAM Devices

MHP with Thermal Activation

Physical Characteristics

Terminals
Molding Plastic

Copper Alloy
LCP (Liquid Crystal Polymer)

RoHS and Halogen-Free Compliance

RoHS Compliant
Halogen Free per IEC 61249-2-21

Storage Conditions

Device must be stored in the original, unopened bag.
Suggested storage temperature (except for packaging material)

Temperature: -10°C – 40°C
Humidity: 75%RH (max)

The following environments should be avoided for storage:
Areas with salt air or with corrosive gas, such as Cl_2 , H_2S , NH_3 , SO_2 and NO_x .
Areas exposed to direct sunlight.
Areas outside of the suggested storage temperature range, as indicated above.

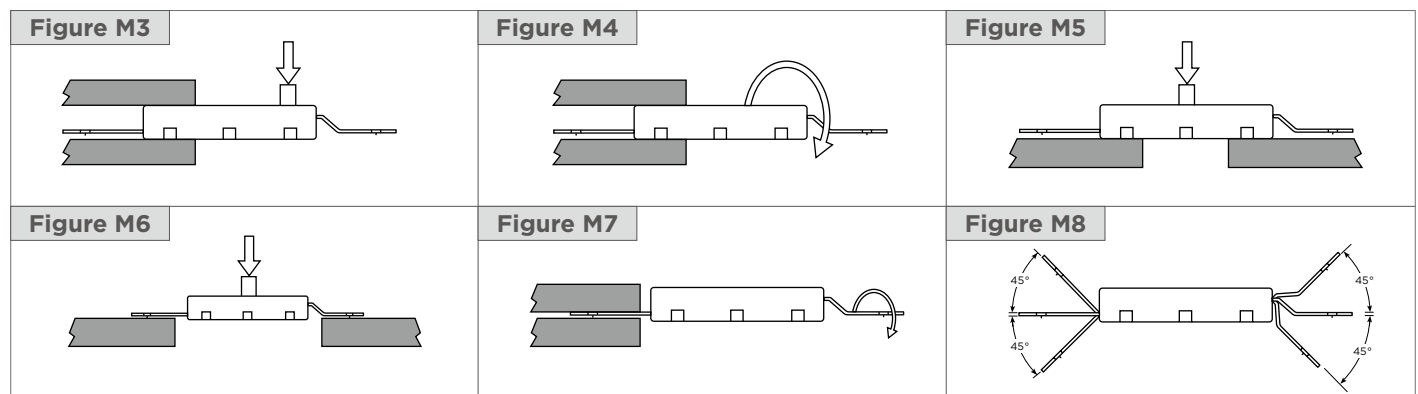
Precautions for Handling

The device is composed of plastic parts, please do not clamp or dent the housing with a tool as this might cause a resistance increase and product damage.

When welding product terminals or mounting the breaker on a battery (cell), please be careful not to apply excessive bending, twisting or force on the product and terminals. The excessive stress might cause a resistance increase or product damage.

Please refer to following cautions:

1. Do not apply more than 10N bend force to product. (Fig. M3)
2. Do not apply more than 1.5cN/m twist torque to the product. (Fig. M4)
3. Do not apply more than 20N deflection force to product. (Fig. M5)
4. Do not apply more than 2N force to the terminals. (Fig. M6)
5. Do not apply more than 0.6cN/m twisting torque to the terminals. (Fig. M7)
6. Do not bend the terminal base more than 45° when the product is mounted in a fixed position. (Fig. M8)



Product terminals can be welded using direct welding and series welding methods. In either case, please use a suitable jig so that the device will not be subjected to the stress conditions listed above.

Pull strength and detach strength of the terminal welds are per user requirements. However, if the welding is controlled by resistance, the measurement should be made as close as possible to the weld point by a “4-point clip method” using milliohm meter to ensure accuracy.

Avoid putting stress on the device, as listed above, when a jig, fitting or additional welding process is used. Please reconfirm the resistance value whenever a new process is added.

MHP-TAM Devices

MHP with Thermal Activation

Table M4 — Packaging and Marking Information

Part Number	Bag Quantity	T & R Quantity	Standard Package	Part Marking	Agency Recognition
MHP-TAM 15 Series					
MHP-TAM15-9-72	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-24160-UL
MHP-TAM15-9-77	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-24160-UL
MHP-TAM15-9-82	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-24160-UL
MHP-TAM15-9-85	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-24160-UL
MHP-TAM15-9-90	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-24160-UL
MHP-TAM 6 Series					
MHP-TAM6-9-72	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-23966-M1-UL
MHP-TAM6-9-77	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-23966-M1-UL
MHP-TAM6-9-82	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-23966-M1-UL
MHP-TAM6-9-85	1,000	—	20,000	Lot ID#, Control# & Co. Logo, Product #	UL & cUL File No. E349829; CB File No. US-23966-M1-UL

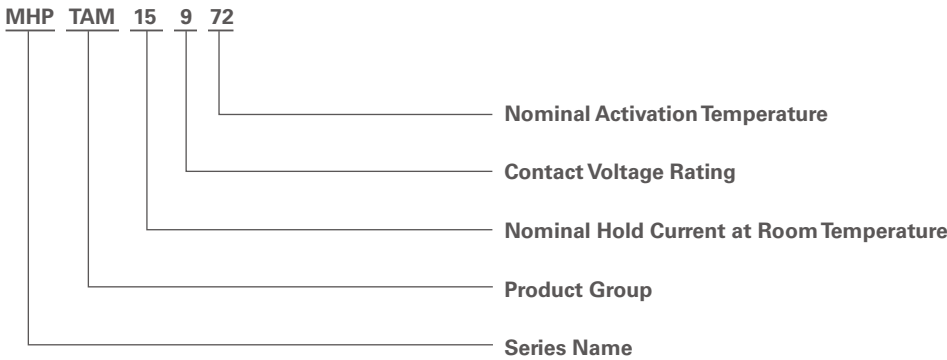
Table M5 — Ordering Information

Bag	1,000	pieces
Box	20,000	pieces

MHP-TAM Devices

MHP with Thermal Activation

Part Numbering System



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Special Recommendations:

1. The power supply voltage must be less than the rated voltage of the device. Operation above the voltage rating may result in device damage, smoking or flame.
2. Designs must be selected in such a manner that the device hold current is higher than the normal current value in the circuit and that the device trip current is lower than the abnormal current value. Selecting device hold current and trip current values that are too low for the application may interrupt the circuit under normal usage conditions.
3. This product should not be used in an application where the maximum interrupt current can be exceeded in a short circuit condition.
4. The devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
5. The devices may not perform as specified if mechanical pressure is added while the device is in the tripped state or exposed to temperature conditions lower than -30°C or over 100°C.

PESD PROTECTION DEVICES

Littelfuse's Polymer ESD (PESD) line of devices helps protect I/O ports on HDMI 1.3, portable video players, LCD and plasma TVs, USB 2.0, digital visual interface (DVI) and antenna switches. PESD devices shunt electrostatic discharge away from sensitive circuitry in HDTV equipment, printers, laptops, cellular phones and other portable devices.

PESD devices offer many advantages over traditional protection devices, such as multi layer varistors (MLVs), which may degrade or distort the signal in high data rate circuits. Compared to miniature gas discharge tubes (GDTs), PESD devices provide a more compact form factor and an economical solution for the shrinking profiles of today's compact information appliances.

Available in a range of form factors, our PESD protection devices provide low capacitance and meet transmission line pulse (TLP) testing, as well as IEC61000-4-2 testing.



BENEFITS

- ESD protection for high frequency application (HDMI 1.3)
- Smaller form factor for board space savings
- Helps protect sensitive electronic circuits against damage caused by electrostatic discharge (ESD) events
- Assists equipment to pass IEC 61000-4-2, level 4 testing

FEATURES

- RoHS compliant
- Lead free
- Halogen free (refers to: Br $\geq$ 900ppm, Cl $\geq$ 900ppm, Br+Cl $\geq$ 1500ppm)
- 0.25 pF (typ) capacitance
- Low-leakage current
- Low-clamping voltage
- Fast response time (< 1ns)
- Capable of withstanding numerous ESD strikes
- Compatible with standard reflow installation procedures
- Thick film technology
- Bi-directional protection

APPLICATIONS

- HDMI 1.3 interfaces
- LCD & plasma TVs
- Cellular phones
- Antennas
- Portable video players
- Portable devices (PDA, DSC, Bluetooth)
- Printer ports
- Satellite radios
- USB 2.0 and IEEE 1394 interfaces
- DVI
- GPS systems

Table E1 — Electrical Characteristics

	Continuous Max	Typ	Typ	Typ Capacitance	Typ Leakage	Max Leakage
	Operating Voltage	Trigger Voltage*	Clamping Voltage†	@ 1 MHz, 1V _{RMS}	Current	Current @ Max V _{DC}
Symbol	V _{DC}	V _{T(TLP)}	V _{C(TLP)}	C _p	I _{L(TYP)}	I _{L(MAX)}
Unit	V	V	V	pF	μA	μA
PESD0402-140	14	250	40	0.25	< 0.01	10.0
PESD0402-240	24	250	40	0.25	< 0.01	10.0
PESD0603-240	24	215	45	0.25	< 0.01	10.0
PESD1206Q-240	24	250	45	0.25	< 0.01	10.0

Notes : * TLP test method at 1kV.
† Measured 30ns after pulse initiation.
Typical capacitance value is at 0V and max operating voltage bias.

Figure E1 — Capacitance vs. Frequency

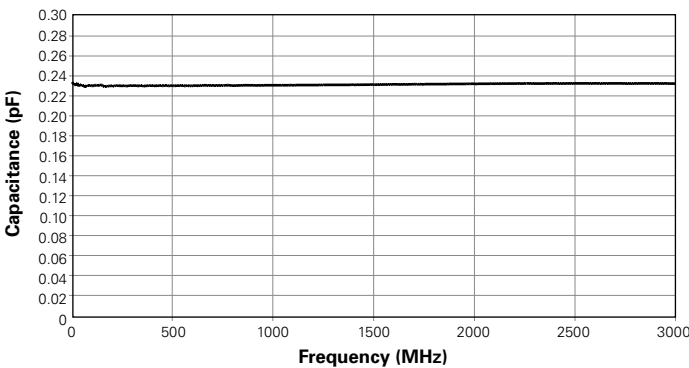


Figure E2 — Eye Diagram Performance at 3.4 GHz

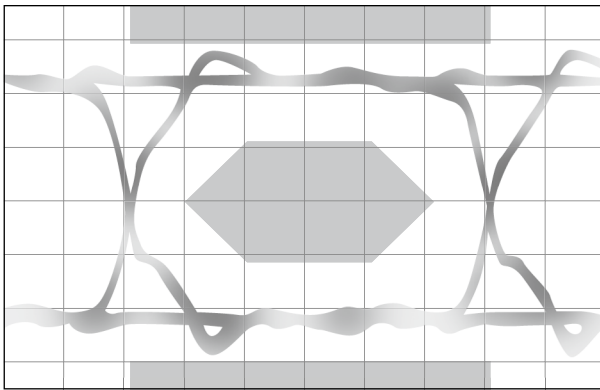
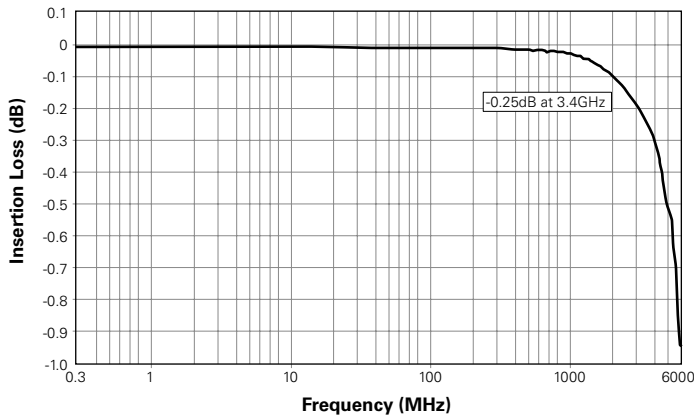


Figure E3 — Insertion Loss Diagram



PESD Protection Devices

Figures E4-E5 — PESD Device Protection for HDMI (PESD devices provide electrostatic discharge protection)

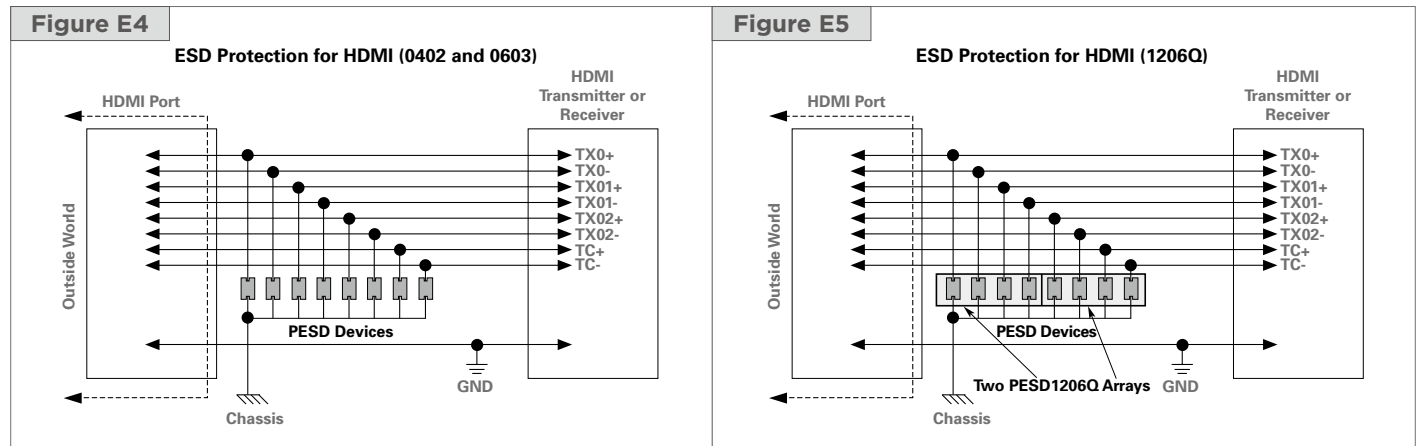


Table E2 — Dimensions in Millimeters (Inches*)

Part Number	A		B		C		D		E		F		Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
PESD0402-140	0.90	1.10	0.23	0.43	0.10	0.30	0.40	0.60	—	—	—	—	E6
PESD0402-240	(0.035)	(0.043)	(0.009)	(0.017)	(0.004)	(0.012)	(0.016)	(0.024)					
PESD0603-240	1.50	1.70	0.45	0.55	0.10	0.50	0.70	0.95	—	—	—	—	E6
	(0.059)	(0.067)	(0.018)	(0.022)	(0.004)	(0.020)	(0.028)	(0.037)					
PESD1206Q-240	3.10	3.30	0.40	0.60	0.10	0.30	1.50	1.70	0.20	0.60	0.20	0.60	E7
	(0.122)	(0.130)	(0.016)	(0.024)	(0.004)	(0.012)	(0.059)	(0.067)	(0.008)	(0.024)	(0.008)	(0.024)	

*The dimensions in inches are rounded approximations.

Figures E6-E7 — Dimension Figures

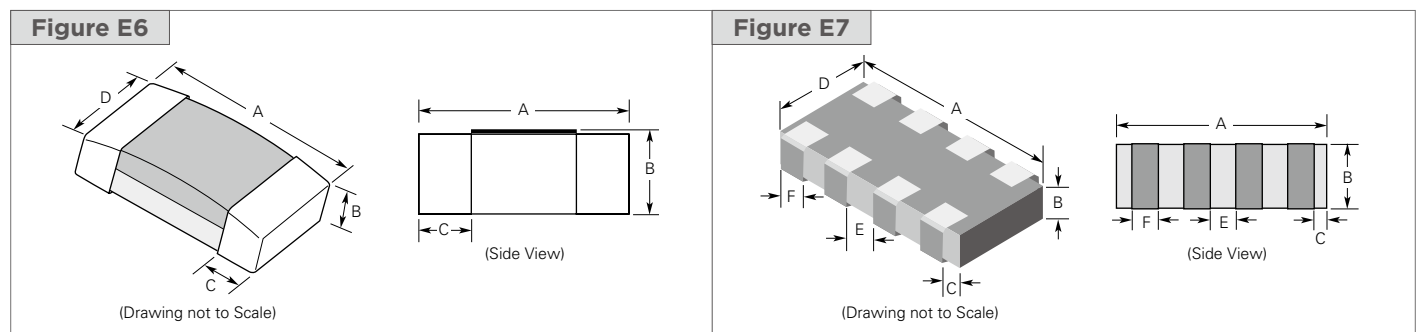


Table E3 — Environmental Specifications

	Test Conditions	Pass / Fail Criteria
Bias Humidity Test	85°C, 85% RH, $V_{DC(max)}$, 1000 hrs	I_L 10 μ A
Thermal Shock	-55°C to 125°C, 30 min Dwell, 1000 Cycles	I_L 10 μ A
Bias Heat Test	125°C, $V_{DC(max)}$, 1000 hrs	I_L 10 μ A
Bias Low Temp Test	-55°C, $V_{DC(max)}$, 1000 hrs	I_L 10 μ A
Solderability	250°C $\pm$ 5°C, 3 $\pm$ 1s	95% Coverage
Solder Heat	260°C, 10s	90% Coverage
Vibration	10 to 50Hz, 60s Cycle, 2 hrs Each in X-Y-Z-Direction	No Physical Damage
Solvent Resistance	IPA Ultrasonic 300s	No Physical Damage
Shock	1500G, 0.5ms Each, X-Y-Z Axis 3 Times Each Axis	No Physical Damage

Table E4 — General Characteristics

Storage Temperature	-40°C to +85°C
Operating Temperature	-55°C to +125°C
ESD Voltage Capability	Contact Discharge Mode: 8kV (Typ), 15kV (max)
(Tested per IEC 61000-4-2)	Air Discharge Mode: 15kV (Typ), 25kV (max) [1 Pulse: per Customer Request]
ESD Pulse Withstand	100 Pulses
	(Tested per IEC 61000-4-2, Level 4, Contact Method)

Table E5 — Materials Information

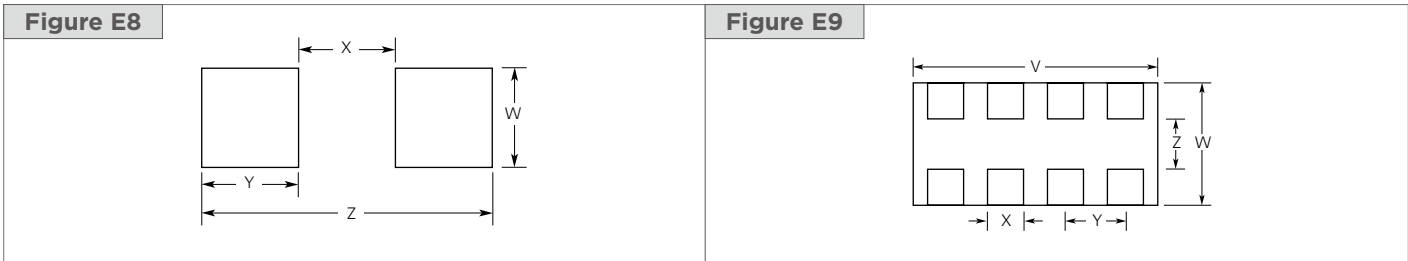
RoHS Compliant	Directive 2002/95/EC Compliant
RoHS 2.0	Directive 2011/65/EU Compliant
ELV Compliant	Directive 2000/53/EC Compliant
Halogen Free	Halogen Free Refers to: Br900ppm, Cl900ppm, Br+Cl1500ppm

Table E6 — Recommended Pad Layout in Millimeters and Inches*

Part Number	V		W		X		Y		Z		Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
PESD0402-140	—	—	0.60	0.70	0.30	0.40	0.80	0.90	2.10	2.20	E8
PESD0402-240			(0.024)	(0.028)	(0.012)	(0.016)	(0.031)	(0.035)	(0.083)	(0.087)	
PESD0603-240	—	—	0.90	1.00	0.50	0.60	1.00	1.10	2.70	2.80	E8
			(0.035)	(0.039)	(0.020)	(0.024)	(0.039)	(0.043)	(0.106)	(0.110)	

Part Number	V	W	X	Y	Z	Figure
	Typ	Typ	Typ	Typ	Typ	
PESD1206Q-240	3.20	2.20	0.50	0.80	1.00	E9
	(0.126)	(0.087)	(0.020)	(0.031)	(0.039)	

*The dimensions in inches are rounded approximations.



Note: Solder thickness 0.15 to 0.2mm.

Table E7 — Solder Reflow Recommendations

A	Temperature Ramp-up 1	From Ambient to Preheating Temperature	30s to 60s
B	Preheating	140°C - 160°C	60s to 120s
C	Temperature Ramp-up 2	From Preheating to Main Heating Temperature	20s to 40s
D	Main Heating	at 200°C	60s to 70s
		at 220°C	50s to 60s
		at 240°C	30s to 40s
		at 260°C	5s to 10s
E	Cooling	From Main Heating Temperature to 100°C	4°C/s (max)

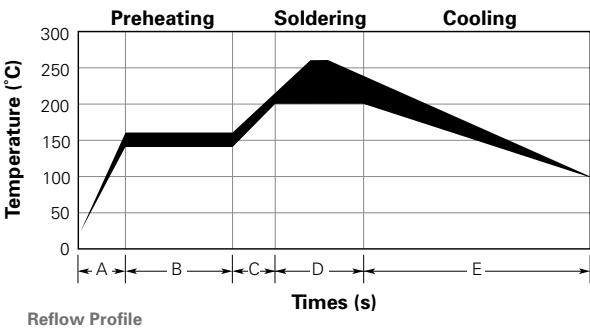


Table E8 — Tape Specifications

Tape Dimension	0402		0603		1206Q	
	Dimension (mm)	Tolerance	Dimension (mm)	Tolerance	Dimension (mm)	Tolerance
EIA Mark						
W	8.00	±0.30	8.00	±0.30	8.00	±0.30
P ₀	4.00	±0.10	4.00	±0.10	4.00	±0.10
P ₁	2.00	±0.05	4.00	±0.05	4.00	±0.05
P ₂	2.00	±0.05	2.00	±0.05	2.00	±0.05
A ₀	0.63	±0.03	1.27	±0.15	2.02	±0.20
B ₀	1.13	±0.03	2.02	±0.20	3.62	±0.20
D ₀	1.50	±0.10	1.50	±0.10	1.50	±0.10
F	3.50	±0.05	3.50	±0.05	3.50	±0.05
E ₁	1.75	±0.10	1.75	±0.10	1.75	±0.10
T	0.48	±0.03	0.60	±0.03	0.75	±0.05

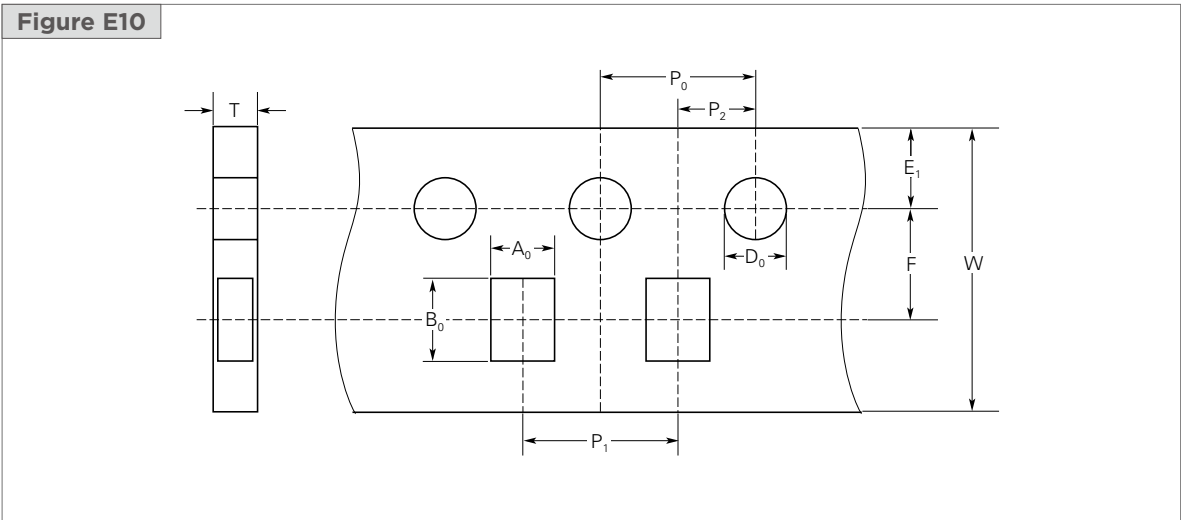
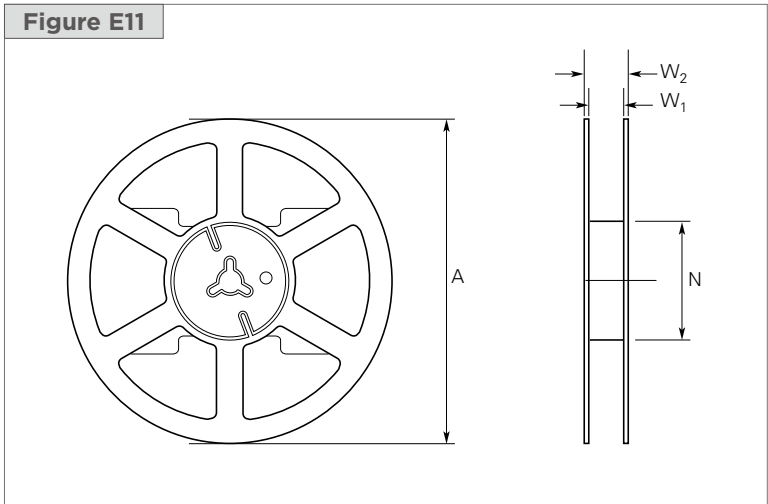


Table E9 — Reel Specifications

Reel Dimensions (0402, 0603 & 1206Q)	
EIA Mark	Dimension (mm)
A max	180.0
N min	60.5
W ₁ max	9.5
W ₂ max	14.0

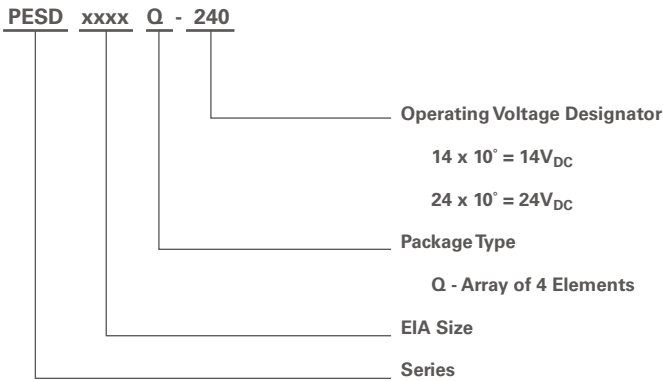


PESD Protection Devices

Parameter Definitions

Operation Voltage (V_{DC})
Defined as DC voltage, under which device is in OFF state and leakage current below certain threshold.
Leakage Current (I_L)
Current through device under Operation Voltage V_{DC} .
Trigger Voltage (V_T)
Voltage at which the device switches from the OFF to the ON state, during the IEC waveform or the TLP system.
Clamping Voltage (V_C)
Voltage cross device under 8kV per IEC or measured by TLP system. Typically measured 30ns after initiation of the ESD pulse (for TLP, both 30ns and 60ns are sometimes used).
Capacitance (C_P)
Capacitance of the device measured at 1MHz with 0V and max operating voltage bias.

Part Numbering System



Warning :

Application Limitations for PESD0402-140, PESD0402-240, PESD0603-240 and PESD1206Q-240: These parts are not intended to be used on power lines or for power bus applications. Users should independently evaluate the suitability of and test each product selected for their own application.

Notice:

Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

CHIPSESD DEVICES

Littelfuse's ChipSESD family of Silicon ESD devices, available in EIA-0201 and EIA-0402 sized rectangular SMT passive component packages, can help protect electronic circuits against damage from electrostatic discharge (ESD) events.

The SESD0201P1BN-0400-090, 0201-sized ChipSESD device's miniature footprint (0.6mm x 0.3mm x 0.3mm) is approximately 70% smaller than prior-generation devices. This offers designers flexibility in space constrained applications.

The ChipSESD devices are high-capacitance, bi-directional devices that can be used for low-speed generic interfaces such as keypads, power buttons, speakers and microphone ports in a portable electronics. The bi-directional operation eliminates orientation constraints and the need for polarity inspections. The surface mount technology (SMT) passive component package allows the devices to be easily installed onto the printed circuit board using the standard PCB assembly process. Once soldered onto the boards, the ChipSESD's solder fillets at the end terminals can easily be visually inspected.

The ChipSESD devices offer 10kV contact and 16kV air discharge protection per the IEC61000-4-2, level 4 standard with a surge rating of 2A under 8x20Qs pulse.

BENEFITS

- Silicon ESD devices in an EIA-0201 and EIA-0402 sized rectangular SMT passive component package
- Bi-directional operation eliminates orientation constraints
- Standard PCB assembly and rework process
- ESD protection in space-constrained portable electronics and mobile handsets
- Helps protect electronic circuits against damage from ESD
- Assists equipment to pass IEC61000-4-2, level 4 testing

FEATURES

- Input capacitance -4.0pF (typ) & 4.5pF (typ)
- Low leakage current - 1.0μA (max)
- Low working reverse voltage - 6.0V (max)
- Capable of withstanding numerous ESD strikes
- RoHS compliant
- Halogen free (refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)



APPLICATIONS

- Mobile phones and portable electronics
- Digital cameras and camcorders
- Notebooks, set top boxes, motherboards
- USB 2.0 and computer I/O ports
- Applications requiring high ESD performance in a small package

Table CE1 — Maximum Ratings

Part Number	IEC61000-4-2, level 4 (ESD Withstand)		Temperature	
	Contact (kV)	Air (kV)	Operating (°C)	Storage (°C)
SESD0201P1BN-0400-090	±10*	±16	-40 to +125	-40 to +125
SESD0402P1BN-0450-090	±10*	±16	-40 to +125	-40 to +125

*10kV @ 50 ± pulses under IEC61000-4-2; 8kV @ 1,000 pulses under IEC61000-4-2

Table CE2 — Electrical Characteristics @T=25°C

Part Number	Input Capacitance*		Leakage Current (max) I _L @ V _{RWM} = 6.0V (μA)	Breakdown Voltage (min) V _{br} @ I _T [†] = 1mA (V)	Working Reverse Voltage V _{RWM} @ peak (V)	Clamping Voltage (typ)
	Typ (pF)	Max (pF)				V _{CL} @ I _{pp} =2A, tp={8/20μs} (V)*
SESD0201P1BN-0400-090	4.0	5.0	1.0	9.0	6.0	+10.0
SESD0402P1BN-0450-090	4.5	5.5	1.0	9.0	6.0	+10.0

* @ Vr=0V, f=1MHz
 † V_{br} is measured at test current I_T

Figure CE1 — ESD Clamping Voltage - 8kV Contact

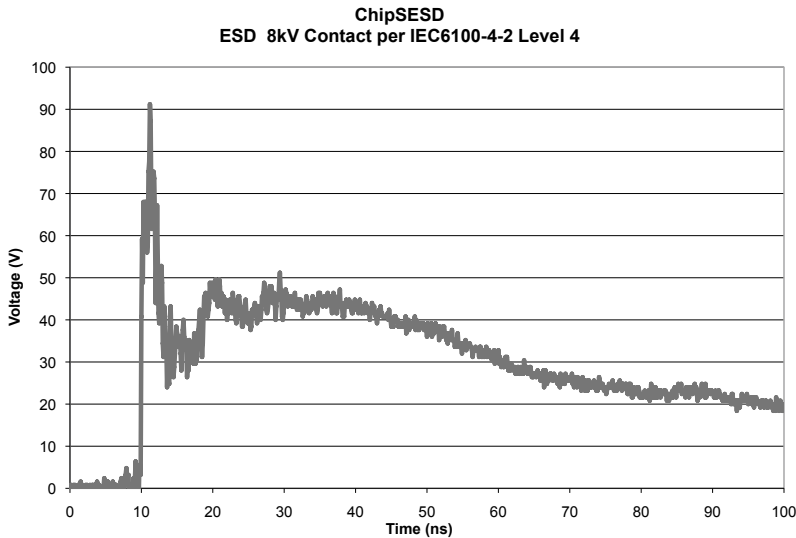


Figure CE2 — ESD Clamping Voltage - 8x20μs, 2A Surge

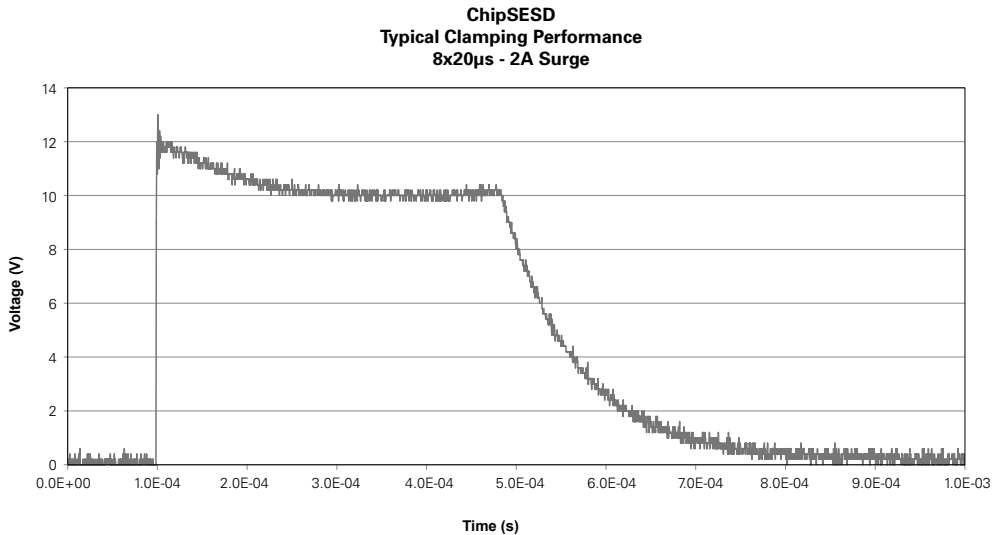


Table CE3 - Dimensions in Millimeters and Mils*

Part Number	A	B	C	D	Figure
SESD0201P	0.60 ± 0.05	0.30 ± 0.05	0.30 ± 0.05	0.21 ± 0.07	CE3
	(23.62 ± 2.00)	(11.81 ± 2.00)	(11.81 ± 2.00)	(8.27 ± 2.80)	
SESD0402P	1.10 ± 0.10	0.50 ± 0.10	0.50 ± 0.10	0.25 ± 0.15	CE3
	(43.31 ± 0.40)	(19.69 ± 4.00)	(19.69 ± 4.00)	(9.84 ± 6.00)	

* Round off approximation

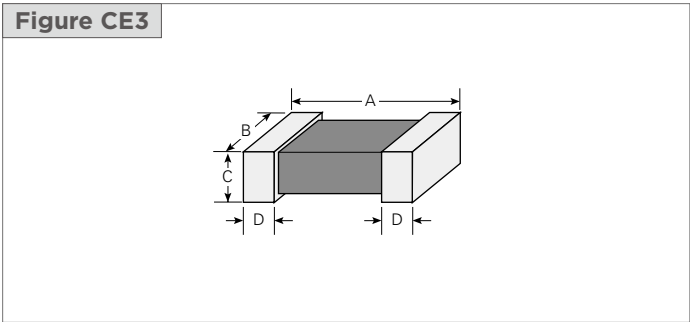


Table CE4 - PCB Pad Layout in Millimeters and Mils*

Part Number	L	S	W	Figure
SESD0201P	0.28 ± 0.01	0.19 ± 0.01	0.30 ± 0.01	CE4
	(11.00 ± 0.40)	(7.50 ± 0.40)	(11.80 ± 0.40)	
SESD0402P	0.61 ± 0.05	0.52 ± 0.05	0.50 ± 0.05	CE4
	(24.00 ± 2.00)	(21.00 ± 2.00)	(20.00 ± 2.00)	

* Round off approximation

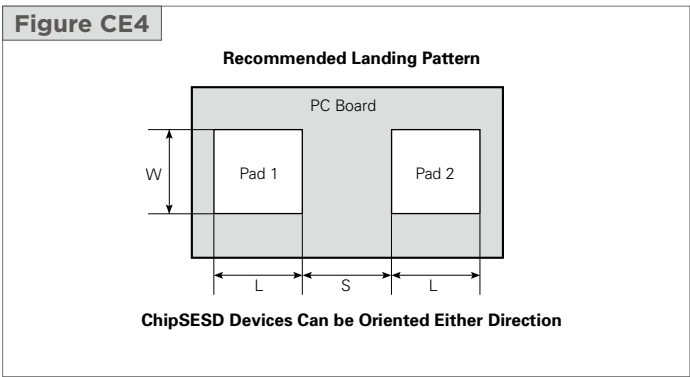


Table CE5 – Tape Specifications

Tape Dimension	SESD0201P1BN-0400-090	SESD0402P1BN-0450-090
EIA Mark	Dimension (mm)	Dimension (mm)
A	0.35 ± 0.02	0.58 ± 0.03
B	0.67 ± 0.02	1.20 ± 0.03
D	1.55 ± 0.05	1.55 ± 0.05
E	1.75 ± 0.05	1.75 ± 0.05
F	3.50 ± 0.05	3.50 ± 0.05
W	8.00 ± 0.10	8.00 ± 0.10
P ₀	4.00 ± 0.10	4.00 ± 0.10
P ₁	2.00 ± 0.05	2.00 ± 0.05
P ₂	2.00 ± 0.05	2.00 ± 0.05
T	0.42 ± 0.03	0.60 ± 0.03

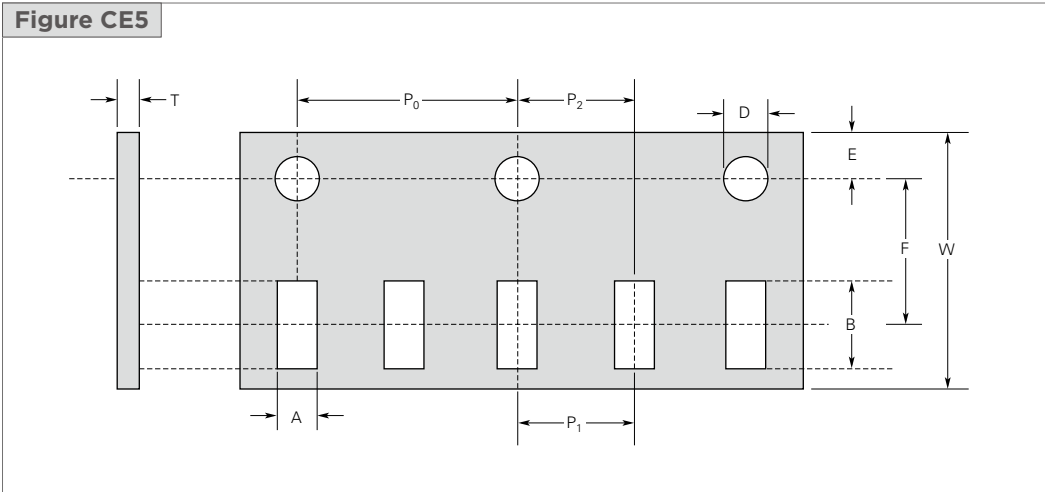
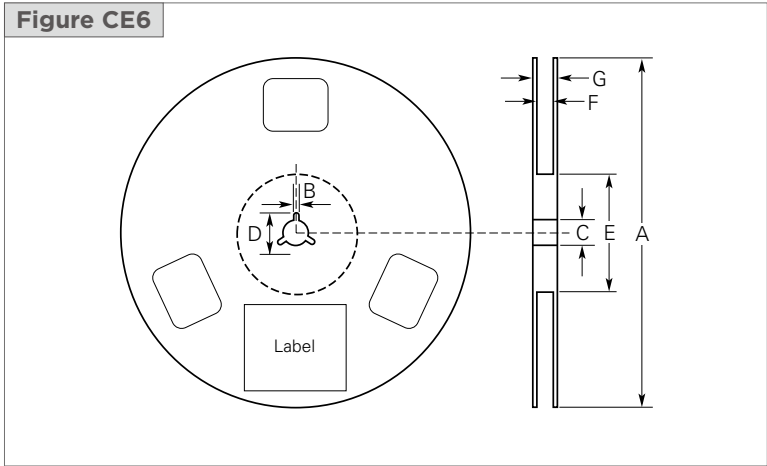


Table CE6 – Reel Specifications

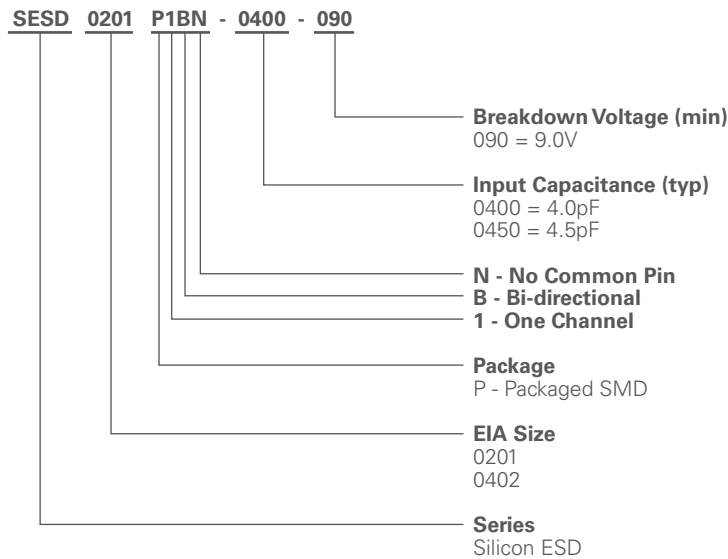
Reel Dimension	Dimension (mm)
EIA Mark	Dimension (mm)
A	178.0 ± 2.0
B	2.0 ± 0.5
C	13.0 ± 0.5
D	21.0 ± 0.8
E	62.0 ± 1.5
F	9.0 ± 0.5
G	13.0 ± 1.0



Definition of Terms

I_L	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Working Peak Reverse Voltage
V_{br}	Breakdown Voltage @ I_T
I_T	Test Current
V_{CL}	Clamping Voltage

Part Numbering System



Notice:

Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, automotive, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

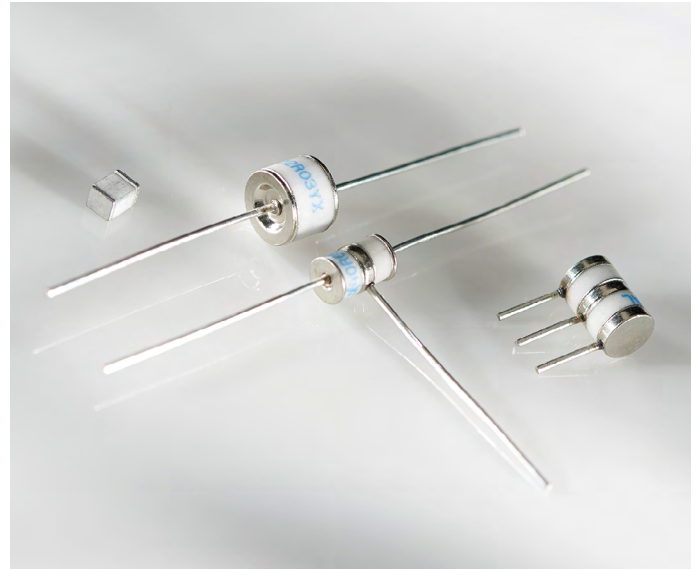
GAS DISCHARGE TUBES (GDTs)



Expertise Applied | Answers Delivered

Littelfuse's GDTs (Gas Discharge Tubes) are placed in front of, and in parallel with, sensitive telecom equipment such as power lines, communication lines, signal lines and data transmission lines to help protect them from damage caused by transient surge voltages that may result from lightning strikes and equipment switching operations. These devices do not influence the signal in normal operation. However, in the event of an overvoltage surge, such as a lightning strike, the GDT switches to a low impedance state and diverts the energy away from the sensitive equipment.

Our GDTs offer a high level of surge protection, a broad voltage range, low capacitance, and many form factors including new surface mount devices, which makes them suitable for applications such as Main Distribution Frame (MDF) modules, high data-rate telecom applications (e.g. ADSL, VDSL), and surge protection on power lines. Their low capacitance also results in less signal distortion. When used in a coordinated circuit protection solution with PolySwitch devices, they can help equipment manufacturers meet stringent safety regulatory standards.



BENEFITS

- Helps provide overvoltage fault protection against damage caused by high energy surges
- Suitable for use in sensitive equipment due to impulse sparkover response
- Suitable for high-frequency applications
- Highly reliable performance
- New surface-mount devices for automated manufacturing

FEATURES

- RoHS compliant
- Halogen free
(refers to: Br $\geq$ 900ppm, Cl $\geq$ 900ppm, Br+Cl $\geq$ 1500ppm)
- Wide range of voltages (75V-4000V)
- Wide range of form factors
(3mm, 5mm, 6mm, 7mm, 8mm diameter devices)
- Low capacitance and insertion loss
- Crowbar device with low arc voltage
- High accuracy spark-over voltages for high precision designs

APPLICATIONS

- Telecommunications
 - MDF modules, xDSL equipment, RF systems, antenna, base stations
- Industrial and Consumer Electronics
 - Power supplies, surge protectors, alarm systems, irrigation systems

- Devices tested per ITU K.12 recommendations
- Various lead configurations and surface-mount options
- Optional fail-short mechanism
- Non radioactive materials
- Devices certified to UL497B and UL1449

Gas Discharge Tubes (GDTs)

Figures G1-G2 – Typical Circuits for Gas Discharge Tubes

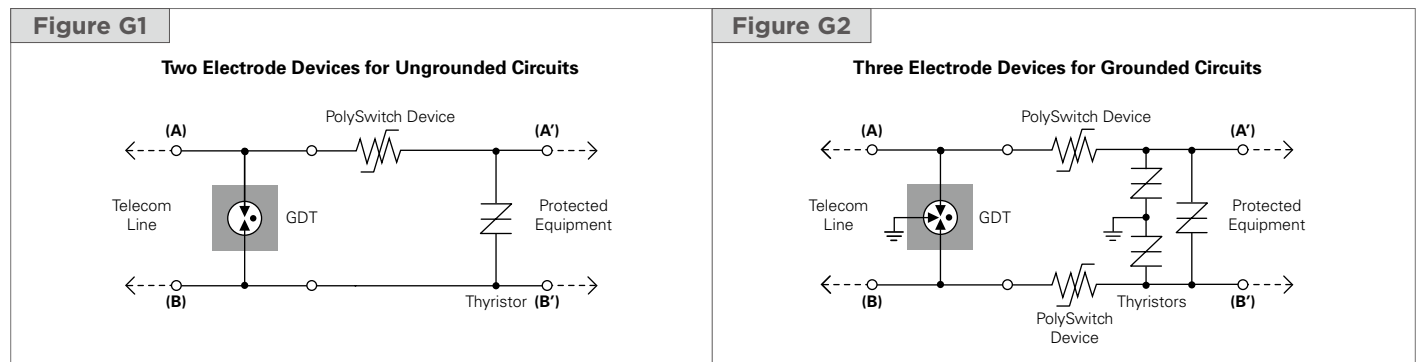


Table G1 – Device Voltage Ratings, Surge Rating, Capacitance, Insulation Resistance and Agency Approval for Two-Electrode Gas Discharge Tubes

Part Number	DC Sparkover Voltage	Impulse Sparkover Voltage	Impulse Discharge Current		Impulse Withstanding Voltage	Capacitance	Insulation Resistance	UL Rating	
	@ 100V/s ± 20% Tolerance	@ 1kV/μs	8x20μs 10 Hits (5 Hits Each Polarity)	8x20μs 300 Hits (150 Hits Each Polarity)	10/700μs 10 Hits (5 Times Each Polarity)	@ 1MHz	@ 100V _{DC} [†]	UL497B	#E179610
GTCS23-XXM-R01-2	75*	600	1kA	100A	4kV	<0.5pF	1,000 (MΩ)	All Devices	
	90	600							
	140	600							
	150	600							
GTCC23-XXM-R01-2	200	700	1kA	100A	6kV [‡]	<0.5pF	1,000 (MΩ)	All Devices	
	230	700							
	300	900							
	350	1000							
	400	1000							

* DCSO 60~105

† Devices ≤150V measured @ 50V_{DC}

‡ Effective output impedance: 40ohms

Part Number	DC Sparkover Voltage	Impulse Sparkover Voltage		DC Holdover Voltage	On-State Voltage	Impulse Discharge Current	Impulse Life	AC Discharge Current (1s duration; 10 hits)	Capacitance	Insulation Resistance	UL Rating
	@ 100V/s ± 20% Tolerance	@ 100V/μs	@ 1kV/μs	Per ITU K.12	Nominal (@1A) (V)	8x20μs 10 Hits	10x1000μs 300 Hits	@ 50 Hz	@ 1MHz	@ 100V _{DC}	#E179610
GTCX25-XXM-R02	75	450	550	<52	20	2.5kA	100A	2.5Arms	<1pF	10,000 (MΩ)	All Devices
	90	450	550	<52	20						
	140	500	600	<80	20						
GTCX26-XXM-R05	150	500	600	<80	20	5kA	100A	5Arms	<1pF	10,000 (MΩ)	All Devices
	200	600	700	<135	20						
	230	600	700	<135	20						
GTCX28-XXM-R05	250	600	700	<135	20	5kA	100A	5Arms	<1pF	10,000 (MΩ)	All Devices
	260	700	800	<135	20						
	300	800	900	<150	20						
	350	900	1000	<150	20						
GTCX28-XXM-R10	400	900	1000	<150	20	10kA	100A	10Arms	<1pF ^{††}	10,000 (MΩ)	All Devices
	420	900	1000	<150	20						
	470	1050	1150	<150	20						
	500	1100	1200	<150	20						
GTCX28-XXM-R20**	550	1300	1400	<150	20	20kA	100A	20Arms	<1.5pF	10,000 (MΩ)	All Devices
	600	1300	1400	<150	20						

** GTCX28-XXM-R20 parts only up to 350V

†† <1.2pF for 75V and 90V devices.

Gas Discharge Tubes (GDTs)

Table G2 — Device Voltage Ratings, Surge Rating, Capacitance, Insulation Resistance and Agency Approval for Two Electrode High-Voltage Gas Discharge Tubes

Part Number	DC Sparkover Voltage	Impulse Sparkover Voltage	Impulse Life	AC Discharge Current, 50Hz		Impulse Discharge Current 8/20µs		Capacitance	UL Rating
	@ 100V/s ± 20% Tolerance	@ 100V/µs		Multiple Hits (1s Duration: 10 Hits)	Single Hit, 9 Cycles	10 Hits (5 Hits Each Polarity)	1 Hit	@ 1MHz	UL1449 #E332226
GTCA28-801M-R05	800	1400	300 times	5A	N/A	5kA	N/A	<1pF	✓
GTCA28-102M-R03	1000	1700	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-122M-R03	1200	1900	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-152LR03	1500 (± 15%)	2200	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-212M-R03	2100	2700	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-242M-R03	2400	3300	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-252M-R03	2500	3500	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-272LR03	2700 (± 15%)*	3700	300 Times [†]	N/A	N/A	3kA	10kA	<1pF	✓
GTCA28-302M-R03	3000	4000	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-312LR03	3100 (± 15%)*	3700 [‡]	300 Times [†]	N/A	N/A	3kA	10kA	<1pF	✓
GTCA28-362M-R03	3600	4600	N/A	1A	5A	3kA	10kA	<1pF	✓
GTCA28-402M-R03	4000	5000	N/A	1A	5A	3kA	10kA	<1pF	✓

Note: Insulation resistance: 10,000MΩ (all parts measured @ 1000V_{DC}, except 800V/1000V/1200V @250V_{DC}; 1500V/2100V @ 500V_{DC})

* DC Sparkover Voltage measured at 5kV/s

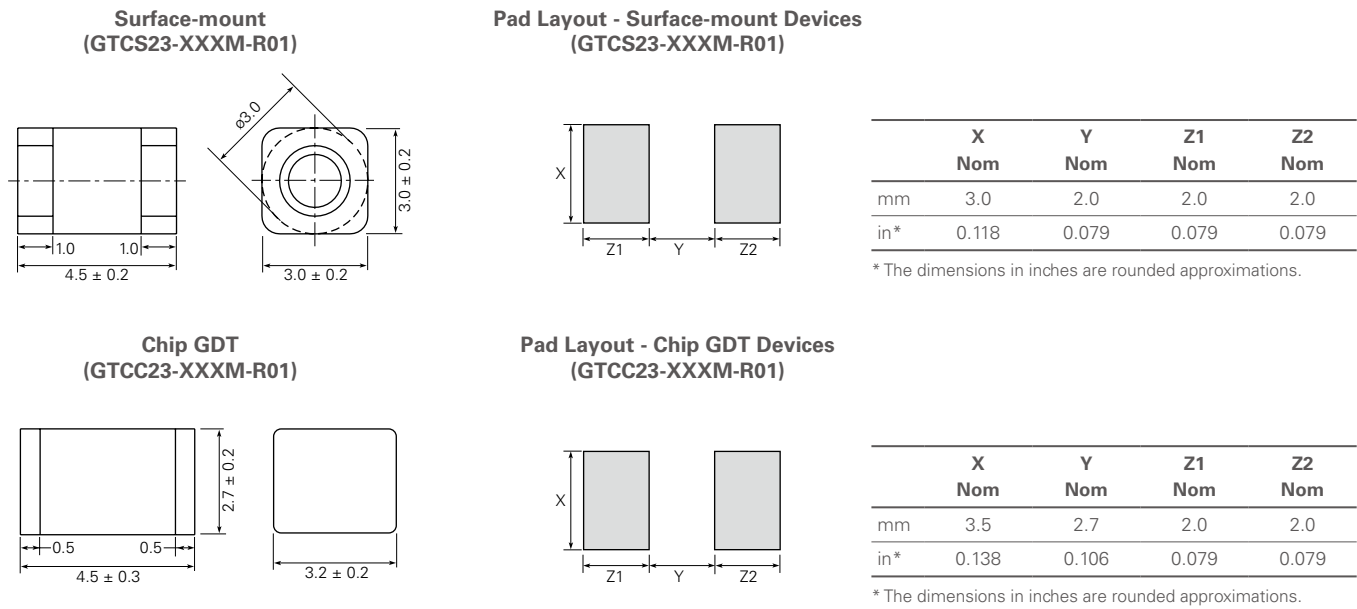
† Measured with 8/20µs, 100A impulse

‡ Measured at 1000V/µs

Gas Discharge Tubes (GDTs)

Figures G3-G11 — Dimensions for Gas Discharge Tubes

Figure G3 — Two Electrode 3mm Product Dimensions



**Chip GDT
(GTCC23-XXXM-R01)**

Side view dimensions: 0.5, 0.5, 4.5 ± 0.3, 2.7 ± 0.2

Top view dimensions: 3.2 ± 0.2

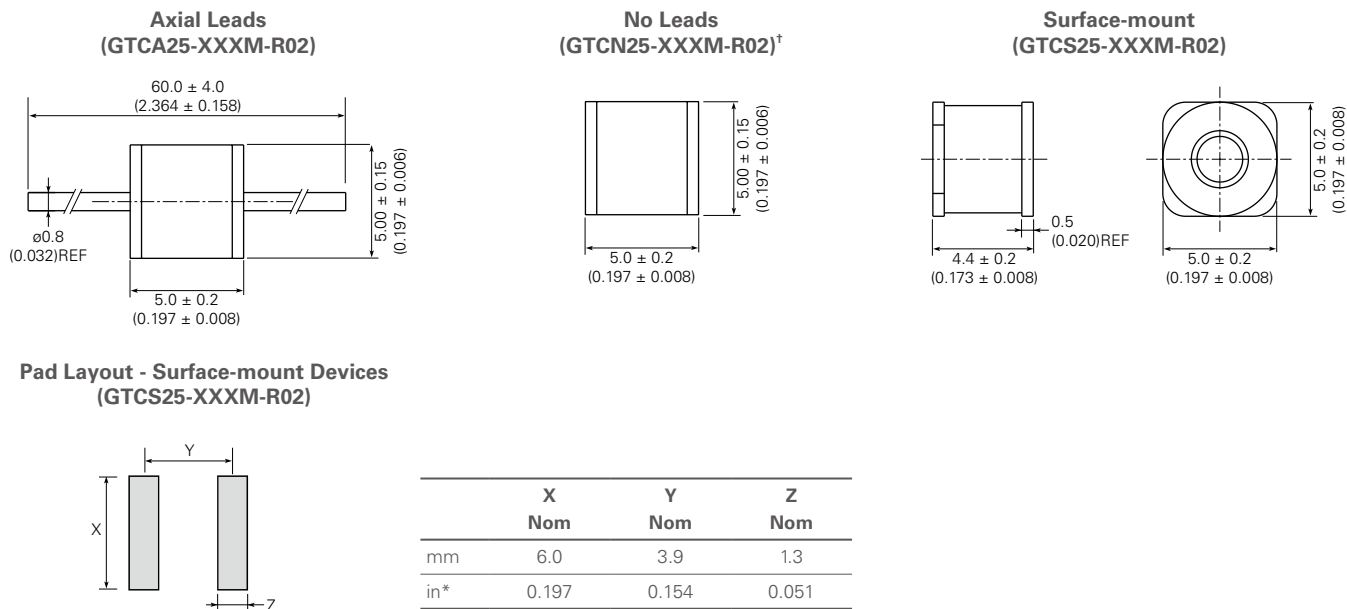
**Pad Layout - Chip GDT Devices
(GTCC23-XXXM-R01)**

Dimensions: X, Y, Z1, Z2

	X Nom	Y Nom	Z1 Nom	Z2 Nom
mm	3.5	2.7	2.0	2.0
in*	0.138	0.106	0.079	0.079

* The dimensions in inches are rounded approximations.

Figure G4 — Two Electrode 5mm Product Dimensions



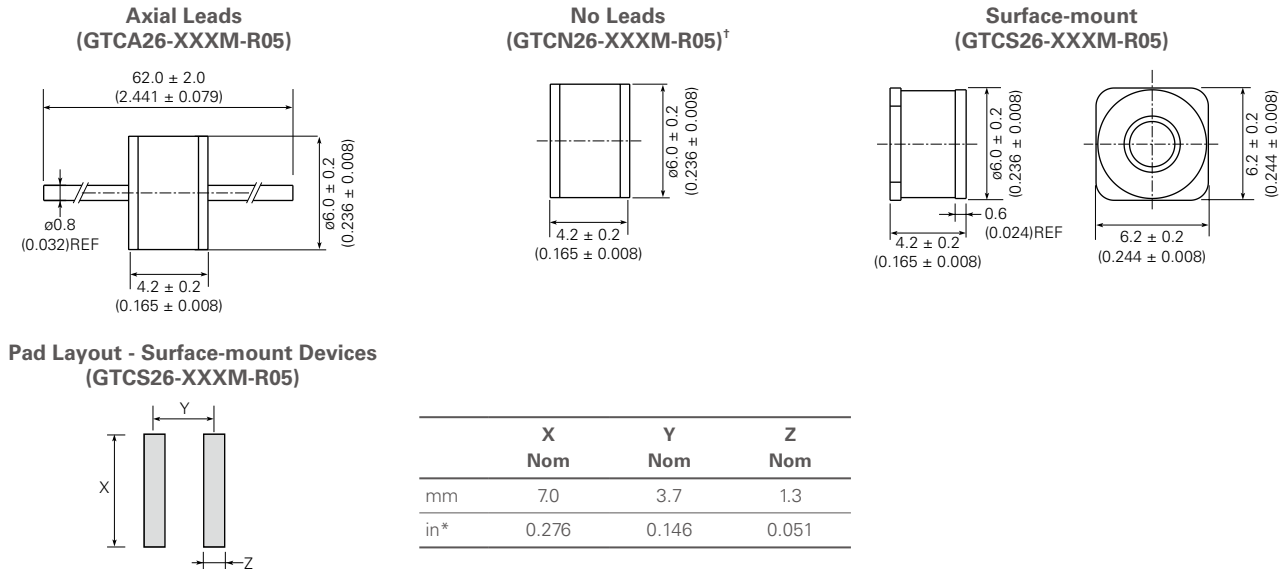
* The dimensions in inches are rounded approximations.
† Parts with no leads are not solderable and are meant for insertion into magazine clips.

Gas Discharge Tubes (GDTs)

Figures G3-G11 — Dimensions for Gas Discharge Tubes

(Cont'd)

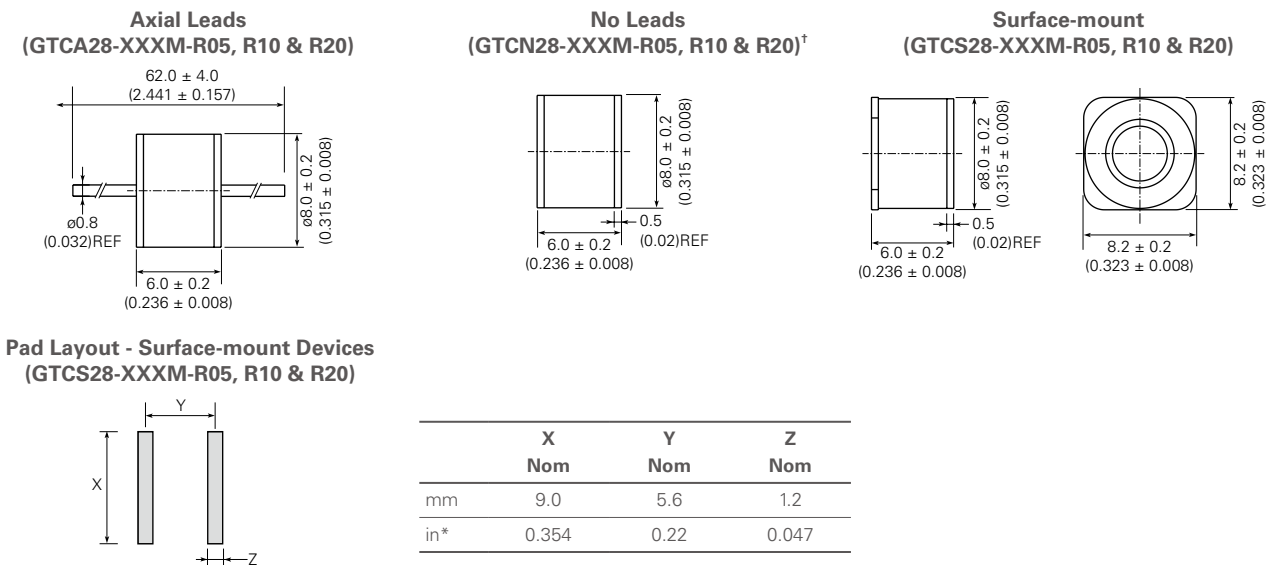
Figure G5 — Two Electrode 6mm Product Dimensions



* The dimensions in inches are rounded approximations.

† Parts with no leads are not solderable and are meant for insertion into magazine clips.

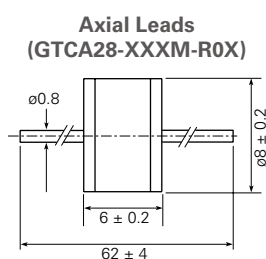
Figure G6 — Two Electrode 8mm Product Dimensions



* The dimensions in inches are rounded approximations.

† Parts with no leads are not solderable and are meant for insertion into magazine clips.

Figure G7 — Two Electrode 8mm High Voltage Product Dimensions

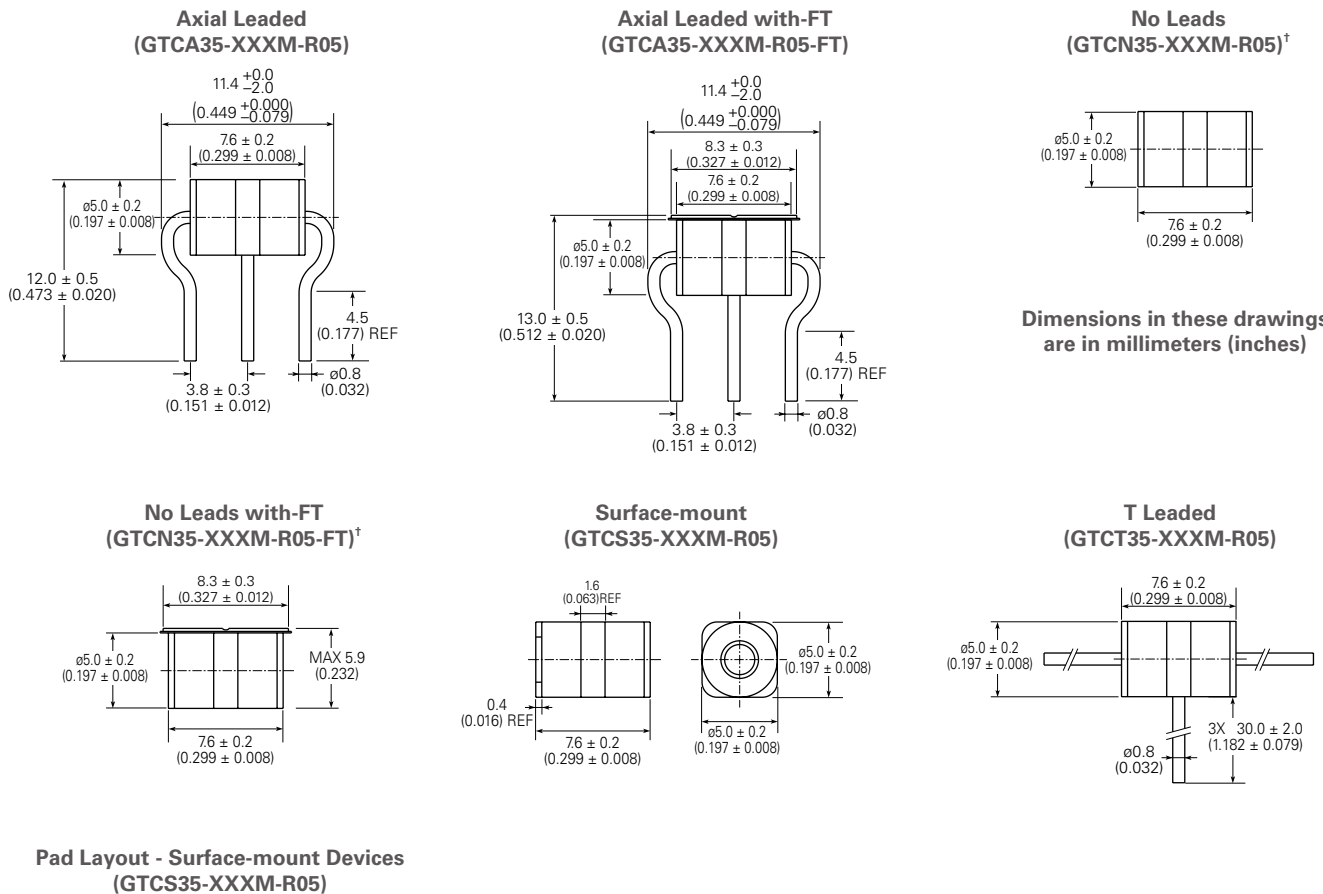


Gas Discharge Tubes (GDTs)

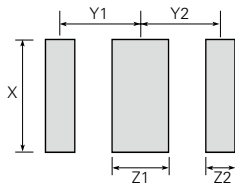
Figures G3-G11 — Dimensions for Gas Discharge Tubes

(Cont'd)

Figure G8 — Three Electrode 5mm Product Dimensions



Pad Layout - Surface-mount Devices (GTCS35-XXXM-R05)



	X	Y1	Y2	Z1	Z2
	Nom	Nom	Nom	Nom	Nom
mm	6.0	3.6	3.6	2.5	1.3
in*	0.236	0.142	0.142	0.098	0.051

* The dimensions in inches are rounded approximations.

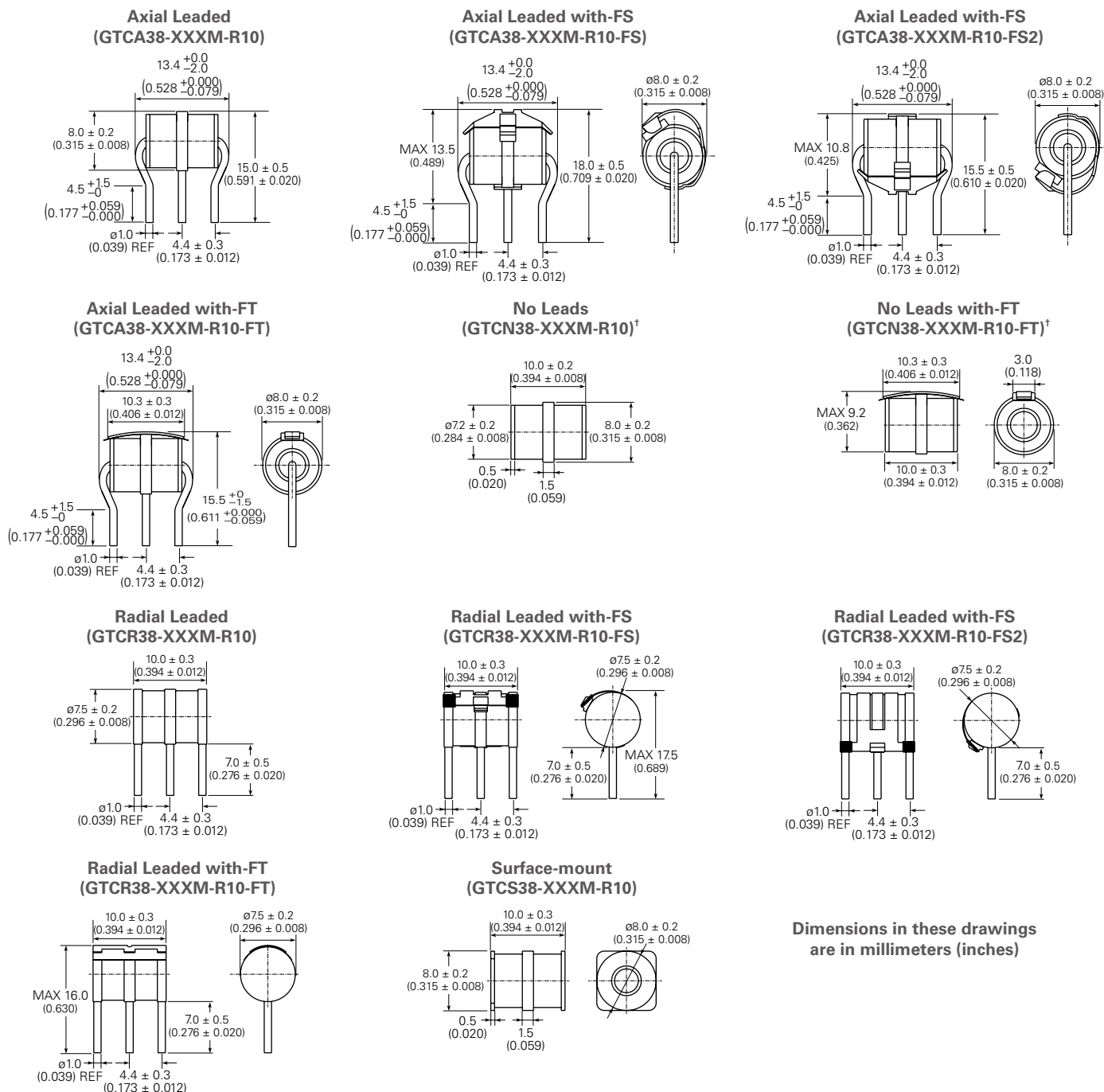
† Parts with no leads are not solderable and are meant for insertion into magazine clips.

Gas Discharge Tubes (GDTs)

Figures G3-G11 — Dimensions for Gas Discharge Tubes

(Cont'd)

Figure G11 — Three Electrode 8mm Product Dimensions



* The dimensions in inches are rounded approximations.

† Parts with no leads are not solderable and are meant for insertion into magazine clips.

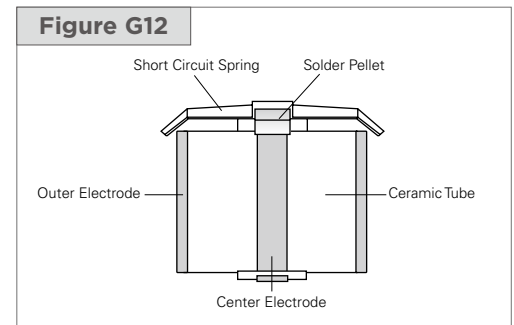
Gas Discharge Tubes (GDTs)

Fail-Short Mechanism for Gas Discharge Tubes

Fail-Short Mechanism — FS

The FS fail-short mechanism is a short circuit spring mounted onto a solder pellet located at the center electrode of the gas tube. Under normal operating conditions, the pellet is positioned to make the spring float above the outer electrodes, as shown in Figure G11 on the previous page..

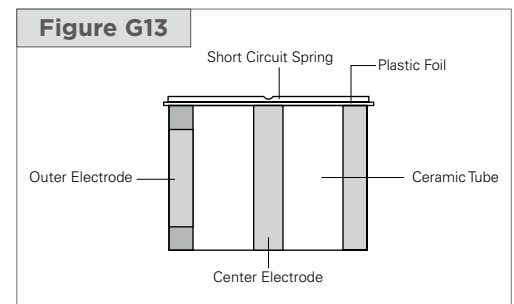
When a prolonged discharge event causes the gas tube temperature to reach the melting point of the solder, the pellet softens allowing the short circuit spring to contact with both outer electrodes (Figure G12). This process results in a permanent short circuit between all three electrodes creating a low resistance path that conducts the fault current to ground without generating a significant amount of heat.



Fail-Short Mechanism — FT

The FT fail-short mechanism is a short circuit spring with a piece of plastic foil spot welded onto the center electrode. Under normal operating conditions, the plastic foil makes the spring insulated from the two outer electrodes.

When a prolonged discharge event causes the gas tube temperature to reach the melting point of the plastic foil, the plastic foil melts allowing the short circuit spring to contact both outer electrodes (Figure G13). This process results in a permanent short circuit between all three electrodes creating a low resistance path that conducts the fault current to ground without generating a significant amount of heat.



Operation and Storage Temperatures for Gas Discharge Tubes

Operation Temperature Range

Models without Fail-Short Mechanism : -40°C/+90°C

Models with Fail-Short Mechanism : -20°C/+65°C

Storage Temperature Range

Models without Fail-Short Mechanism : -40°C/+90°C

Models with Fail-Short Mechanism : -20°C/+65°C

Packaging Information for Gas Discharge Tubes

Part Description	Parts in Bulk		Parts in Tape and Reel	
	Min Order Quantity	Box Quantity	Tape and Reel Min Order Quantity	Box Quantity
3mm 2Pole Surface-mount	—	—	2000	16000
5mm 2Pole No leads	5000	20000	—	—
5mm 2Pole Leads	1000	5000	—	—
5mm 2Pole Surface-mount	—	—	1500	12000
6mm 2Pole No leads	2000	10000	—	—
6mm 2Pole Leads	1000	5000	—	—
6mm 2Pole Surface-mount	—	—	750	6000
8mm 2pole No leads	2000	10000	—	—
8mm 2Pole Leads	1000	5000	—	—
8mm 2Pole Surface-mount	—	—	500	4000
5mm 3Pole No leads	2500	10000	—	—
5mm 3Pole Leads	1000	5000	—	—
5mm 3Pole Surface-mount	—	—	1000	8000
6mm 3Pole No leads	2500	10000	—	—
6mm 3Pole Leads	1000	5000	—	—
6mm 3Pole Surface-mount	—	—	750	4500
7mm 3Pole Leads	1000	5000	—	—
8mm 3Pole No leads	1000	5000	—	—
8mm 3Pole Leads	1000	5000	—	—
8mm 3Pole Surface-mount	—	—	500	2500

Gas Discharge Tubes (GDTs)

Installation for Gas Discharge Tubes

Care should be taken when installing GDTs equipped with fail-short mechanisms into arrester magazines, printed circuit boards, etc. Too much downward pressure may force the short circuit spring through the thin insulation tube creating a shorted condition.

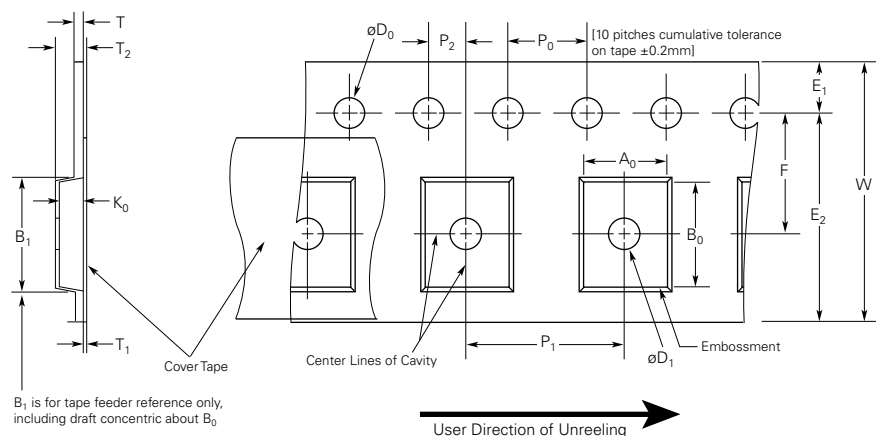
Solder Reflow Recommendations for Surface-mount GDT Devices

Surface-mount GDTs can be soldered using standard Pb-free reflow profiles.

Table G4 — Tape and Reel Specifications

Tape Dimension	3mm devices (2 pole)	5mm devices (2 pole)	6mm devices (2 pole)	8mm devices (2 pole)
EIA Mark	Dimension (mm)	Dimension (mm)	Dimension (mm)	Dimension (mm)
A ₀	3.40±0.10	4.9±0.10	6.70±0.10	8.60±0.10
B ₀	5.00±0.10	5.5±0.10	4.60±0.10	6.40±0.10
D ₀	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0
D ₁	—	1.5 MIN	—	—
E ₁	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
E ₂	14.25±0.30	14.25±0.30	14.25±0.30	14.25±0.30
F	7.50±0.10	7.50±0.10	7.50±0.10	7.50±0.10
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
P ₁	8.00±0.10	8.00±0.10	12.00±0.10	12.00±0.10
P ₂	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10
W	16.00±0.30	16.00±0.30	16.00±0.30	16.00±0.30
Tape Thickness				
EIA Mark	Dimension (mm)	Dimension (mm)	Dimension (mm)	Dimension (mm)
B ₁	—	—	—	—
K ₀	3.30±0.10	5.30±0.10	6.50±0.10	8.50±0.10
T	0.35±0.05	0.40±0.05	0.35±0.05	0.50±0.05
T ₁	—	—	—	—
T ₂	—	—	—	—
Reel Dimension	Dimension (mm)	Dimension (mm)	Dimension (mm)	Dimension (mm)
EIA Mark	Dimension (mm)	Dimension (mm)	Dimension (mm)	Dimension (mm)
A	330	330	330	330
B	2.20±0.50	2.20±0.50	2.20±0.50	2.20±0.50
C	13.00±0.20	13.00±0.20	13.00±0.20	13.00±0.20
D	20.20±1.00	20.20±1.00	20.20±1.00	20.20±1.00
N	100.00±1.00	100.00±1.00	100.00±1.00	100.00±1.00
W ₁	16.50±0.10	16.50±0.10	16.50±0.10	16.50±0.10
W ₂	21.10±02.00	21.10±02.00	21.10±02.00	21.10±02.00

Figure G14 — EIA Referenced Taped Component Dimensions

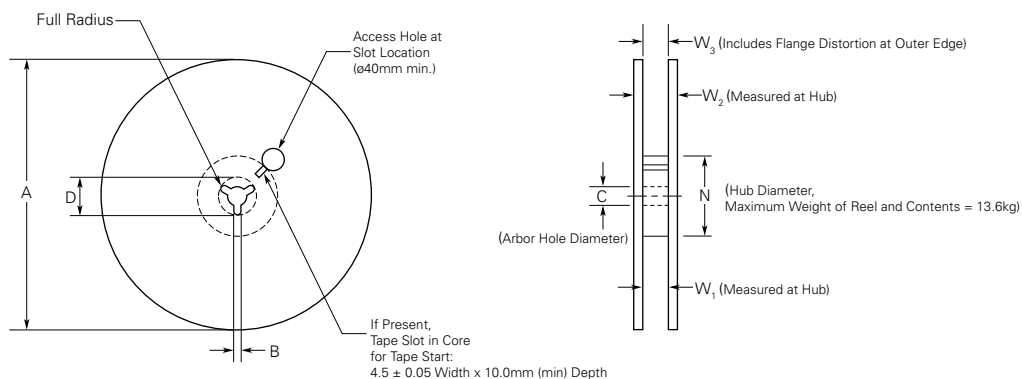


Gas Discharge Tubes (GDTs)

Table G5 — Tape and Reel Specifications

Tape Dimension	5mm devices (3 pole)	6mm devices (3 pole)	8mm devices (3 pole)
EIA Mark	Dimension (mm)	Dimension (mm)	Dimension (mm)
A ₀	5.40±0.10	6.50±0.10	8.50±0.10
B ₀	8.00±0.10	8.60±0.10	10.60±0.10
D ₀	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0
D ₁	1.50(min)	1.50(min)	—
E ₁	1.75±0.10	1.75±0.10	1.75±0.10
E ₂	14.25±0.30	22.25±0.30	22.25±0.30
F	7.50±0.10	11.50±0.10	11.50±0.10
P ₀	4.00±0.10	4.00±0.10	4.00±0.10
P ₁	8.00±0.10	12.00±0.10	16.00±0.10
P ₂	2.00±0.10	2.00±0.10	2.00±0.10
W	16.00±0.30	24.00±0.30	24.00±0.30
Tape Thickness			
EIA Mark	Dimension (mm)	Dimension (mm)	Dimension (mm)
B ₁	—	—	—
K ₀	5.70±0.10	6.30±0.10	8.40±0.10
T	0.50±0.05	0.50±0.05	0.50±0.05
T ₁	—	—	—
T ₂	—	—	—
Reel Dimension			
EIA Mark	Dimension (mm)	Dimension (mm)	Dimension (mm)
A	330	330	330
B	2.20±0.50	2.20±0.50	2.20±0.50
C	13.00±0.20	13.00±0.20	13.00±0.20
D	20.20±1.00	20.20±1.00	20.20±1.00
N	100.00±1.00	100.00±1.00	100.00±1.00
W ₁	16.50±0.10	24.50±0.10	24.50±0.10
W ₂	21.10±02.00	29.10±02.00	29.10±02.00
W ₃	—	—	—

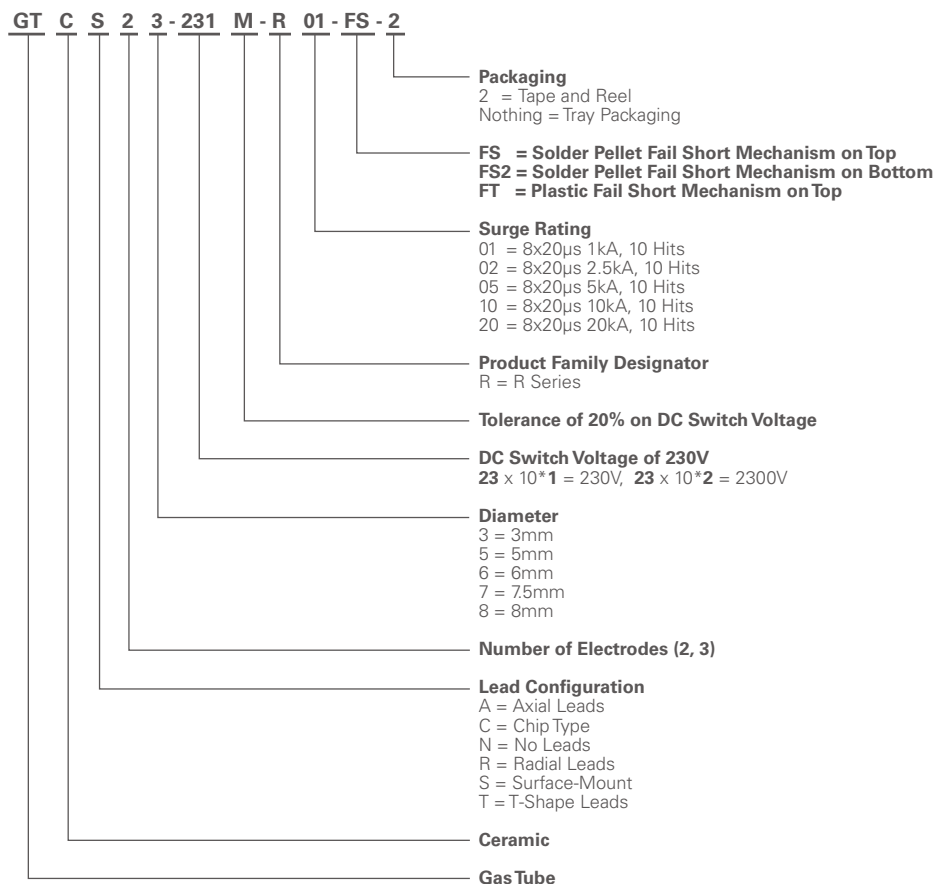
Figure G15 — EIA Referenced Reel Dimensions



Gas Discharge Tubes (GDTs)

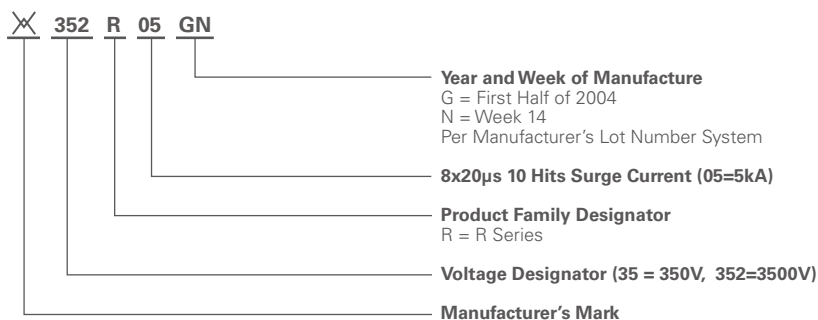
Part Numbering System for Gas Discharge Tubes

Example Part Number



NOTE: GTCS23-XXXM-R01 and GTCC23-XXXM-R01 parts available only in surface-mount and tape and reel packaging.

Marking Reference Guide — Example



NOTES: GTCS23-XXXM-R01 and GTCC23-XXXM-R01 parts will have no marking. Devices with no leads (GTCNxx-xxxx-xx) are not able to be soldered as their electrodes are nickel plated. They should be installed by insertion into a magazine clip.

Notice:

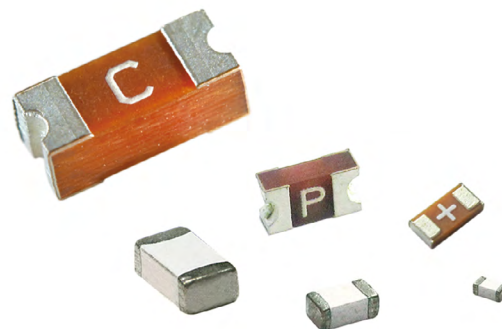
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SURFACE-MOUNT FUSES

Fundamentals

Overview

Littelfuse offers the widest selection of surface-mount fuses available for addressing a broad range of overcurrent protection applications. Helping to prevent costly damage and promote a safe environment for electronic and electrical equipment, our single-use chip fuses provide performance stability to support applications with current ratings from .5A up to 30A.



Multi-layer Design for Chip Fuses

The multi-layer design has the benefit of exposing more fuse element surface area to the glass-ceramic absorption material. When the fuse elements open, there is more material for the vaporizing fuse metals to absorb into, resulting in a very efficient and effective quenching of the fuse arc.

Figure SF1 compares the multi-layer design of our SFF fuses with standard glass coated designs. The glass coated designs rely on the coating on only one side of the fuse element to absorb the vaporizing fuse material when it opens. Therefore, there is much less absorption material available to absorb the fuse metals. The result can be prolonged arcing and possible coating breach.

Figure SF2 shows how the absorption characteristics of the two designs differ. The multi-layer design indicates a clean separation with the fuse element evenly diffusing into the surrounding ceramic substrate. In the glass coated design, the element diffusion takes place in a small portion of the device and is only absorbed by the glass material directly above the area of failure.

Figure SF1

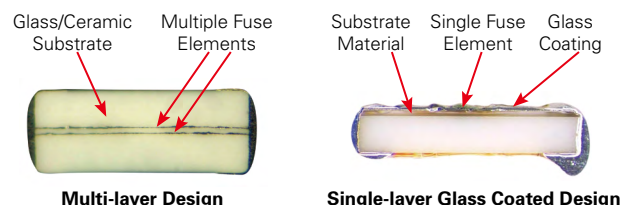
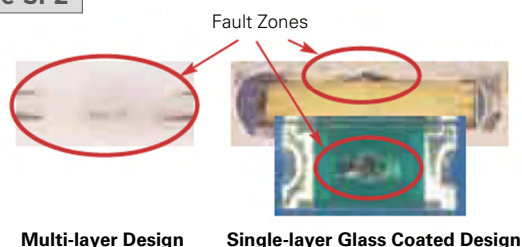


Figure SF2



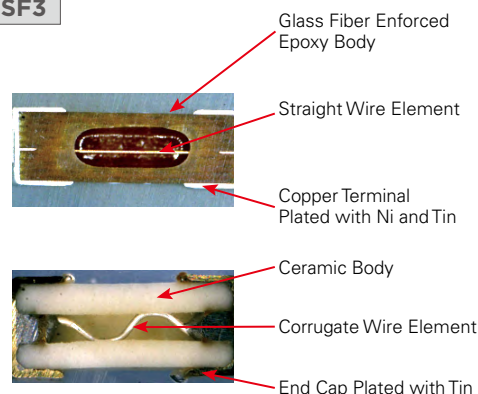
Wire-In-Air Design for 2410SFV, 1206SFV Fuses

The 2410SFV, 1206SFV fuse are Wire-In-Air SMD fuse that is suitable for secondary level overcurrent protection applications.

Figure SF3 compares our straight wire element design 2410SFV, 1206SFV fuses with normal corrugated wire design fuse. The straight wire element in air provides consistent fusing and cutting characteristics together with inrush current withstanding capability.

By introducing PCB assembly technology into the 2410SFV, 1206SFV fuse design and manufacturing process, lead-free compliance has been achieved without the problems associated with end caps on traditional ceramic devices.

Figure SF3



Surface Mount Fuses

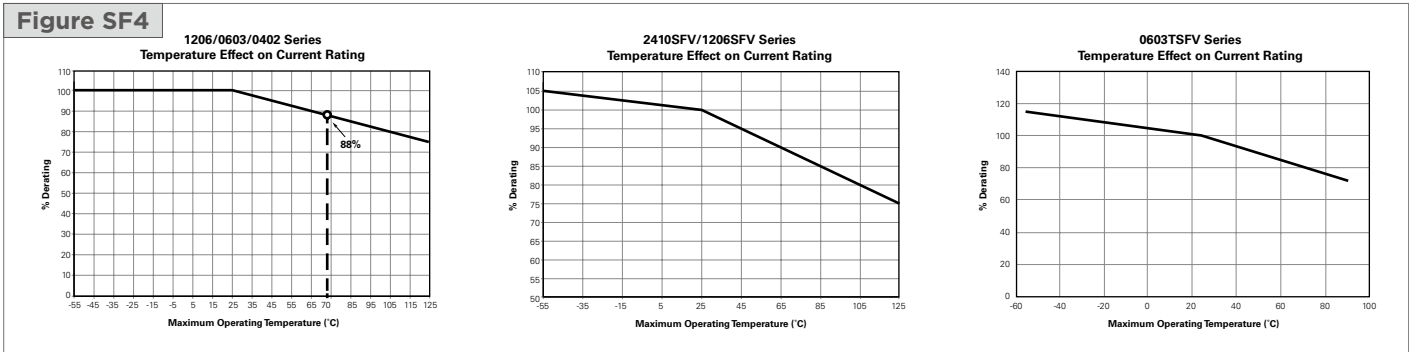
Fundamentals

Thin Film Design for 0603TSFV Fuses

The 0603TSFV fuses are thin film fuses that are suitable for secondary level overcurrent protection applications. The thin film design has the benefit of fast fusing under low overload current and thin thickness.

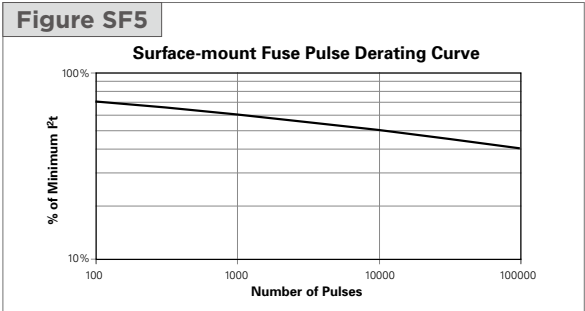
Temperature Derating

A fuse is a temperature sensitive device. Therefore, operating temperature will have an effect on fuse performance and lifetime. Operating temperature should be taken into consideration when selecting the fuse current rating. The Thermal Derating Curve for surface-mount fuses is presented in Figure SF4. Use it to determine the derating percentage based on operating temperature and apply it to the derated system current.



Pulse Cycle Derating

Once the I^2t value for the application waveform has been determined, it must be derated based on the number of cycles expected over the system lifetime. Since the stress induced by the current pulse is mechanical in nature, the number of times the stress is applied has significant bearing on how much derating must be applied to the fuse rating. Figure SF5 presents the current pulse derating curve for our surface-mount chip fuses up to 100,000 cycles.

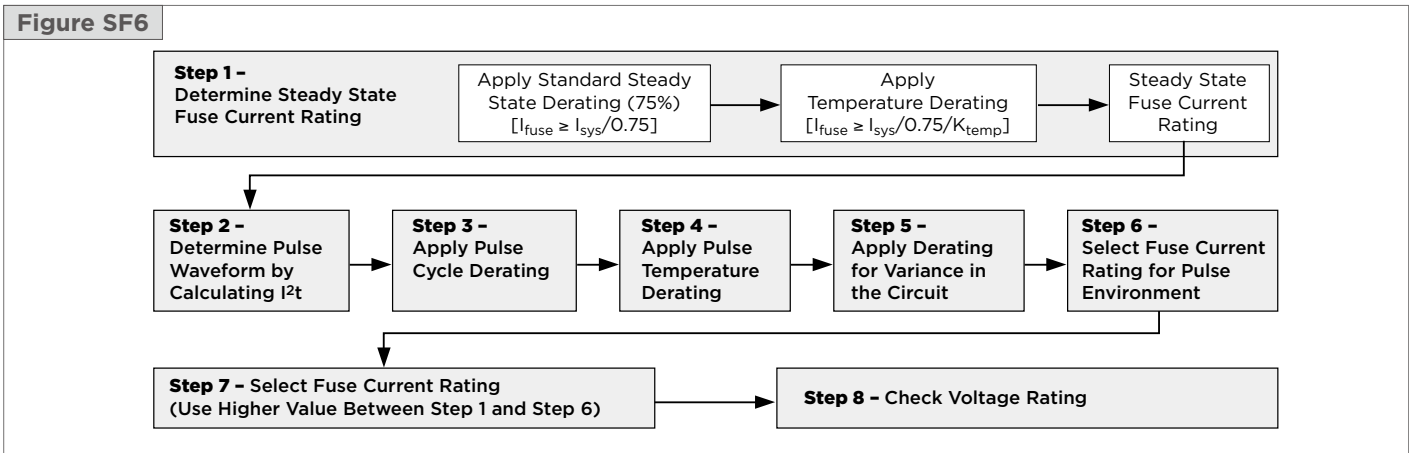


Selecting Surface-mount Fuses

Fuse selection seems straightforward, in that you pick one which has a current rating just a bit higher than your worst case system operating current. Unfortunately, it is not that simple. There are derating considerations for operating current and application temperature. Turn-on and other system operations (like processor speed changes or motor start up) cause current surges or spikes that also require consideration when selecting a fuse. So selecting the right fuse for your application is not as simple as knowing the nominal current drawn by the system.

Fuse Selection Flowchart

However, the basic considerations for fuse selection are shown in the flow chart presented in Figure SF6. Following this flow chart will help you select a fuse best suited for your application conditions. For a detailed example of this process you can download our Fuse Selection Guide available on our website.



Surface Mount Fuses

Fundamentals

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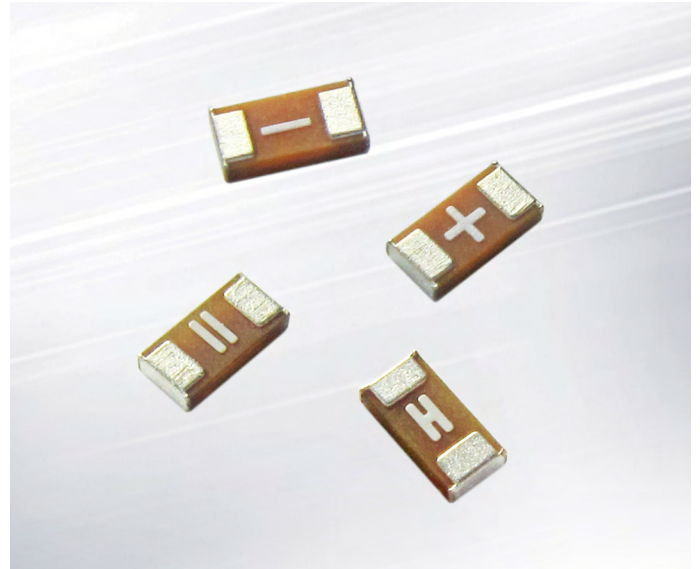
SURFACE-MOUNT FUSES

0603 Thin Film Very Fast-Acting Chip Fuses



Very fast-acting fuses help provide overcurrent protection for systems using DC power sources up to 65V_{DC}. The fuses' thin film design helps provide fast fusing under low overload current and low DCR (Direct Current Resistance).

These RoHS-compliant, surface-mount devices offer strong arc suppression characteristics and facilitate the development of more reliable, high-performance consumer electronics, such as notebook computers and tablets, digital cameras, memory cards, toys, Bluetooth earphones and other portable electronics devices.



BENEFITS

- Very fast acting at 200% and 300% overloads
- Inrush current withstand capability at high overloads
- Thin body for space-limited applications
- Fiberglass enforced epoxy fuse body
- Copper termination with nickel and tin plating
- RoHS compliant and lead-free materials

FEATURES

- Lead-free materials and RoHS compliant
- Halogen free
(refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)
- Fiberglass enforces epoxy fuse body design
- Low DCR
- -55°C to +90°C operating temperature range

APPLICATIONS

- Notebook computers and tablets
- Digital cameras
- Memory cards
- Toys
- Bluetooth earphones
- Portable electronics devices

Surface Mount Fuses
0063 Thin Film Very Fast-Acting Chip Fuses

Table FV1 — ClearTime Characteristics

Table with 3 columns: % of Rated Current, ClearTime at 25°C. Rows show 100%, 200%, and 300% current levels and their corresponding clear times.

Table FV2 — Typical Electrical Characteristics and Dimensions

0603 (1608 mm) Very Fast-Acting Chip Fuses

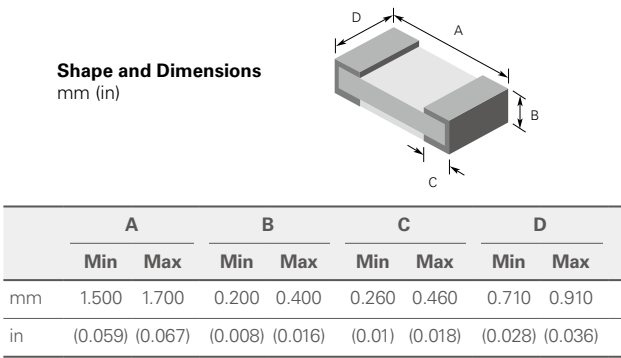
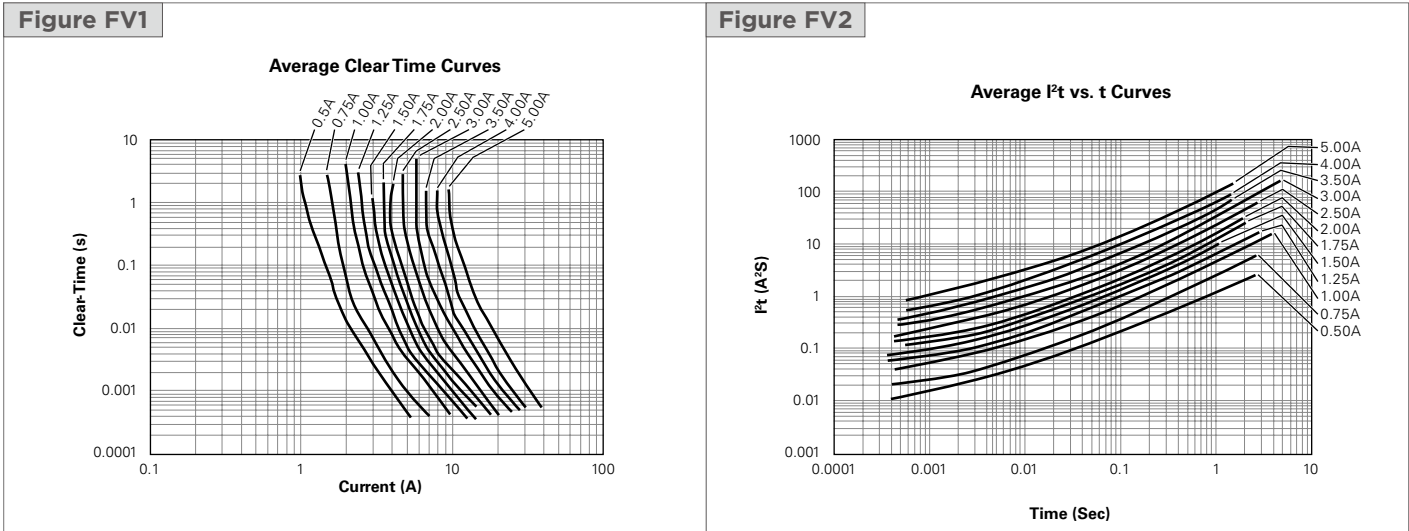


Table with 7 columns: Part Number, Marking Code, Rated Current (A), Interrupt Rating, Voltage Rating (VDC), Nominal Cold DC Resistance (DCR) (Ω), Nominal I²t (A²s)². Rows list various fuse models and their specifications.

1 Measured at ≥10% of rated current and 25°C ambient.
2 Melting I²t at 1 ms.

Figures FV1-FV2 — Family Performance Curves



➔ Please go to page 108 for more information about 0603 Thin Film Very Fast-Acting Chip Fuses.

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SURFACE-MOUNT FUSES

Fast-Acting Chip Fuses

Fast-acting chip fuses help provide overcurrent protection for systems using DC power sources up to 63V_{DC}. The fuse's monolithic, multilayer design helps provide the highest hold current in the smallest footprint, reduce diffusion-related aging, improve product reliability and resilience, and enhance high-temperature performance in a wide range of circuit designs.

These RoHS-compliant surface-mount devices offer strong arc suppression characteristics and help facilitate the development of more reliable, high-performance consumer electronics such as laptops, multimedia devices, cell phones and other portable electronics.



BENEFITS

- Small size with high current ratings
- Temperature stability
- High reliability and resilience
- Strong arc suppression characteristics

FEATURES

- Lead-free and RoHS compliant
- Halogen free
(refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)
- Monolithic, multilayer design
- High-temperature performance
- -55°C to +125°C operating temperature range

APPLICATIONS

- Laptops
- Digital cameras
- Cell phones
- Printers
- DVD players
- Portable electronics
- Game systems
- LCD monitors
- Scanners

Surface Mount Fuses

Fast-Acting Chip Fuses

Figures FF1-FF6 — Family Performance Curves

Figure FF1

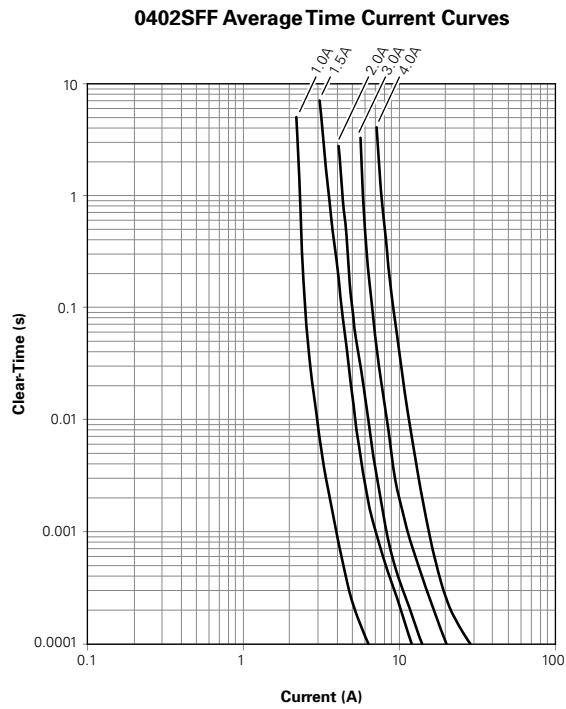
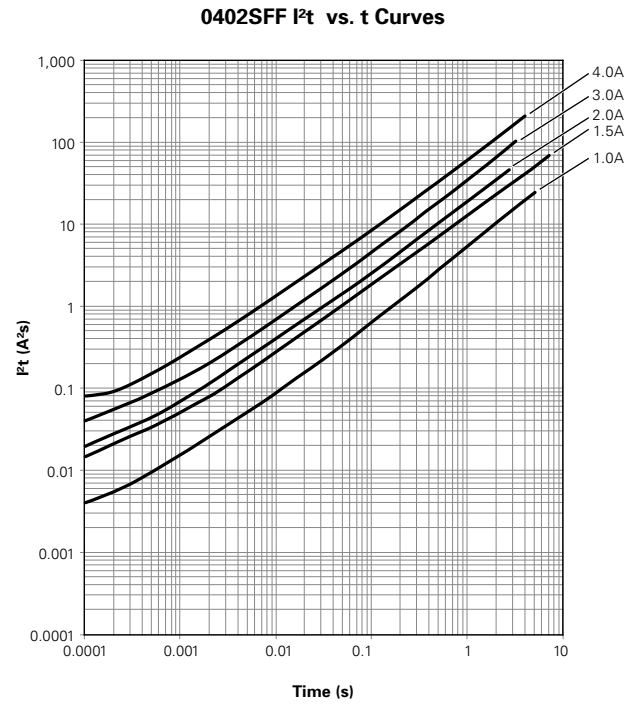


Figure FF2



Note: Curves are nominal.

Figure FF3

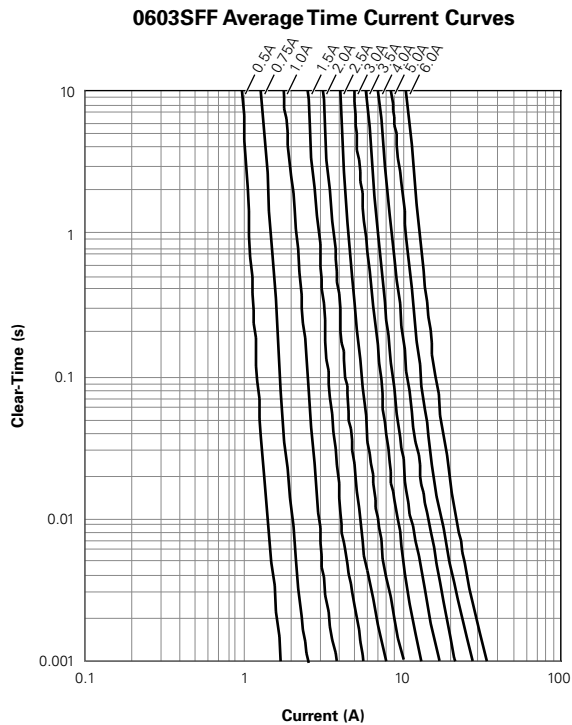
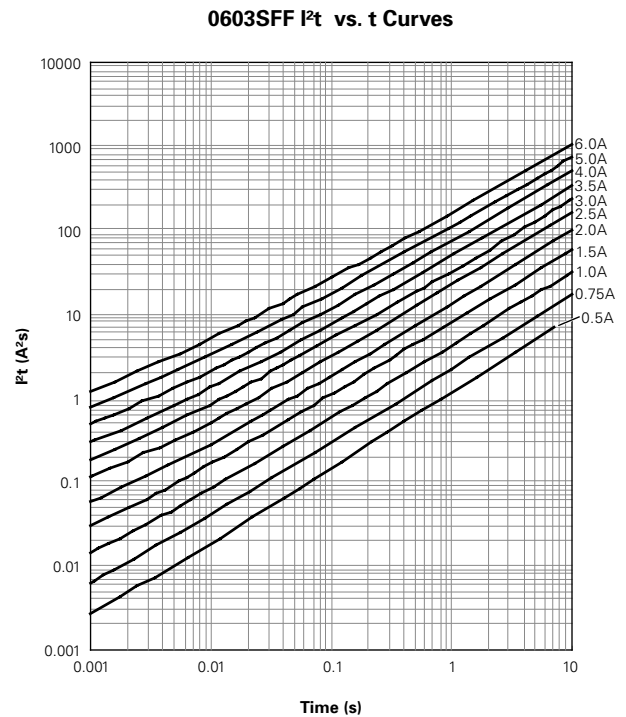


Figure FF4



Note: Curves are nominal.

Surface Mount Fuses Fast-Acting Chip Fuses

Figures FF1-FF6 — Family Performance Curves

(Cont'd)

Figure FF5

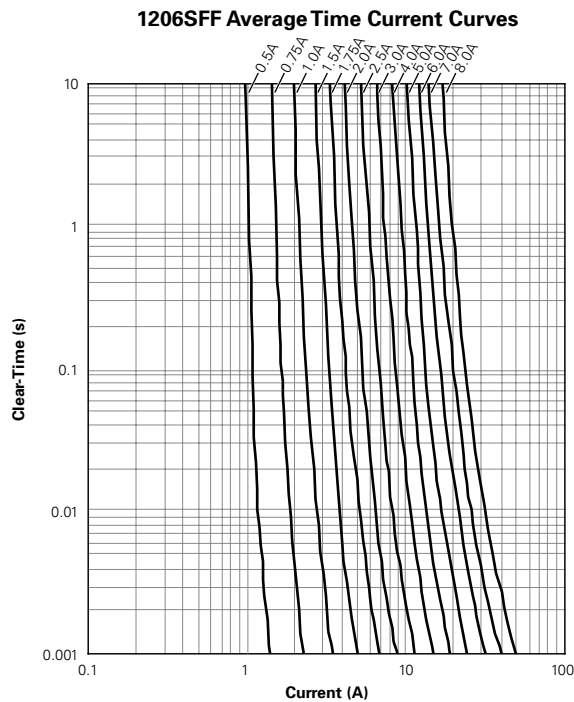
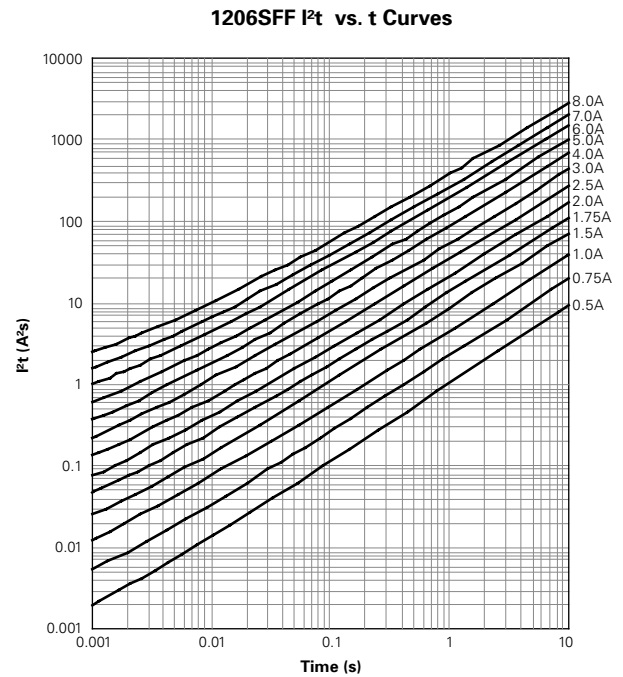


Figure FF6



Note: Curves are nominal.

→ Please go to page 108 for more information about Fast-Acting Chip Fuses.

Notice:

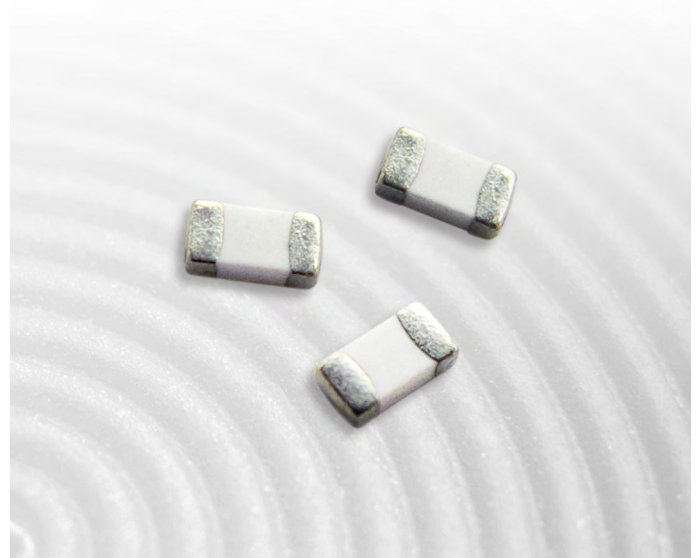
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SURFACE-MOUNT FUSES

0603 Very Fast-Acting Chip Fuses

Very fast-acting chip fuses help provide overcurrent protection for systems using DC power sources up to 32V_{DC}. The fuse's monolithic, multilayer design helps provide the highest hold current in the smallest footprint, reduce diffusion-related aging, improve product reliability and resilience, and enhance high-temperature performance in a wide range of circuit designs.

These RoHS-compliant surface-mount devices offer strong arc suppression characteristics and facilitate the development of more reliable, high-performance consumer electronics such as laptops, multimedia devices, cell phones and other portable electronics.



BENEFITS

- Very fast acting at 200% and 300% overloads
- Inrush current withstand capability at high overloads
- Thin body for space-limited applications
- Glass ceramic monolithic structure
- Silver fusing element and silver termination with nickel and tin plating
- RoHS compliant and lead-free materials
- Symmetrical design with marking on both sides (optional)

FEATURES

- Lead-free materials and RoHS compliant
- Halogen free
(refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)
- Monolithic, multilayer design
- High-temperature performance
- -55°C to +125°C operating temperature range

APPLICATIONS

- Laptops
- Digital cameras
- Cell phones
- Printers
- DVD players
- Portable electronics
- Game systems
- LCD monitors
- Scanners

Surface Mount Fuses

0603 Very Fast-Acting Chip Fuses

Table FV1 — ClearTime Characteristics

% of Rated Current		ClearTime at 25°C	
100%	4 hrs (min)	—	
200%	0.01 s (min)	5 s (max)	
300%	0.001 s (min)	0.2 s (max)	

Table FV2 — Typical Electrical Characteristics and Dimensions

0603 (1608 mm) Very Fast-Acting Chip Fuses

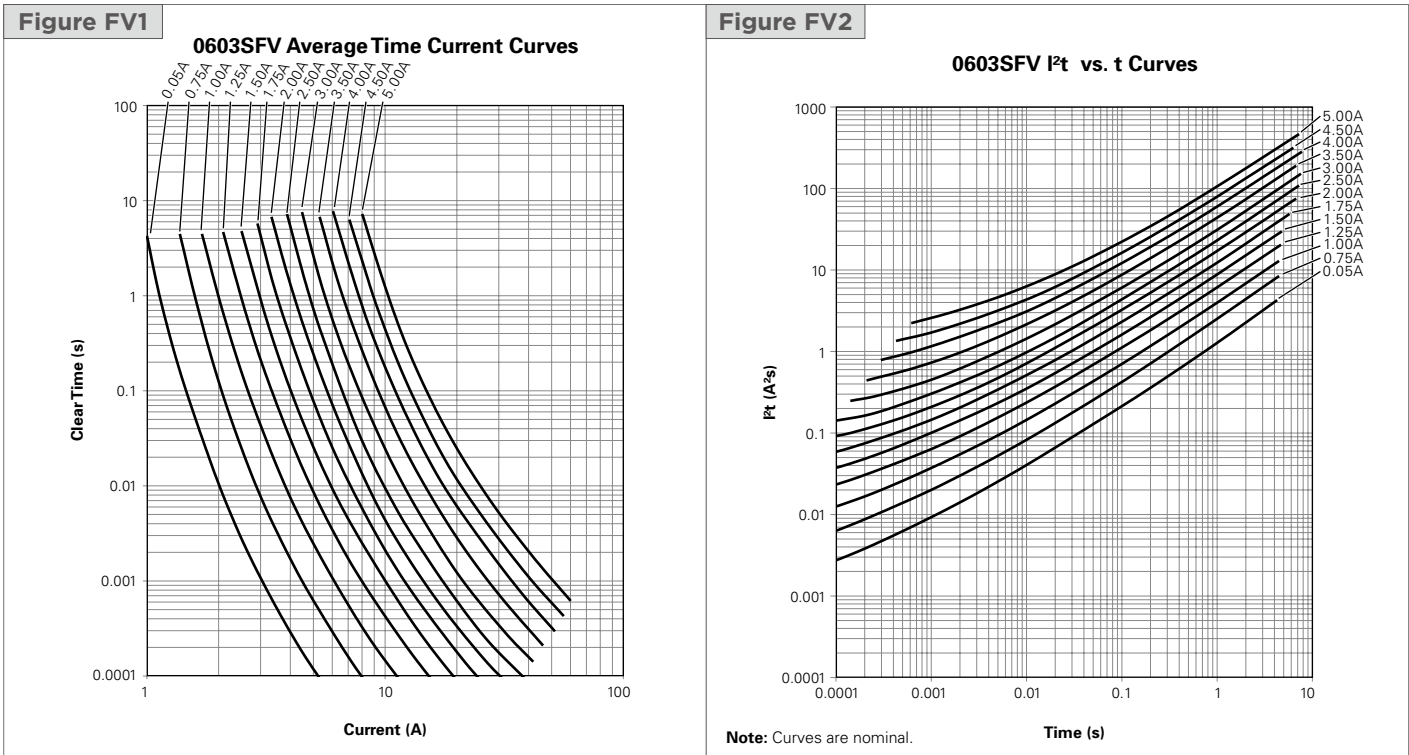


	A		B		C		D	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	1.45	1.75	0.22	0.48	0.21	0.51	0.65	0.95
in	(0.057)	(0.069)	(0.009)	(0.019)	(0.008)	(0.020)	(0.025)	(0.037)

Part Number	Typical			Max	
	Electrical Characteristics			Interrupt Ratings	
	Rated Current (A)	Nominal Cold DCR (Ω)*	Nominal I²t (A²sec)	Voltage (V _{DC})	Current (A)
0603SFV050F/32-2	0.5	0.860	0.0093	32	50
0603SFV075F/32-2	0.8	0.450	0.0191	32	50
0603SFV100F/32-2	1.0	0.280	0.0360	32	50
0603SFV125F/32-2	1.3	0.205	0.0630	32	35
0603SFV150F/32-2	1.5	0.143	0.0950	32	35
0603SFV175F/32-2	1.8	0.095	0.1400	32	35
0603SFV200F/32-2	2.0	0.073	0.2100	32	35
0603SFV250F/32-2	2.5	0.046	0.3000	32	35
0603SFV300F/32-2	3.0	0.039	0.4600	32	35
0603SFV350F/32-2	3.5	0.028	0.7300	32	35
0603SFV400F/32-2	4.0	0.023	1.1500	32	35
0603SFV450F/32-2	4.5	0.019	1.6800	32	35
0603SFV500F/32-2	5.0	0.015	2.6200	32	35

* Measured at 10% of rated current and 25°C.

Figures FV1-FV2 — Family Performance Curves



➔ Please go to page 108 for more information about Very Fast-Acting Chip Fuses.

Surface Mount Fuses

0603 Very Fast-Acting Chip Fuses

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SURFACE-MOUNT FUSES

1206 Very Fast-Acting Chip Fuses

Very fast-acting chip fuses help provide overcurrent protection for systems using DC power sources up to 65V_{DC}. The fuses' wire-in-air design helps provide the highest voltage rating and excellent inrush current withstand capability, reduces diffusion-related aging, improves product reliability and resilience, and enhances high-temperature performance in a wide range of circuit designs.

These RoHS-compliant, surface-mount devices offer strong arc suppression characteristics and facilitate the development of more reliable, high-performance consumer electronics. These include laptop computers and ultra-portable notebooks, backlight drivers, DC/DC converters, low-voltage power for lighting applications and automotive electronics.



BENEFITS

- Fast acting at 250% overloads
- Inrush current withstand capability at high overloads
- Thin body for space-limited applications
- Fiberglass-enforced epoxy fuse body for reliability
- Symmetrical design with markings on both sides (optional)
- Wire-in-air design increases safety
- Meet environmental standards for greener designs

FEATURES

- Lead-free materials and RoHS compliant
- Halogen free
(refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)
- -55°C to +125°C operating temperature range
- Fast acting at 250% overload current level
- Copper/copper alloy fusing element

APPLICATIONS

- Laptop computers and ultra-portable notebooks
- Backlight Drivers
- DC/DC Converters
- Low-voltage Power for Lighting Applications
- Automotive Electronics

Surface Mount Fuses

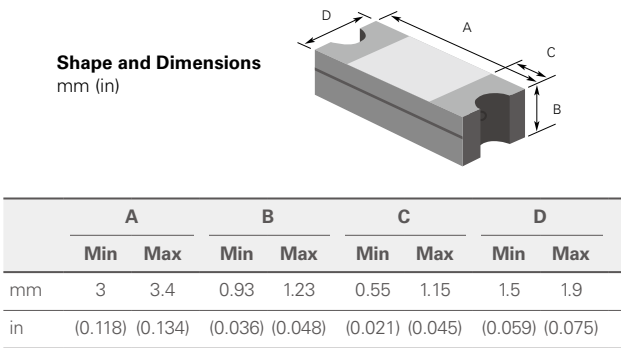
1206 Very Fast-Acting Chip Fuses

Table FV1 — ClearTime Characteristics

% of Rated Current		ClearTime at 25°C	
100%		4 hrs (min)	—
250%		—	5 s (max)

Table FV2 — Typical Electrical Characteristics and Dimensions

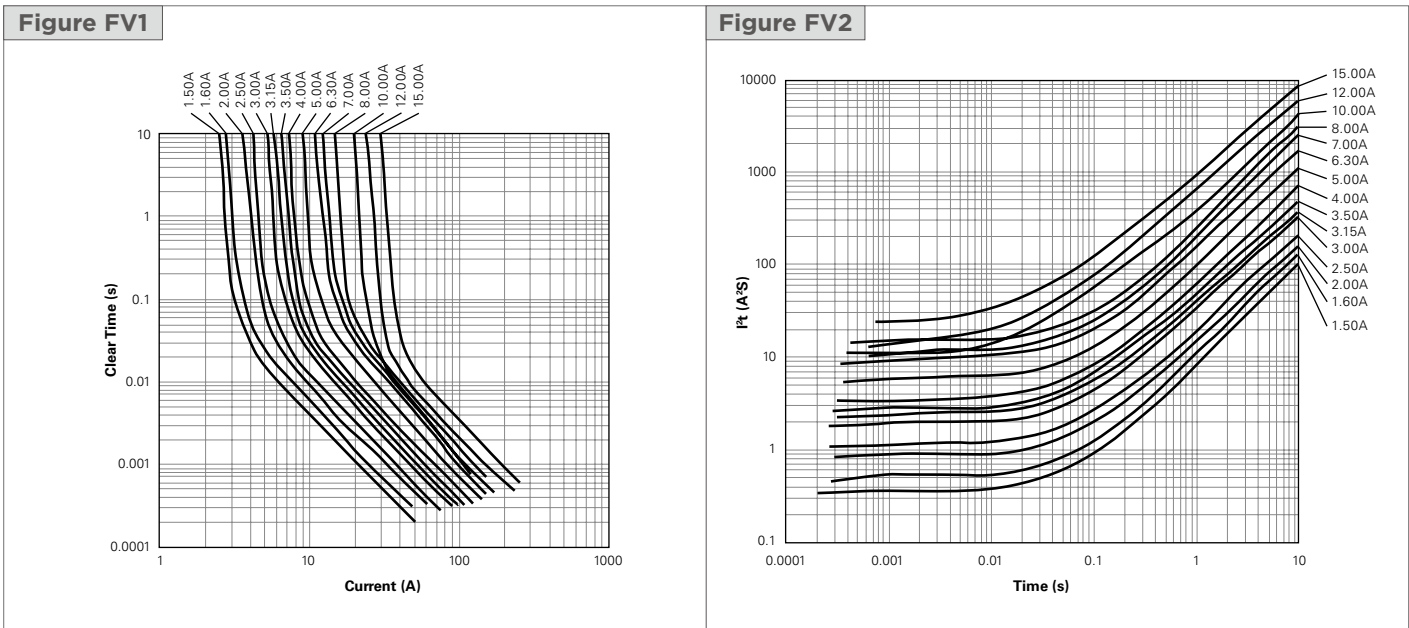
1206 (3216 mm) Very Fast-Acting Fuses



Part Number	Marking Code	Rated Current (A)	Interrupt Rating	Voltage Rating (V _{DC})	Nominal Cold DC Resistance (DCR) (Ω) ¹	Nominal I ² t (A ² s)
1206SFV1.50FM/065-2	G	1.50	50A@ 65V _{DC}	65	0.050	0.37
1206SFV1.60FM/065-2	T	1.60		65	0.043	0.52
1206SFV2.00FM/065-2	I	2.00		65	0.032	0.88
1206SFV2.50FM/065-2	J	2.50		65	0.028	1.1
1206SFV3.00FM/065-2	K	3.00		65	0.022	1.9
1206SFV3.15FM/065-2	V	3.15		65	0.020	2.2
1206SFV3.50FM/065-2	L	3.50	50A@ 32V _{DC}	65	0.018	2.6
1206SFV4.00FM/065-2	M	4.00		65	0.016	3.3
1206SFV5.00FM/032-2	N	5.00		32	0.013	5.4
1206SFV6.30FM/032-2	O	6.30		32	0.010	8.9
1206SFV7.00FM/032-2	P	7.00		32	0.0092	10.4
1206SFV8.00FM/032-2	R	8.00		32	0.0084	13.5
1206SFV10.0FM/032-2	Q	10.00		32	0.0050	11.2
1206SFV12.0FM/032-2	X	12.00		32	0.0041	15.0
1206SFV15.0FM/032-2	Y	15.00		32	0.0035	24.5

¹ Measured at ≥10% of rated current and 25°C ambient.

Figures FV1-FV2 — Family Performance Curves



→ Please go to page 108 for more information about Very Fast-Acting Chip Fuses.

Surface Mount Fuses

1206 Very Fast-Acting Chip Fuses

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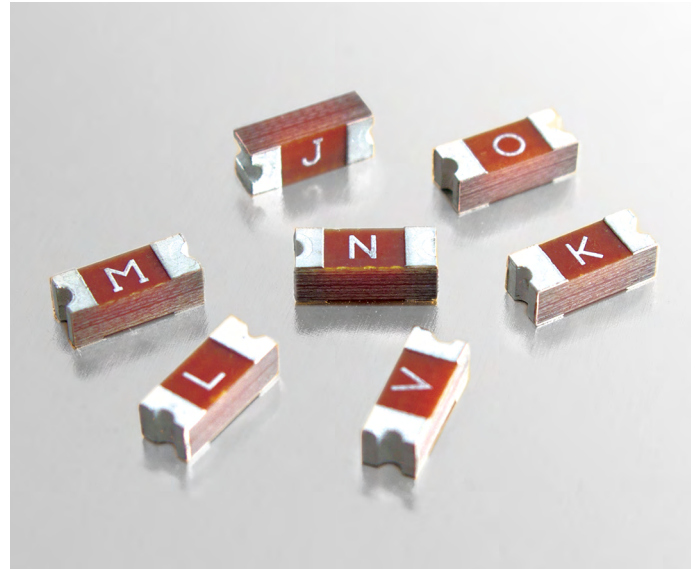
SURFACE-MOUNT FUSES

2410 Very Fast-Acting Chip Fuses



The 2410 (6125mm) Wire-in-Air (WIA) SMD Fuse is suitable for secondary-level overcurrent protection applications.

These lead-free surface-mount devices offer increased reliability and avoid the risk of end caps falling off. Their straight wire element in air performs consistent fusing and cutting characteristics.



BENEFITS

- Very fast acting at 200% overload current level
- Excellent inrush current withstand capability
- High reliability and resilience
- Strong arc suppression characteristics
- Copper terminal with nickel and tin plating

FEATURES

- Halogen free, RoHS compliant and 100% lead free
- Copper or copper alloy composite fuse link
- Fiberglass enforced epoxy fuse body
- Wide range of current rating
- -55°C to +125°C operating temperature range (With de-rating)

APPLICATIONS

- Industrial equipment
- LCD/PDP TV
- Backlight inverter
- Power supplier
- Telecom system
- Networking
- Game systems
- White goods
- Automotive

Surface Mount Fuses

2410 Very Fast-Acting Chip Fuses

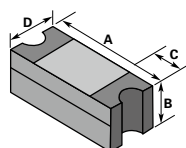
Table SFV1 — ClearTime Characteristics

% of Rated Current		ClearTime at 25°C	
100%		4 hrs (min)	—
200% (0.5A-10.0A)		0.01 s (min)	5 s (max)
200% (12.0A-20.0A)		0.01 s (min)	20 s (max)

Table SFV2 — Typical Electrical Characteristics, Dimensions and Recommended Pad Layout

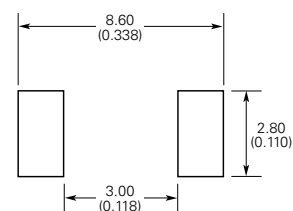
2410 (6125 mm) Very Fast-Acting Fuse

Shape and Dimensions
mm (in)



	A		B		C		D	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	5.95	6.25	1.96	2.36	0.97	1.73	2.34	2.64
in	(0.234)	(0.246)	(0.077)	(0.093)	(0.038)	(0.068)	(0.092)	(0.104)

Recommended Pad Layout
mm (Inch)

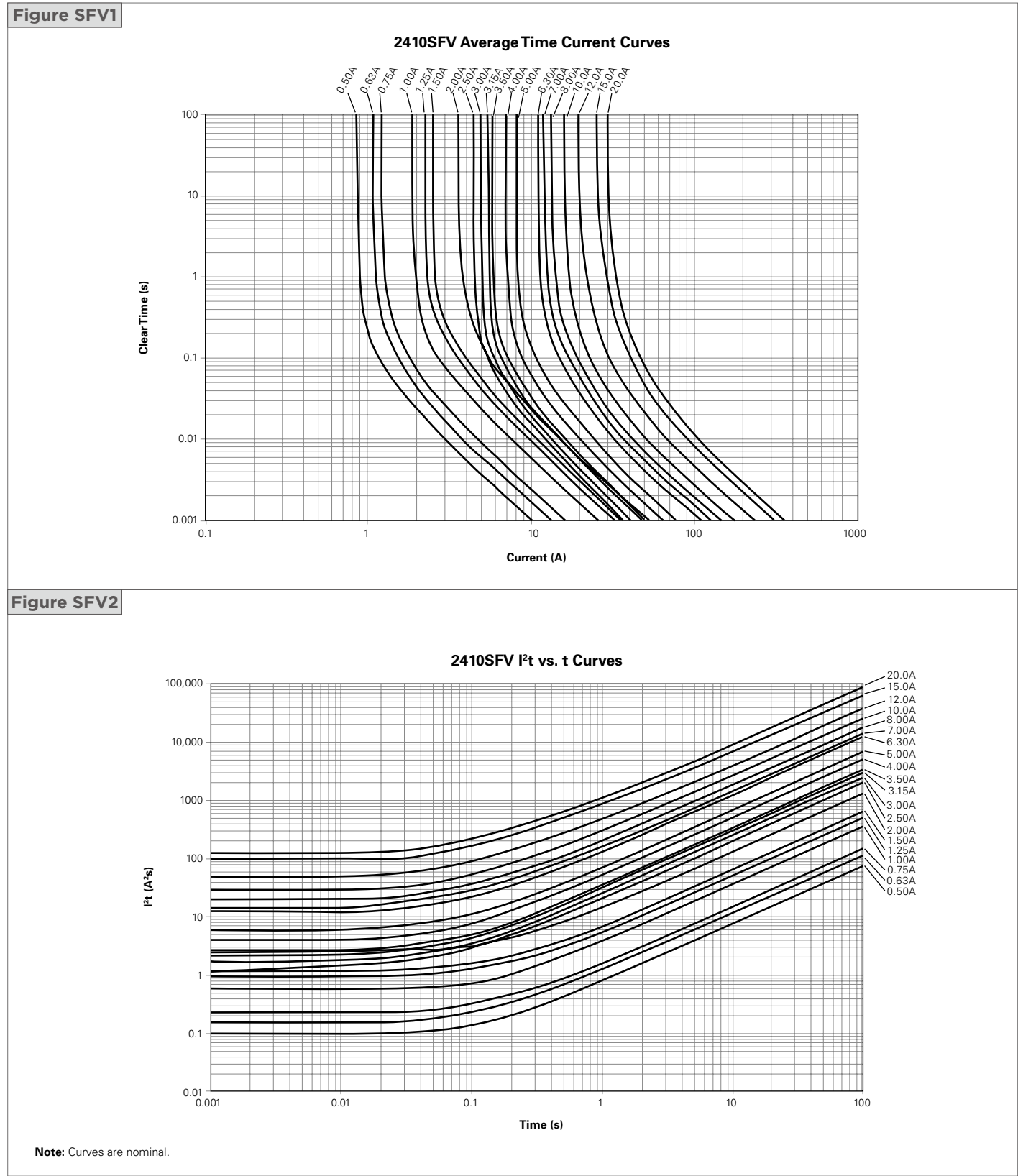


Part Number	Marking Code	Rated Current (A)	Interrupt Rating	Voltage Rating (V)		Nominal Cold DC Resistance (DCR) (Ω)*	Nominal I ² t (A ² s)
				AC	DC		
2410SFV0.50FM/125	C	0.5	UL: 0.5~2A 100A @ 250V _{AC} 2.5~8A 50A @ 125V _{AC} 0.5~8A 50A @ 125V _{DC} 300A @ 32V _{DC} TUV: 0.5A, 0.63A, 1A, 1.25A, 2A 100A @ 250V _{AC} 50A @ 125V _{DC} CQC: 0.5A, 1A, 2A 100A @ 250V _{AC} 50A @ 125V _{DC}	250	125	0.231	0.1
2410SFV0.63FM/125	S	0.63		250	125	0.174	0.16
2410SFV0.75FM/125	D	0.75		250	125	0.148	0.23
2410SFV1.00FM/125	E	1		250	125	0.093	0.59
2410SFV1.25FM/125	F	1.25		250	125	0.07	0.96
2410SFV1.50FM/125	G	1.5		250	125	0.062	1.19
2410SFV2.00FM/125	I	2		250	125	0.042	2.75
2410SFV2.50FM/125	J	2.5		125	125	0.031	1.21
2410SFV3.00FM/125	K	3		125	125	0.0249	1.73
2410SFV3.15FM/125	V	3.15		125	125	0.0232	2.2
2410SFV3.50FM/125	L	3.5	UL: 35A @ 125V _{AC} 50A @ 125V _{DC} 300A @ 32V _{DC} UL: 50A @ 65V _{AC} 50A @ 65V _{DC} 300A @ 32V _{DC} UL: 50A @ 65V _{AC} 100A @ 65V _{DC} 300A @ 32V _{DC}	125	125	0.022	2.5
2410SFV4.00FM/125	M	4		125	125	0.0172	4.1
2410SFV5.00FM/125	N	5		125	125	0.0143	5.9
2410SFV6.30FM/125	O	6.3		125	125	0.01	12.5
2410SFV7.00FM/125	P	7		125	125	0.0094	14.2
2410SFV8.00FM/125	R	8		125	125	0.0086	20.3
2410SFV10.0FM/125	Q	10		125	125	0.0066	29.2
2410SFV12.0FM/065	X	12		65	65	0.0053	49.2
2410SFV15.0FM/065	Y	15		65	65	0.0038	102.5
2410SFV20.0FM/065	Z	20		65	65	0.0034	126.2

* Measured at ≤10% of rated current and 25°C ambient

Surface Mount Fuses
2410 Very Fast-Acting Chip Fuses

Figures SFV1-SFV2 — Family Performance Curves



→ Please go to page 108 for more information about 2410 Very Fast-Acting Chip Fuses.

Surface Mount Fuses

2410 Very Fast-Acting Chip Fuses

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SURFACE-MOUNT FUSES

Pulse Tolerant Chip Fuses

Pulse Tolerant Chip Fuses have high inrush current withstand capability and provide overcurrent protection for DC power systems. These devices combine a silver fusing element and monolithic, multilayer design to provide strong arc suppression characteristics.

These RoHS-compliant surface-mount devices can help facilitate the development of more reliable, high-performance consumer electronics such as laptops, multimedia devices, cell phones and other portable electronics.



BENEFITS

- High inrush current withstanding capability
- Ceramic monolithic structure
- Silver fusing element and silver termination with nickel and tin plating
- Temperature stability
- Strong arc suppression characteristics

FEATURES

- Lead free materials and RoHS compliant
- Halogen free
(refers to: Br#900ppm, Cl#900ppm, Br+Cl#1500ppm)
- Monolithic, multilayer design
- High-temperature performance
- -55°C to +125°C operating temperature range

APPLICATIONS

- Laptops
- Digital cameras
- Cell phones
- Printers
- DVD players
- Portable electronics
- Game systems
- LCD monitors
- Scanners

Surface Mount Fuses

Pulse Tolerant Chip Fuses

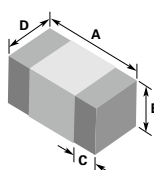
Table FP1 — ClearTime Characteristics

% of Rated Current		ClearTime at 25°C	
100%	4 hrs (min)	—	
200%	1 s (min)	60 s (max)	
1000%	0.0002 s (min)	0.02 s (max)	

Table FP2 — Typical Electrical Characteristics and Dimensions

0603 (1608 mm) Pulse Tolerant Chip Fuses

Shape and Dimensions
mm (in)

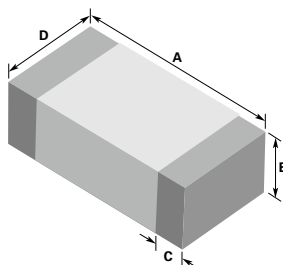


	A		B		C		D	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	1.45	1.75	0.65	0.95	0.21	0.51	0.65	0.95
in	(0.057)	(0.069)	(0.026)	(0.037)	(0.008)	(0.020)	(0.026)	(0.037)

Part Number	Typical			Max	
	Electrical Characteristics			Interrupt Ratings	
	Rated Current (A)	Nominal Cold DCR (Ω)*	Nominal I ² t (A ² sec) [†]	Voltage (V _{DC})	Current (A)
0603SFP100F/32-2	1.0	0.210	0.08	32	50
0603SFP150F/32-2	1.5	0.101	0.11	32	50
0603SFP200F/32-2	2.0	0.057	0.24	32	50
0603SFP250F/32-2	2.5	0.042	0.56	32	50
0603SFP300F/32-2	3.0	0.030	0.72	32	50
0603SFP350F/32-2	3.5	0.022	1.10	32	50
0603SFP400F/32-2	4.0	0.018	2.08	32	50
0603SFP450F/32-2	4.5	0.014	2.63	32	50
0603SFP500F/32-2	5.0	0.013	3.25	32	50
0603SFP600F/32-2	6.0	0.010	4.00	32	70

1206 (3216 mm) Pulse Tolerant Chip Fuses

Shape and Dimensions
mm (in)



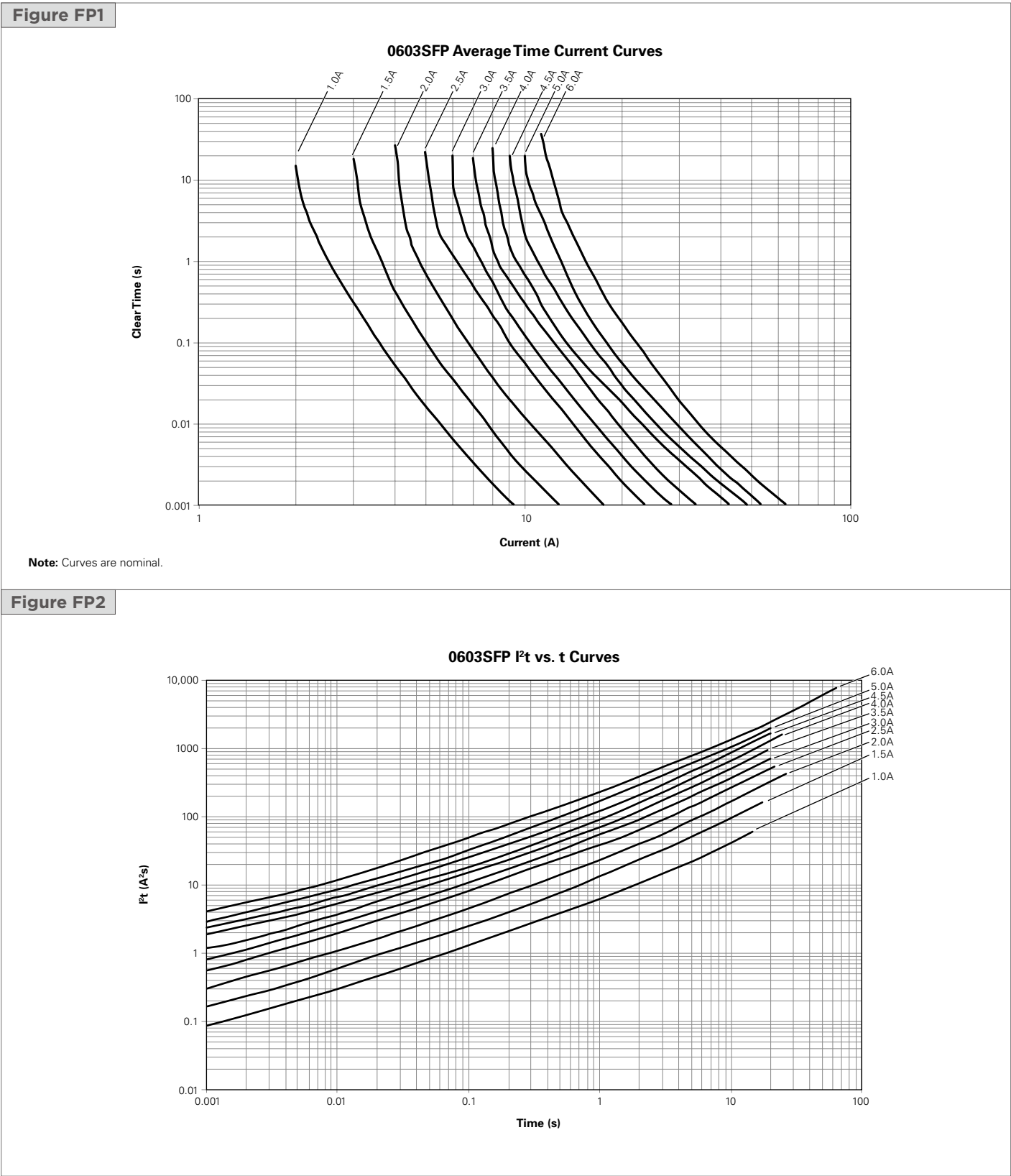
	A		B		C		D	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	3.00	3.40	0.77	1.17	0.26	0.76	1.40	1.80
in	(0.118)	(0.134)	(0.030)	(0.046)	(0.010)	(0.030)	(0.055)	(0.071)

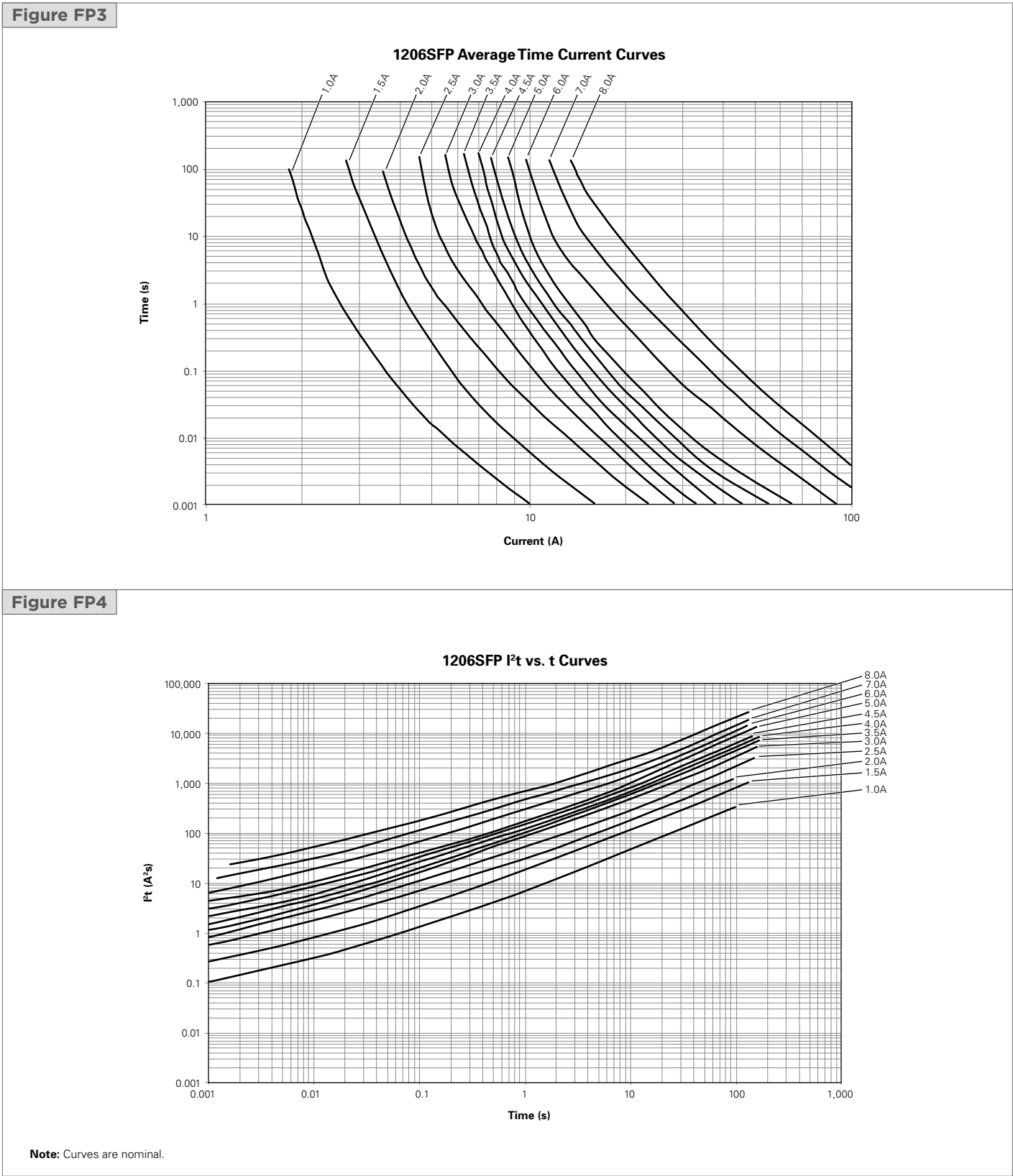
Part Number	Typical			Max	
	Electrical Characteristics			Interrupt Ratings	
	Rated Current (A)	Nominal Cold DCR (Ω)*	Nominal I ² t (A ² sec) [†]	Voltage (V _{DC})	Current (A)
1206SFP100F/63-2	1.0	0.340	0.11	63	50
1206SFP150F/63-2	1.5	0.150	0.33	63	50
1206SFP200F/63-2	2.0	0.090	0.80	63	50
1206SFP250F/32-2	2.5	0.070	1.19	32	50
1206SFP300F/32-2	3.0	0.035	1.35	32	50
1206SFP350F/32-2	3.5	0.029	1.84	32	50
1206SFP400F/32-2	4.0	0.023	2.74	32	50
1206SFP450F/32-2	4.5	0.021	3.20	32	50
1206SFP500F/32-2	5.0	0.017	5.50	32	50
1206SFP600F/24-2	6.0	0.013	12.50	24	80
1206SFP700F/24-2	7.0	0.010	30.00	24	80
1206SFP800F/24-2	8.0	0.009	60.00	24	80

* Measured at ≤10% of rated current and 25°C ambient temperature.

† Melting I²t at 0.001 sec clear time.

Figures FP1-FP4 — Family Performance Curves





➔ Please go to page 108 for more information about Pulse Tolerant Chip Fuses.

Surface Mount Fuses

Pulse Tolerant Chip Fuses

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SURFACE-MOUNT FUSES

High-Current-Rated Chip Fuses

The monolithic multilayer design of the Littelfuse high-current-rated chip fuses helps to provide some of the highest current ratings available in the 1206 size and enhances high-temperature performance in a wide range of circuit protection designs. The devices' small size, high reliability and strong arc suppression characteristics make them suitable for overcurrent protection of power supplies, servers, communications equipment, voltage regulator modules, and other high current, small size applications.



BENEFITS

- Glass ceramic monolithic structure provides stability in application cycling
- High-current rating in a small package allows more efficient use in system space
- Strong arc suppression in overcurrent conditions

FEATURES

- Lead-free materials and RoHS compliant
- Halogen free
(refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)
- Monolithic multilayer design
- High-temperature performance
- -55°C to +150°C operating temperature range

APPLICATIONS

- Communications equipment
- Voltage regulator modules
- Power supplies
- Servers

Surface Mount Fuses

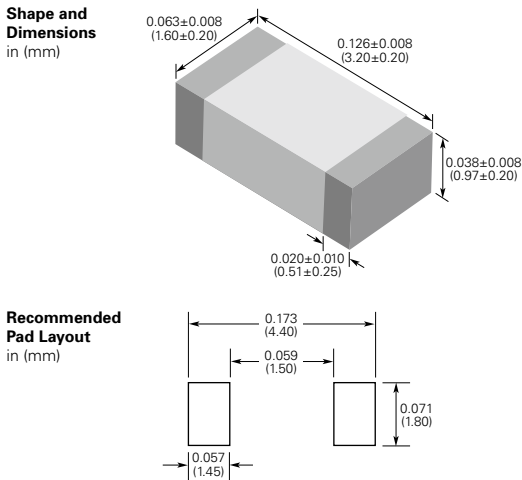
High-Current-Rated Chip Fuses

Table FH1 — ClearTime Characteristics

1206SFH Series	
% of Rated Current	Clear Time at 25°C
100%	4 hrs (min)
250% (10-20A)	5 s (max)
350% (25-30A)	5 s (max)

Table FH2 — Typical Electrical Characteristics, Dimensions and Recommended Pad Layout

1206 (3216mm) High-Current-Rated Chip Fuses

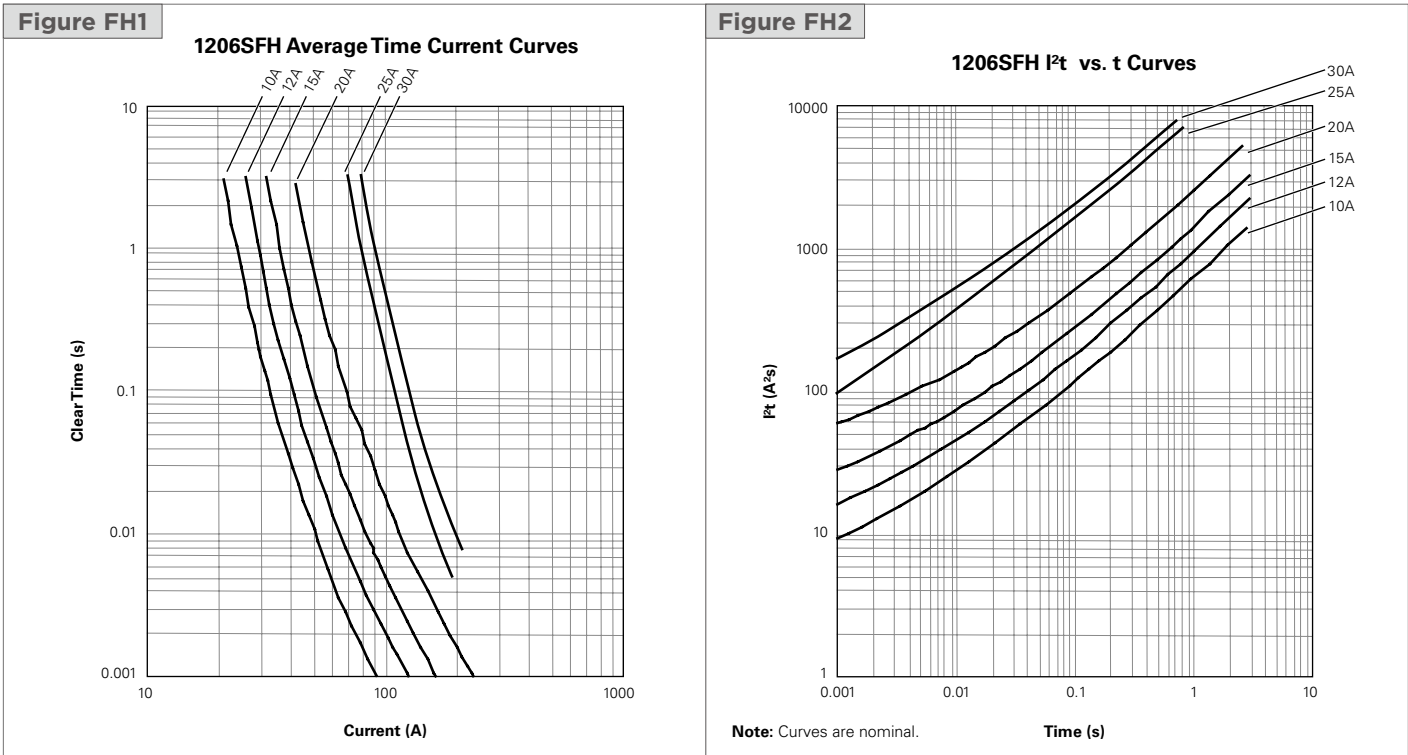


Part Number	Typical			Max	
	Electrical Characteristics			Interrupt Ratings	
	Rated Current (A)	Nominal Cold DCR (Ω)*	Nominal I²t (A²sec)†	Voltage (V _{DC})	Current (A)
1206SFH100F/24	10	0.010	9	24	100
1206SFH120F/24	12	0.008	14	24	100
1206SFH150F/24	15	0.005	26	24	100
1206SFH200F/24	20	0.003	56	24	100
1206SFH250F/24	25	0.0016	187	24	250
1206SFH300F/24	30	0.0012	270	24	300

* Measured at ≤10% of rated current and 25°C ambient temperature.

† Melting I²t at 0.001 sec clear time.

Figures FH1-FH2 — Family Performance Curves



➔ Please go to page 108 for more information about High-Current-Rated Chip Fuses.

Surface Mount Fuses

High-Current-Rated Chip Fuses

Notice:

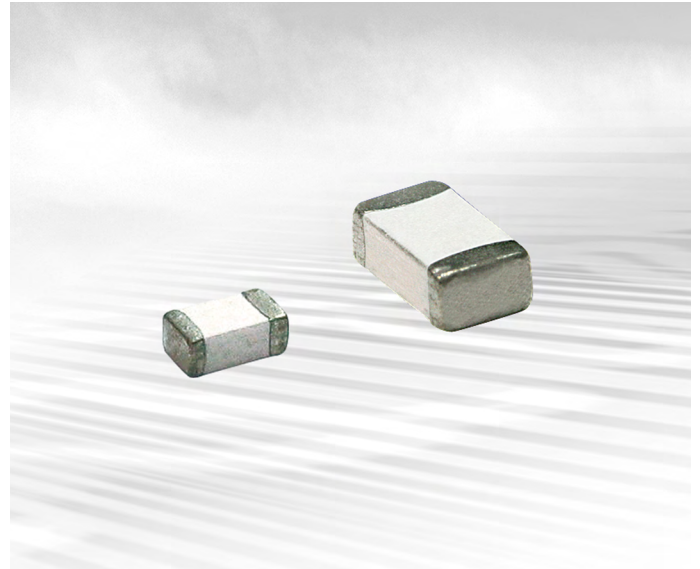
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SURFACE-MOUNT FUSES

Slow-Blow Chip Fuses

Available in industry standard 1206 and 0603 chip sizes, Littelfuse slow-blow chip fuses help provide overcurrent protection on systems that experience large and frequent current surges as part of their normal operation.

The slow-blow chip fuse's monolithic, multilayer design helps provide some of the highest current ratings available in the 1206 and 0603 footprints and enhances high-temperature performance in a wide range of circuit protection designs. The devices' small size, high reliability and strong arc suppression characteristics make them suitable for overcurrent protection of power supplies, capacitor filter banks, Liquid Crystal Display (LCD) backlight inverters, electric motors and portable electronics.



BENEFITS

- Time-delayed design prevents nuisance openings in pulsed and high inrush current applications
- Small size with high-current ratings
- Strong arc suppression characteristics

FEATURES

- Lead-free materials and RoHS compliant
- Halogen free
(refers to: Br≥900ppm, Cl≥900ppm, Br+Cl≥1500ppm)
- Monolithic multilayer design
- High-temperature performance
- -55°C to +125°C operating temperature range

APPLICATIONS

- Small motors systems
- Portable electronics
- Input power ports
- Power over Ethernet (PoE)
- Test equipment
- POL converter protection
- Computer drives
- Displays
- Printers

Surface Mount Fuses

Slow-Blow Chip Fuses

Table FS1 — Clear Time Characteristics

0603SFS Series

% of Rated Current	Clear Time at 25°C	
100%	4 hrs (min)	—
200%	1 s (min)	120 s (max)
300%	0.1 s (min)	3 s (max)
800% (1.0A-1.5A)	0.0005 s (min)	0.05 s (max)
800% (2.0A-5.0A)	0.001 s (min)	0.05 s (max)

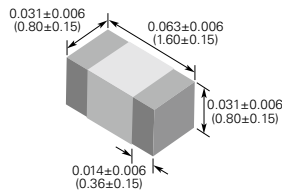
1206SFS Series

% of Rated Current	Clear Time at 25°C	
100%	4 hrs (min)	—
200%	1 s (min)	120 s (max)
300%	0.1 s (min)	3 s (max)
800% (1.0A-1.5A)	0.0016 s (min)	0.05 s (max)
800% (2.0A-8.0A)	0.002 s (min)	0.05 s (max)

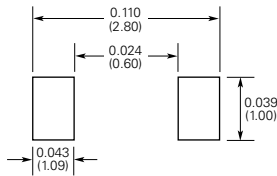
Table FS2 — Typical Electrical Characteristics, Dimensions and Recommended Pad Layout

0603 (1608 mm) Slow-Blow Chip Fuses

Shape and Dimensions in (mm)

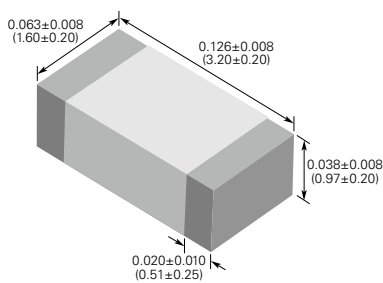


Recommended Pad Layout in (mm)

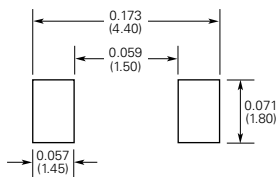


1206 (3216 mm) Slow-Blow Chip Fuses

Shape and Dimensions in (mm)



Recommended Pad Layout in (mm)



Part Number	Typical			Max	
	Electrical Characteristics			Interrupt Ratings	
	Rated Current (A)	Nominal Cold DCR (Ω)*	Nominal I ² t (A ² sec) [†]	Voltage (V _{DC})	Current (A)
0603SFS100F/32	1.0	0.200	0.093	32	50
0603SFS150F/32	1.5	0.100	0.18	32	50
0603SFS200F/32	2.0	0.052	0.32	32	50
0603SFS250F/32	2.5	0.041	0.63	32	50
0603SFS300F/32	3.0	0.031	0.87	32	50
0603SFS350F/32	3.5	0.021	1.20	32	50
0603SFS400F/32	4.0	0.017	2.30	32	50
0603SFS450F/32	4.5	0.015	2.70	32	50
0603SFS500F/32	5.0	0.013	3.20	32	50

Part Number	Typical			Max	
	Electrical Characteristics			Interrupt Ratings	
	Rated Current (A)	Nominal Cold DCR (Ω)*	Nominal I ² t (A ² sec) [†]	Voltage (V _{DC})	Current (A)
1206SFS100F/63	1.0	0.360	0.11	63	50
1206SFS125F/63	1.25	0.200	0.22	63	50
1206SFS150F/63	1.5	0.150	0.23	63	50
1206SFS200F/63	2.0	0.088	0.63	63	50
1206SFS250F/32	2.5	0.065	0.90	32	50
1206SFS300F/32	3.0	0.034	1.20	32	50
1206SFS350F/32	3.5	0.028	1.60	32	50
1206SFS400F/32	4.0	0.024	2.20	32	50
1206SFS450F/32	4.5	0.020	3.60	32	50
1206SFS500F/32	5.0	0.016	5.30	32	50
1206SFS550F/24	5.5	0.014	6.40	24	50
1206SFS600F/24	6.0	0.011	8.50	24	60
1206SFS700F/24	7.0	0.010	10.00	24	60
1206SFS800F/24	8.0	0.009	16.90	24	60

* Measured at ≤10% of rated current and 25°C ambient temperature.

† Melting I²t at 0.001 sec clear time.

Figures FS1-FS4 — Family Performance Curves

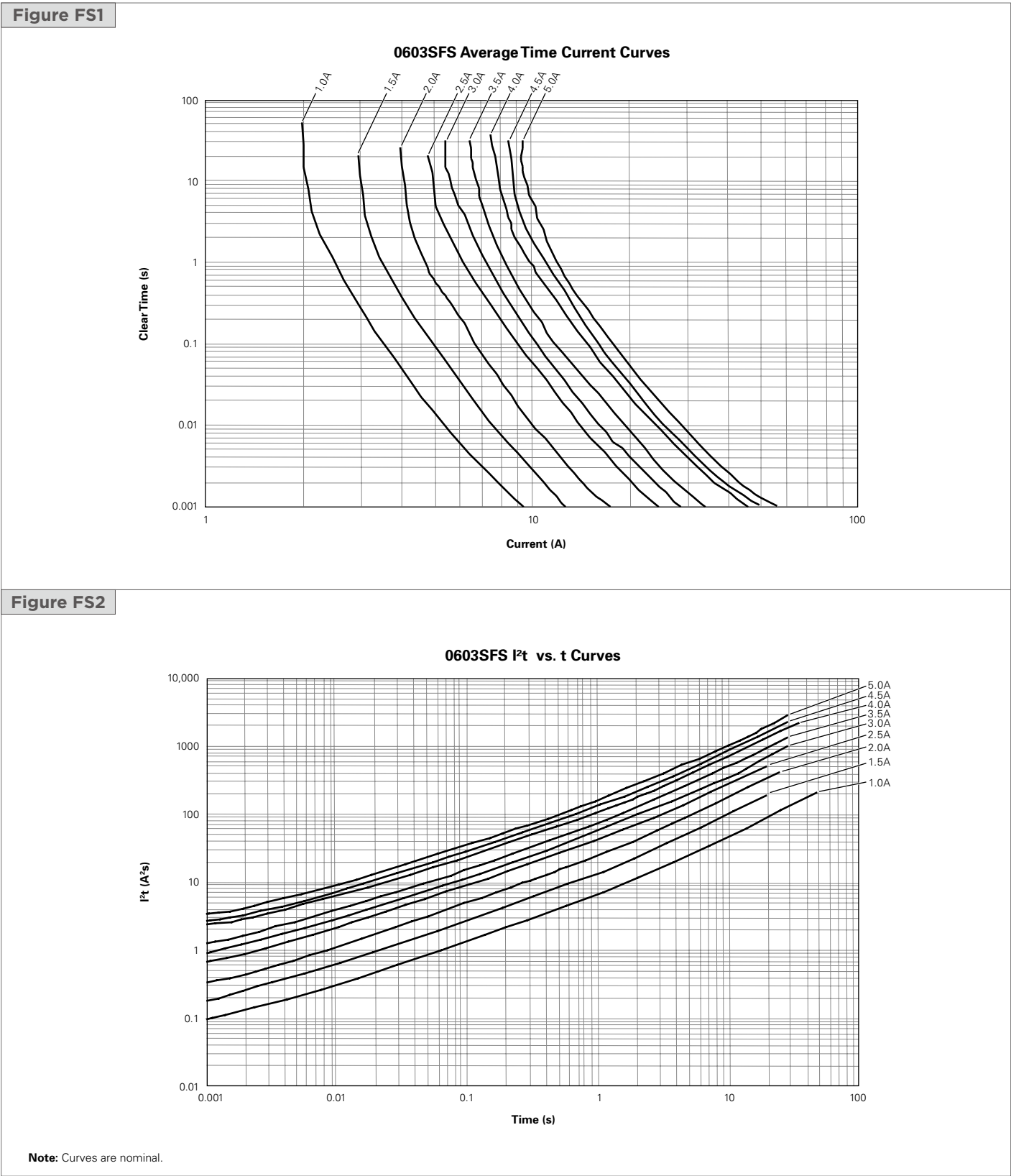


Figure FS3

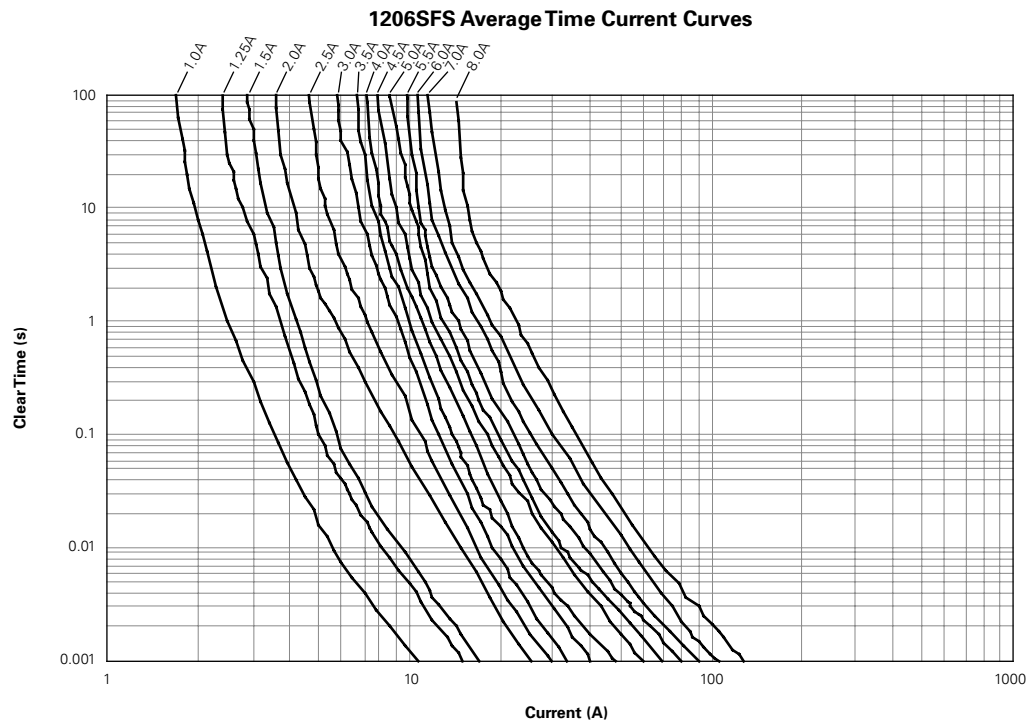
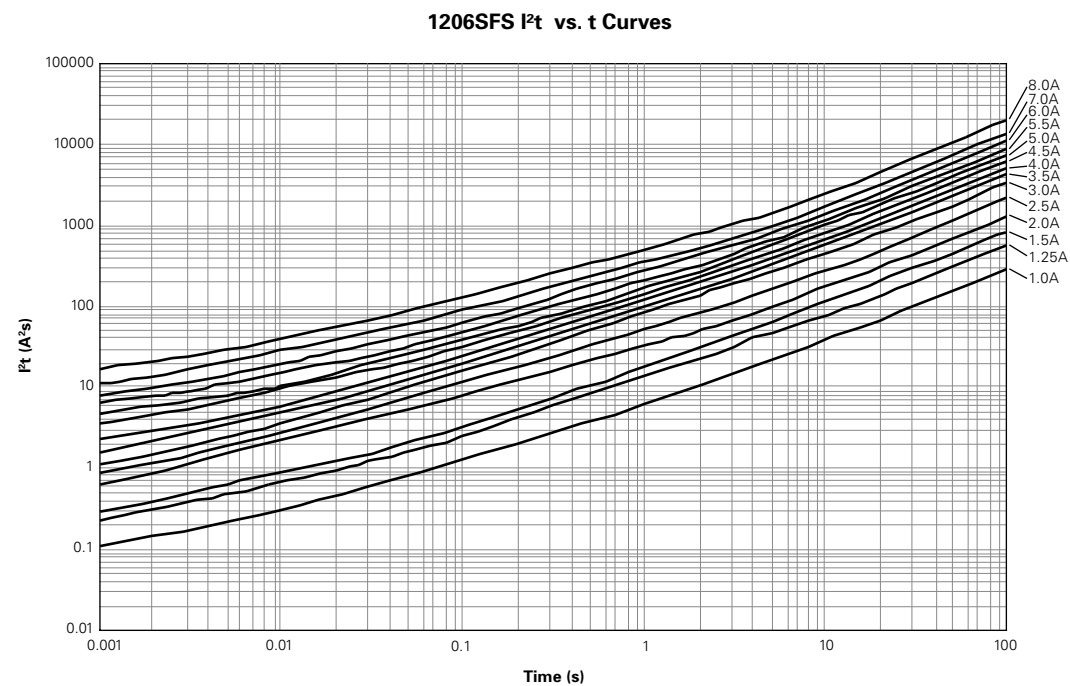


Figure FS4



Note: Curves are nominal.

➔ Please go to page 108 for more information about Slow-Blow Chip Fuses.

Surface Mount Fuses

Slow-Blow Chip Fuses

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SPECIFICATIONS, PACKAGING INFORMATION, AGENCY APPROVALS AND PART NUMBERING SYSTEMS FOR ALL FUSES

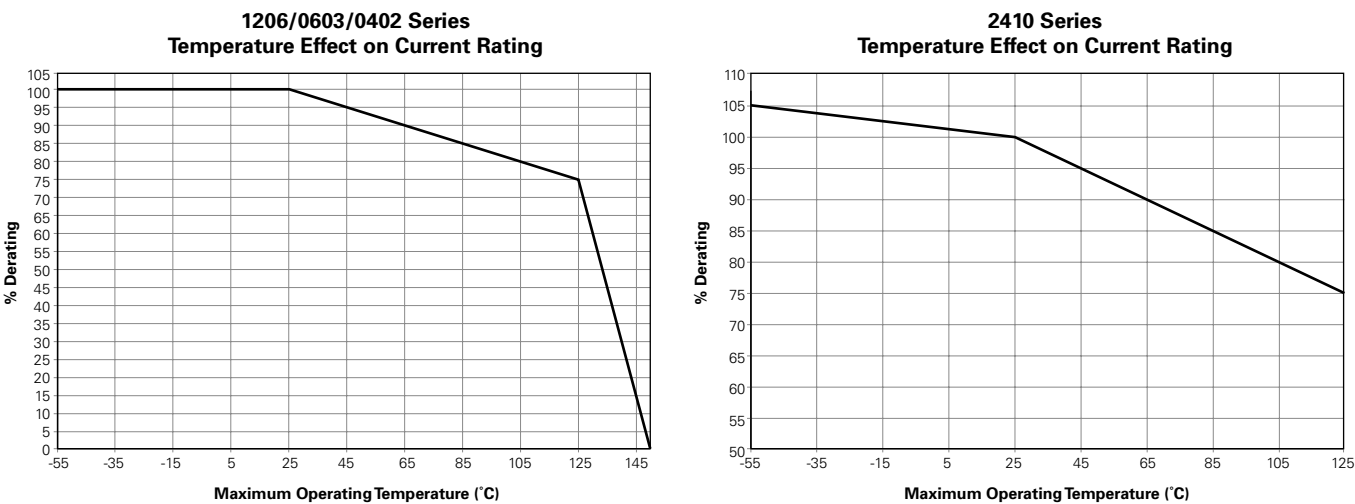
Table F1 — Environmental Specifications for All Fuses

Operating Temperature	-55°C to +125°C (for the 0603TSFV series the Operating Temperature is -55°C to +90°C)
Mechanical Vibration	Withstands 5-3000 Hz at 30Gs when evaluated per Method 204 of MIL-STD-202
Mechanical Shock	Withstands 1500Gs, 0.5 millisecond half-sine pulses when evaluated per Method 213 of MIL-STD-202
Thermal Shock	Withstands 100 cycles from -65°C to +125°C when evaluated per Method 107 of MIL-STD-202
Resistance to Soldering Heat	Withstands 60 seconds at +260°C when evaluated per Method 210 of MIL-STD-202
Solderability	Meets 95% minimum coverage requirement when evaluated per Method 208 of MIL-STD-202
Moisture Resistance	Withstands 10 cycles when evaluated per Method 106 of MIL-STD-202
Salt Spray	Withstands 48-hour exposure when evaluated per Method 101 of MIL-STD-202
Storage Condition	#35°C/ 75% RH

Table F2 — Material Specifications for All Fuses

Construction Body Material	Ceramic (1206/0603/0402SFF, 1206/0603SFS, 1206/0603SFP, 1206SFH, 0603SFV)
	Fiberglass/Epoxy (2410SFV, 1206SFV, 0603TSFV)
Termination Material	Silver, Nickel, Tin (1206/0603/0402SFF, 1206/0603SFS, 1206/0603SFP, 1206SFH, 0603SFV)
	Copper, Nickel, Tin(2410SFV, 1206SFV, 0603TSFV)
Fuse Element	Silver (1206/0603/0402SFF, 1206/0603SFS, 1206/0603SFP, 1206SFH, 0603SFV)
	Copper/Copper Alloy (2410SFV, 1206SFV)
	Copper/Tin Alloy (0603TSFV)

Figure F1 — Thermal Derating Current for All Fuses



Figures F1 — Thermal Derating Current for All Fuses

(Cont'd)

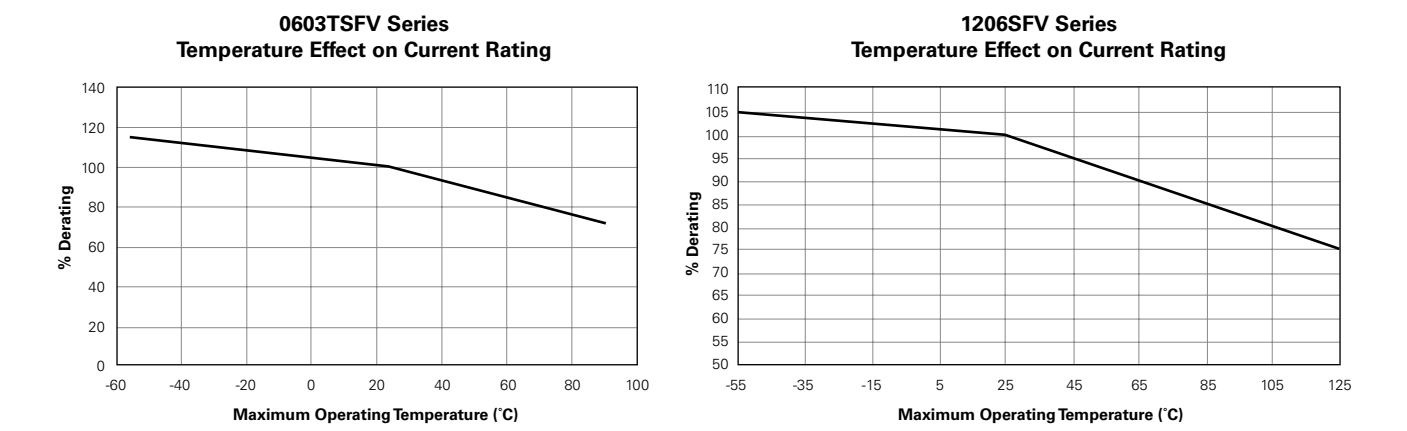


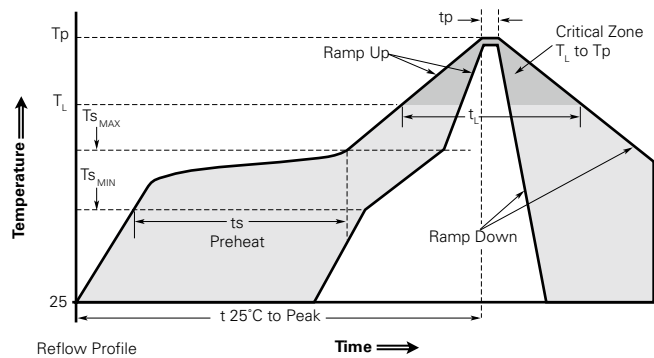
Table F3 — Electrical Specifications for All Fuses

Insulation Resistance after Opening	20,000Ω minimum @ rated voltage. Fuse clearing under low-voltage conditions may result in lower post-clearing insulation values. Under normal fault conditions Littelfuse fuses help provide sufficient insulation resistance for circuit protection. Notes: for 1206SFV series, the minimum DCR is 10,000Ω; for 0603TSFV, the minimum DCR is 100Ω.
Current Carrying Capacity	Withstands 100% rated current at +25°C ambient for 4 hours when evaluated per MIL-PRF-23419.

Table F4 — Packaging Information for All Fuses

Size	Reel Quantity (pcs)	Reel Diameter	Reel Width	Carrier Tape Size	Tape Type	Reels per Outside Shipment Box	Outside Shipment Boxes per Overpack
0402 (1005)	10,000	178mm white plastic	9.0 ± 0.5mm	8.00 ± 0.10mm	Paper	5	1 to 10
0603 (1608)	4,000	178mm white plastic	9.0 ± 0.5mm	8.00 ± 0.10mm	Paper	5	1 to 10
0603SFV (1608)	6,000	178mm white plastic	9.0 ± 0.5mm	8.00 ± 0.10mm	Paper	5	1 to 10
0603TSFV (1608)	8,000	178mm white plastic	9.0 ± 0.5mm	8.00 ± 0.10mm	Paper	5	1 to 10
1206 (3216)	3,000	178mm white plastic	9.0 ± 0.5mm	8.00 ± 0.10mm	Plastic	5	1 to 10
1206SFV (3216)	3,500	178mm white plastic	9.0 ± 0.5mm	8.00 ± 0.10mm	Plastic	5	1 to 10
2410SFV (6125)	2,000	178mm white plastic	13.4 ± 0.5mm	12.00 ± 0.10mm	Plastic	4	1 to 10

Figure F2 — Recommended Soldering Temperature Profile for All Fuses

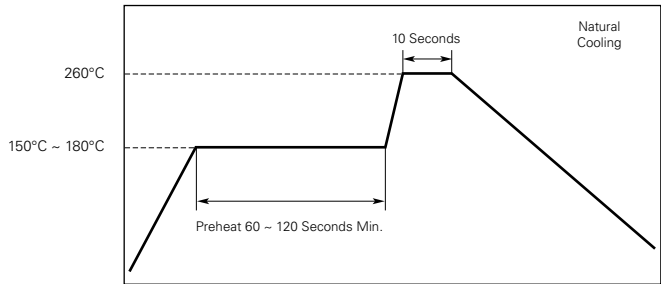


Classification Reflow Profile

Profile Feature	1206/0603/0402	2410
Average Ramp Up Rate (Ts_MAX to Tp)	3°C/second max	3°C/second max
Preheat		
• Temperature min (Ts_MIN)	150°C	150°C
• Temperature max (Ts_MAX)	200°C	200°C
• Time (ts_MIN to ts_MAX)	60-180 seconds	40-100 seconds
Time Maintained Above:		
• Temperature (T_L)	217°C	200°C
• Time (t_L)	60-150 seconds	30-90 seconds
Peak/Classification Temperature (Tp)	260°C max	250°C max
Time Within 5°C of Actual Peak Temperature		
Time (tp)	20-40 seconds	30-40 seconds
From 25°C to Preheating (150°C)	8 minutes max	40-100 seconds
Ramp Down Rate	4°C/seconds max	Natural Cooling

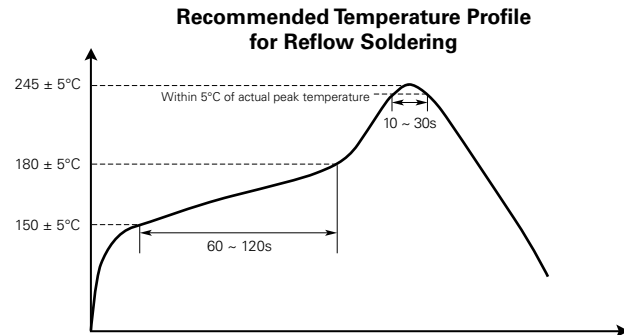
Classification Reflow Profile

Profile Feature	0603TSFV
Average Ramp Up Rate	3°C/second max
Preheat	
• Temperature min	150°C
• Temperature max	180°C
• Time	60 -120 seconds
Peak/Classification temperature (Tp)	260°C Max
Time of actual peak temperature	
Time	10 seconds
Ramp down rate	Natural Cooling



Classification Reflow Profile

Profile Feature	1206SFV
Average Ramp Up Rate	3°C/second max
Preheat	
• Temperature min	150°C
• Temperature max	180°C
• Time	60-120 seconds
Peak/Classification temperature (Tp)	245°C Max
Time within 5°C of actual peak temperature	
Time	10-30 seconds
Ramp down rate	Natural Cooling



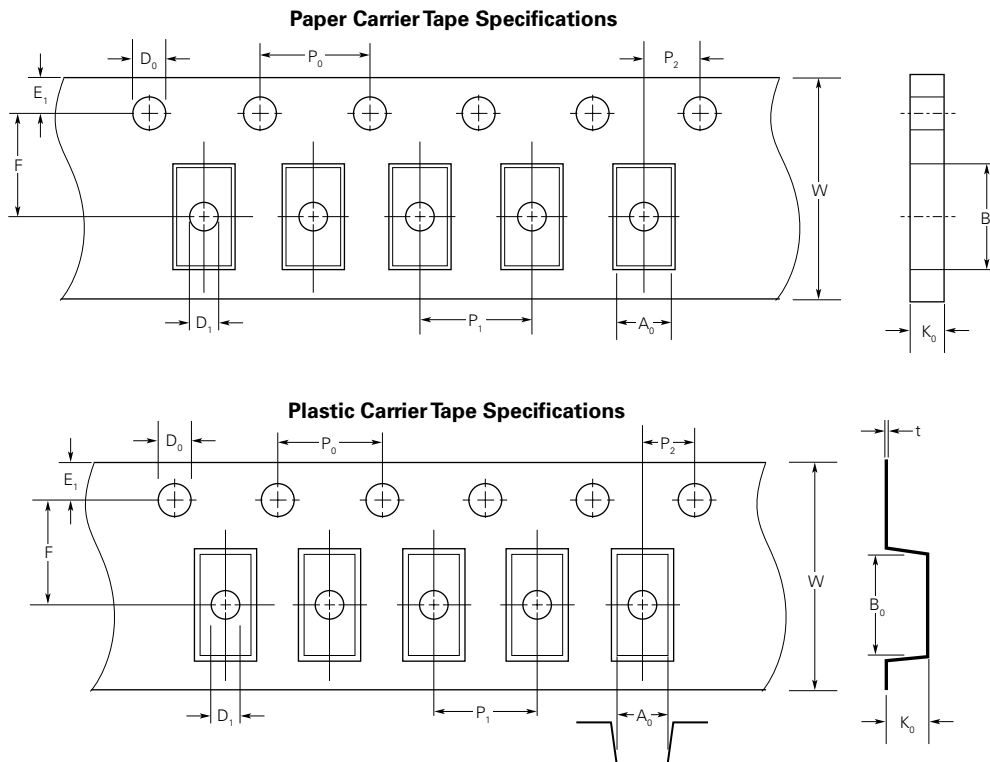
Recommended Conditions for Hand Soldering:

- Using a hot air rework station that can reflow the solder on both terminations at the same time is strongly recommended; do not directly contact the chip termination with the tip of soldering iron.
- Preheating: 150°C, 60s (min)
Appropriate temperature (max) of soldering iron tip/soldering time (max): 280°C /10s or 350°C /3s.

Table F4 — Packaging Information for All Fuses

Mark	Dimension in in (mm)					
	0402 (1005)	0603 (1608)	1206 (3216)	0603SFV(1608)	2410SFV(6125)	1206SFV (3216)
E ₁	0.069 ± 0.004 (1.75 ± 0.10)	0.069 ± 0.004 (1.75 ± 0.10)	0.069 ± 0.004 (1.75 ± 0.10)	0.069 ± 0.004 (1.75 ± 0.10)	0.069 ± 0.004 (1.75 ± 0.10)	0.069±0.004 (1.75 ± 0.10)
F	0.138 ± 0.002 (3.50 ± 0.05)	0.138 ± 0.002 (3.50 ± 0.05)	0.138 ± 0.002 (3.50 ± 0.05)	0.138 ± 0.002 (3.50 ± 0.05)	0.217 ± 0.004 (5.50 ± 0.10)	0.138 ± 0.002 (3.50 ± 0.05)
W	0.315 ± 0.004 (8.00 ± 0.10)	0.315 ± 0.004 (8.00 ± 0.10)	0.315 ± 0.004 (8.00 ± 0.10)	0.315 ± 0.004 (8.00 ± 0.10)	0.472 ± 0.004 (12.00 ± 0.10)	0.315 ± 0.004 (8.00 ± 0.10)
P ₁	0.079 ± 0.004 (2.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)
P ₀	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)
P ₂	0.079 ± 0.002 (2.00 ± 0.05)	0.079 ± 0.002 (2.00 ± 0.05)	0.079 ± 0.002 (2.00 ± 0.05)	0.079 ± 0.002 (2.00 ± 0.05)	0.079 ± 0.004 (2.00 ± 0.10)	0.079 ± 0.002 (2.00 ± 0.05)
D ₀	0.059 ± 0.004 (1.50+0.10/-0.00)	0.059 ± 0.004 (1.50+0.10/-0.00)	0.059 ± 0.004 (1.50+0.10/-0.00)	0.059 ± 0.004 (1.50+0.10/-0.00)	0.059 ± 0.004 (1.50+0.10/-0.00)	0.059+0.004/-0.00 1.50+0.10/-0.00
D ₁	—	—	0.039 max (1.00 max)	—	0.61 ± 0.004 (1.55 ± 0.10)	0.039 ± 0.002 1.00 ± 0.05
t	—	—	0.009 ± 0.001 (0.23 ± 0.02)	—	0.010 ± 0.002 (0.25 ± 0.05)	0.009 ± 0.002 0.22±0.05
A ₀	0.026 ± 0.004 (0.67 ± 0.10)	0.039 ± 0.004 (0.98 ± 0.10)	0.071 ± 0.004 (1.80 ± 0.10)	0.039 ± 0.004 (0.98 ± 0.10)	0.112 ± 0.004 (2.85 ± 0.10)	0.081±0.004 (2.05 ± 0.10)
B ₀	0.046 ± 0.004 (1.17 ± 0.10)	0.071 ± 0.004 (1.80 ± 0.10)	0.138 ± 0.004 (3.50 ± 0.10)	0.071 ± 0.004 (1.80 ± 0.10)	0.252 ± 0.004 (6.40 ± 0.10)	0.138 ± 0.004 (3.50 ± 0.10)
K ₀	0.025 ± 0.004 (0.63 ± 0.10)	0.037 ± 0.003 (0.95 ± 0.08)	0.050 ± 0.004 (1.27 ± 0.10)	0.024 ± 0.003 (0.60 ± 0.08)	0.093 ± 0.004 (2.35 ± 0.10)	0.051 ± 0.004 (1.30 ± 0.10)

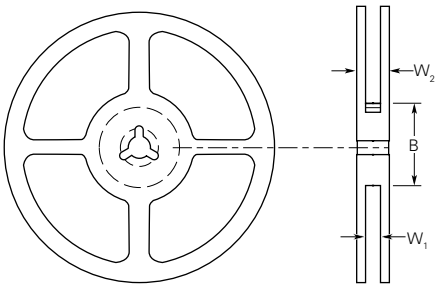
Figure F3 — ComponentTape Dimensions for All Fuses



Specifications, Packaging Information

Figure F4 — Reel Dimensions for All Fuses

Dimension Description	Mark	Dimension (mm)	
		1206/0603/0402	2410
Hub Outer Diameter	B	60	60.2
Reel Inside Width	W ₁	9	13.4
Reel Outside Width	W ₂	11.4	16
Tape Width		8	



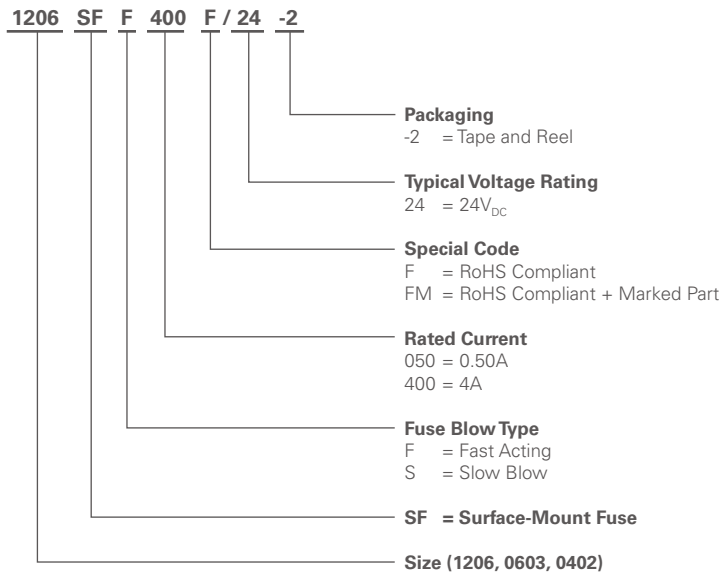
Agency Approvals for All Fuses

UL: All fuses

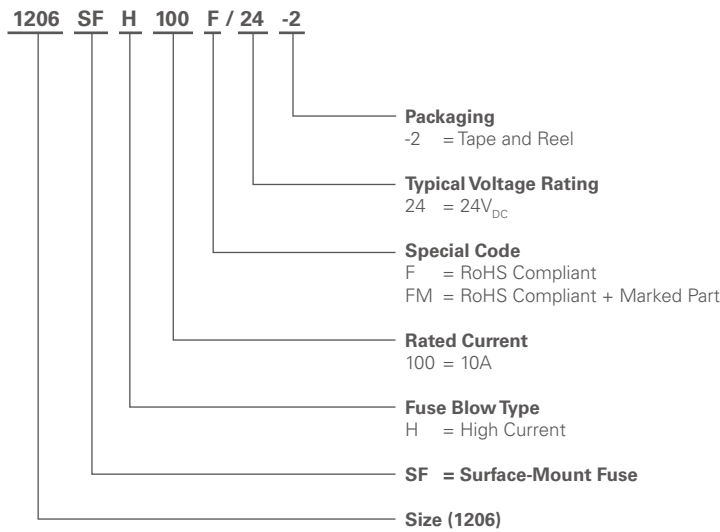
CQC: File # 12012078873 (for 2410SFV 0.5A, 1A, 2A)

TUV: File # 50236400 (for 2410SFV 0.5A, 0.63A, 1A, 1.25A, 2A)

Part Numbering System for Fast-Acting, Slow-Blow And 0603 Very Fast-Acting Chip Fuses

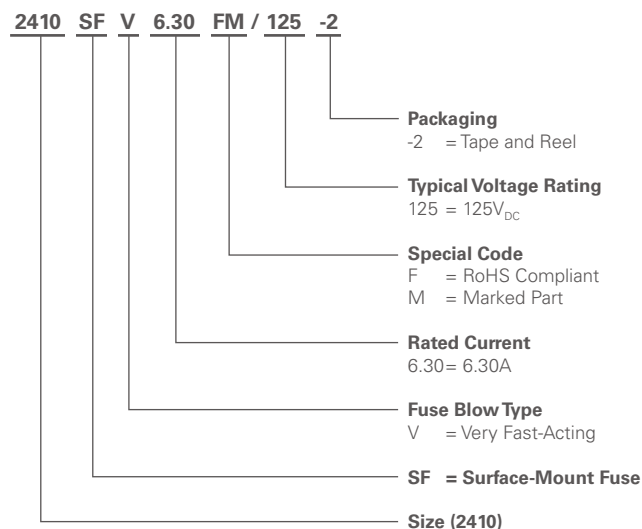


Part Numbering System for High-Current-Rated Chip Fuses

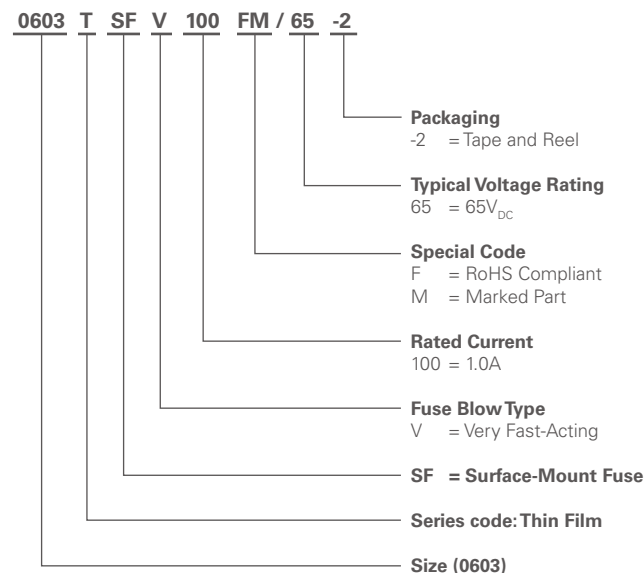


Specifications, Packaging Information

Part Numbering System for 1206/2410 Very Fast-Acting Fuses



Part Numbering System for 0603 Thin Film Very Fast-Acting Chip Fuses



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POLYSWITCH RESETTABLE DEVICES

Fundamentals

Overview

PolySwitch polymeric positive temperature coefficient (PPTC) devices help protect against damage caused by harmful overcurrent surges and overtemperature faults. Like traditional fuses, these devices limit the flow of dangerously high current during fault conditions. The PolySwitch device, however, resets after the fault is cleared and power to the circuit is removed, thereby helping to reduce warranty, service and repair costs.

PolySwitch circuit protection devices are made from a composite of semi-crystalline polymer and conductive particles. At normal temperature, the conductive particles form low-resistance networks in the polymer (Figure 1.a). However, if the temperature rises, either from high current through the part or from an increase in the ambient temperature, the crystallites in the polymer melt and become amorphous. The increase in volume during melting of the crystalline phase separates the conductive particles, resulting in a large non-linear increase in the resistance of the device.

Overcurrent Protection Using a PPTC Device

The PPTC device is a series element in a circuit. The PPTC device helps protect the circuit by going from a low-resistance to a high-resistance state in response to an overcurrent condition, as shown in Figure 2. This is referred to as “tripping” the device.

In normal operation the device has a resistance that is much lower than that of the circuit. In response to an overcurrent condition, the device increases in resistance (trips), reducing the current in the circuit to a value that can be safely carried by any of the circuit elements. This change is the result of a rapid increase in the temperature of the device caused by I^2R heating.

Principles of Operation

PolySwitch PPTC device's operation is based on an overall energy balance, as shown in Figure 3. Under normal operating conditions, the heat generated by the device and the heat lost by the device to the environment are in balance at a relatively low temperature, as shown between Points 1 and 2.

If the current through the device is increased while the ambient temperature is kept constant, the temperature of the device increases. Further increases in either current, ambient temperature, or both, will cause the device to reach a temperature where the resistance rapidly increases, as shown in Point 3.

Any further increase in current or ambient temperature will cause the device to generate heat at a rate greater than the rate at which heat can be dissipated, thus causing the device to heat up rapidly. At this stage, a very large increase in resistance occurs for a very small change in temperature, between Points 3 and 4. This is the normal operating region for a device in the tripped state. This large change in resistance causes a corresponding decrease in the current flowing to the circuit. This relation holds until the device resistance reaches the upper knee of the curve (Point 4). As long as the applied voltage remains at this level, the device will remain in the tripped state (that is, the device will remain latched in its protective state). Once the voltage decreases, the power is removed and the device cools, the device will reset.

Figure 1

How a PolySwitch Device Works

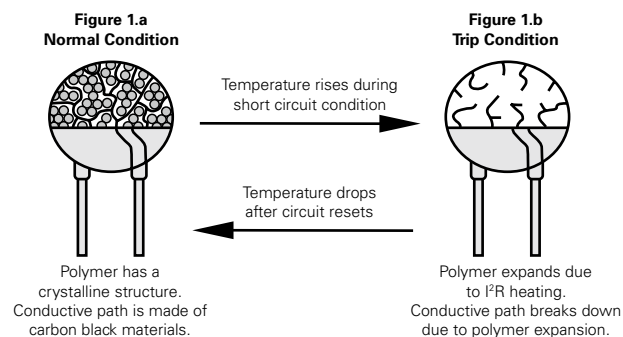


Figure 2

Typical PPTC Application

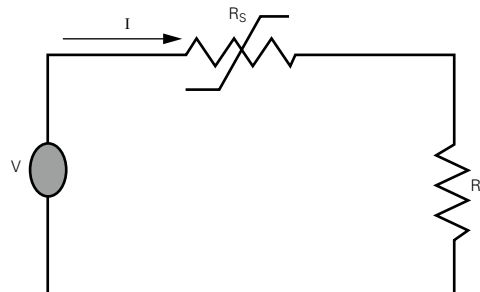
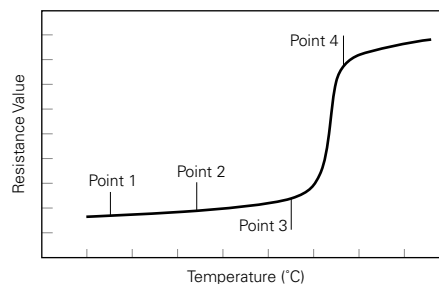


Figure 3

Example of Operating Curve for PPTC Device

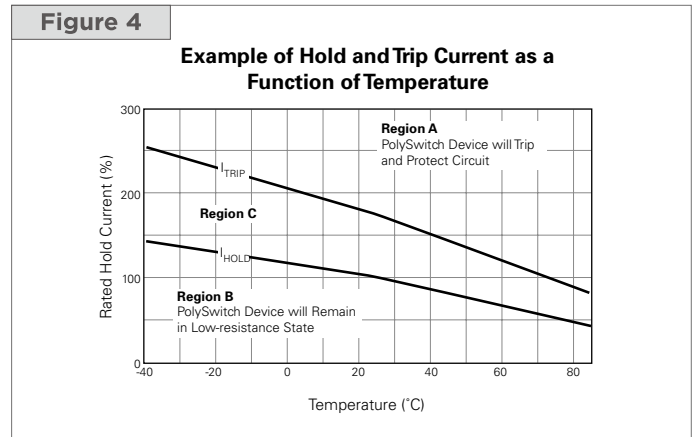


Polyswitch Resettable Devices

Fundamentals

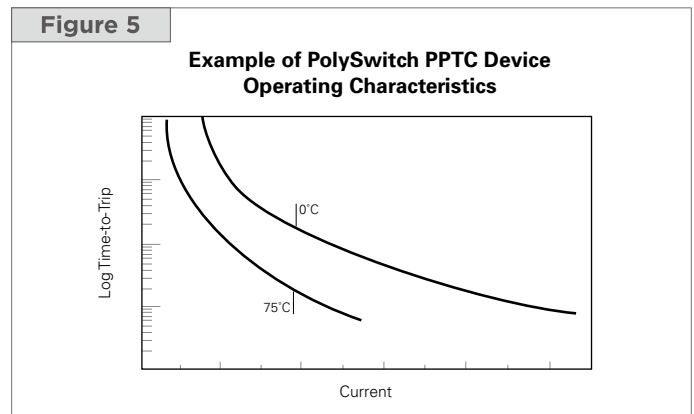
Example of Hold and Trip Current as a Function of Temperature

Figure 4 illustrates the hold- and trip-current behavior of a PolySwitch PPTC device as a function of temperature. One such curve can be defined for each available device. Region A describes the combinations of current and temperature at which the PolySwitch device will trip (go into the high-resistance state) and protect the circuit. Region B describes the combinations of current and temperature at which the PolySwitch device will allow for normal operation of the circuit. In Region C, it is possible for the device to either trip or remain in the low-resistance state (depending on individual device resistance).



Operating Characteristics of a PolySwitch PPTC Device

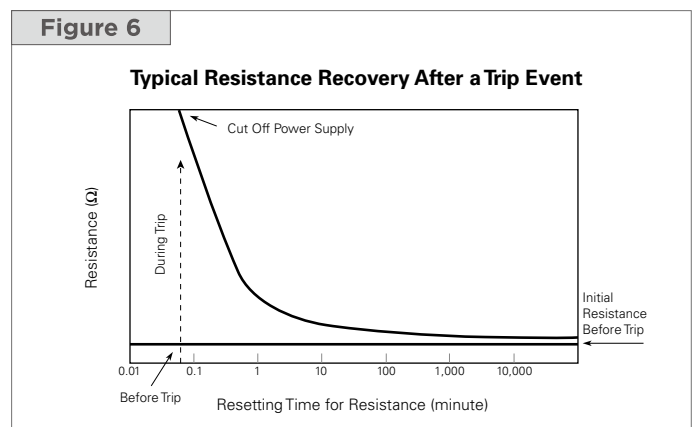
Figure 5 shows a typical pair of operating curves for a PolySwitch device in still air at 0°C and 75°C. The curves are different because the heat required to trip the device comes both from electrical I^2R heating and from the device environment. At 75°C the heat input from the environment is substantially greater than it is at 0°C, so the additional I^2R needed to trip the device is correspondingly less. This results in a lower trip current at a given trip time (or a faster trip at given trip current).



Typical Resistance Recovery After a Trip Event

Figure 6 shows typical behavior of a PolySwitch device that is tripped and then allowed to cool. This figure illustrates how, even after a number of hours, the device resistance is still greater than the initial resistance. Over an extended period of time, device resistance will continue to fall and will eventually approach initial resistance.

However, since this time can be measured in days, months, or years, it is not practical to expect that the device resistance will reach the original value for operational purposes. Therefore, when PolySwitch devices are chosen, R_{IMAX} should be taken into consideration when determining hold current. R_{IMAX} is the resistance of the device one hour after the thermal event.



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POLYSWITCH RESETTABLE DEVICES

Product Selection Guide

Table 1 — PolySwitch Device Characteristics

PolySwitch Device Family	V _{MAX} Operating (V _{DC})	V _{MAX} Interrupt (V _{RMS})	I _H	Temp. Range	Form Factor	Agency Spec.	Application
LVR	120V/240V	135V/265V	0.05 to 2A	-20 to 85°C	Radial-leaded	UL, CSA, TÜV	Line Voltage
LVB	240V	265V	1.25A	-40 to 85°C	Radial-leaded	UL	Line Voltage
RGEF	16V	—	2.5 to 14.0A	-40 to 85°C	Radial-leaded	UL, CSA, TÜV	General Electronics
RHEF	16 to 30V	—	0.5 to 15A	-40 to 125°C	Radial-leaded	UL, CSA, TÜV	General Electronics
RUEF	30V	—	0.9 to 9.0A	-40 to 85°C	Radial-leaded	UL, CSA, TÜV, CQC	General Electronics
RKEF	60V	—	0.50 to 5A	-40 to 85°C	Radial-leaded	UL, CSA, TÜV	General Electronics
RXEF	60 to 72V	—	0.05 to 3.75A	-40 to 85°C	Radial-leaded	UL, CSA, TÜV, CQC	General Electronics
RUSBF	6 to 16V	—	0.75 to 2.5A	-40 to 85°C	Radial-leaded	UL, CSA, TÜV	Computer/General Electronics
femtoSMDC	6 to 15V	—	0.05 to 0.35A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
High Temperature SMD	6 to 30V	—	0.10 to 0.75A	-40 to 125°C	Surface-mount	—	Computer/General Electronics
microSMD	6 to 30V	—	0.05 to 2.0A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
midSMD	6 to 60V	—	0.3 to 2.0A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
miniSMDC	6 to 60V	—	0.10 to 3A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
nanoSMDC	6 to 60V	—	0.10 to 2.0A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
picoSMDC	6 to 15V	—	0.10 to 1.1A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
SMD	6 to 60V	—	0.3 to 3.0A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
SMD2	15 to 33V	—	1.5 to 2.5A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
SMDC	18 to 33V	—	1.25 to 3.1A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Computer/General Electronics
BD	16V	—	8 to 21A	-40 to 125°C	Plug-in	—	Automotive
AGRF	16V	—	4.0 to 14.0A	-40 to 85°C	Radial-leaded	—	Automotive
AHRF	16 to 30V	—	0.50 to 15A	-40 to 125°C	Radial-leaded	—	Automotive
AHS	16V	—	0.80 to 3.0A	-40 to 125°C	Surface-mount	—	Automotive
ASMD	16 to 60V	—	0.23 to 1.97A	-40 to 85°C	Surface-mount	—	Automotive
AHEF	32V	—	0.50 to 10A	-40 to 125°C	Radial-leaded	—	Automotive
nanoASMD	16 to 48V	—	0.12 to 0.35A	-40 to 85°C	Surface-mount	—	Automotive
microASMD	30V	—	0.05 to 0.1A	-40 to 85°C	Surface-mount	—	Automotive
miniASMD	16 to 60V	—	0.1 to 2.6A	-40 to 85°C	Surface-mount	—	Automotive
TCF	60V	250V	0.09 to 0.18A	-40 to 85°C	Chip	—	Telecom & Networking
TRF250	60 to 100V	250V	0.055 to 0.184A	-40 to 85°C	Radial-leaded	UL, CSA, TÜV	Telecom & Networking
TRF600	60 to 250V	600V	0.15 to 0.40A	-40 to 85°C	Radial-leaded	UL, CSA, TÜV	Telecom & Networking
TS250/TSV250	60V	250V	0.13 to 0.184A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Telecom & Networking
TSL250	80V	250V	0.08A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Telecom & Networking
TS600/TSM600	60 to 250V	600V	0.17 to 0.40A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Telecom & Networking
MXP	6V	—	1.9 to 3.7A	-40 to 85°C	Axial-leaded	UL, CSA, TÜV	Battery
MGP	6V	—	4.5 to 5.0A	-40 to 85°C	Axial-leaded	UL, TÜV	Battery
LR4	15 to 20V	—	1.9 to 13.0A	-40 to 85°C	Axial-leaded	UL, CSA, TÜV	Battery
SRP	15 to 30V	—	1.2 to 4.2A	-40 to 85°C	Axial-leaded	UL, CSA, TÜV	Battery
VLP	16V	—	1.2 to 2.7A	-40 to 85°C	Axial-leaded	UL, CSA, TÜV	Battery
VLR	12V	—	1.7 to 2.3A	-40 to 85°C	Axial-leaded	UL, CSA, TÜV	Battery
VTP	16V	—	1.1 to 2.1A	-40 to 85°C	Axial-leaded	UL, CSA, TÜV	Battery
low resistivity SMD	6V	—	1.75 to 5.0A	-40 to 85°C	Surface-mount	UL, CSA, TÜV	Battery

Polyswitch Resettable Devices

Product Selection Guide

Table 2 — Thermal Derating PPTC

PolySwitch Device Family	-40°C	-20°C	0°C	20°C	25°C	30°C	40°C	50°C	60°C	70°C	85°C	125°C
LVR005-055	—	1.48	1.24	1.00	0.99	0.93	0.82	0.72	0.60	0.51	0.35	—
LVR075-200	—	1.69	1.34	1.00	0.99	0.95	0.88	0.80	0.73	0.66	0.55	—
LVB	1.67	1.45	1.22	1.00	0.98	0.88	0.79	0.69	0.59	0.48	0.33	—
RGEF	1.47	1.33	1.20	1.04	1.00	0.95	0.87	0.80	0.71	0.63	0.47	—
RHEF	1.36	1.25	1.15	1.03	1.00	0.96	0.88	0.81	0.75	0.67	0.55	0.25
RUEF	1.48	1.32	1.16	1.00	0.96	0.92	0.84	0.76	0.68	0.60	0.48	—
RKEF	1.45	1.30	1.15	1.00	0.97	0.92	0.83	0.77	0.68	0.61	0.52	—
RXEF	1.56	1.37	1.19	1.00	0.95	0.91	0.82	0.72	0.63	0.54	0.40	—
RUSBF	1.41	1.27	1.14	1.00	0.97	0.93	0.87	0.80	0.73	0.66	0.56	—
femtoSMDC	1.59	1.39	1.18	1.05	1.00	0.86	0.78	0.66	0.61	0.47	0.41	—
High Temperature SMD	0.18	0.16	0.15	0.11	0.10	0.09	0.08	0.07	0.07	0.06	0.06	0.03
microSMD	1.45	1.30	1.15	1.00	0.96	0.93	0.85	0.78	0.70	0.63	0.51	—
midSMD	1.41	1.27	1.14	1.00	0.97	0.93	0.87	0.80	0.73	0.66	0.56	—
miniSMDC	1.45	1.30	1.15	1.00	0.96	0.93	0.85	0.78	0.70	0.63	0.51	—
nanoSMDC	1.56	1.39	1.15	1.04	1.00	0.96	0.87	0.79	0.70	0.61	0.49	—
picoSMDC	1.45	1.30	1.15	1.00	0.96	0.93	0.85	0.78	0.70	0.63	0.51	—
SMD	1.45	1.30	1.15	1.00	0.96	0.93	0.85	0.78	0.70	0.63	0.51	—
SMDC	2.02	1.78	1.55	1.31	1.25	1.08	0.96	0.84	0.72	0.60	0.54	—
BD	1.50	1.35	1.19	1.04	1.00	0.96	0.88	0.81	0.73	0.65	0.54	0.23
AGRF	1.47	1.33	1.20	1.04	1.00	0.95	0.87	0.80	0.71	0.63	0.47	—
AHRF	1.36	1.25	1.15	1.03	1.00	0.96	0.88	0.81	0.75	0.67	0.55	0.25
AHS	1.41	1.28	1.16	1.03	1.00	0.97	0.91	0.84	0.78	0.72	0.62	0.37
ASMD	1.59	1.41	1.23	1.05	1.00	0.95	0.86	0.77	0.68	0.59	0.45	—
AHEF	1.36	1.25	1.14	1.03	1.00	0.96	0.89	0.81	0.74	0.66	0.55	0.20
nanoASMD	1.56	1.39	1.15	1.04	1.00	0.96	0.87	0.79	0.70	0.61	0.49	—
microASMD	1.45	1.30	1.15	1.00	0.96	0.93	0.85	0.78	0.70	0.63	0.51	—
miniASMD	1.45	1.30	1.15	1.00	0.96	0.93	0.85	0.78	0.70	0.63	0.51	—
TCF	1.54	1.36	1.18	1.00	0.96	0.91	0.82	0.73	0.64	0.55	0.42	—
TRF	1.54	1.36	1.18	1.00	0.96	0.91	0.82	0.73	0.64	0.55	0.42	—
TS	1.54	1.36	1.18	1.00	0.96	0.91	0.82	0.73	0.64	0.55	0.42	—
MXP	1.99	1.68	1.37	1.07	1.00	0.91	0.76	0.61	0.45	0.30	0.07	—
MGP	1.90	1.65	1.35	1.08	1.00	0.93	0.80	0.65	0.50	0.35	0.13	—
LR4	1.41	1.27	1.14	1.00	0.97	0.93	0.87	0.80	0.73	0.66	0.56	—
SRP	1.47	1.31	1.16	1.00	0.96	0.92	0.85	0.77	0.69	0.61	0.50	—
VLP	1.88	1.67	1.43	1.05	1.00	0.95	0.76	0.62	0.48	0.33	0.04	—
VLR	2.05	1.70	1.41	1.08	1.00	0.92	0.74	0.59	0.41	0.18	—	—
VTP	1.88	1.67	1.43	1.05	1.00	0.95	0.76	0.62	0.48	0.33	0.04	—
low resistivity SMD	5.80	5.20	4.60	4.00	3.90	3.40	3.10	2.82	2.52	2.23	2.10	—

Polyswitch Resettable Devices

Product Selection Guide

PolySwitch Device Selection Guide

Step 1. Determine your circuit's parameters

You will need to determine the following parameters of your circuit:

- Maximum ambient operating temperature
- Normal operating current
- Maximum operating voltage
- Maximum interrupt current

Step 2. Select a PolySwitch device that will accommodate the circuit's maximum ambient temperature and normal operating current

Use the Thermal Derating [Hold Current (A) at Ambient Temperature (°C)] table on page 112 and choose the column with the temperature that most closely matches the circuit's maximum ambient temperature. Look down that column to find the value equal to or greater than the

circuit's normal operating current. Now look to the far left of that row to find the part number that will best accommodate that current.

Step 3. Compare the selected device's maximum electrical ratings with the circuit's maximum operating voltage and interrupt current

Use the Electrical Characteristics table on page 111 to verify that the part you selected in Step 2 will handle your circuit's maximum operating voltage and interrupt current. Find the device's maximum operating voltage (V_{MAX}) and maximum interrupt current (I_{MAX}). Ensure that V_{MAX} and I_{MAX} are greater than or equal to the circuit's maximum operating voltage and maximum fault current.

Step 4. Determine time-to-trip

Time-to-trip is the amount of time it takes for a device to switch to a high-resistance state once a fault current has been applied through the device. Identifying the PolySwitch device's time-to-trip is important in order to provide the desired protection capabilities. If the chosen device trips too fast, undesired or nuisance tripping may occur. If the device trips too slowly, the components being protected may be damaged

before the device can trip and limit the current.

Use the Typical Time-to-trip Curves at 20°C on page 110 Figure 5 to determine if the PolySwitch device's time-to-trip characteristics are acceptable at expected fault levels. If not, go back to Step 2 and choose an alternate device.

Step 5. Verify ambient operating temperature

Ensure that your application's minimum and maximum ambient temperatures are within the operating temperature of the PolySwitch device. Most PolySwitch devices have an operating temperature range from -40°C to 85°C with some exceptions to 125°C.

Step 6. Verify the PolySwitch device dimensions

Use the Dimensions table on pages 122-125 to compare the dimensions of the PolySwitch device you selected with the application's space considerations.

Polyswitch Resettable Devices

Product Selection Guide

Definitions of terms

I_H	the maximum steady state current at 20°C that can be passed through a PolySwitch device without causing the device to trip
I_T	the minimum current that will cause the PolySwitch device to trip at 20°C
V_{MAX}	the maximum voltage that can safely be dropped across a PolySwitch device in its tripped state also called: Maximum Device Voltage, Maximum Voltage, Vmax, Max Interrupt Voltage
I_{MAX}	the maximum fault current that can safely be used to trip a PolySwitch device
P_D	the power (in Watts) dissipated by a PolySwitch device in its tripped state
R_{MAX}	the maximum resistance prior to the trip of a PolySwitch device
R_{MIN}	the minimum resistance prior to the trip of a PolySwitch device
R_{1MAX}	the maximum resistance of a PolySwitch device at 20°C 1 hour after being tripped and reset or after reflow soldering
$R_{Tripped Typ}$	the typical resistance of a PolySwitch device 1 hour after the initial trip and reset

Notice:

Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, automotive, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

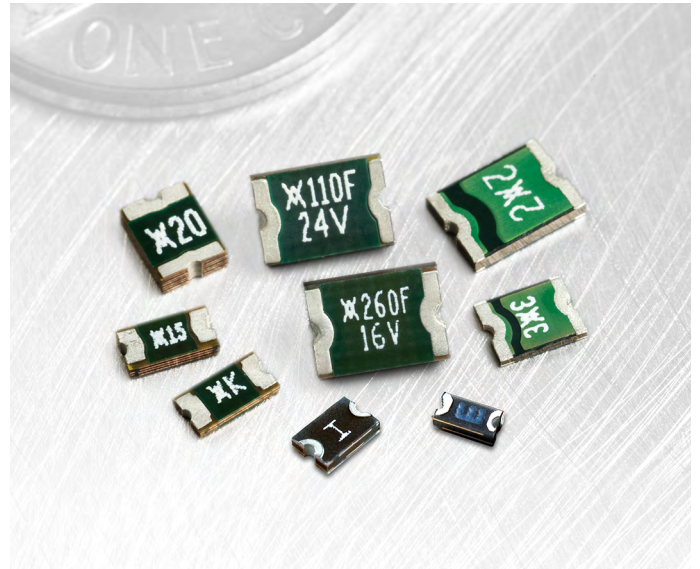
POLYSWITCH RESETTABLE DEVICES

Surface-Mount Devices

PolySwitch surface-mount devices are an effective circuit protection method for computer, consumer, multimedia, portable and automotive electronics applications.

In an effort to reduce the size and cost of surface-mount devices, Littelfuse PolySwitch team introduced the miniSMD product series in 1995. Subsequently, we developed the microSMD, nanoSMD, picoSMD and femtoSMD family of products. The femtoSMD series reduced the device size to a 1608mm (0603 mils) footprint, which is one-twelfth the size of the popular miniSMD series.

Recent additions to the PolySwitch surface-mount series include 1.1A picoSMD 1210mm (0805 mils) and 0.35A femtoSMD 1608mm (0603 mils) devices.



BENEFITS

- Smaller size helps save board space and cost
- Many product choices optimizes design flexibility
- Compatible with high-volume electronics assembly
- Assists in meeting regulatory requirements
- Higher voltage ratings allow use in new applications

FEATURES

- RoHS compliant
- Halogen free
(refers to: Br $\geq$ 900ppm, Cl $\geq$ 900ppm, Br+Cl $\geq$ 1500ppm)
- Broadest range of resettable devices available in the industry
- Current ratings from 0.05 to 3.1A
- Voltage ratings from 6V computer and electronic applications to 60V telecom applications
- Agency recognition: UL, CSA, TÜV
- Small footprint
- Fast time-to-trip
- Low resistance

APPLICATIONS

- Computer
- Portable electronics
- Multimedia
- Game machines
- Telephony and broadband
- Mobile phones
- Automotive
- Industrial controls
- Battery

PolySwitch Resettable Devices

Surface-Mount Devices

Application Selection Table

- The table below lists PolySwitch surface-mount devices recommended for use in typical applications
- Specifications for the suggested PolySwitch surface-mount device part numbers can be found in this table
- Once a part has been selected, the user should evaluate and test each product for the intended application

			PolySwitch Resettable Devices - Key Selection Criteria		
Protection Application	Additional Comments	Overcurrent Overvoltage	Small Size	Low Resistance	Fast Time-to-trip (Temperature Protection)
AC Adapter Input Power	Use w/ Zener & Triac		SMD250F	SMD250F	SMD200F
Battery Pack Protection			nanoSMDC150F	miniSMDC260F	miniSMDE200F/16
Charger Protection			nanoSMDC050F	miniSMDC110F/16	nanoSMDC075F
CPU/IC Protection			nanoSMDC110F	nanoSMDC150F	nanoSMDC075F
Data Acquisition/Sensor			microSMD005F	—	microSMD005F
DC Input/Output Power	≤6V		nanoSMDC075F	nanoSMDC150F	nanoSMDC050F/13.2
	≤12V		miniSMDC075F	miniSMDC110F/16	miniSMDC075F
DDC			nanoSMDC075F	nanoSMDC110F	nanoSMDC050F/13.2
Device Bay System	DB12, DB20		miniSMDC200F	miniSMDC260F	miniSMDC200F
	DB32		miniSMDC260F	SMD300F	miniSMDC200F
Ethernet/LAN			nanoSMDC050F/13.2	miniSMDC110F/16	nanoSMDC075F
Fan			microSMD035F	microSMD050F	microSMD035F
HDMI			picoSMDC035S	picoSMDC035S	picoSMDC035S
IEEE 802.3af	VoIP		decaSMDC050F/60	decaSMDC050F/60	decaSMDC050F/60
IEEE-1394	Power Provider		SMD100F/33	SMD185F	SMD100F/33
	Alt. Power Provider		SMD185F	SMD185F	SMD150F/33
	Self-Powered		SMD185F	SMD185F	SMD150F/33
LCD Inverter			nanoSMDC050F/13.2	miniSMDC110F/16	nanoSMDC075F
LCD Screen Power			nanoSMDC050F/13.2	nanoSMDC050F/13.2	microSMD035F
LNB (Low Noise Block)			SMD075F	SMD075F	SMD050F
Motor	≤6V		nanoSMDC110F	nanoSMDC150F	microSMD075F
	≤13.2V		miniSMDC075F	miniSMDC110F/16	miniSMDC075F
PS/2 Mouse/Keyboard			nanoSMDC075F	nanoSMDC110F	nanoSMDC050F/13.2
Signal - Data Communication	≤6V		nanoSMDC075F	nanoSMDC075F	nanoSMDC075F
	≤13.2V		miniSMDC050F	miniSMDC075F	miniSMDC020F
	≤30V		SMD030F/2018	SMD075F	SMD050F
SCSI			nanoSMDC110F	nanoSMDC150F	nanoSMDC075F
SIM/Smart Card Reader			femtoSMDC010F	femtoSMDC010F	femtoSMDC005F
Telecom - Modem	Digital Line	OC	miniSMDC014F	miniSMDC014F	miniSMDC014F
Telecom - PBX	Subscriber	OC	miniSMDC014F	miniSMDC014F	miniSMDC014F
Temperature Sensor	CPU		nanoSMDC050F/13.2	nanoSMDC075F	nanoSMDC050F/13.2
USB	Individual Port		nanoSMDC075F	nanoSMDC110F	nanoSMDC050F/13.2
	2 Port Ganged		nanoSMDC150F	miniSMDC150F	miniSMDC125F
	3 Port Ganged		miniSMDC200F	miniSMDC200F	miniSMDC200F

Note: This list is not exhaustive. Littelfuse welcomes our customers' input for additional application ideas for PolySwitch resettable devices.

PolySwitch Resettable Devices

Surface-Mount Devices

Table S1 — Product Series: Size, Current Rating, Voltage Rating/Maximum Resistance

	femtoSMD	picoSMD	nanoSMD	microSMD	miniSMD	midSMD
Size mm	1608	2012	3216	3225	4532	5050
(mils)	(0603)	(0805)	(1206)	(1210)	(1812)	(2018)
Hold Current (A)						
0.050	15V _{DC} /30.00Ω	—	—	30V _{DC} /50Ω	—	—
0.080	12V _{DC} /14.00Ω	—	—	—	—	—
0.100	12V _{DC} /8.00Ω	15V _{DC} /11.00Ω	60V _{DC} /15.00Ω	30V _{DC} /15Ω	60V _{DC} /12.70Ω	—
	—	—	—	—	—	—
0.120	9V _{DC} /5.80Ω	15V _{DC} /9.00Ω	48V _{DC} /6.50Ω	—	—	—
0.140	—	—	—	—	60V _{DC} /6.00Ω	—
0.160	9V _{DC} /4.20Ω	—	48V _{DC} /5.00Ω	—	—	—
0.200	9V _{DC} /3.00Ω	9V _{DC} /3.20Ω	24V _{DC} /3.10Ω	—	30V _{DC} /3.30Ω	—
0.250	—	—	16V _{DC} /2.10Ω	—	—	—
0.300	—	—	—	—	30V _{DC} /1.75Ω	60V _{DC} /2.30Ω
0.350	6V _{DC} /1.00Ω	6V _{DC} /1.40Ω	16V _{DC} /1.35Ω	6V _{DC} /1.30Ω	—	—
0.500	—	6V _{DC} /0.80Ω	13.2V _{DC} /0.75Ω	13.2V _{DC} /0.90Ω	24V _{DC} /1.00Ω	—
0.750	—	6V _{DC} /0.35Ω*	6V _{DC} /0.30Ω	6V _{DC} /0.40Ω	13.2V _{DC} /0.45Ω	—
	—	—	—	—	24V _{DC} /0.29Ω	—
	—	—	—	—	33V _{DC} /0.39Ω	—
1.000	—	—	—	—	—	15V _{DC} /0.40Ω
	—	—	—	—	—	—
1.100	—	6V _{DC} /0.17Ω*	6V _{DC} /0.20Ω	6V _{DC} /0.21Ω	8V _{DC} /0.21Ω	—
	—	—	—	—	16V _{DC} /0.18Ω	—
	—	—	—	—	24V _{DC} /0.18Ω	—
1.200	—	—	—	—	—	—
1.250	—	—	—	—	6V _{DC} /0.14Ω	—
	—	—	—	—	16V _{DC} /0.14Ω	—
1.500	—	—	6V _{DC} /0.11Ω	6V _{DC} /0.11Ω	6V _{DC} /0.11Ω	15V _{DC} /0.18Ω
	—	—	—	—	12V _{DC} /0.11Ω	—
	—	—	—	—	16V _{DC} /0.11Ω	—
	—	—	—	—	24V _{DC} /0.12Ω	—
1.600	—	—	—	—	9V _{DC} /0.10Ω	—
1.750	—	—	—	6V _{DC} /0.08Ω	—	—
1.850	—	—	—	—	—	—
2.000	—	—	6V _{DC} /0.072Ω	6V _{DC} /0.06Ω	8V _{DC} /0.07Ω	6V _{DC} /0.10Ω
	—	—	—	—	16V _{DC} /0.085Ω	—
2.500	—	—	—	—	—	—
2.600	—	—	—	—	6V _{DC} /0.043Ω	—
	—	—	—	—	12V _{DC} /0.047Ω	—
	—	—	—	—	13.2V _{DC} /0.050Ω	—
	—	—	—	—	16V _{DC} /0.050Ω	—
3.000	—	—	—	—	6V _{DC} /0.036Ω	—
	—	—	—	—	—	—
3.100	—	—	—	—	—	—

PolySwitch Resettable Devices

Surface-Mount Devices

Table S1 — Product Series: Size, Current Rating, Voltage Rating/Maximum Resistance
(Cont'd)

	SMDC	SMD	SMD2	decaSMD	High Temperature SMD
Size mm	7555	7555	8763	5050	3216 & 3225
(mils)	(2920)	(2920)	(3425)	(2018)	(1206) & (1210)
Hold Current (A)					
0.050	—	—	—	—	—
0.080	—	—	—	—	—
0.100	—	—	—	—	30V _{DC} /10.0Ω
	—	—	—	—	30V _{DC} /11.0Ω
0.120	—	—	—	—	—
0.140	—	—	—	—	—
0.160	—	—	—	—	—
0.200	—	—	—	—	—
0.250	—	—	—	—	—
0.300	—	60V _{DC} /4.80Ω	—	—	—
0.350	—	—	—	—	—
0.500	—	60V _{DC} /1.40Ω	—	60V _{DC} /1.10Ω	6V _{DC} /0.90Ω
0.750	—	30V _{DC} /1.00Ω	—	—	6V _{DC} /0.36Ω
	—	60V _{DC} /1.00Ω	—	—	—
	—	—	—	—	—
1.000	—	30V _{DC} /0.48Ω	—	—	—
	—	33V _{DC} /0.41Ω	—	—	—
1.100	—	—	—	—	—
	—	—	—	—	—
	—	—	—	—	—
1.200	—	16V _{DC} /0.34Ω	—	—	—
1.250	33V _{DC} /0.25Ω	15V _{DC} /0.25Ω	—	—	—
	—	—	—	—	—
1.500	—	33V _{DC} /0.23Ω	15V _{DC} /0.25Ω	—	—
	—	—	33V _{DC} /0.23Ω	—	—
	—	—	—	—	—
	—	—	—	—	—
1.600	—	—	16V _{DC} /0.15Ω	—	—
1.750	—	—	—	—	—
1.850	33V _{DC} /0.15Ω	—	33V _{DC} /0.165Ω	—	—
2.000	—	24V _{DC} /0.125Ω	15V _{DC} /0.125Ω	—	—
	—	—	—	—	—
2.500	—	15V _{DC} /0.085Ω	15V _{DC} /0.85Ω	—	—
2.600	—	6V _{DC} /0.075Ω	—	—	—
	—	—	—	—	—
	—	—	—	—	—
	—	—	—	—	—
3.000	24V _{DC} /0.072Ω	6V _{DC} /0.048Ω	—	—	—
	—	15V _{DC} /0.05Ω	—	—	—
3.100	18V _{DC} /0.036Ω	—	—	—	—

PolySwitch Resettable Devices

Surface-Mount Devices

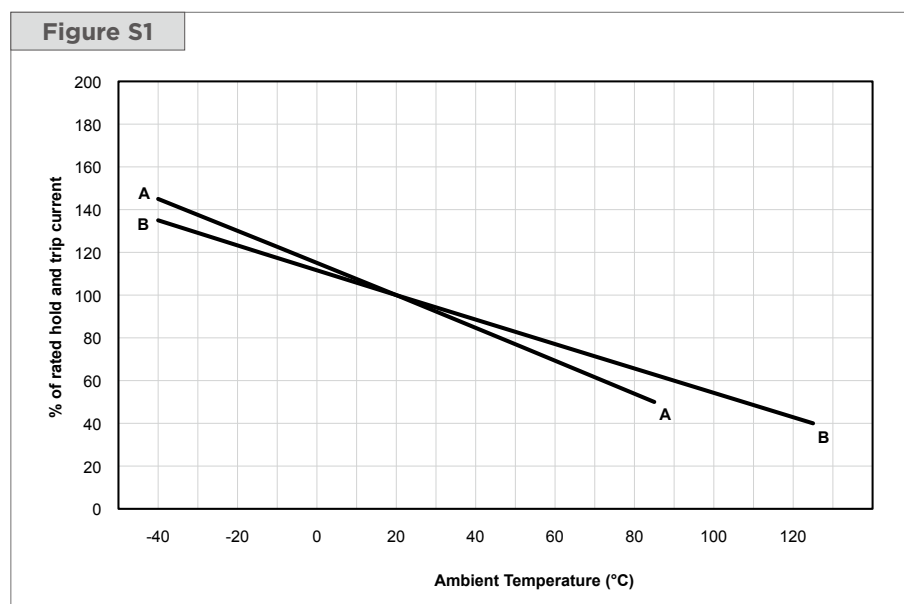
Table S2 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)] (Cont'd)

Part Number	Maximum Ambient Temperature											
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	80°C	85°C	125°C
SMD2 Series; Size 8763mm/3425mils												
SMD150F	2.30	2.04	1.80	1.50	1.45	1.23	1.10	0.99	0.83	0.70	0.63	—
SMD150F/33	2.30	2.04	1.80	1.50	1.45	1.23	1.10	0.99	0.83	0.70	0.63	—
SMDH160	2.14	1.96	1.78	1.60	1.56	1.42	1.33	1.24	1.15	1.06	1.02	0.44
SMD185F	2.54	2.29	2.20	1.85	1.80	1.55	1.43	1.31	1.19	1.06	1.00	—
SMD200F	3.01	2.67	2.30	2.00	1.90	1.66	1.50	1.30	1.16	0.99	0.91	—
SMD250F	3.72	3.31	2.80	2.50	2.35	2.09	1.89	1.60	1.48	1.28	1.18	—
High Temperature SMD Series; Size 3216mm/1206mils & 3225mm/1210mils												
NEW nanoSMDCH010F	0.18	0.16	0.15	0.11	0.10	0.09	0.08	0.07	0.07	0.06	0.06	0.03
NEW nanoSMDH075F	1.07	0.98	0.90	0.78	0.75	0.70	0.66	0.61	0.56	0.52	0.50	0.30
NEW microSMDCH010F	0.18	0.16	0.15	0.11	0.10	0.09	0.08	0.07	0.06	0.05	0.05	0.02
NEW microSMDCH050F	0.85	0.78	0.75	0.54	0.50	0.48	0.45	0.42	0.38	0.35	0.35	0.18

Figure S1 — Thermal Derating Curve

A = femtoSMD / picoSMD /
nanoSMD / microSMD / miniSMD
decaSMD / SMDC and SMD

B = SMDH120 / SMDH160
and High Temperature SMD



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Table S3 — Electrical Characteristics for Surface-Mount Devices at Room Temperature

Part	I _H	I _T	V _{MAX}	I _{MAX}	P _{D MAX}	Max Time-to-Trip		R _{MIN}	R _{1MAX}	Figure for
Number	(A)	(A)	(V _{DC})	(A)	(W)	(A)	(S)	(Ω)	(Ω)	Dimensions
femtoSMDC Series; Size 1608mm/0603mils										
femtoSMDC005F	0.05	0.15	15	40	0.50	0.50	0.10	3.80	30.00	S2
femtoSMDC008F	0.08	0.20	12	40	0.50	0.60	0.10	2.80	14.00	S2
femtoSMDC010F	0.10	0.25	12	40	0.50	0.70	0.10	1.70	8.00	S2
femtoSMDC012F	0.12	0.30	9	40	0.50	0.80	0.10	1.10	5.80	S2
femtoSMDC016F	0.16	0.40	9	40	0.50	1.00	0.10	1.00	4.20	S2
femtoSMDC020F	0.20	0.45	9	40	0.50	2.00	0.10	0.70	3.00	S2
femtoSMDC035F	0.35	0.70	6	40	0.50	3.50	0.10	0.28	1.00	S2
picoSMDC Series; Size 2012mm/0805mils										
picoSMDC010S	0.10	0.30	15	100	0.50	0.50	0.60	1.50	11.00	S2
picoSMDC012S	0.12	0.30	15	100	0.50	1.00	0.10	1.50	9.00	S2
picoSMDC020S	0.20	0.47	9	100	0.50	2.00	0.10	0.75	3.20	S2
picoSMDC035S	0.35	0.75	6	100	0.50	1.75	0.20	0.35	1.40	S2
picoSMDC050S	0.50	1.00	6	100	0.50	8.00	0.10	0.15	0.80	S2
picoSMDC075S	0.75	1.50	6	40	0.70	8.00	0.20	0.10	0.35	S2
picoSMDC110S	1.10	2.20	6	40	0.80	8.00	0.20	0.05	0.17	S2
nanoSMDC Series; Size 3216mm/1206mils										
nanoSMDC010F	0.10	0.25	60	10	0.80	0.50	1.00	1.60	15.00	S2
nanoSMDC012F	0.12	0.39	48	10	0.50	1.00	0.20	1.40	6.50	S2
nanoSMDC016F	0.16	0.45	48	10	0.50	1.00	0.30	1.10	5.00	S2
nanoSMDC020F	0.20	0.42	24	100	0.60	8.00	0.10	0.65	3.10	S2
nanoSMDC025F	0.25	0.58	16	100	0.60	8.00	0.10	0.40	2.10	S2
nanoSMDC035F	0.35	0.75	16	20	0.60	3.50	0.10	0.45	1.35	S2
nanoSMDC050F/13.2	0.50	1.10	13.2	100	0.80	8.00	0.10	0.20	0.75	S2
nanoSMDC075F	0.75	1.50	6	100	0.80	8.00	0.10	0.09	0.30	S2
nanoSMDC110F	1.10	2.20	6	100	0.80	8.00	0.10	0.07	0.20	S2
nanoSMDC150F	1.50	3.00	6	100	0.80	8.00	0.30	0.04	0.11	S2
nanoSMDC200F	2.00	4.00	6	100	1.00	8.00	1.50	0.02	0.072	S2
microSMD Series; Size 3225mm/1210mils										
microSMD005F	0.05	0.15	30	10	1.00	0.25	1.50	3.60	50.00	S2
microSMD010F	0.10	0.25	30	10	0.80	0.50	1.00	2.10	15.00	S2
microSMD035F	0.35	0.75	6	40	0.80	8.00	0.20	0.32	1.30	S2
microSMD050F	0.50	1.00	13.2	40	0.80	8.00	0.05	0.25	0.90	S2
microSMD075F	0.75	1.50	6	40	0.80	8.00	0.10	0.11	0.40	S2
microSMD110F	1.10	2.20	6	40	0.80	8.00	0.20	0.07	0.21	S2
microSMD150F	1.50	3.00	6	40	0.80	8.00	1.00	0.04	0.11	S2
microSMD175F	1.75	3.50	6	40	0.80	8.00	0.80	0.025	0.08	S2
microSMD200F	2.00	4.00	6	100	0.80	8.00	2.50	0.020	0.06	S2
miniSMDC Series; Size 4532mm/1812mils										
miniSMDC010F	0.10	0.30	60	40	0.75	0.50	5.00	0.70	12.70	S2
miniSMDC014F	0.14	0.28	60	10	0.75	8.00	0.008	1.50	6.00	S2
miniSMDC020F	0.20	0.40	30	10	0.80	8.00	0.02	0.60	3.30	S2
miniSMDC030F	0.30	0.60	30	40	0.80	8.00	0.10	0.20	1.75	S2
miniSMDC050F	0.50	1.00	24	100	0.80	8.00	0.15	0.15	1.00	S2
miniSMDC075F	0.75	1.50	13.2	100	1.00	8.00	0.20	0.11	0.45	S2
miniSMDC075F/24	0.75	1.50	24	40	0.80	8.00	0.30	0.09	0.29	S2

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Table S3 — Electrical Characteristics for Surface-Mount Devices
at Room Temperature

(Cont'd)

Part	I _H	I _T	V _{MAX}	I _{MAX}	P _{D MAX}	Max Time-to-Trip		R _{MIN}	R _{1MAX}	Figure for
Number	(A)	(A)	(V _{DC})	(A)	(W)	(A)	(S)	(Ω)	(Ω)	Dimensions
miniSMDC Series; Size 4532mm/1812mils										
miniSMDC075F/33	0.75	1.60	33	100	1.00	8.00	1.00	0.11	0.39	S2
miniSMDC100F	1.10	2.20	8	100	1.20	8.00	0.30	0.04	0.21	S2
miniSMDC110F	1.10	2.20	8	100	1.20	8.00	0.30	0.04	0.21	S2
miniSMDC110F/16	1.10	2.20	16	100	0.80	8.00	0.30	0.06	0.18	S2
miniSMDC110F/24	1.10	2.20	24	20	0.80	8.00	0.50	0.06	0.18	S2
miniSMDC125F	1.25	2.50	6	100	0.80	8.00	0.40	0.05	0.14	S2
miniSMDC125F/16	1.25	2.50	16	100	0.80	8.00	0.40	0.05	0.14	S2
miniSMDC150F	1.50	3.00	6	100	0.80	8.00	0.50	0.04	0.11	S2
miniSMDC150F/12	1.50	2.80	12	100	0.80	8.00	0.50	0.04	0.11	S2
miniSMDC150F/16	1.50	2.80	16	100	0.80	8.00	0.50	0.04	0.11	S2
miniSMDC150F/24	1.50	3.00	24	20	1.00	8.00	1.50	0.04	0.12	S2
miniSMDC160F	1.60	3.20	9	100	0.80	8.00	1.00	0.03	0.10	S2
miniSMDC200F	2.00	4.00	8	100	1.00	8.00	5.00	0.020	0.070	S2
miniSMDC200F/16	2.00	4.00	16	40	1.20	8.00	5.00	0.020	0.085	S2
miniSMDC260F	2.60	5.00	6	100	1.00	8.00	5.00	0.015	0.043	S2
miniSMDC260F/12	2.60	5.00	12	100	1.00	8.00	5.00	0.015	0.047	S2
miniSMDC260F/13.2	2.60	5.00	13.2	100	1.20	8.00	5.00	0.015	0.050	S2
miniSMDC260F/16	2.60	5.00	16	100	1.20	8.00	5.00	0.015	0.050	S2
miniSMDC300F	3.00	6.00	6	100	1.00	8.00	5.00	0.011	0.036	S2
midSMD Series; Size 5050mm/2018mils										
SMD030F-2018	0.30	0.80	60	20	1.50	1.50	1.50	0.500	2.30	S3
decaSMDC050F/60	0.55	1.10	60	10	1.00	8.00	0.10	0.200	1.10	S2
SMD100F-2018	1.10	2.20	15	40	1.40	8.00	0.50	0.100	0.40	S3
SMD150F-2018	1.50	3.00	15	40	1.80	8.00	1.00	0.070	0.18	S3
SMD200F-2018	2.00	4.20	6	40	1.50	8.00	3.00	0.048	0.10	S3
SMDC Series; Size 7555mm/2920mils										
SMDC125F/33	1.25	2.50	33	40	1.50	8.00	2.00	0.040	0.250	S2
SMDC185F/33	1.85	3.70	33	40	1.70	8.00	2.50	0.050	0.150	S2
SMDC300F/24	3.00	6.00	24	40	1.70	8.00	5.00	0.015	0.072	S2
SMDC310F/18	3.10	6.00	18	50	1.50	8.00	25.00	0.013	0.036	S2
SMD Series; Size 7555mm/2920mils										
SMD030F	0.30	0.60	60	10	1.70	1.50	3.00	1.200	4.800	S4
SMD050F	0.50	1.00	60	10	1.70	2.50	4.00	0.350	1.400	S4
SMD075F	0.75	1.50	30	40	1.70	8.00	0.30	0.350	1.000	S4
SMD075F/60	0.75	1.50	60	10	1.70	8.00	0.30	0.350	1.000	S4
SMD100F	1.10	2.20	30	40	1.70	8.00	0.50	0.120	0.480	S4
SMD100F/33	1.10	2.20	33	40	1.70	8.00	0.50	0.120	0.410	S4
SMDH120	1.20	2.30	16	50	2.00	8.00	2.00	0.150	0.340	S4
SMD125F	1.25	2.50	15	40	1.70	8.00	2.00	0.070	0.250	S4
SMD150F/33-2920	1.50	3.00	33	40	1.50	8.00	5.00	0.080	0.230	S4
SMD200F/24-2920	2.00	4.00	24	40	1.50	8.00	5.00	0.050	0.125	S4
SMD250F/15-2920	2.50	5.00	15	40	1.50	8.00	10.00	0.035	0.085	S4
SMD260F	2.60	5.20	6	40	1.70	8.00	20.00	0.025	0.075	S4
SMD300F	3.00	6.00	6	40	1.50	8.00	35.00	0.015	0.048	S4
SMD300F/15	3.00	6.00	15	40	1.50	8.00	35.00	0.015	0.050	S4

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Table S3 — Electrical Characteristics for Surface-Mount Devices at Room Temperature

(Cont'd)

Part	I _H	I _T	V _{MAX}	I _{MAX}	P _{D MAX}	Max Time-to-Trip		R _{MIN}	R _{1MAX}	Figure for
Number	(A)	(A)	(V _{DC})	(A)	(W)	(A)	(S)	(Ω)	(Ω)	Dimensions
SMD2 Devices; Size 8763mm/3425mils										
SMD150F	1.50	3.00	15	40	1.90	8.00	5.00	0.060	0.250	S4
SMD150F/33	1.50	3.00	33	40	1.90	8.00	5.00	0.080	0.230	S4
SMDH160	1.60	3.20	16	70	2.20	8.00	15.00	0.050	0.150	S4
SMD185F	1.85	3.60	33	40	1.50	8.00	5.00	0.065	0.165	S4
SMD200F	2.00	4.00	15	40	1.90	8.00	12.00	0.050	0.125	S4
SMD250F	2.50	5.00	15	40	1.90	8.00	25.00	0.035	0.085	S4
High Temperature SMD Series; Size 3216mm/1206mils & 3225mm/1210mils										
nanoSMDCH010F	0.10	0.35	30	10	0.80	1.00	0.10	1.10	10.00	S2
nanoSMDH075F	0.75	2.00	6	10	1.10	8.00	0.10	0.10	0.36	S5
microSMDCH010F	0.10	0.35	30	10	0.90	1.00	0.10	1.20	11.00	S2
microSMDCH050F	0.50	1.50	6	10	1.10	8.00	0.05	0.19	0.90	S2

Figures S2-S5 — Dimension Figures

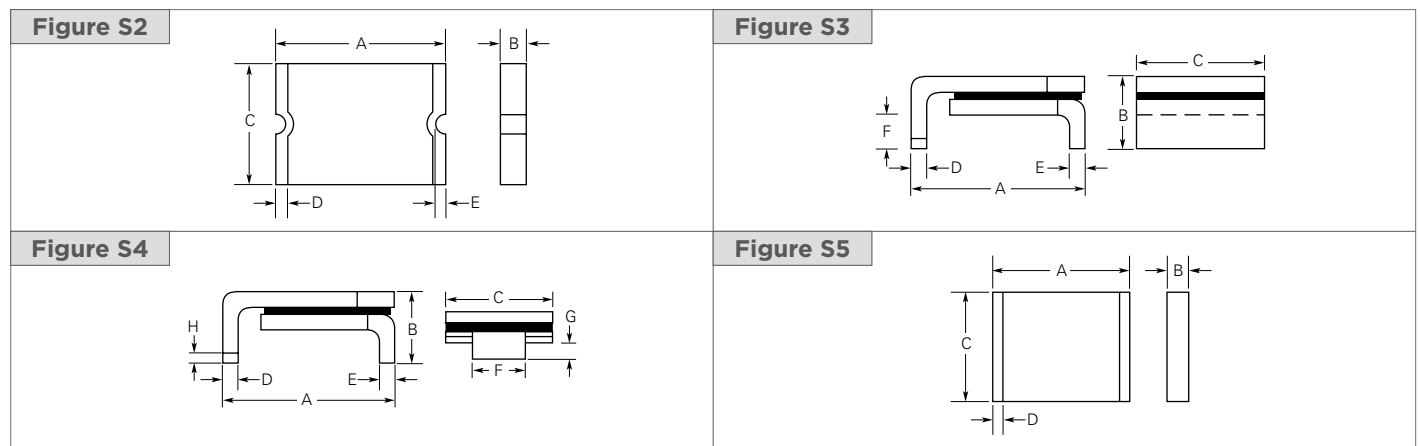


Table S4 — Dimensions in Millimeters (Inches)

Part Number	A		B		C		D		E		F		G		H	Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
femtoSMDC Series; Size 1608mm/0603mils																
femtoSMDC005F	1.40 (0.055)	1.80 (0.071)	0.45 (0.017)	0.85 (0.033)	0.60 (0.023)	1.00 (0.039)	0.10 (0.004)	0.50 (0.020)	0.075 (0.003)	—	—	—	—	—	—	S2
femtoSMDC008F	1.40 (0.055)	1.80 (0.071)	0.45 (0.017)	0.85 (0.033)	0.60 (0.023)	1.00 (0.039)	0.10 (0.004)	0.50 (0.020)	0.075 (0.003)	—	—	—	—	—	—	S2
femtoSMDC010F	1.40 (0.055)	1.80 (0.071)	0.45 (0.017)	0.85 (0.033)	0.60 (0.023)	1.00 (0.039)	0.10 (0.004)	0.50 (0.020)	0.075 (0.003)	—	—	—	—	—	—	S2
femtoSMDC012F	1.40 (0.055)	1.80 (0.071)	0.35 (0.013)	0.75 (0.030)	0.60 (0.023)	1.00 (0.039)	0.10 (0.004)	0.50 (0.020)	0.075 (0.003)	—	—	—	—	—	—	S2

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Table S4 — Dimensions in Millimeters (Inches)

(Cont'd)

Part	A		B		C		D		E		F		G		H	Figure
Number	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
femtoSMDC Series; Size 1608mm/0603mils																
femtoSMDC016F	1.40 (0.055)	1.80 (0.071)	0.35 (0.013)	0.75 (0.030)	0.60 (0.023)	1.00 (0.039)	0.10 (0.004)	0.50 (0.020)	0.075 (0.003)	—	—	—	—	—	—	S2
femtoSMDC020F	1.40 (0.055)	1.80 (0.071)	0.35 (0.013)	0.75 (0.030)	0.60 (0.023)	1.00 (0.039)	0.10 (0.004)	0.50 (0.020)	0.075 (0.003)	—	—	—	—	—	—	S2
femtoSMDC035F	1.40 (0.055)	1.80 (0.071)	0.55 (0.021)	0.95 (0.037)	0.60 (0.023)	1.00 (0.039)	0.10 (0.004)	0.50 (0.020)	0.075 (0.003)	—	—	—	—	—	—	S2
picoSMDC Series; Size 2012mm/0805mils																
picoSMDC010S	2.00 (0.079)	2.20 (0.087)	0.60 (0.023)	1.00 (0.040)	1.30 (0.051)	1.50 (0.059)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
picoSMDC012S	2.00 (0.079)	2.20 (0.087)	0.44 (0.017)	0.68 (0.027)	1.30 (0.051)	1.50 (0.059)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
picoSMDC020S	2.00 (0.079)	2.20 (0.087)	0.44 (0.017)	0.68 (0.027)	1.30 (0.051)	1.50 (0.059)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
picoSMDC035S	2.00 (0.079)	2.20 (0.087)	0.44 (0.017)	0.68 (0.027)	1.30 (0.051)	1.50 (0.059)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
picoSMDC050S	2.00 (0.079)	2.20 (0.087)	0.63 (0.025)	0.93 (0.036)	1.30 (0.051)	1.50 (0.059)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
picoSMDC075S	2.00 (0.079)	2.20 (0.087)	0.63 (0.025)	0.93 (0.036)	1.30 (0.051)	1.50 (0.059)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
picoSMDC110S	2.00 (0.079)	2.20 (0.087)	0.80 (0.031)	1.20 (0.047)	1.30 (0.051)	1.50 (0.059)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC Series; Size 3216mm/1206mils																
nanoSMDC010F	3.00 (0.118)	3.40 (0.134)	0.62 (0.024)	1.00 (0.039)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC012F	3.00 (0.118)	3.40 (0.134)	0.62 (0.024)	1.00 (0.039)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC016F	3.00 (0.118)	3.40 (0.134)	0.62 (0.024)	1.00 (0.039)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC020F	3.00 (0.118)	3.40 (0.134)	0.58 (0.023)	0.82 (0.032)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC025F	3.00 (0.118)	3.40 (0.134)	0.58 (0.023)	0.82 (0.032)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC035F	3.00 (0.118)	3.40 (0.134)	0.58 (0.023)	0.82 (0.032)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
/13.2	3.00 (0.118)	3.40 (0.134)	0.50 (0.019)	0.74 (0.029)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC075F	3.00 (0.118)	3.40 (0.134)	0.44 (0.017)	0.68 (0.027)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC110F	3.00 (0.118)	3.40 (0.134)	0.28 (0.011)	0.67 (0.026)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC150F	3.00 (0.118)	3.40 (0.134)	0.55 (0.022)	0.89 (0.035)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
nanoSMDC200F	3.00 (0.118)	3.40 (0.134)	0.83 (0.033)	1.10 (0.043)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2

PolySwitch Resettable Devices

Surface-Mount Devices

Table S4 — Dimensions in Millimeters (Inches)

(Cont'd)

Part Number	A		B		C		D		E		F		G		H	Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
microSMD Series; Size 3225mm/1210mils																
microSMD005F	3.0 (0.118)	3.43 (0.135)	0.50 (0.019)	0.85 (0.034)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD010F	3.0 (0.118)	3.43 (0.135)	0.50 (0.019)	0.85 (0.034)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD035F	3.0 (0.118)	3.43 (0.135)	0.38 (0.015)	0.62 (0.025)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD050F	3.0 (0.118)	3.43 (0.135)	0.38 (0.015)	0.62 (0.025)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD075F	3.0 (0.118)	3.43 (0.135)	0.38 (0.015)	0.62 (0.025)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD110F	3.0 (0.118)	3.43 (0.135)	0.28 (0.011)	0.48 (0.019)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD150F	3.0 (0.118)	3.43 (0.135)	0.51 (0.020)	1.22 (0.048)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD175F	3.0 (0.118)	3.43 (0.135)	0.40 (0.016)	0.76 (0.030)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
microSMD200F	3.0 (0.118)	3.43 (0.135)	0.79 (0.031)	1.17 (0.046)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	—	—	—	—	—	S2
miniSMDC Series; Size 4532mm/1812mils																
miniSMDC010F	4.37 (0.172)	4.73 (0.186)	0.635 (0.025)	0.89 (0.035)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC014F	4.37 (0.172)	4.73 (0.186)	0.635 (0.025)	0.89 (0.035)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC020F	4.37 (0.172)	4.73 (0.186)	0.635 (0.025)	0.89 (0.035)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC030F	4.37 (0.172)	4.73 (0.186)	0.635 (0.025)	0.89 (0.035)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC050F	4.37 (0.172)	4.73 (0.186)	0.38 (0.015)	0.62 (0.025)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC075F	4.37 (0.172)	4.73 (0.186)	0.38 (0.015)	0.62 (0.025)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC075F/24	4.37 (0.172)	4.83 (0.190)	0.81 (0.032)	1.46 (0.057)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC075F/33	4.37 (0.172)	4.83 (0.190)	0.94 (0.037)	1.46 (0.057)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC100F	4.37 (0.172)	4.73 (0.186)	0.38 (0.015)	0.62 (0.025)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC110F	4.37 (0.172)	4.73 (0.186)	0.38 (0.015)	0.62 (0.025)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC110F/16	4.37 (0.172)	4.83 (0.190)	0.28 (0.011)	0.48 (0.019)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC110F/24	4.37 (0.172)	4.83 (0.190)	0.81 (0.032)	1.46 (0.057)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC125F	4.37 (0.172)	4.73 (0.186)	0.28 (0.011)	0.48 (0.019)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2
miniSMDC125F/16	4.37 (0.172)	4.83 (0.190)	0.28 (0.011)	0.48 (0.019)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	S2

PolySwitch Resettable Devices

Surface-Mount Devices

Table S4 — Dimensions in Millimeters (Inches)

(Cont'd)

Part	A		B		C		D		E		F		G		H		Figure
Number	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
miniSMDC Series; Size 4532mm/1812mils																	
miniSMDC150F	4.37 (0.172)	4.73 (0.186)	0.28 (0.011)	0.48 (0.019)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC150F/12	4.37 (0.172)	4.83 (0.190)	0.28 (0.011)	0.48 (0.019)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC150F/16	4.37 (0.172)	4.83 (0.190)	0.28 (0.011)	0.48 (0.019)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC150F/24	4.37 (0.172)	4.83 (0.190)	1.00 (0.040)	1.94 (0.077)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC160F	4.37 (0.172)	4.73 (0.186)	0.28 (0.011)	0.48 (0.019)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC200F	4.37 (0.172)	4.73 (0.186)	0.51 (0.020)	1.22 (0.048)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC200F/16	4.37 (0.172)	4.73 (0.186)	0.51 (0.020)	1.22 (0.048)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC260F	4.37 (0.172)	4.73 (0.186)	0.48 (0.019)	0.78 (0.031)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC260F/12	4.37 (0.172)	4.83 (0.190)	1.02 (0.042)	1.52 (0.060)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC260F/13.2	4.37 (0.172)	4.83 (0.190)	1.02 (0.042)	1.52 (0.060)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC260F/16	4.37 (0.172)	4.83 (0.190)	1.02 (0.042)	1.52 (0.060)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
miniSMDC300F	4.37 (0.172)	4.73 (0.186)	0.45 (0.018)	0.76 (0.030)	3.07 (0.121)	3.41 (0.134)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
midSMD Series; Size 5050mm/2018mils																	
SMD030F-2018	4.72 (0.186)	5.44 (0.214)	—	1.78 (0.070)	4.22 (0.166)	4.93 (0.194)	0.25 (0.010)	0.36 (0.014)	0.25 (0.010)	0.36 (0.014)	0.30 (0.012)	0.46 (0.018)	—	—	—	—	S3
decaSMDC050F/60	4.70 (0.185)	5.31 (0.209)	0.63 (0.025)	0.89 (0.035)	4.19 (0.165)	4.81 (0.189)	0.25 (0.010)	0.95 (0.040)	0.25 (0.010)	—	—	—	—	—	—	—	S2
SMD100F-2018	4.72 (0.186)	5.44 (0.214)	—	1.52 (0.060)	4.22 (0.166)	4.93 (0.194)	0.25 (0.010)	0.36 (0.014)	0.25 (0.010)	0.36 (0.014)	0.30 (0.012)	0.46 (0.018)	—	—	—	—	S3
SMD150F-2018	4.72 (0.186)	5.44 (0.214)	—	1.52 (0.060)	4.22 (0.166)	4.93 (0.194)	0.25 (0.010)	0.36 (0.014)	0.25 (0.010)	0.36 (0.014)	0.30 (0.012)	0.46 (0.018)	—	—	—	—	S3
SMD200F-2018	4.72 (0.186)	5.44 (0.214)	—	1.52 (0.060)	4.22 (0.166)	4.93 (0.194)	0.25 (0.010)	0.36 (0.014)	0.25 (0.010)	0.36 (0.014)	0.30 (0.012)	0.46 (0.018)	—	—	—	—	S3
SMDC Series; Size 7555mm/2920mils																	
SMDC125F/33	7.30 (0.287)	7.70 (0.303)	0.45 (0.018)	0.71 (0.028)	4.90 (0.193)	5.30 (0.209)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
SMDC185F/33	7.30 (0.287)	7.70 (0.303)	0.90 (0.035)	1.20 (0.047)	4.90 (0.193)	5.30 (0.209)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
SMDC300F/24	7.30 (0.287)	7.70 (0.303)	0.80 (0.031)	1.10 (0.043)	4.90 (0.193)	5.30 (0.209)	0.25 (0.010)	0.95 (0.040)	0.20 (0.008)	—	—	—	—	—	—	—	S2
SMDC310F/18	7.30 (0.287)	7.70 (0.303)	1.10 (0.043)	1.70 (0.067)	4.90 (0.193)	5.30 (0.209)	0.95 (0.037)	1.45 (0.057)	0.35 (0.014)	—	—	—	—	—	—	—	S2

PolySwitch Resettable Devices

Surface-Mount Devices

Table S4 — Dimensions in Millimeters (Inches)

(Cont'd)

Part Number	A		B		C		D		E		F		G		H	Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
SMD Series; Size 7555mm/2920mils																
SMD030F	6.73	7.98	—	3.18	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.125)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD050F	6.73	7.98	—	3.18	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.125)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD075F	6.73	7.98	—	3.18	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.125)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD075F/60	6.73	7.98	—	3.18	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.125)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD100F	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD100F/33	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMDH120	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD125F	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD150F/33-2920	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD200F/24-2920	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD250F/15-2920	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD260F	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD300F	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD300F/15	6.73	7.98	—	3.00	4.80	5.44	0.56	0.71	0.56	0.71	2.16	2.41	0.66	1.37	0.43	S4
	(0.265)	(0.314)	—	(0.118)	(0.19)	(0.214)	(0.022)	(0.028)	(0.022)	(0.028)	(0.085)	(0.095)	(0.026)	(0.054)	(0.017)	
SMD2 Devices; Size 8763mm/3425mils																
SMD150F	8.00	9.40	—	3.00	6.00	6.71	0.56	0.71	0.56	0.71	3.68	3.94	0.66	1.37	0.43	S4
	(0.315)	(0.370)	—	(0.118)	(0.236)	(0.264)	(0.022)	(0.028)	(0.022)	(0.028)	(0.145)	(0.155)	(0.026)	(0.054)	(0.017)	
SMD150F/33	8.00	9.40	—	3.00	6.00	6.71	0.56	0.71	0.56	0.71	3.68	3.94	0.66	1.37	0.43	S4
	(0.315)	(0.370)	—	(0.118)	(0.236)	(0.264)	(0.022)	(0.028)	(0.022)	(0.028)	(0.145)	(0.155)	(0.026)	(0.054)	(0.017)	
SMDH160	8.00	9.40	—	3.00	6.00	6.71	0.56	0.71	0.56	0.71	3.68	3.94	0.66	1.37	0.43	S4
	(0.315)	(0.370)	—	(0.118)	(0.236)	(0.264)	(0.022)	(0.028)	(0.022)	(0.028)	(0.145)	(0.155)	(0.026)	(0.054)	(0.017)	
SMD185F	8.00	9.40	—	3.00	6.00	6.71	0.56	0.71	0.56	0.71	3.68	3.94	0.66	1.37	0.43	S4
	(0.315)	(0.370)	—	(0.118)	(0.236)	(0.264)	(0.022)	(0.028)	(0.022)	(0.028)	(0.145)	(0.155)	(0.026)	(0.054)	(0.017)	
SMD200F	8.00	9.40	—	3.00	6.00	6.71	0.56	0.71	0.56	0.71	3.68	3.94	0.66	1.37	0.43	S4
	(0.315)	(0.370)	—	(0.118)	(0.236)	(0.264)	(0.022)	(0.028)	(0.022)	(0.028)	(0.145)	(0.155)	(0.026)	(0.054)	(0.017)	
SMD250F	8.00	9.40	—	3.00	6.00	6.71	0.56	0.71	0.56	0.71	3.68	3.94	0.66	1.37	0.43	S4
	(0.315)	(0.370)	—	(0.118)	(0.236)	(0.264)	(0.022)	(0.028)	(0.022)	(0.028)	(0.145)	(0.155)	(0.026)	(0.054)	(0.017)	
High Temperature SMD Series; Size 3216mm/1206mils & 3225mm/1210mils																
nanoSMDCH010F	3.00	3.40	0.30	0.70	1.37	1.80	0.25	0.75	0.076	—	—	—	—	—	—	S2
	(0.118)	(0.134)	(0.012)	(0.028)	(0.054)	(0.071)	(0.010)	(0.030)	(0.003)	—	—	—	—	—	—	
nanoSMDH075F	3.00	3.40	0.60	1.00	1.40	1.80	0.20	0.80	—	—	—	—	—	—	—	S5
	(0.118)	(0.134)	(0.023)	(0.039)	(0.055)	(0.071)	(0.008)	(0.032)	—	—	—	—	—	—	—	
microSMDCH010F	3.00	3.43	0.57	0.97	2.35	2.80	0.25	0.75	0.076	—	—	—	—	—	—	S2
	(0.118)	(0.135)	(0.022)	(0.038)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)	—	—	—	—	—	—	
microSMDCH050F	3.00	3.43	0.24	0.64	2.35	2.80	0.25	0.75	0.076	—	—	—	—	—	—	S2
	(0.118)	(0.135)	(0.009)	(0.025)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)	—	—	—	—	—	—	

PolySwitch Resettable Devices

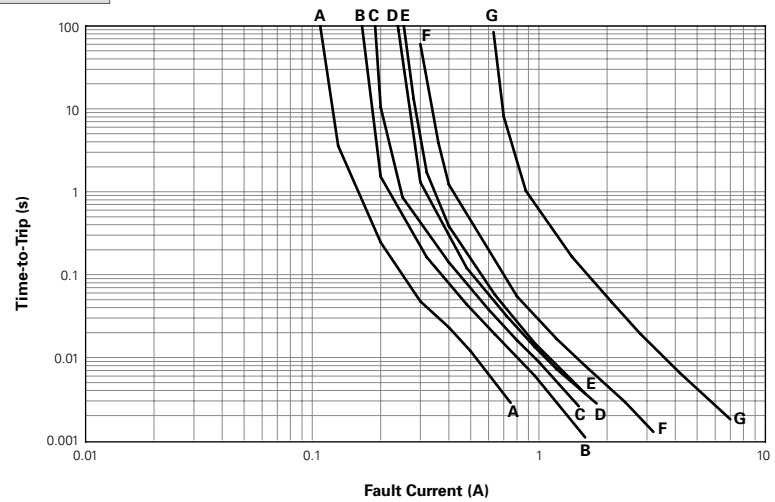
Surface-Mount Devices

Figures S6-S15 — Typical Time-to-Trip Curves at 20°C

femtoSMDCxxxF

- A = femtoSMDC005F
- B = femtoSMDC008F
- C = femtoSMDC010F
- D = femtoSMDC012F
- E = femtoSMDC016F
- F = femtoSMDC020F
- G = femtoSMDC035F

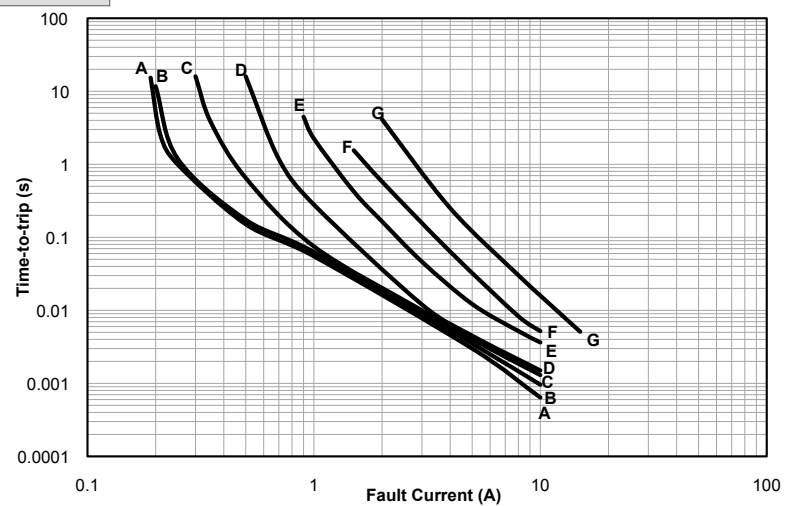
Figure S6



picoSMDCxxxS

- A = picoSMDC010S
- B = picoSMDC012S
- C = picoSMDC020S
- D = picoSMDC035S
- E = picoSMDC050S
- F = picoSMDC075S
- G = picoSMDC110S

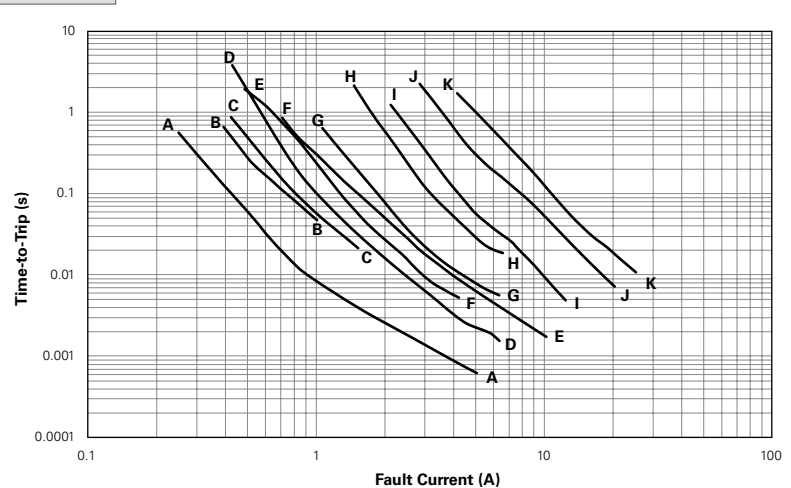
Figure S7



nanoSMDCxxxF

- A = nanoSMDC010F
- B = nanoSMDC012F
- C = nanoSMDC016F
- D = nanoSMDC020F
- E = nanoSMDC025F
- F = nanoSMDC035F
- G = nanoSMDC050F/13.2
- H = nanoSMDC075F
- I = nanoSMDC110F
- J = nanoSMDC150F
- K = nanoSMDC200F

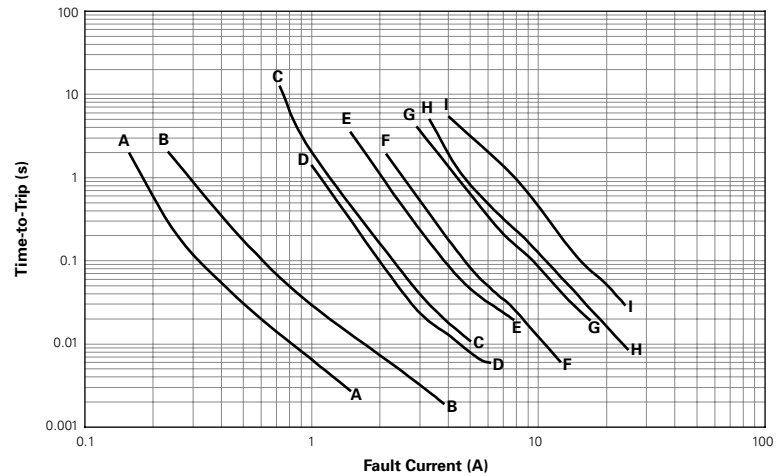
Figure S8



microSMDxxxF

- A = microSMD005F
- B = microSMD010F
- C = microSMD035F
- D = microSMD050F
- E = microSMD075F
- F = microSMD110F
- G = microSMD150F
- H = microSMD175F
- I = microSMD200F

Figure S9



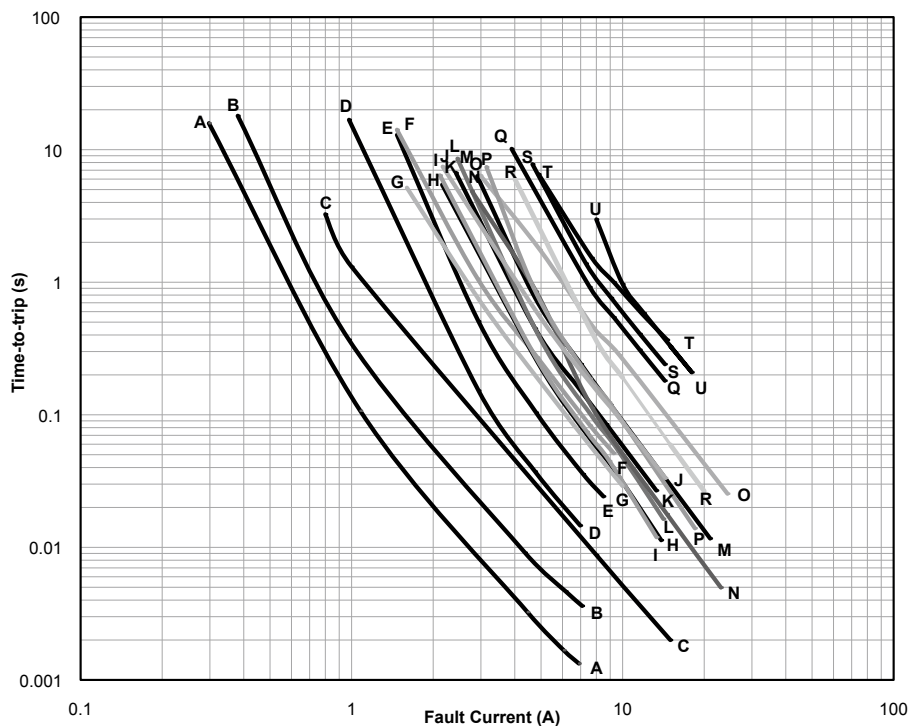
miniSMDCxxxF

- A = miniSMDC010F, miniSMDC014F
- B = miniSMDC020F
- C = miniSMDC030F
- D = miniSMDC050F
- E = miniSMDC075F
- F = miniSMDC075F/24

- G = miniSMDC075F/33
- H = miniSMDC100F, miniSMDC110F
- I = miniSMDC110F/16
- J = miniSMDC110F/24
- K = miniSMDC125F
- L = miniSMDC125F/16
- M = miniSMDC150F, miniSMDC150F/12
- N = miniSMDC150F/16

- O = miniSMDC150F/24
- P = miniSMDC160F
- Q = miniSMDC200F
- R = miniSMDC200F/16
- S = miniSMDC260F
- T = miniSMDC260F/12, miniSMDC260F/13.2, miniSMDC260F/16
- U = miniSMDC300F

Figure S10



PolySwitch Resettable Devices

Surface-Mount Devices

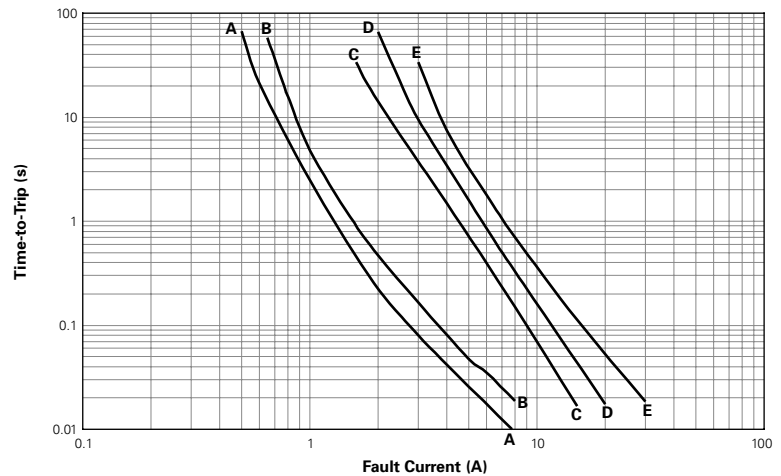
Figures S6-S15 — Typical Time-to-Trip Curves at 20°C

(Cont'd)

midSMD

- A = SMD030F-2018
- B = decaSMDC050F/60
- C = SMD100F-2018
- D = SMD150F-2018
- E = SMD200F-2018

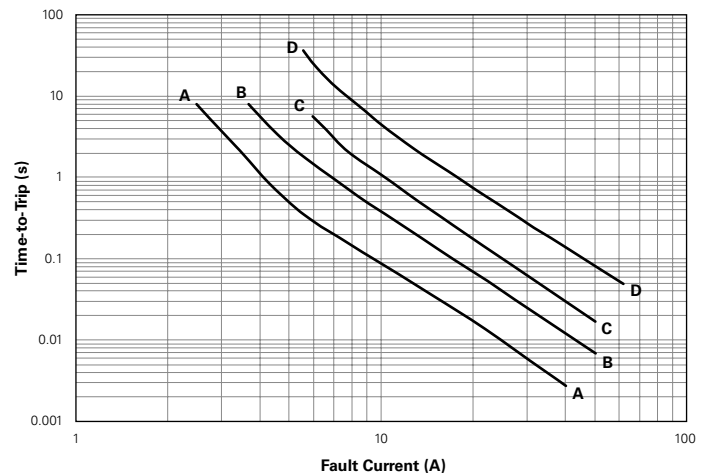
Figure S11



SMDCxxxF

- A = SMDC125F/33
- B = SMDC185F/33
- C = SMDC300F/24
- D = SMDC310F/18

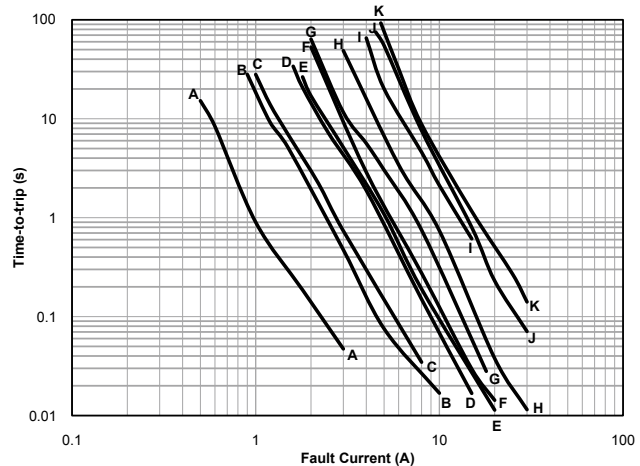
Figure S12



SMDxxxF

- A = SMD030F
- B = SMD050F
- C = SMD075F, SMD075F/60
- D = SMD100F, SMD100F/33
- E = SMDH120
- F = SMD150F/33-2920
- G = SMD125F
- H = SMD200F/24-2920
- I = SMD250F/15-2920
- J = SMD260F
- K = SMD300F, SMD300F/15

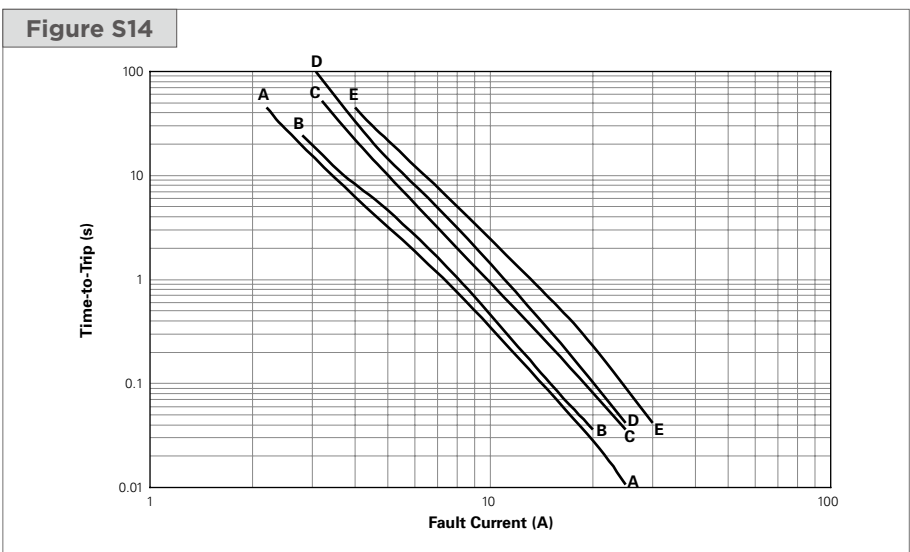
Figure S13



Figures S6-S15 — Typical Time-to-Trip Curves at 20°C (Cont'd)

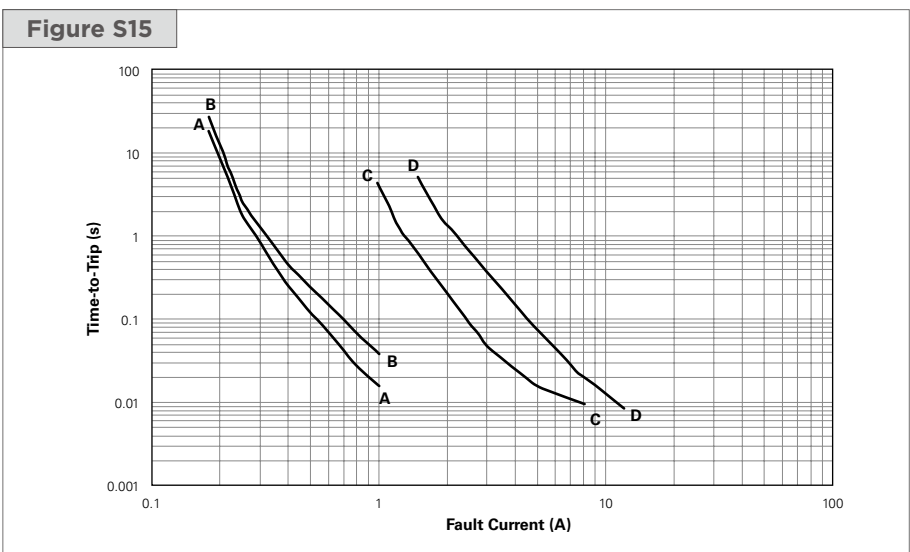
SMD2xxxF

- A = SMD150F, SMD150F/33
- B = SMDH160
- C = SMD185F
- D = SMD200F
- E = SMD250F



High Temperature SMD

- A = nanoSMDCH010F
- B = microSMDCH010F
- C = microSMDCH050F
- D = nanoSMDH075F



PolySwitch Resettable Devices

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Table S5 — Physical Characteristics and Environmental Specifications

Physical Characteristics			
Terminal Pad Material	100% Matte Tin with Nickel Underplate		
Soldering Characteristics	ANSI/J-STD-002 Category 3 for femtoSMD, picoSMD, nanoSMD, microSMD, miniSMD and SMDC Series		
	ANSI/J-STD-002 Category 1 for SMD Series		
Solder Heat Withstand	per IEC-STD 68-2-20, Test Tb, Section 5, Method 1A		
Flammability Resistance	per IEC 695-2-2 Needle Flame Test for 20 seconds		
Recommended Storage Conditions	40°C max, 70% R.H. max; Devices May Not Meet Specified Ratings if Storage Conditions Are Exceeded		
Environmental Specifications			
Test	Test Method	Conditions	Resistance Change
Storage Life	PS300, Section 5.3.2	60°C, 1000 hrs	±3% typ
		85°C, 1000 hrs	±5% typ
Humidity Aging	PS300, Section 5.3.1	85°C, 85% RH, 100 hrs	±1.2% typ
Thermal Shock	MIL-STD-202, Method 107G	85°C, -40°C (20 Times)	-33% typ
		125°C, -55°C (10 Times)	-33% typ
Vibration	MIL-STD-883C	per MIL-STD-883C	No Change
Solvent Resistance	PS300, Section 5.2.2	Freon	No Change
		Trichloroethane	No Change
		Hydrocarbons	No Change

Table S6 — Packaging and Marking Information

Part Number	Tape and Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (in)]			Agency Recognition
				Dimension	Dimension	Dimension	
				A (Nom)	B (Nom)	C (Nom)	
femtoSMDC Series; Size 1608mm/0603mils							
femtoSMDC005F	4,000	20,000	A	0.80 (0.032)	0.60 (0.024)	0.80 (0.032)	UL, CSA
femtoSMDC008F	4,000	20,000	T	0.80 (0.032)	0.60 (0.024)	0.80 (0.032)	UL, CSA
femtoSMDC010F	4,000	20,000	B	0.80 (0.032)	0.60 (0.024)	0.80 (0.032)	UL, CSA, TÜV
femtoSMDC012F	5,000	25,000	C	0.80 (0.032)	0.60 (0.024)	0.80 (0.032)	UL, CSA
femtoSMDC016F	5,000	25,000	E	0.80 (0.032)	0.60 (0.024)	0.80 (0.032)	UL, CSA
femtoSMDC020F	5,000	25,000	F	0.80 (0.032)	0.60 (0.024)	0.80 (0.032)	UL, CSA, TÜV
femtoSMDC035F	4,000	20,000	K	0.80 (0.032)	0.60 (0.024)	0.80 (0.032)	UL, CSA
picoSMDC Series; Size 2012mm/0805mils							
picoSMDC010S	3,000	15,000	C	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	UL, CSA, TÜV
picoSMDC012S	4,000	20,000	F	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	UL, CSA, TÜV
picoSMDC020S	4,000	20,000	H	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	UL, CSA, TÜV
picoSMDC035S	4,000	20,000	I	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	UL, CSA, TÜV
picoSMDC050S	3,000	15,000	K	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	UL, CSA, TÜV
picoSMDC075S	3,000	15,000	M	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	UL, CSA, TÜV
picoSMDC110S	3,000	15,000	S	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	UL, TÜV
nanoSMDC Series; Size 3216mm/1206mils							
nanoSMDC010F	3,000	15,000	A	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, TÜV
nanoSMDC012F	3,000	15,000	P	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC016F	3,000	15,000	N	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV

PolySwitch Resettable Devices

Surface-Mount Devices

Table S6 — Packaging and Marking Information

(Cont'd)

Part Number	Tape and Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (in)]			Agency Recognition
				Dimension	Dimension	Dimension	
				A (Nom)	B (Nom)	C (Nom)	
nanoSMDC Series; Size 3216mm/1206mils							
nanoSMDC020F	3,000	15,000	02	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC025F	3,000	15,000	C	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC035F	3,000	15,000	03	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC050F/13.2	3,000	15,000	M	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC075F	3,000	15,000	L	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC110F	3,000	15,000	K	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC150F	3,000	15,000	15	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC200F	3,000	15,000	T	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD Series; Size 3225mm/1210mils							
microSMD005F	4,000	20,000	05	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD010F	4,000	20,000	10	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD035F	4,000	20,000	3	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD050F	4,000	20,000	50	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD075F	4,000	20,000	75	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD110F	4,000	20,000	11	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD150F	4,000	20,000	15	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD175F	4,000	20,000	17	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD200F	3,000	15,000	20	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
miniSMDC Series; Size 4532mm/1812mils							
miniSMDC010F	2,000	10,000	10	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC014F	2,000	10,000	14	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC020F	2,000	10,000	2	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC030F	2,000	10,000	3	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC050F	2,000	10,000	5	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC075F	2,000	10,000	7	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC075F/24	1,500	7,500	075F 24V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC075F/33	1,500	7,500	075F 33V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC100F	2,000	10,000	1	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC110F	2,000	10,000	1	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC110F/16	2,000	10,000	110F 16V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC110F/24	1,500	7,500	110F 24V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC125F	2,000	10,000	12	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC125F/16	2,000	10,000	125F 16V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC150F	2,000	10,000	15	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC150F/12	2,000	10,000	150F 12V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC150F/16	2,000	10,000	150 16V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC150F/24	1,000	5,000	150F 24V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC160F	2,000	10,000	16	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC200F	2,000	10,000	20	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC200F/16	2,000	10,000	200F 16V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, TÜV
miniSMDC260F	2,000	10,000	260F	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC260F/12	1,500	7,500	260F 12V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC260F/13.2	1,500	7,500	260F 13V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC260F/16	1,500	7,500	260F 16V	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV
miniSMDC300F	2,000	10,000	30	3.15 (0.124)	1.68 (0.066)	3.10 (0.122)	UL, CSA, TÜV

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Table S6 — Packaging and Marking Information

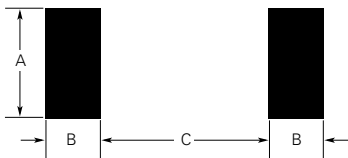
(Cont'd)

				Recommended Pad Layout Figures [mm (in)]			Agency Recognition	
	Part	Tape and Reel Quantity	Standard Package	Part	Dimension	Dimension		Dimension
	Number			Marking	A (Nom)	B (Nom)		C (Nom)
midSMD Series; Size 5050mm/2018mils								
	SMD030F-2018	4,000	20,000	A03F	4.60 (0.18)	1.50 (0.059)	3.40 (0.134)	UL, CSA, TÜV
	decaSMDC050F/60	1,000	5,000	050F 60V	4.32 (0.17)	1.40 (0.055)	3.61 (0.142)	UL, CSA, TÜV
	SMD100F-2018	4,000	20,000	A10F	4.60 (0.18)	1.50 (0.059)	3.40 (0.134)	UL, CSA, TÜV
	SMD150F-2018	4,000	20,000	A15F	4.60 (0.18)	1.50 (0.059)	3.40 (0.134)	UL, CSA, TÜV
	SMD200F-2018	4,000	20,000	A20F	4.60 (0.18)	1.50 (0.059)	3.40 (0.134)	UL, CSA, TÜV
SMDC Series; Size 7555mm/2920mils								
NEW	SMDC125F/33	4,000	20,000	125F	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)	UL
NEW	SMDC185F/33	4,000	20,000	185F 33V	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)	UL, CSA, TÜV
NEW	SMDC300F/24	4,000	20,000	300F 24V	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)	UL, CSA, TÜV
NEW	SMDC310F/18	3,000	15,000	310F 18V	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)	UL, CSA, TUV
SMD Series; Size 7555mm/2920mils								
	SMD030F	2,000	10,000	030F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD050F	2,000	10,000	050F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD075F	2,000	10,000	075F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD075F/60	2,000	10,000	756F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD100F	2,000	10,000	100F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD100F/33	2,000	10,000	103F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMDH120	2,000	10,000	H12	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD125F	2,000	10,000	125F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD150F/33-2920	2,000	10,000	S15F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD200F/24-2920	2,000	10,000	S20F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD250F/15-2920	2,000	10,000	S25F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD260F	2,000	10,000	260F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD300F	2,000	10,000	300F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
	SMD300F/15	2,000	10,000	315F	3.10 (0.12)	2.30 (0.09)	5.10 (0.201)	UL, CSA, TÜV
SMD2 Devices; Size 8763mm/3425mils								
	SMD150F	1,500	7,500	150F	4.60 (0.18)	2.30 (0.09)	6.10 (0.240)	UL, CSA, TÜV
	SMD150F/33	1,500	7,500	153F	4.60 (0.18)	2.30 (0.09)	6.10 (0.240)	UL, CSA, TÜV
	SMDH160	1,500	7,500	160F	4.60 (0.18)	2.30 (0.09)	6.10 (0.240)	UL, CSA, TÜV
	SMD185F	1,500	7,500	185F	4.60 (0.18)	2.30 (0.09)	6.10 (0.240)	UL, CSA, TÜV
	SMD200F	1,500	7,500	200F	4.60 (0.18)	2.30 (0.09)	6.10 (0.240)	UL, CSA, TÜV
	SMD250F	1,500	7,500	250F	4.60 (0.18)	2.30 (0.09)	6.10 (0.240)	UL, CSA, TÜV
High Temperature SMD Series; Size 3216mm/1206mils & 3225mm/1210mils								
NEW	nanoSMDCH010F	4,000	20,000	H01	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	—
NEW	nanoSMDH075F	3,000	15,000	H75	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	—
NEW	microSMDCH010F	3,000	15,000	H01	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	—
NEW	microSMDCH050F	4,000	20,000	H05	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	—

PolySwitch Resettable Devices

Surface-Mount Devices

Figure S16 — Recommended Pad Layout



Agency Recognition

UL	File # E74889 for all Surface-mount Devices
CSA	File # CA78165 for all Surface-mount Devices
TÜV	Certificate Number Available Upon Request (Certified to IEC 60730-1)

Solder Reflow and Rework Recommendation

Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-up Rate ($T_{s_{MAX}}$ to T_p)	3°C/s max
Preheat	
• Temperature min ($T_{s_{MIN}}$)	150°C
• Temperature max ($T_{s_{MAX}}$)	200°C
• Time ($t_{s_{MIN}}$ to $t_{s_{MAX}}$)	60-120s
Time Maintained Above:	
• Temperature (T_L)	217°C
• Time (t_L)	60-150s
Peak/Classification Temperature (T_p)	260°C
Time within 5°C of Actual Peak Temperature	
Time (t_p)	30s max
Ramp-down Rate	3°C/s max
Time 25°C to Peak Temperature	8 mins max

Note: All temperatures refer to topside of the package, measured on the package body surface.

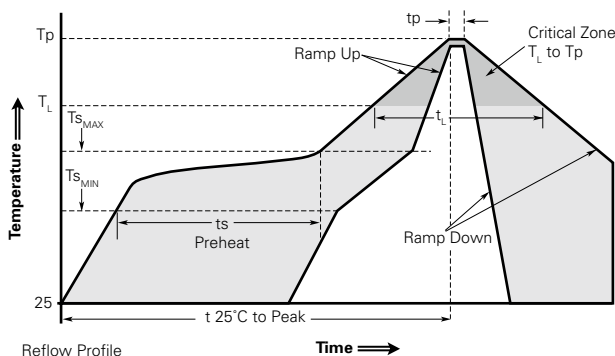
Solder Reflow

- Recommended reflow methods:
 - IR
 - Hot air
 - Nitrogen
- Recommended maximum paste thickness: 0.25mm (0.010in)
- Devices can be cleaned using standard methods and aqueous solvents.
- Experience has shown the optimum conditions for forming acceptable solder fillets occur when a reasonable amount of solder paste is placed underneath each device’s termination. As such, we request that customers comply with our recommended solder pad layouts.
- Customer should validate that the solder paste amount and reflow recommendations meet its application.
- We request that customer board layouts refrain from placing raised features (e.g. vias, nomenclature, traces, etc.) underneath PolySwitch devices. It is possible that raised features could negatively impact solderability performance of our devices.

Rework

- femtoSMD, picoSMD, nanoSMD, microSMD, miniSMD and SMDC series: standard industry practices. (Please also avoid direct contact to the device.)
- SMD series: Rework should be confined to removal of the installed product and replacement with a fresh device.

Figure S17



PolySwitch Resettable Devices

Surface-Mount Devices

Table S7 — Tape and Reel Specifications (Millimeters)

Description	femtoSMDC EIA 481-1	picoSMDC EIA 481-1	nanoSMDC nanoSMDCH010F and nanoSMDH075F EIA 481-1	microSMD microSMDCH010F and microSMDCH050F EIA 481-1	miniSMDC and decaSMDC050F/60 EIA 481-1	midSMD except decaSMDC050F/60 EIA 481-2	SMDC EIA 481-1	SMD EIA 481-2	SMD2 EIA 481-2
W	8.0 ± 0.30	8.0 ± 0.30	8.0 ± 0.30	8.0 ± 0.30	12.0 ± 0.30	16.0 ± 0.30	16.0 ± 0.30	16.0 ± 0.30	16.0 ± 0.30
P ₀	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10
P ₁	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10	8.0 ± 0.10	8.0 ± 0.10	8.0 ± 0.10	8.0 ± 0.10	12.0 ± 0.10
P ₂	2.0 ± 0.05	2.0 ± 0.10	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.10	2.0 ± 0.10	2.0 ± 0.10	2.0 ± 0.10
A ₀	0.95 ± 0.05	1.70 ± 0.10	1.95 ± 0.10	2.9 ± 0.10	Table S8	5.11 ± 0.15	Table S8	5.6 ± 0.23	6.9 ± 0.23
B ₀	1.85 ± 0.05	2.45 ± 0.10	Table S8	Table S8	Table S8	5.6 ± 0.23	Table S8	8.1 ± 0.15	9.6 ± 0.15
B ₁ max	4.35	4.35	4.35	4.35	6.15	6.4	12.1	12.1	12.1
D ₀	1.55 ± 0.05	1.55 ± 0.05	1.55 ± 0.05	1.55 ± 0.05	1.55 ± 0.05	1.5 + 0.10/-0.00	1.5 + 0.10/-0.00	1.5 + 0.10/-0.00	1.5 + 0.10/-0.00
F	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	5.50 ± 0.10	7.50 ± 0.10	7.50 ± 0.10	7.50 ± 0.10	7.50 ± 0.10
E ₁	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10
E ₂ min	6.25	6.25	6.25	6.25	10.25	14.25	14.25	14.25	14.25
T max	0.3	0.3	0.3	0.3	0.35	0.4	0.35	0.4	0.4
T ₁ max	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.1
K ₀	Table S8	Table S8	Table S8	Table S8	Table S8	1.8 ± 0.15	Table S8	3.2 ± 0.15	3.4 ± 0.15

Table S8 — Tape and Reel Specifications (Millimeters)

	femtoSMDC005F femtoSMDC008F femtoSMDC010F femtoSMDC035F	femtoSMDC012F femtoSMDC016F femtoSMDC020F	picoSMDC012S picoSMDC020S picoSMDC035S	picoSMDC010S picoSMDC050S picoSMDC075S	picoSMDC110S	nanoSMDCH010F and All nanoSMDC series except nanoSMDC010F nanoSMDC012F nanoSMDC016F nanoSMDC200F	nanoSMDH075F nanoSMDC010F nanoSMDC012F nanoSMDC016F nanoSMDC200F	microSMDCH050F and All microSMD series except microSMD200F
A ₀	0.95 ± 0.05	0.95 ± 0.05	1.70 ± 0.1	1.70 ± 0.1	1.70 ± 0.1	1.95 ± 0.1	1.95 ± 0.1	2.9 ± 0.1
B ₀	1.85 ± 0.05	1.85 ± 0.05	2.45 ± 0.1	2.45 ± 0.1	2.45 ± 0.1	3.50 ± 0.1/-0.08	3.5 ± 0.1	3.5 ± 0.1
K ₀	0.90 ± 0.1	0.55 ± 0.05	0.86 ± 0.1	1.12 ± 0.1	1.35 ± 0.1	0.89 ± 0.1	1.27 ± 0.1	0.9 ± 0.1
	microSMDCH010F microSMD200F	miniSMDC010F miniSMDC014F~075F miniSMDC100F~110F/16 miniSMDC125F~150F/16 miniSMDC160F~260F miniSMDC300F	miniSMDC075F/24 miniSMDC075F/33 miniSMDC110F/24 miniSMDC260F/12 miniSMDC260F/13.2 miniSMDC260F/16	miniSMDC150F/24	decaSMDC050F/60	SMDC125F/33	SMDC185F/33 SMDC300F/24	SMDC310F/18
A ₀	2.9 ± 0.1	3.5 ± 0.1	3.7 ± 0.1	3.7 ± 0.1	5.0 ± 0.1	5.5 ± 0.1	5.35 ± 0.1	5.5 ± 0.1
B ₀	3.55 ± 0.1	4.95 ± 0.1	4.9 ± 0.1	4.9 ± 0.1	5.4 ± 0.1	7.9 ± 0.1	7.85 ± 0.1	8.0 ± 0.1
K ₀	1.27 ± 0.1	0.9 ± 0.1	1.4 ± 0.1	1.78 ± 0.1	1.7 ± 0.1	0.9 ± 0.1	1.45 ± 0.1	2.0 ± 0.1

Table S9 — Reel Dimensions (Millimeters)

femto/pico/nano/microSMD/				
High Temperature SMD		miniSMDC	midSMD	SMD/SMDC
A max	185	185	330	330
N min	50	50	50	50
W ₁	8.4 + 1.5/-0.0	12.4 + 2.0/-0.0	16.4 + 2.0/-0.0	16.4 + 2.0/-0.0
W ₂ max	14.4	18.4	22.4	22.4

PolySwitch Resettable Devices Surface-Mount Devices

Figure S18 — EIA Referenced Taped Component Dimensions

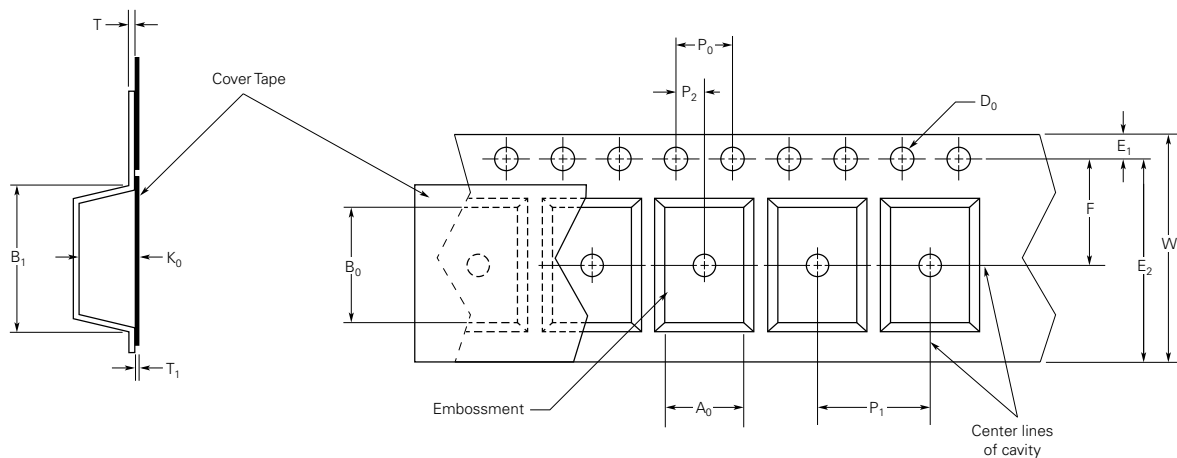
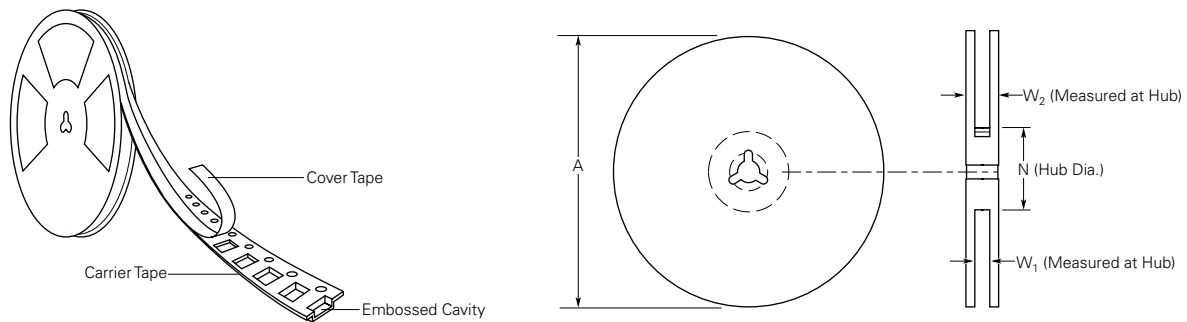
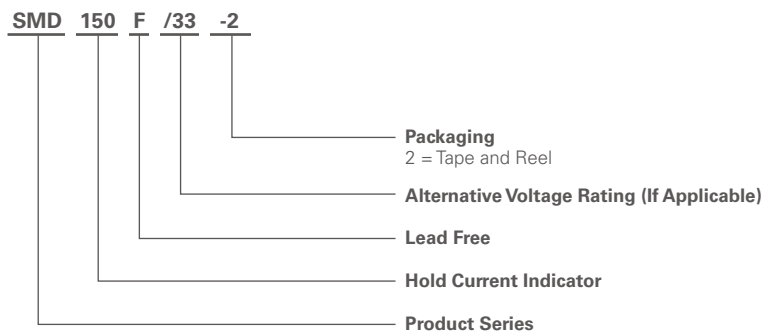


Figure S19 — EIA Referenced Reel Dimensions



Part Numbering System



Warning :

- Users should independently evaluate the suitability of and test each product selected for their own application.
- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- These devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommodate device expansion.
- Operation in circuits with a large inductance can generate a circuit voltage ($L di/dt$) above the rated voltage of the device.

PolySwitch Resettable Devices

Surface-Mount Devices

Notice:

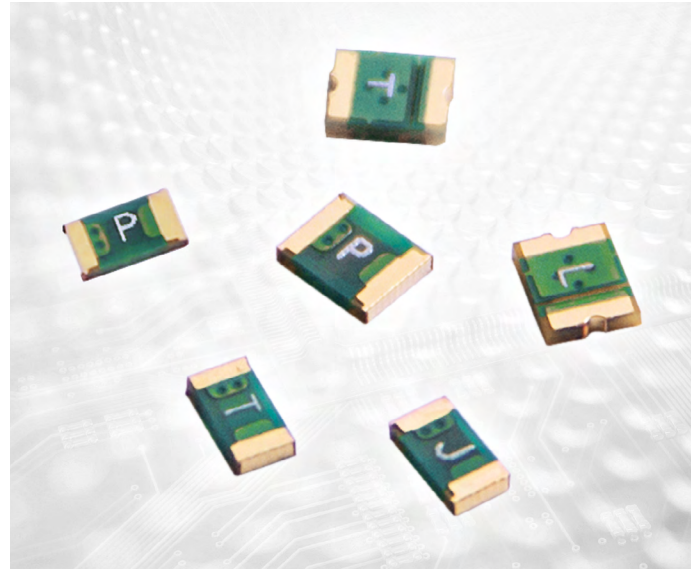
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POLYSWITCH RESETTABLE DEVICES

Low Resistivity SMD Devices

The low resistivity SMD (surface-mount device) series is well suited to space-constrained mobile applications. The devices can help provide both overcurrent and overtemperature protection for battery pack PCMs (protection circuit modules) used in compact consumer devices such as smartphones and MP3/MP4 media players. In particular, the low resistivity SMD series helps battery pack suppliers achieve their design goals and simplify their installation methods.

The low resistivity SMD series comprises eleven devices. In the model number descriptions, the “micro” prefix refers to the 1210 form factor and the “nano” prefix refers to the 1206 form factor.



BENEFITS

- Helps save board space and power consumption, and therefore costs, in space-constrained mobile electronics
- Are more compact in comparison with similar offerings and are available in an industry-standard form factor
- Can be assembled with a reflowable soldering technique, as opposed to the spot welding process required by many other components
- Maximum electrical rating: Voltage $6V_{DC}$ and short circuit current 50A
- Industry-standard form factor of 1210 (3.0mmx2.54mm, or 0.12inx0.10in), or 1206 (3.0mmx1.52mm; or 0.12inx0.060in)
- Useful for an operating current of 2A and above
- Useful for and packaged for surface mounting on the PCB

FEATURES

- RoHS compliant
- Halogen free (refers to: Br $\geq$ 900ppm, Cl $\geq$ 900ppm, Br+Cl $\geq$ 1500ppm)
- Current ratings from 1.75 to 5.0A

APPLICATIONS

- Mobile and smart phones
- Media players (MP3/MP4)
- Digital still and video cameras
- Mini notebooks
- Tablets

- Agency recognition: UL, CSA, TÜV
- Small footprint
- Fast time-to-trip

PolySwitch Resettable Devices

Low Resistivity SMD Devices

Table LR1 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)]

Part Number	Maximum Ambient Temperature										
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	80°C	85°C
nanoSMDLR Series Size 3216mm/1206mils											
nanoSMD175LR	3.00	2.60	2.20	1.75	1.70	1.40	1.20	1.00	0.80	0.60	0.50
nanoSMD200LR	3.60	3.20	2.80	2.00	1.90	1.80	1.60	1.40	1.20	1.00	0.80
nanoSMD270LR	4.00	3.50	3.00	2.70	2.60	2.20	2.00	1.60	1.40	1.20	1.10
nanoSMD350LR	5.50	4.80	4.00	3.50	3.30	2.70	2.30	1.90	1.60	1.40	1.30
nanoSMD500LR	7.40	6.60	6.00	5.00	4.90	4.60	4.20	3.70	3.30	3.00	2.80
microSMDLR Series Size 3225mm/1210mils											
microSMD190LR	3.40	2.90	2.40	1.90	1.80	1.40	1.15	0.90	0.65	0.40	0.28
microSMD200LR	3.50	3.00	2.50	2.00	1.90	1.50	1.25	1.00	0.75	0.50	0.38
microSMD250LR	4.40	3.80	3.20	2.50	2.40	1.90	1.60	1.30	1.00	0.65	0.50
microSMD350LR	5.40	4.75	4.00	3.50	3.20	2.70	2.40	2.00	1.70	1.35	1.20
microSMD450LR	7.00	6.20	5.50	4.50	4.40	3.80	3.50	3.20	2.75	2.35	2.16

Figure LR1 — Thermal Derating Curve

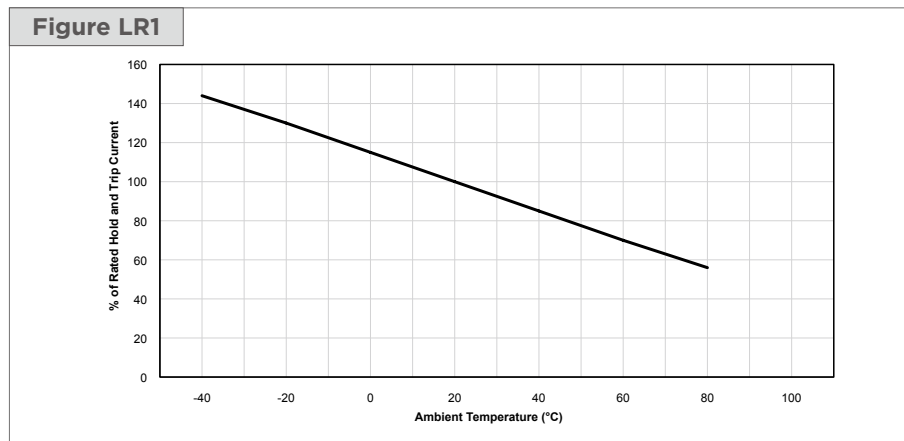


Table LR2 — Electrical Characteristics for low resistivity SMD Devices at Room Temperature

Part	I _H	I _T	V _{MAX}	I _{MAX}	P _{D MAX}	Max Time-to-Trip		R _{MIN}	R _{1MAX}	Figure for
Number	(A)	(A)	(V _{DC})	(A)	(W)	(A)	(S)	(Ω)	(Ω)	Dimensions
nanoSMDLR Series Size 3216mm/1206mils										
nanoSMD175LR	1.75	5.00	6	50	1.00	9.50	1.00	0.008	0.034	LR2
nanoSMD200LR	2.00	6.00	6	50	1.00	9.50	3.00	0.006	0.024	LR2
nanoSMD270LR	2.70	6.30	6	50	1.00	8.00	5.00	0.005	0.018	LR2
nanoSMD350LR	3.50	6.30	6	50	1.00	8.00	5.00	0.004	0.018	LR2
nanoSMD500LR	5.00	10.00	6	50	1.00	25.00	2.00	0.002	0.008	LR2
microSMDLR Series Size 3225mm/1210mils										
microSMD190LR	1.90	4.90	6	50	1.00	9.50	4.00	0.006	0.021	LR3
microSMD200LR	2.00	5.00	6	50	1.00	9.50	4.00	0.006	0.021	LR3
microSMD250LR	2.50	5.20	6	50	1.00	9.50	5.00	0.005	0.018	LR3
microSMD350LR	3.50	9.00	6	50	1.00	9.50	10.00	0.0025	0.011	LR2
microSMD450LR	4.50	9.00	5	50	1.00	25.00	2.00	0.002	0.008	LR3

PolySwitch Resettable Devices

Low Resistivity SMD Devices

Figures LR2-LR3 — Dimensions Figures

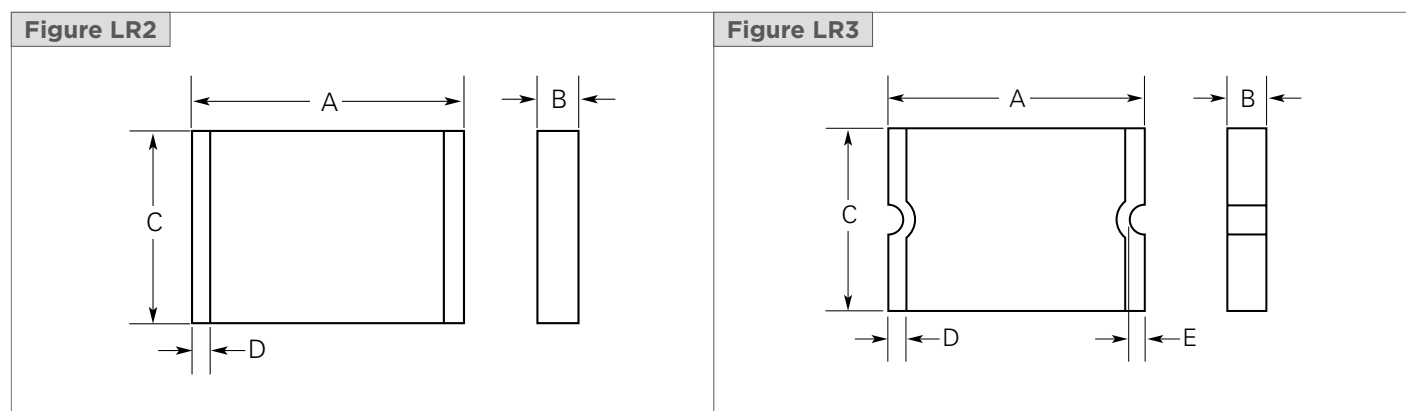


Table LR3 — Dimensions in Millimeters (Inches)

Part Number	A		B		C		D		E	Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	
nanoSMDLR Series Size 3216mm/1206mils										
nanoSMD175LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	1.37 (0.054)	1.85 (0.073)	0.25 (0.010)	0.75 (0.030)	—	LR2
nanoSMD200LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	1.37 (0.054)	1.85 (0.073)	0.25 (0.010)	0.75 (0.030)	—	LR2
nanoSMD270LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	1.37 (0.054)	1.85 (0.073)	0.25 (0.010)	0.75 (0.030)	—	LR2
nanoSMD350LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	1.37 (0.054)	1.85 (0.073)	0.25 (0.010)	0.75 (0.030)	—	LR2
nanoSMD500LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	0.80 (0.031)	1.37 (0.054)	1.85 (0.073)	0.25 (0.010)	0.75 (0.030)	—	LR2
microSMDLR Series Size 3225mm/1210mils										
microSMD190LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	LR3
microSMD200LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	LR3
microSMD250LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	LR3
microSMD350LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	—	LR2
microSMD450LR	3.00 (0.118)	3.43 (0.135)	0.50 (0.019)	1.00 (0.039)	2.35 (0.092)	2.80 (0.110)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	LR3

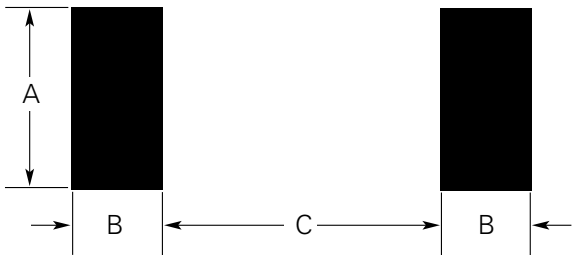
Table LR4 — Physical Characteristics [Operating Temperature Range -40°C to 85°C]

Physical Characteristics	
Terminal Pad Material	Gold with Nickel Underplate
Soldering Characteristics	ANSI/J-STD-002 Category 3
Solder Heat Withstand	per IEC-STD 68-2-20, Test Tb, Section 5, Method 1A
Flammability Resistance	per IEC 695-2-2 Needle Flame Test for 20 sec.
Recommended Storage Conditions	40°C max, 70% R.H. max; Devices May Not Meet Specified Ratings if Storage Conditions Are Exceeded.

Table LR5 — Packaging and Marking Information

Part Number	Tape & Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (in)]			Agency Recognition
				Dimension A (Nom)	Dimension B (Nom)	Dimension C (Nom)	
nanoSMDLR Series Size 3216mm/1206mils							
nanoSMD175LR	3,000	15,000	J	1.75 (0.069)	1.10 (0.043)	2.00 (0.079)	UL, CSA, TÜV
nanoSMD200LR	3,000	15,000	T	1.75 (0.069)	1.10 (0.043)	2.00 (0.079)	UL, CSA
nanoSMD270LR	3,000	15,000	L	1.75 (0.069)	1.10 (0.043)	2.00 (0.079)	UL, CSA, TÜV
nanoSMD350LR	3,000	15,000	P	1.75 (0.069)	1.10 (0.043)	2.00 (0.079)	UL, CSA, TÜV
nanoSMD500LR	3,000	15,000	H	1.75 (0.069)	1.10 (0.043)	2.00 (0.079)	UL, CSA, TÜV
microSMDLR Series Size 3225mm/1210mils							
microSMD190LR	3,000	15,000	None	2.65 (0.104)	1.00 (0.039)	2.00 (0.079)	UL, CSA
microSMD200LR	3,000	15,000	T	2.65 (0.104)	1.00 (0.039)	2.00 (0.079)	UL, CSA
microSMD250LR	3,000	15,000	L	2.65 (0.104)	1.00 (0.039)	2.00 (0.079)	UL, CSA
microSMD350LR	3,000	15,000	P	2.65 (0.104)	1.10 (0.043)	2.00 (0.079)	UL, CSA
microSMD450LR	3,000	15,000	H	2.65 (0.104)	1.00 (0.039)	2.00 (0.079)	UL

Figure LR4 — Recommended Pad Layout



Agency Recognition

UL	File # E74889 for all low resistivity SMD Devices
CSA	File # CA78165 for all low resistivity SMD Devices
TÜV	Certificate Number Available Upon Request (Certified to IEC 60730-1)

PolySwitch Resettable Devices

Low Resistivity SMD Devices

Solder Reflow Recommendation

Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-up Rate (T_{s_MAX} to T_p)	3°C/s max
Preheat	
• Temperature min (T_{s_MIN})	150°C
• Temperature max (T_{s_MAX})	200°C
• Time (t_{s_MIN} to t_{s_MAX})	60-120s
Time Maintained Above:	
• Temperature (T_L)	217°C
• Time (t_L)	60-150s
Peak/Classification Temperature (T_p)	260°C
Time within 5°C of Actual Peak Temperature	
Time (t_p)	30s max
Ramp-down Rate	2°C/s max
Time 25°C to Peak Temperature	8 mins max

Note: All temperatures refer to topside of the package measured on the package body surface.

Solder Reflow

- Recommended reflow methods:
 - IR
 - Hot air
 - Nitrogen
- Recommended maximum paste thickness: 0.25mm (0.010 inch)
- Devices can be cleaned using standard methods and aqueous solvents.
- Experience has shown the optimum conditions for forming acceptable solder fillets occur when a reasonable amount of solder paste is placed underneath each device's termination. As such, we request that customers comply with our recommended solder pad layouts.
- Customer should validate that the solder paste amount and reflow recommendations meet its application.
- We request that customer board layouts refrain from placing raised features (e.g. vias, nomenclature, traces, etc.) underneath PolySwitch devices. It is possible that raised features could negatively impact solderability performance of our devices.

Figure LR5

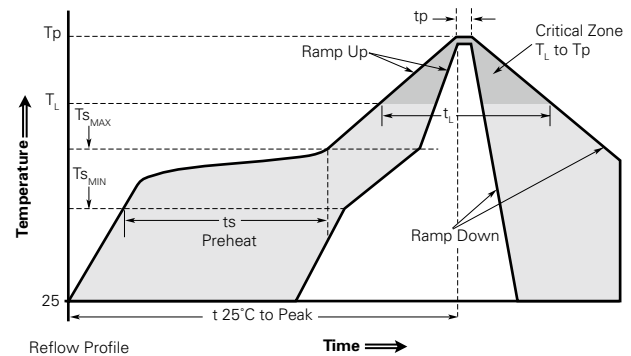


Table LR6 – Tape and Reel Specifications in Millimeters

Description	nanoSMDLR Series EIA 481-1	microSMDLR Series EIA 481-1
W	8.0 ± 0.30	8.0 ± 0.30
P ₀	4.0 ± 0.10	4.0 ± 0.10
P ₁	4.0 ± 0.10	4.0 ± 0.10
P ₂	2.0 ± 0.05	2.0 ± 0.05
A ₀	1.95 ± 0.10	2.9 ± 0.10
B ₀	3.50 +0.1/-0.08	3.55 ± 0.10
B _{1 MAX}	4.35	4.35
D ₀	1.55 ± 0.05	1.55 ± 0.05
F	3.50 ± 0.05	3.50 ± 0.05
E ₁	1.75 ± 0.10	1.75 ± 0.10
E _{2 MIN}	6.25	6.25
T MAX	0.3	0.3
T _{1 MAX}	0.1	0.1
K ₀	0.89 ± 0.10	1.27 ± 0.10
A MAX	185	185
N MIN	50	50
W ₁	12.4 + 2.0/-0.00	12.4 + 2.0/-0.00
W _{2 MAX}	14.4	14.4

Figure LR6 — EIA Referenced Taped Component Dimensions

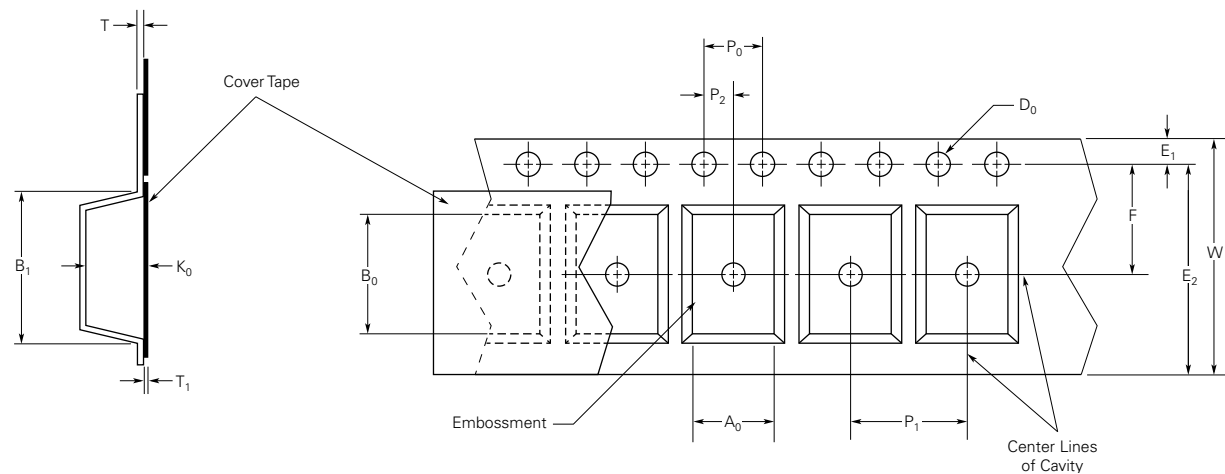
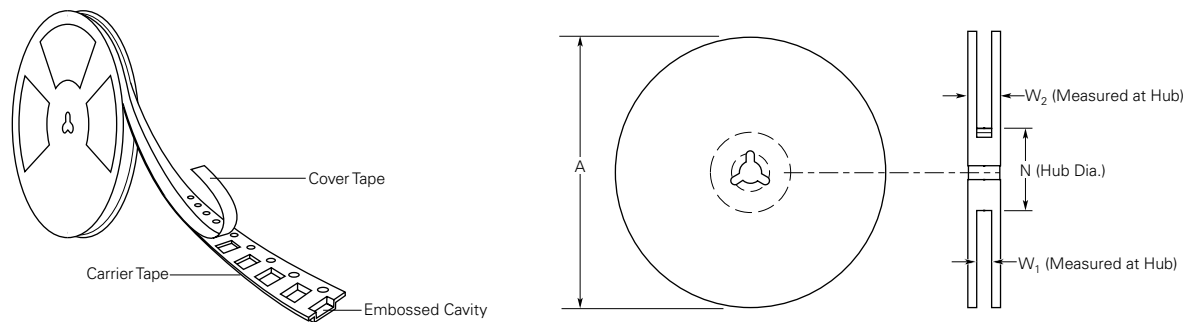


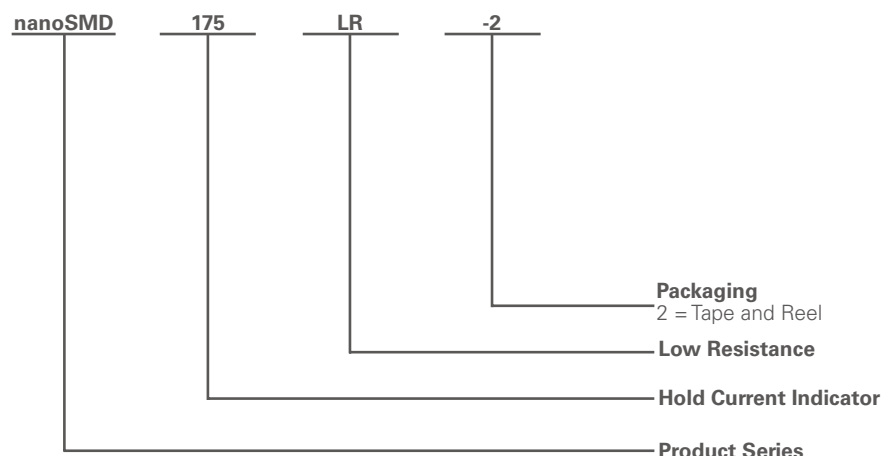
Figure LR7 — EIA Referenced Reel Dimensions



PolySwitch Resettable Devices

Low Resistivity SMD Devices

Part Numbering System



Warning :

- Users should independently evaluate the suitability of and test each product selected for their own application.
- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- These devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommodate device expansion.
- Operation in circuits with a large inductance can generate a circuit voltage ($L di/dt$) above the rated voltage of the device.

Notice:

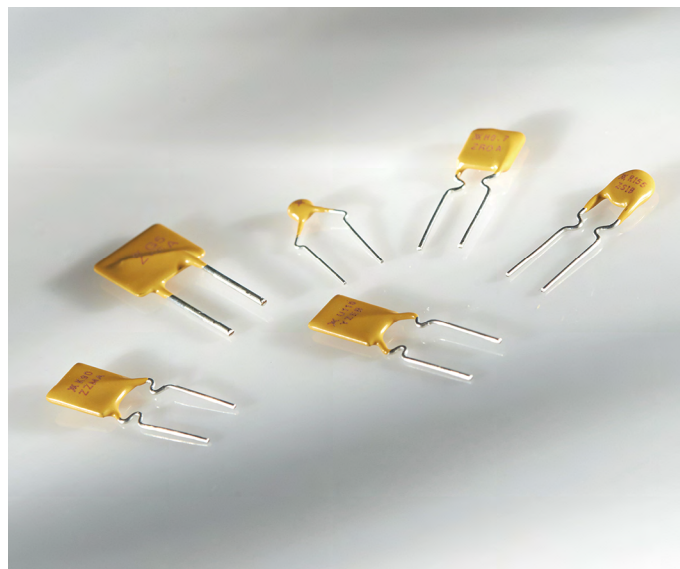
Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

POLYSWITCH RESETTABLE DEVICES

Radial-Leaded Devices

Littelfuse's PolySwitch radial-leaded products represent the most comprehensive and complete set of PPTC products available in the industry today.

- RGEF series for hold currents up to 14A
- RHEF series for flatter thermal derating and operating temperatures up to 125°C
- RUEF series for balance of voltage rating (30V) and hold current (up to 9A)
- RUSBF series for fast time-to-trip and low-resistance computer applications
- RXEF series for low hold currents (down to 50mA) and high voltage rating (up to 72V)
- RKEF series for balance of voltage rating (60V) and hold current (up to 5A)
- Now offering halogen free versions of all products



BENEFITS

- Many product choices help provide engineers more design flexibility
- Compatible with high-volume electronics assembly
- Assists in meeting regulatory requirements
- Higher voltage ratings allow use in new applications

FEATURES

- RoHS compliant
- Halogen free
(refers to: Br $\geq$ 900ppm, Cl $\geq$ 900ppm, Br+Cl $\geq$ 1500ppm)
- Broadest range of radial-leaded resettable devices available in the industry
- Current ratings from 50mA to 15A
- Voltage ratings from 6V (computer and electronic applications) to 72V
- Agency recognition : UL, CSA, TÜV, CQC**
- Fast time-to-trip
- Low resistance

**CQC only applies to RXEF, RUEF family parts

APPLICATIONS

- Satellite video receivers
- Industrial controls
- Transformers
- Modems
- CD-ROMs
- Game machines
- Phones
- Fax machines
- Analog and digital line cards
- Printers
- Intelligent appliance
- Robotic machine
- Power supply
- Security
- Lighting
- Medical application

PolySwitch Resettable Devices

Radial-Leaded Devices

Application Selection Guide

The guide below lists PolySwitch radial-leaded devices that are typically used in each of the applications described.

Specifications for the suggested device part numbers can be found in this section.

Once a part number has been selected, the user should evaluate and test each product for its intended application.

Protection Application	PolySwitch Resettable Devices — Key Selection Criteria		
	Small Size	Flatter Derating	Lower Current Higher Voltage
Electromagnetic Loads	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
Halogen Lighting	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
Lighting Ballast	RXEF (<72V)		
Loudspeakers	RXEF (<72V)		RXEF (<72V), RKEF (<60V)
Medical Equipment	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
MOSFET Devices	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
Motors, Fans and Blowers	RXEF (<72V), RGEF (<16V)	RHEF (<16V)	
POS Equipment	RXEF (<72V), RUEF (<30V)		
Process and Industrial Controls	RXEF (<72V), RUEF (<30V)		
Satellite Video Receivers	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
Security and Fire Alarm Systems	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
Test and Measurement Equipment	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
Transformers	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)
DDC Computer and Consumer Electronics	RUEF (<30V)		
Mouse and Keyboard	RUEF (<30V)		
SCSI	RUEF (<30V)		
USB	RUSBF (<16V)		
Traces and Printed Circuit Board Protection	RGEF (<16V), RUEF (<30V)	RHEF (<16V)	RXEF (<72V), RKEF (<60V)

Note: This list is not exhaustive. Littelfuse welcomes customer input for additional application ideas for PolySwitch resettable devices.

Table R1 — Product Series - Current Rating, Voltage Rating/Typical Resistance

Voltage Rating	RXEF 72V	RKEF 60V	RXEF 60V	RUEF 30V	RGEF 16V	RHEF 16V	RHEF 30V	RUSBF 16V	RUSBF 6V
Hold Current (A)									
0.050	—	—	9.20Ω	—	—	—	—	—	—
0.100	—	—	3.50Ω	—	—	—	—	—	—
0.170	—	—	4.30Ω	—	—	—	—	—	—
0.200	2.290Ω	—	—	—	—	—	—	—	—
0.250	1.600Ω	—	—	—	—	—	—	—	—
0.300	1.110Ω	—	—	—	—	—	—	—	—
0.400	0.710Ω	—	—	—	—	—	—	—	—
0.500	0.640Ω	0.425Ω	—	—	—	—	0.68Ω	—	—
0.550	—	—	—	—	—	—	—	—	—
0.650	0.400Ω	0.350Ω	—	—	—	—	—	—	—
0.700	—	—	—	—	—	—	0.42Ω	—	—
0.750	0.325Ω	0.295Ω	—	—	—	—	—	—	0.140Ω
0.900	0.255Ω	0.255Ω	—	0.095Ω	—	—	—	0.100Ω	—
1.000	—	—	—	—	—	—	0.24Ω	—	—
1.100	0.200Ω	0.225Ω	—	0.075Ω	—	—	—	0.075Ω	—
1.200	—	—	—	—	—	—	—	—	0.080Ω
1.350	0.155Ω	0.165Ω	—	0.060Ω	—	—	—	0.060Ω	—
1.550	—	—	—	—	—	—	—	—	0.058Ω
1.600	0.115Ω	0.150Ω	—	0.050Ω	—	—	—	0.050Ω	—
1.850	0.100Ω	0.106Ω	—	0.045Ω	—	—	—	0.045Ω	—
1.900	—	—	—	—	—	—	—	—	—

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R1 — Product Series - Current Rating, Voltage Rating/Typical Resistance (Cont'd)

Voltage Rating	RXEF 72V	RKEF 60V	RXEF 60V	RUEF 30V	RGEF 16V	RHEF 16V	RHEF 30V	RUSBF 16V	RUSBF 6V
Hold Current (A)									
2.000	—	—	—	—	—	0.0610Ω	—	—	—
2.500	0.065Ω	0.063Ω	—	0.030Ω	0.0380Ω	—	—	0.030Ω	—
3.000	0.050Ω	0.040Ω	—	0.035Ω	0.0514Ω	0.0430Ω	—	—	—
3.750	0.040Ω	0.029Ω	—	—	—	—	—	—	—
4.000	—	0.026Ω	—	0.020Ω	0.0300Ω	0.0320Ω	—	—	—
4.500	—	—	—	—	—	0.0290Ω	—	—	—
5.000	—	0.021Ω	—	0.020Ω	0.0192Ω	—	—	—	—
5.500	—	—	—	—	—	0.0200Ω	—	—	—
6.000	—	—	—	0.013Ω	0.0145Ω	0.0175Ω	—	—	—
6.500	—	—	—	—	—	0.0144Ω	—	—	—
7.000	—	—	—	0.013Ω	0.0105Ω	0.0132Ω	—	—	—
7.500	—	—	—	—	—	0.0120Ω	—	—	—
8.000	—	—	—	0.013Ω	0.0086Ω	0.0110Ω	—	—	—
9.000	—	—	—	0.008Ω	0.0070Ω	0.0100Ω	—	—	—
10.00	—	—	—	—	0.0056Ω	0.0083Ω	—	—	—
11.00	—	—	—	—	0.0050Ω	0.0073Ω	—	—	—
12.00	—	—	—	—	0.0046Ω	—	—	—	—
13.00	—	—	—	—	—	0.0055Ω	—	—	—
14.00	—	—	—	—	0.0040Ω	0.0050Ω	—	—	—
15.00	—	—	—	—	—	0.0050Ω	—	—	—

Table R2 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)]

Part Number	Maximum Ambient Temperature										
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
RXEF 60V											
RXEF005	0.078	0.068	0.06	0.05	0.048	0.04	0.035	0.032	0.027	0.02	—
RXEF010	0.160	0.140	0.11	0.10	0.096	0.08	0.072	0.067	0.050	0.04	—
RXEF017	0.260	0.230	0.21	0.17	0.160	0.14	0.120	0.110	0.090	0.07	—
RXEF 72V											
RXEF020	0.31	0.27	0.24	0.20	0.19	0.16	0.14	0.13	0.11	0.08	—
RXEF025	0.39	0.34	0.30	0.25	0.24	0.20	0.18	0.16	0.14	0.10	—
RXEF030	0.47	0.41	0.36	0.30	0.29	0.24	0.22	0.20	0.16	0.12	—
RXEF040	0.62	0.54	0.48	0.40	0.38	0.32	0.29	0.25	0.22	0.16	—
RXEF050	0.78	0.68	0.60	0.50	0.48	0.41	0.36	0.32	0.27	0.20	—
RXEF065	1.01	0.88	0.77	0.65	0.62	0.53	0.47	0.41	0.35	0.26	—
RXEF075	1.16	1.02	0.89	0.75	0.72	0.61	0.54	0.47	0.41	0.30	—
RXEF090	1.40	1.22	1.07	0.90	0.86	0.73	0.65	0.57	0.49	0.36	—
RXEF110	1.71	1.50	1.31	1.10	1.06	0.89	0.79	0.69	0.59	0.44	—
RXEF135	2.09	1.84	1.61	1.35	1.30	1.09	0.97	0.85	0.73	0.54	—
RXEF160	2.48	2.18	1.90	1.60	1.54	1.30	1.15	1.01	0.86	0.64	—
RXEF185	2.87	2.52	2.20	1.85	1.78	1.50	1.33	1.17	1.00	0.74	—
RXEF250	3.88	3.40	2.98	2.50	2.40	2.03	1.80	1.58	1.35	1.00	—
RXEF300	4.65	4.08	3.57	3.00	2.88	2.43	2.16	1.89	1.62	1.20	—
RXEF375	5.81	5.10	4.46	3.75	3.60	3.04	2.70	2.36	2.03	1.50	—

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R2 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)] (Cont'd)

Part Number	Maximum Ambient Temperature										
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
RKEF; 60V											
RKEF050	0.73	0.65	0.58	0.50	0.48	0.42	0.38	0.34	0.31	0.26	—
RKEF065	0.94	0.85	0.75	0.65	0.63	0.54	0.50	0.44	0.40	0.34	—
RKEF075	1.09	0.98	0.86	0.75	0.73	0.62	0.58	0.51	0.46	0.39	—
RKEF090	1.30	1.17	1.04	0.90	0.87	0.75	0.69	0.61	0.55	0.47	—
RKEF110	1.60	1.43	1.27	1.10	1.06	0.92	0.85	0.75	0.67	0.57	—
RKEF135	1.96	1.76	1.55	1.35	1.31	1.12	1.04	0.92	0.83	0.71	—
RKEF160	2.32	2.08	1.84	1.60	1.55	1.33	1.23	1.08	0.98	0.83	—
RKEF185	2.68	2.41	2.13	1.85	1.79	1.54	1.43	1.26	1.13	0.96	—
RKEF250	3.63	3.25	2.88	2.50	2.43	2.08	1.93	1.70	1.52	1.31	—
RKEF300	4.35	3.90	3.45	3.00	2.91	2.50	2.30	2.04	1.84	1.55	—
RKEF375	5.44	4.88	4.31	3.75	3.64	3.11	2.90	2.54	2.29	1.94	—
RKEF400	5.80	5.20	4.60	4.00	3.88	3.32	3.08	2.73	2.45	2.08	—
RKEF500	7.25	6.50	5.75	5.00	4.85	4.15	3.85	3.41	3.06	2.59	—
RUEF; 30V											
RUEF090	1.31	1.17	1.04	0.90	0.87	0.75	0.69	0.61	0.55	0.47	—
RUEF110	1.60	1.43	1.27	1.10	1.07	0.91	0.85	0.75	0.67	0.57	—
RUEF135	1.96	1.76	1.55	1.35	1.31	1.12	1.04	0.92	0.82	0.70	—
RUEF160	2.32	2.08	1.84	1.60	1.55	1.33	1.23	1.09	0.98	0.83	—
RUEF185	2.68	2.41	2.13	1.85	1.79	1.54	1.42	1.26	1.13	0.96	—
RUEF250	3.63	3.25	2.88	2.50	2.43	2.08	1.93	1.70	1.53	1.30	—
RUEF300	4.35	3.90	3.45	3.00	2.91	2.49	2.31	2.04	1.83	1.56	—
RUEF400	5.80	5.20	4.60	4.00	3.88	3.32	3.08	2.72	2.44	2.08	—
RUEF500	7.25	6.50	5.75	5.00	4.85	4.15	3.85	3.40	3.05	2.60	—
RUEF600	8.70	7.80	6.90	6.00	5.82	4.98	4.62	4.08	3.66	3.12	—
RUEF700	10.15	9.10	8.05	7.00	6.79	5.81	5.39	4.76	4.27	3.64	—

PolySwitch Resettable Devices

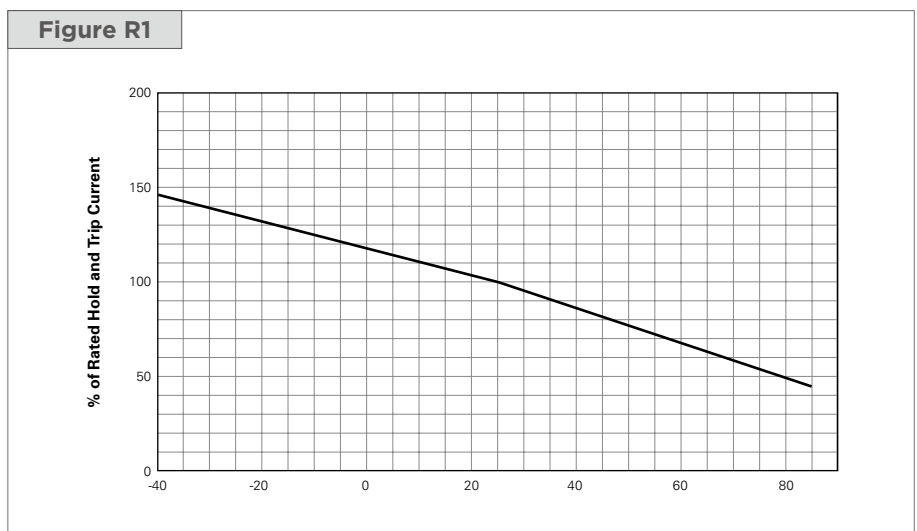
Radial-Leaded Devices

Table R2 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)] (Cont'd)

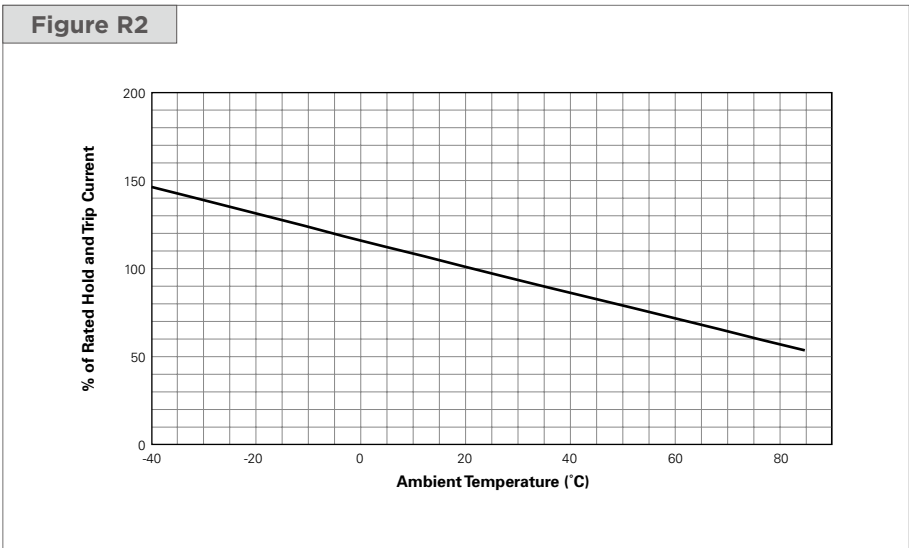
Part Number	Maximum Ambient Temperature										
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
RGEF; 16V											
RGEF900	13.2	11.9	10.7	9.4	9.00	7.9	7.2	6.4	5.6	4.2	—
RGEF1000	14.7	13.3	12.0	10.3	10.00	8.7	8.0	7.0	6.3	4.7	—
RGEF1100	16.1	14.6	13.1	11.5	11.00	9.7	8.8	7.8	6.9	5.2	—
RGEF1200	17.6	16.0	14.4	12.4	12.00	10.4	9.6	8.4	7.6	5.6	—
RGEF1400	20.5	18.7	16.8	14.5	14.00	12.1	11.2	9.8	8.9	6.5	—
RHEF; 16V - High Temperature											
RHEF200	2.71	2.49	2.26	2.06	2.00	1.77	1.60	1.46	1.34	1.11	0.49
RHEF300	4.07	3.74	3.41	3.09	3.00	2.65	2.40	2.21	2.00	1.66	0.74
RHEF400	5.57	5.11	4.65	4.22	4.00	3.62	3.29	3.01	2.73	2.27	1.01
RHEF450	6.10	5.60	5.10	4.60	4.50	4.00	3.60	3.30	3.00	2.50	1.10
RHEF550	7.47	6.86	6.24	5.66	5.50	4.85	4.41	4.04	3.66	3.05	1.36
RHEF600	8.20	7.50	6.80	6.20	6.00	5.30	4.90	4.40	4.00	3.30	1.50
RHEF650	8.80	8.10	7.40	6.70	6.50	5.70	5.30	4.80	4.30	3.60	1.60
RHEF700	9.51	8.73	7.95	7.20	7.00	6.17	5.61	5.15	4.66	3.88	1.73
RHEF750	10.20	9.40	8.60	7.70	7.50	6.60	6.10	5.60	5.00	4.10	1.90
RHEF800	10.87	9.98	9.08	8.23	8.00	7.06	6.41	5.88	5.33	4.43	1.97
RHEF900	12.21	11.19	10.16	9.26	9.00	7.97	7.20	6.56	6.04	5.01	2.19
RHEF1000	13.60	12.50	11.40	10.30	10.00	8.80	8.10	7.40	6.60	5.50	2.50
RHEF1100	14.94	13.72	12.49	11.31	11.00	9.70	8.82	8.09	7.32	6.09	2.71
RHEF1300	17.70	16.30	14.80	13.40	13.00	11.40	10.50	9.60	8.60	7.20	3.30
RHEF1400	19.01	17.46	15.89	14.40	14.00	12.35	11.22	10.29	9.32	7.76	3.45
RHEF1500	20.40	18.80	17.10	15.50	15.00	13.20	12.10	11.10	9.90	8.30	3.80
RUSBF; 6V											
RUSBF075	1.05	0.95	0.85	0.75	0.73	0.65	0.60	0.55	0.50	0.43	—
RUSBF120	1.69	1.52	1.36	1.20	1.16	1.04	0.96	0.88	0.80	0.68	—
RUSBF155	2.17	1.96	1.75	1.55	1.50	1.34	1.24	1.14	1.03	0.88	—

Figures R1-R5 — Thermal Derating Curve

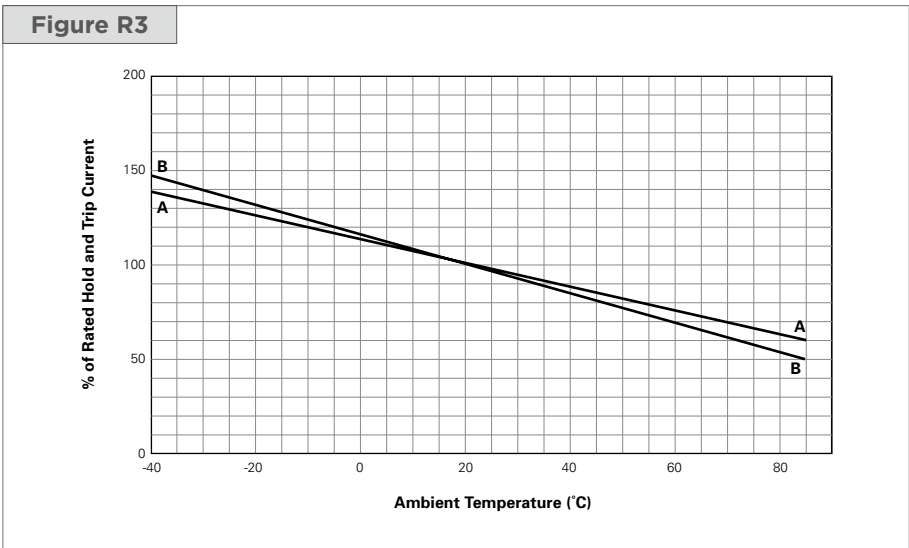
RXEF



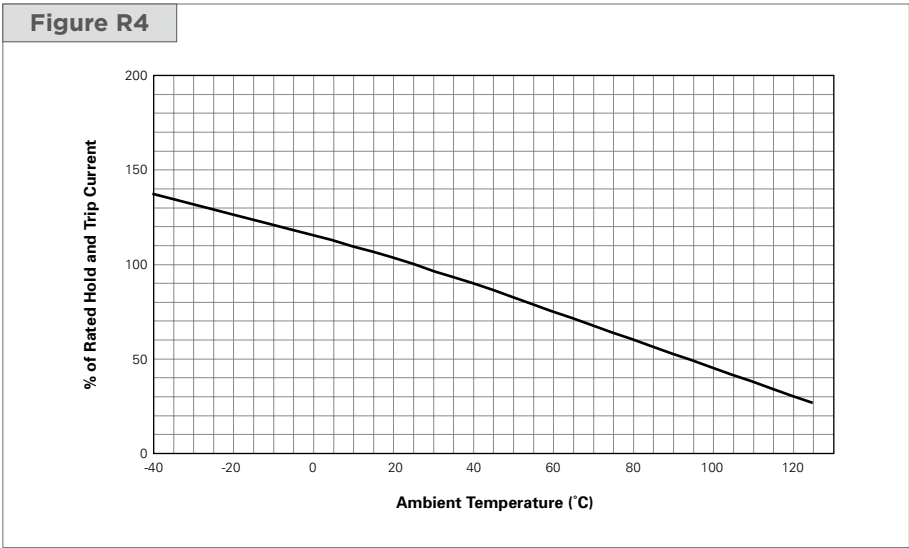
RKEF



- A = RUSBF075,
RUSBF120,
RUSBF155
- B = RUEF,
and all other RUSBF



RHEF



PolySwitch Resettable Devices
Radial-Leaded Devices

Figures R1-R5 — Thermal Derating Curve

(Cont'd)

RGEF

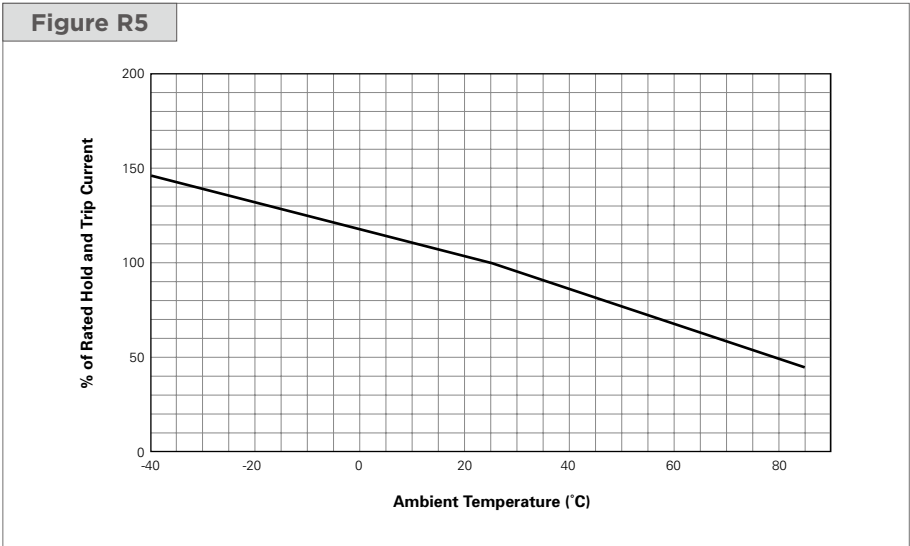


Table R3 — Electrical Characteristics

Part	I _H	I _T	V _{MAX}		I _{MAX}		P _{D Typ}	Max Time-to-trip		R _{MIN}	R _{MAX}	R _{1MAX}	Lead Size
Number	(A)	(A)	(V _{DC})	(V _{AC RMS})	(DC _{ADC})	(AC _{ARMS})	(W)	(A)	(s)	(Ω)	(Ω)	(Ω)	[mm ² (AWG)]
RXEF													
60V													
RXEF005	0.05	0.10	60	—	40	—	0.22	0.25	5.0	7.3	11.10	20.00	[0.128mm ² (26)]
RXEF010	0.10	0.20	60	—	40	—	0.38	0.50	4.0	2.5	4.50	7.50	[0.205mm ² (24)]
RXEF017	0.17	0.34	60	—	40	—	0.48	0.85	3.0	3.3	5.21	8.00	[0.205mm ² (24)]
RXEF													
72V													
RXEF020	0.20	0.40	72	72	40	40	0.41	1.00	2.2	1.83	2.75	4.40	[0.205mm ² (24)]
RXEF025	0.25	0.50	72	72	40	40	0.45	1.25	2.5	1.25	1.95	3.00	[0.205mm ² (24)]
RXEF030	0.30	0.60	72	72	40	40	0.49	1.50	3.0	0.88	1.33	2.10	[0.205mm ² (24)]
RXEF040	0.40	0.80	72	72	40	40	0.56	2.00	3.8	0.55	0.86	1.29	[0.205mm ² (24)]
RXEF050	0.50	1.00	72	72	40	40	0.77	2.50	4.0	0.50	0.77	1.17	[0.205mm ² (24)]
RXEF065	0.65	1.30	72	72	40	40	0.88	3.25	5.3	0.31	0.48	0.72	[0.205mm ² (24)]
RXEF075	0.75	1.50	72	72	40	40	0.92	3.75	6.3	0.25	0.40	0.60	[0.205mm ² (24)]
RXEF090	0.90	1.80	72	72	40	40	0.99	4.50	7.2	0.20	0.31	0.47	[0.205mm ² (24)]
RXEF110	1.10	2.20	72	72	40	40	1.50	5.50	8.2	0.15	0.25	0.38	[0.520mm ² (20)]
RXEF135	1.35	2.70	72	72	40	40	1.70	6.75	9.6	0.12	0.19	0.30	[0.520mm ² (20)]
RXEF160	1.60	3.20	72	72	40	40	1.90	8.00	11.4	0.09	0.14	0.22	[0.520mm ² (20)]
RXEF185	1.85	3.70	72	72	40	40	2.10	9.25	12.6	0.08	0.12	0.19	[0.520mm ² (20)]
RXEF250	2.50	5.00	72	72	40	40	2.50	12.50	15.6	0.05	0.08	0.13	[0.520mm ² (20)]
RXEF300	3.00	6.00	72	72	40	40	2.80	15.00	19.8	0.04	0.06	0.10	[0.520mm ² (20)]
RXEF375	3.75	7.50	72	72	40	40	3.20	18.75	24.0	0.03	0.05	0.08	[0.520mm ² (20)]

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R3 — Electrical Characteristics

(Cont'd)

Part Number	I _H (A)	I _T (A)	V _{MAX}		I _{MAX}		P _D Typ (W)	Max Time-to-trip		R _{MIN} (Ω)	R _{MAX} (Ω)	R _{1MAX} (Ω)	Lead Size [mm ² (AWG)]
			(V _{DC})	(V _{AC RMS})	(DC _{ADC})	(AC _{ARMS})		(A)	(s)				
RKEF; 60V													
RKEF050	0.50	1.00	60	—	40	—	1.00	8.00	0.8	0.320	0.529	0.900	[0.205mm ² (24)]
RKEF065	0.65	1.30	60	—	40	—	1.25	8.00	1.0	0.250	0.450	0.720	[0.205mm ² (24)]
RKEF075	0.75	1.50	60	—	40	—	1.40	8.00	1.5	0.200	0.390	0.640	[0.205mm ² (24)]
RKEF090	0.90	1.80	60	—	40	—	1.50	8.00	2.0	0.190	0.320	0.520	[0.205mm ² (24)]
RKEF110	1.10	2.20	60	—	40	—	2.20	8.00	3.0	0.170	0.280	0.470	[0.520mm ² (20)]
RKEF135	1.35	2.70	60	—	40	—	2.30	8.00	4.5	0.110	0.220	0.370	[0.520mm ² (20)]
RKEF160	1.60	3.20	60	—	40	—	2.40	8.20	9.0	0.100	0.200	0.320	[0.520mm ² (20)]
RKEF185	1.85	3.70	60	—	40	—	2.60	9.25	12.6	0.060	0.152	0.250	[0.520mm ² (20)]
RKEF250	2.50	5.00	60	—	40	—	2.80	12.50	15.6	0.040	0.085	0.140	[0.520mm ² (20)]
RKEF300	3.00	6.00	60	—	40	—	3.20	15.00	19.8	0.030	0.050	0.080	[0.520mm ² (20)]
RKEF375	3.75	7.50	60	—	40	—	3.40	18.75	22.0	0.017	0.040	0.060	[0.520mm ² (20)]
RKEF400	4.00	8.00	60	—	40	—	3.70	20.00	24.0	0.014	0.038	0.060	[0.520mm ² (20)]
RKEF500	5.00	10.00	60	—	40	—	5.00	25.00	28.0	0.012	0.030	0.050	[0.520mm ² (20)]
RUEF; 30V													
RUEF090	0.90	1.80	30	30	100	70	0.60	4.50	5.9	0.070	0.120	0.22	[0.205mm ² (24)]
RUEF110	1.10	2.20	30	30	100	70	0.70	5.50	6.6	0.070	0.100	0.17	[0.205mm ² (24)]
RUEF135	1.35	2.70	30	30	100	70	0.80	6.75	7.3	0.040	0.080	0.13	[0.205mm ² (24)]
RUEF160	1.60	3.20	30	30	100								

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R3 — Electrical Characteristics

(Cont'd)

Part	I_H	I_T	V_{MAX}		I_{MAX}		$P_{D\text{ Typ}}$	Max Time-to-trip		R_{MIN}	R_{MAX}	R_{1MAX}	Lead Size
Number	(A)	(A)	(V_{DC})	($V_{AC\text{ RMS}}$)	(DC_{ADC})	(AC_{ARMS})	(W)	(A)	(s)	(Ω)	(Ω)	(Ω)	[mm ² (AWG)]
RHEF*; 16V - High Temperature													
RHEF200	2.0	3.8	16	—	100	—	1.4	10.0	4.3	0.0450	0.07400	0.1100	[0.205mm ² (24)]
RHEF300	3.0	6.0	16	—	100	—	3.0	15.0	5.0	0.0330	0.05300	0.0790	[0.520mm ² (20)]
RHEF400	4.0	7.5	16	—	100	—	3.3	20.0	5.0	0.0240	0.04000	0.0600	[0.520mm ² (20)]
RHEF450	4.5	7.8	16	—	100	—	3.6	22.5	3.0	0.0220	0.03600	0.0540	[0.520mm ² (20)]
RHEF55													

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R4 — Dimensions and Weights

(Cont'd)

Part Number	Dimensions in Millimeters (Inches)												Figure	Device Mass (g) (Only for Reference)	
	A		B		C		D		E		F	H	J		
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Typ	Typ	Typ		
RKEF; 60V															
RKEF050	—	7.10 (0.28)	—	11.43 (0.45)	4.32 (0.17)	5.84 (0.23)	7.60 (0.30)	—	—	3.56 (0.14)	—	—	—	R10, R13, R14	0.166
RKEF065	—	7.11 (0.28)	—	12.20 (0.48)	4.32 (0.17)	5.84									

PolySwitch Resettable Devices

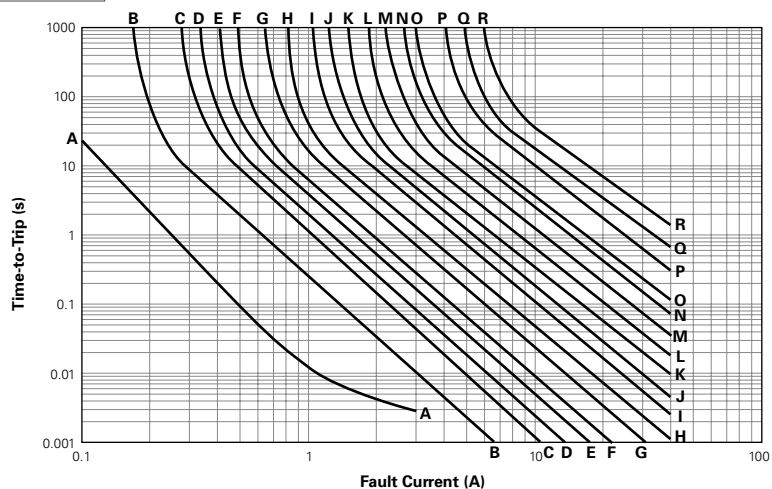
Radial-Leaded Devices

Figures R15-R20 — Typical Time-to-Trip Curves at 20°C

RXEF

A = RXEF005	J = RXEF075
B = RXEF010	K = RXEF090
C = RXEF017	L = RXEF110
D = RXEF020	M = RXEF135
E = RXEF025	N = RXEF160
F = RXEF030	O = RXEF185
G = RXEF040	P = RXEF250
H = RXEF050	Q = RXEF300
I = RXEF065	R = RXEF375

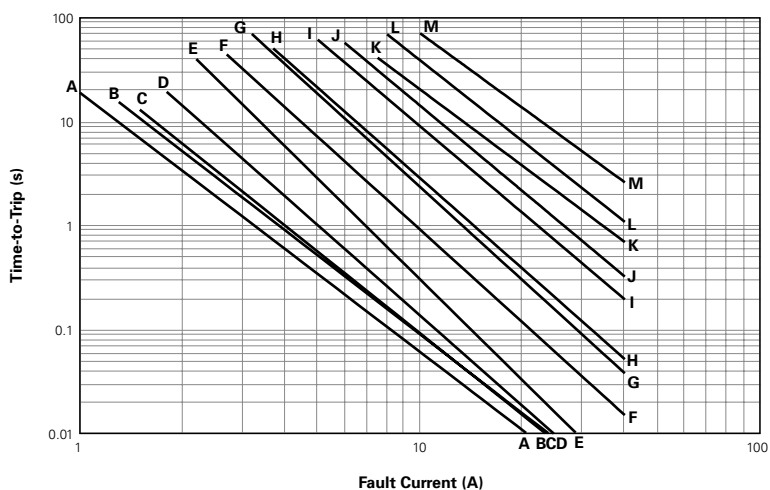
Figure R15



RKEF

A = RKEF050	J = RKEF300
B = RKEF065	K = RKEF375
C = RKEF075	L = RKEF400
D = RKEF090	M = RKEF500
E = RKEF110	
F = RKEF135	
G = RKEF160	
H = RKEF185	
I = RKEF250	

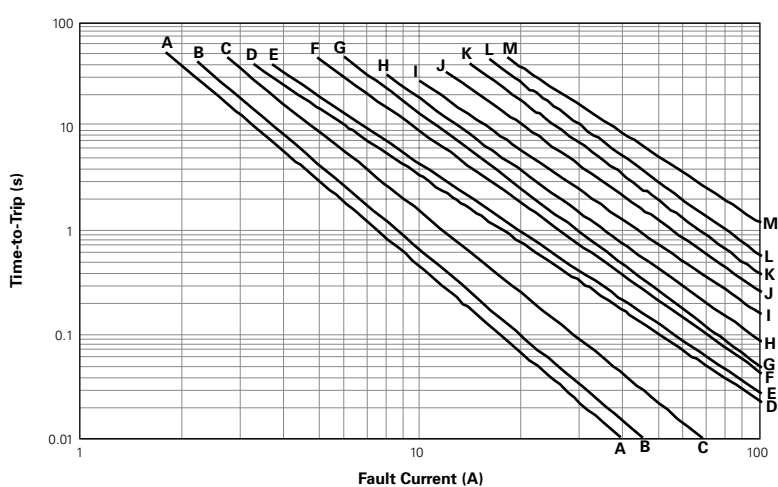
Figure R16



RUEF

A = RUEF090	H = RUEF400
B = RUEF110	I = RUEF500
C = RUEF135	J = RUEF600
D = RUEF160	K = RUEF700
E = RUEF185	L = RUEF800
F = RUEF250	M = RUEF900
G = RUEF300	

Figure R17



PolySwitch Resettable Devices

Radial-Leaded Devices

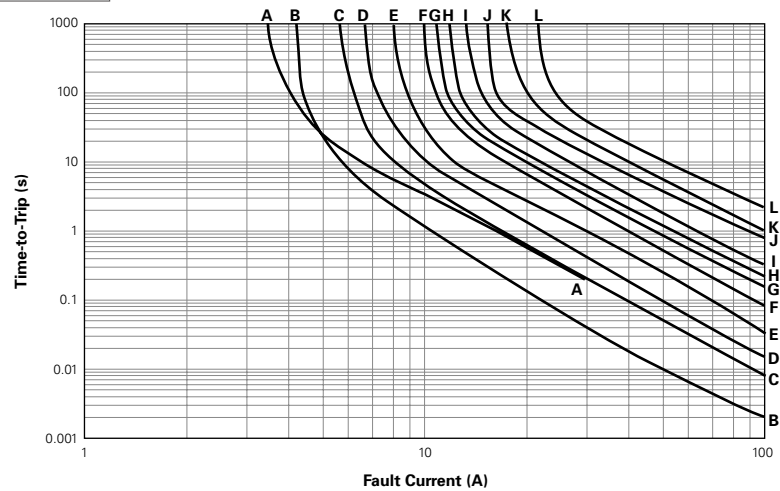
Figures R15-R20 — Typical Time-to-Trip Curves at 20°C

(Cont'd)

RGEF (data at 25°C)

A = RGEF250	G = RGEF800
B = RGEF300	H = RGEF900
C = RGEF400	I = RGEF1000
D = RGEF500	J = RGEF1100
E = RGEF600	K = RGEF1200
F = RGEF700	L = RGEF1400

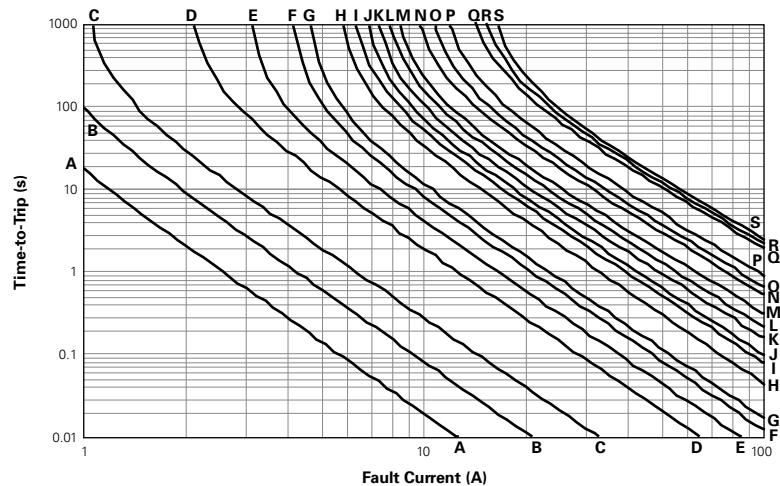
Figure R18



RHEF (data at 25°C)

A = RHEF050	K = RHEF700
B = RHEF070	L = RHEF750
C = RHEF100	M = RHEF800
D = RHEF200	N = RHEF900
E = RHEF300	O = RHEF1000
F = RHEF400	P = RHEF1100
G = RHEF450	Q = RHEF1300
H = RHEF550	R = RHEF1400
I = RHEF600	S = RHEF1500
J = RHEF650	

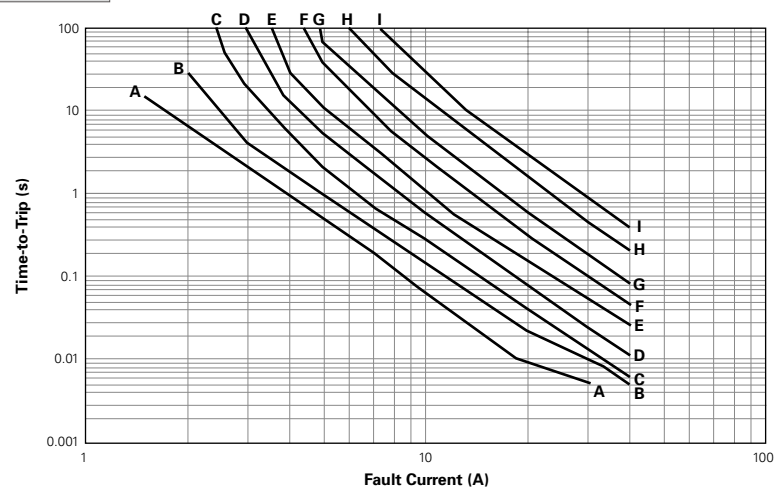
Figure R19



RUSBF

A = RUSBF075
B = RUSBF090
C = RUSBF110
D = RUSBF120
E = RUSBF135
F = RUSBF155
G = RUSBF160
H = RUSBF185
I = RUSBF250

Figure R20



PolySwitch Resettable Devices

Radial-Leaded Devices

Table R5 — Physical Characteristics and Environmental Specifications

RXEF		
Physical Characteristics		
Lead Material	RXEF005	: Tin-plated Nickel-copper Alloy, 0.128mm ² (26AWG), ø0.40mm (0.016in)
	RXEF010	: Tin-plated Nickel-copper Alloy, 0.205mm ² (24AWG), ø0.51mm (0.020in)
	RXEF017 to 040	: Tin-plated Copper-clad Steel, 0.205mm ² (24AWG), ø0.51mm (0.020in)
	RXEF050 to 090	: Tin-plated Copper, 0.205mm ² (24AWG), ø0.51mm (0.020in)
	RXEF110 to 375	: Tin-plated Copper, 0.52mm ² (20AWG), ø0.81mm (0.032in)
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3	
	RXEF005, RXEF010 Meet ANSI/J-STD-002 Category 1	
Solder Heat Withstand	RXEF005- RXEF025: per IEC-STD 68-2-20, Test Tb, Method 1a, Condition a;	
	Can Withstand 5s at 260°C ±5°C	
	All Other Sizes : per IEC-STD 68-2-20, Test Tb, Method 1a, Condition b;	
	Can Withstand 10s at 260°C ±5°C	
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0	
Operation Temperature	-40°C~85°C	

Note: Devices are not designed to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	-40°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85%RH, 1000 hrs	±10%
Thermal Shock	85°C, -40°C (10 Times)	±10%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

RKEF		
Physical Characteristics		
Lead Material	RKEF050 to 090	: Tin-plated Copper, 0.205mm ² (24AWG), ø0.51mm (0.020in)
	RKEF110 to 500	: Tin-plated Copper, 0.52mm ² (20AWG), ø0.81mm (0.032in)
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3	
Solder Heat Withstand	RKEF050-RKEF185: per IEC-STD 68-2-20, Test Tb, Method 1a, Condition a;	
	Can Withstand 5s at 260°C ±5°C	
	All Other Sizes : per IEC-STD 68-2-20, Test Tb, Method 1a, Condition b;	
	RKEF Can Withstand 10s at 260°C ±5°C	
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0	
Operation Temperature	-40°C~85°C	

Note: Devices are not designed to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	-40°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85%RH, 1000 hrs	±10%
Thermal Shock	85°C, -40°C (10 Times)	±10%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R5 — Physical Characteristics and Environmental Specifications

(Cont'd)

RUEF	
Physical Characteristics	
Lead Material	RUEF090 to RUEF250: Tin-plated Copper-clad Steel, 0.205mm ² (24AWG) RUEF300 to RUEF900: Tin-plated Copper, 0.52mm ² (20AWG), ø0.81mm (0.032in)
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3
Solder Heat Withstand	per IEC-STD 68-2-20, Test Tb, Method1A, Condition B, Can Withstand 10s at 260°C ±5°C
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0
Operation Temperature	-40°C~85°C

Note: Devices are not designed to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%
Thermal Shock	85°C, -40°C (10 times)	±5%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

RUSBF	
Physical Characteristics	
Lead Material	RUSBF075 : Tin-plated Nickel-copper Alloy, 0.205mm ² (24AWG), ø0.51mm/0.020in RUSBF090 to RUSBF250: Tin-plated Copper-clad Steel, 0.205mm ² (24AWG), ø0.51mm/0.020in
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3 Except RUSBF075 Meet ANSI/J-STD-002 Category 1
Solder Heat Withstand	RUSBF120: per IEC-STD 68-2-20, Test Tb, Method 1A, Condition A; Can Withstand 5s at 260°C ±5°C All Others : per IEC-STD 68-2-20, Test Tb, Method 1A, Condition B; Can Withstand 10s at 260°C ±5°C
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0
Operation Temperature	-40°C~85°C

Note: Devices are not designed to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%
Thermal Shock	85°C, -40°C (10 Times)	±5%
Solvent Resistance	MIL-STD-202, Method 215F	No change

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R5 — Physical Characteristics and Environmental Specifications

(Cont'd)

RGEF		
Physical Characteristics		
Lead Material	RGEF250	: Tin-plated Copper-clad Steel, 0.205mm ² (24AWG), ø0.51mm/0.020in
	RGEF300 to RGEF1100	: Tin-plated Copper, 0.52mm ² (20AWG), ø0.81mm/0.032in
	RGEF1200 to RGEF1400	: Tin-plated Copper, 0.82mm ² (18AWG), ø1.0mm/0.04in
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3	
Solder Heat Withstand	RGEF250 and RGEF400 : per IEC 68-2-20, Test Tb, Method 1a, Condition a; can withstand 5s at 260°C ±5°C	
	RGEF500 to RGEF1400 : per IEC 68-2-20, Test Tb, Method 1a, Condition b; can withstand 10s at 260°C ±5°C	
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0	
Operation Temperature	-40°C~85°C	

Note: Devices are not designed to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	-40°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%
Thermal Shock	85°C, -40°C (10 Times)	±5%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

RHEF		
Physical Characteristics		
Lead Material	RHEF050 to RHEF200	: Tin-plated Copper-clad Steel, 0.205mm ² (24AWG), ø0.51mm/0.020in
	RHEF300 to RHEF1100	: Tin-plated Copper, 0.52mm ² (20AWG), ø0.81mm/0.032in
	RHEF1300 to RHEF1500	: Tin-plated Copper, 0.82mm ² (18AWG), ø1.0mm/0.04in
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3	
Solder Heat Withstand	per IEC 68-2-20, Test Tb, Method 1A, Condition B; Can Withstand 10s at 260°C ±5°C	
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0	
Operation Temperature	-40°C~125°C	

Note: Devices are not designed to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%
Thermal Shock	125°C, -40°C (10 Times)	±5%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

Storage Conditions

Storage Conditions 40°C max, 70% RH max; devices should remain in original sealed bags prior to use.

Devices may not meet specified values if these storage conditions are exceeded.

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R6 — Packaging and Marking Information

Part Number	Bag Quantity	Tape and Reel Quantity	Ammo Pack Quantity	Standard Package Quantity	Part Marking	Agency Recognition
RXEF 60V						
RXEF005	500	—	—	10,000	—	UL, CSA, TÜV, CQC
RXEF005-2	—	3,000	—	15,000	—	UL, CSA, TÜV, CQC
RXEF005-AP	—	—	2,000	10,000	—	UL, CSA, TÜV, CQC
RXEF010	500	—	—	10,000	X10	UL, CSA, TÜV, CQC
RXEF010-2	—	3,000	—	15,000	X10	UL, CSA, TÜV, CQC
RXEF010-AP	—	—	2,000	10,000	X10	UL, CSA, TÜV, CQC
RXEF017	500	—	—	10,000	X17	UL, CSA, TÜV, CQC
RXEF017-2	—	2,500	—	12,500	X17	UL, CSA, TÜV, CQC
RXEF017-AP	—	—	2,000	10,000	X17	UL, CSA, TÜV, CQC
RXEF 72V						
RXEF020	500	—	—	10,000	X20	UL, CSA, TÜV, CQC
RXEF020-2	—	3,000	—	15,000	X20	UL, CSA, TÜV, CQC
RXEF020-AP	—	—	2,000	10,000	X20	UL, CSA, TÜV, CQC
RXEF025	500	—	—	10,000	X25	UL, CSA, TÜV, CQC
RXEF025-2	—	3,000	—	15,000	X25	UL, CSA, TÜV, CQC
RXEF025-AP	—	—	2,000	10,000	X25	UL, CSA, TÜV, CQC
RXEF030	500	—	—	10,000	X30	UL, CSA, TÜV, CQC
RXEF030-2	—	3,000	—	15,000	X30	UL, CSA, TÜV, CQC
RXEF030-AP	—	—	2,000	10,000	X30	UL, CSA, TÜV, CQC
RXEF040	500	—	—	10,000	X40	UL, CSA, TÜV, CQC
RXEF040-2	—	3,000	—	15,000	X40	UL, CSA, TÜV, CQC
RXEF040-AP	—	—	2,000	10,000	X40	UL, CSA, TÜV, CQC
RXEF050	500	—	—	10,000	X50	UL, CSA, TÜV, CQC
RXEF050-2	—	3,000	—	15,000	X50	UL, CSA, TÜV, CQC
RXEF050-AP	—	—	2,000	10,000	X50	UL, CSA, TÜV, CQC
RXEF065	500	—	—	10,000	X65	UL, CSA, TÜV, CQC
RXEF065-2	—	3,000	—	15,000	X65	UL, CSA, TÜV, CQC
RXEF065-AP	—	—	2,000	10,000	X65	UL, CSA, TÜV, CQC
RXEF075	500	—	—	10,000	X75	UL, CSA, TÜV, CQC
RXEF075-2	—	3,000	—	15,000	X75	UL, CSA, TÜV, CQC
RXEF075-AP	—	—	2,000	10,000	X75	UL, CSA, TÜV, CQC
RXEF090	500	—	—	10,000	X90	UL, CSA, TÜV, CQC
RXEF090-2	—	3,000	—	15,000	X90	UL, CSA, TÜV, CQC
RXEF090-AP	—	—	2,000	10,000	X90	UL, CSA, TÜV, CQC
RXEF110	500	—	—	10,000	X110	UL, CSA, TÜV, CQC
RXEF110-2	—	1,500	—	7,500	X110	UL, CSA, TÜV, CQC
RXEF110-AP	—	—	1,000	5,000	X110	UL, CSA, TÜV, CQC
RXEF135	500	—	—	10,000	X135	UL, CSA, TÜV, CQC
RXEF135-2	—	1,500	—	7,500	X135	UL, CSA, TÜV, CQC
RXEF135-AP	—	—	1,000	5,000	X135	UL, CSA, TÜV, CQC
RXEF160	500	—	—	10,000	X160	UL, CSA, TÜV, CQC
RXEF160-2	—	1,500	—	7,500	X160	UL, CSA, TÜV, CQC
RXEF160-AP	—	—	1,000	5,000	X160	UL, CSA, TÜV, CQC
RXEF185	500	—	—	10,000	X185	UL, CSA, TÜV, CQC
RXEF185-2	—	1,500	—	7,500	X185	UL, CSA, TÜV, CQC
RXEF185-AP	—	—	1,000	5,000	X185	UL, CSA, TÜV, CQC
RXEF250	250	—	—	5,000	X250	UL, CSA, TÜV, CQC
RXEF250-2	—	1,000	—	5,000	X250	UL, CSA, TÜV, CQC
RXEF250-AP	—	—	1,000	5,000	X250	UL, CSA, TÜV, CQC

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R6 — Packaging and Marking Information

(Cont'd)

Part Number	Bag Quantity	Tape and Reel Quantity	Ammo Pack Quantity	Standard Package Quantity	Part Marking	Agency Recognition
RXEF						
72V						
RXEF300	250	—	—	5,000	X300	UL, CSA, TÜV, CQC
RXEF300-2	—	1,000	—	5,000	X300	UL, CSA, TÜV, CQC
RXEF300-AP	—	—	1,000	5,000	X300	UL, CSA, TÜV, CQC
RXEF375	250	—	—	5,000	X375	UL, CSA, TÜV, CQC
RKEF						
60V						
RKEF050	500	—	—	10,000	K50	UL, CSA, TÜV
RKEF065	500	—	—	10,000	K65	UL, CSA, TÜV
RKEF075	500	—	—	10,000	K75	UL, CSA, TÜV
RKEF090	500	—	—	10,000	K90	UL, CSA, TÜV
RKEF110	500	—	—	10,000	K110	UL, CSA, TÜV
RKEF135	500	—	—	10,000	K135	UL, CSA, TÜV
RKEF160	500	—	—	10,000	K160	UL, CSA, TÜV
RKEF185	500	—	—	10,000	K185	UL, CSA, TÜV
RKEF250	500	—	—	10,000	K250	UL, CSA, TÜV
RKEF300	250	—	—	5,000	K300	UL, CSA, TÜV
RKEF375	250	—	—	5,000	K375	UL, CSA, TÜV
RKEF400	250	—	—	5,000	K400	UL, CSA, TÜV
RKEF500	250	—	—	5,000	K500	UL, CSA, TÜV
RUEF						
30V						
RUEF090	500	—	—	10,000	U90	UL, CSA, TÜV, CQC
RUEF090-2	—	3,000	—	15,000	U90	UL, CSA, TÜV, CQC
RUEF090-AP	—	—	2,000	10,000	U90	UL, CSA, TÜV, CQC
RUEF110	500	—	—	10,000	U110	UL, CSA, TÜV, CQC
RUEF110-2	—	3,000	—	15,000	U110	UL, CSA, TÜV, CQC
RUEF110-AP	—	—	2,000	10,000	U110	UL, CSA, TÜV, CQC
RUEF135	500	—	—	10,000	U135	UL, CSA, TÜV, CQC
RUEF135-2	—	3,000	—	15,000	U135	UL, CSA, TÜV, CQC
RUEF135-AP	—	—	2,000	10,000	U135	UL, CSA, TÜV, CQC
RUEF160	500	—	—	10,000	U160	UL, CSA, TÜV, CQC
RUEF160-2	—	3,000	—	15,000	U160	UL, CSA, TÜV, CQC
RUEF160-AP	—	—	2,000	10,000	U160	UL, CSA, TÜV, CQC
RUEF185	500	—	—	10,000	U185	UL, CSA, TÜV, CQC
RUEF185-2	—	3,000	—	15,000	U185	UL, CSA, TÜV, CQC
RUEF185-AP	—	—	2,000	10,000	U185	UL, CSA, TÜV, CQC
RUEF250	500	—	—	10,000	U250	UL, CSA, TÜV, CQC
RUEF250-2	—	3,000	—	15,000	U250	UL, CSA, TÜV, CQC
RUEF250-AP	—	—	2,000	10,000	U250	UL, CSA, TÜV, CQC
RUEF300	500	—	—	10,000	U300	UL, CSA, TÜV, CQC
RUEF300-2	—	2,500	—	12,500	U300	UL, CSA, TÜV, CQC
RUEF300-AP	—	—	1,000	5,000	U300	UL, CSA, TÜV, CQC
RUEF400	500	—	—	10,000	U400	UL, CSA, TÜV, CQC
RUEF400-2	—	1,500	—	7,500	U400	UL, CSA, TÜV, CQC
RUEF400-AP	—	—	1,000	5,000	U400	UL, CSA, TÜV, CQC
RUEF500	250	—	—	5,000	U500	UL, CSA, TÜV, CQC
RUEF500-2	—	1,500	—	7,500	U500	UL, CSA, TÜV, CQC
RUEF500-AP	—	—	1,000	5,000	U500	UL, CSA, TÜV, CQC
RUEF600	250	—	—	5,000	U600	UL, CSA, TÜV, CQC
RUEF600-2	—	1,000	—	5,000	U600	UL, CSA, TÜV, CQC

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R6 — Packaging and Marking Information

(Cont'd)

Part Number	Bag Quantity	Tape and Reel Quantity	Ammo Pack Quantity	Standard Package Quantity	Part Marking	Agency Recognition
RUEF						
30V						
RUEF600-AP	—	—	1,000	5,000	U600	UL, CSA, TÜV, CQC
RUEF700	250	—	—	5,000	U700	UL, CSA, TÜV, CQC
RUEF700-2	—	1,000	—	5,000	U700	UL, CSA, TÜV, CQC
RUEF700-AP	—	—	1,000	5,000	U700	UL, CSA, TÜV, CQC
RUEF800	250	—	—	5,000	U800	UL, CSA, TÜV, CQC
RUEF800-2	—	1,000	—	5,000	U800	UL, CSA, TÜV, CQC
RUEF800-AP	—	—	1,000	5,000	U800	UL, CSA, TÜV, CQC
RUEF900	250	—	—	5,000	U900	UL, CSA, TÜV, CQC
RUEF900-2	—	1,000	—	4,000	U900	UL, CSA, TÜV, CQC
RUEF900-AP	—	—	1,000	4,000	U900	UL, CSA, TÜV, CQC
RHEF						
30V - High Temperature						
RHEF050	500	—	—	10,000	H0.5	UL, CSA, TÜV
RHEF050-2	—	2,500	—	12,500	H0.5	UL, CSA, TÜV
RHEF070	500	—	—	10,000	H0.7	UL, CSA, TÜV
RHEF070-2	—	2,500	—	12,500	H0.7	UL, CSA, TÜV
RHEF100	500	—	—	10,000	H1	UL, CSA, TÜV
RHEF100-2	—	2,500	—	12,500	H1	UL, CSA, TÜV
RUSBF						
16V						
RUSBF090	500	—	—	10,000	R90	UL, CSA, TÜV
RUSBF090-2	—	3,000	—	15,000	R90	UL, CSA, TÜV
RUSBF090-AP	—	—	2,000	10,000	R90	UL, CSA, TÜV
RUSBF110	500	—	—	10,000	R110	UL, CSA, TÜV
RUSBF110-2	—	3,000	—	15,000	R110	UL, CSA, TÜV
RUSBF110-AP	—	—	2,000	10,000	R110	UL, CSA, TÜV
RUSBF135	500	—	—	10,000	R135	UL, CSA, TÜV
RUSBF135-2	—	3,000	—	15,000	R135	UL, CSA, TÜV
RUSBF135-AP	—	—	2,000	10,000	R135	UL, CSA, TÜV
RUSBF160	500	—	—	10,000	R160	UL, CSA, TÜV
RUSBF160-2	—	3,000	—	15,000	R160	UL, CSA, TÜV
RUSBF160-AP	—	—	2,000	10,000	R160	UL, CSA, TÜV
RUSBF185	500	—	—	10,000	R185	UL, CSA, TÜV
RUSBF185-2	—	3,000	—	15,000	R185	UL, CSA, TÜV
RUSBF185-AP	—	—	2,000	10,000	R185	UL, CSA, TÜV
RUSBF250	500	—	—	10,000	R250	UL, CSA, TÜV
RUSBF250-2	—	3,000	—	15,000	R250	UL, CSA, TÜV
RUSBF250-AP	—	—	2,000	10,000	R250	UL, CSA, TÜV
RGEF						
16V						
RGEF250	500	—	—	10,000	G2.5	UL, CSA, TÜV
RGEF250-2	—	3,000	—	15,000	G2.5	UL, CSA, TÜV
RGEF250-AP	—	—	2,000	10,000	G2.5	UL, CSA, TÜV
RGEF300	500	—	—	10,000	G3	UL, CSA, TÜV
RGEF300-2	—	2,500	—	12,500	G3	UL, CSA, TÜV
RGEF300-AP	—	—	2,000	10,000	G3	UL, CSA, TÜV
RGEF400	500	—	—	10,000	G4	UL, CSA, TÜV
RGEF400-2	—	2,500	—	12,500	G4	UL, CSA, TÜV
RGEF400-AP	—	—	2,000	10,000	G4	UL, CSA, TÜV
RGEF500	500	—	—	10,000	G5	UL, CSA, TÜV

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R6 — Packaging and Marking Information

(Cont'd)

Part Number	Bag Quantity	Tape and Reel Quantity	Ammo Pack Quantity	Standard Package Quantity	Part Marking	Agency Recognition
RGEF						
16V						
RGEF500-2	—	2,000	—	10,000	G5	UL, CSA, TÜV
RGEF500-AP	—	—	2,000	10,000	G5	UL, CSA, TÜV
RGEF600	500	—	—	10,000	G6	UL, CSA, TÜV
RGEF600-2	—	2,000	—	10,000	G6	UL, CSA, TÜV
RGEF600-AP	—	—	2,000	10,000	G6	UL, CSA, TÜV
RGEF700	500	—	—	10,000	G7	UL, CSA, TÜV
RGEF700-2	—	1,500	—	7,500	G7	UL, CSA, TÜV
RGEF700-AP	—	—	1,500	7,500	G7	UL, CSA, TÜV
RGEF800	500	—	—	10,000	G8	UL, CSA, TÜV
RGEF800-2	—	1,500	—	7,500	G8	UL, CSA, TÜV
RGEF800-AP	—	—	1,500	7,500	G8	UL, CSA, TÜV
RGEF900	500	—	—	10,000	G9	UL, CSA, TÜV
RGEF900-2	—	1,000	—	5,000	G9	UL, CSA, TÜV
RGEF900-AP	—	—	1,000	5,000	G9	UL, CSA, TÜV
RGEF1000	250	—	—	5,000	G10	UL, CSA, TÜV
RGEF1000-2	—	1,000	—	5,000	G10	UL, CSA, TÜV
RGEF1000-AP	—	—	1,000	5,000	G10	UL, CSA, TÜV
RGEF1100	250	—	—	5,000	G11	UL, CSA, TÜV
RGEF1100-2	—	1,000	—	5,000	G11	UL, CSA, TÜV
RGEF1100-AP	—	—	1,000	5,000	G11	UL, CSA, TÜV
RGEF1200	250	—	—	5,000	G12	UL, CSA, TÜV
RGEF1200-2	—	1,000	—	5,000	G12	UL, CSA, TÜV
RGEF1200-AP	—	—	1,000	5,000	G12	UL, CSA, TÜV
RGEF1400	250	—	—	5,000	G14	UL, CSA, TÜV
RGEF1400-2	—	1,000	—	5,000	G14	UL, CSA, TÜV
RGEF1400-AP	—	—	1,000	5,000	G14	UL, CSA, TÜV
RHEF						
16V - High Temperature						
RHEF200	500	—	—	10,000	H2	UL, CSA, TÜV
RHEF200-2	—	2,500	—	12,500	H2	UL, CSA, TÜV
RHEF200-AP	—	—	2,500	12,500	H2	UL, CSA, TÜV
RHEF300	500	—	—	10,000	H3	UL, CSA, TÜV
RHEF300-2	—	2,000	—	10,000	H3	UL, CSA, TÜV
RHEF300-AP	—	—	2,000	10,000	H3	UL, CSA, TÜV
RHEF400	500	—	—	10,000	H4	UL, CSA, TÜV
RHEF400-2	—	1,500	—	7,500	H4	UL, CSA, TÜV
RHEF400-AP	—	—	1,500	7,500	H4	UL, CSA, TÜV
RHEF450	500	—	—	10,000	H4.5	UL, CSA, TÜV
RHEF450-2	—	1,500	—	7,500	H4.5	UL, CSA, TÜV
RHEF450-AP	—	—	1,500	7,500	H4.5	UL, CSA, TÜV
RHEF550	500	—	—	10,000	H5.5	UL, CSA, TÜV
RHEF550-2	—	2,000	—	10,000	H5.5	UL, CSA, TÜV
RHEF550-AP	—	—	2,000	10,000	H5.5	UL, CSA, TÜV
RHEF600	500	—	—	10,000	H6	UL, CSA, TÜV
RHEF600-2	—	2,000	—	10,000	H6	UL, CSA, TÜV
RHEF600-AP	—	—	2,000	10,000	H6	UL, CSA, TÜV
RHEF650	500	—	—	10,000	H6.5	UL, CSA, TÜV
RHEF650-2	—	1,500	—	7,500	H6.5	UL, CSA, TÜV
RHEF650-AP	—	—	1,500	7,500	H6.5	UL, CSA, TÜV
RHEF700	500	—	—	10,000	H7	UL, CSA, TÜV

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R6 — Packaging and Marking Information

(Cont'd)

Part Number	Bag Quantity	Tape and Reel Quantity	Ammo Pack Quantity	Standard Package Quantity	Part Marking	Agency Recognition
RHEF						
16V - High Temperature						
RHEF700-2	—	1,500	—	7,500	H7	UL, CSA, TÜV
RHEF700-AP	—	—	1,500	7,500	H7	UL, CSA, TÜV
RHEF750	500	—	—	10,000	H7.5	UL, CSA, TÜV
RHEF750-2	—	1,000	—	5,000	H7.5	UL, CSA, TÜV
RHEF750-AP	—	—	1,000	5,000	H7.5	UL, CSA, TÜV
RHEF800	500	—	—	10,000	H8	UL, CSA, TÜV
RHEF800-2	—	1,000	—	5,000	H8	UL, CSA, TÜV
RHEF800-AP	—	—	1,000	5,000	H8	UL, CSA, TÜV
RHEF900	250	—	—	5,000	H9	UL, CSA, TÜV
RHEF900-2	—	1,000	—	5,000	H9	UL, CSA, TÜV
RHEF900-AP	—	—	1,000	5,000	H9	UL, CSA, TÜV
RHEF1000	250	—	—	5,000	H10	UL, CSA, TÜV
RHEF1000-2	—	1,000	—	5,000	H10	UL, CSA, TÜV
RHEF1000-AP	—	—	1,000	5,000	H10	UL, CSA, TÜV
RHEF1100	250	—	—	5,000	H11	UL, CSA, TÜV
RHEF1100-2	—	1,000	—	5,000	H11	UL, CSA, TÜV
RHEF1100-AP	—	—	1,000	5,000	H11	UL, CSA, TÜV
RHEF1300	250	—	—	5,000	H13	UL, CSA, TÜV
RHEF1300-2	—	1,000	—	5,000	H13	UL, CSA, TÜV
RHEF1300-AP	—	—	1,000	5,000	H13	UL, CSA, TÜV
RHEF1400	250	—	—	5,000	H14	UL, CSA, TÜV
RHEF1400-2	—	1,000	—	5,000	H14	UL, CSA, TÜV
RHEF1400-AP	—	—	1,000	5,000	H14	UL, CSA, TÜV
RHEF1500	250	—	—	5,000	H15	UL, CSA, TÜV
RHEF1500-2	—	1,000	—	5,000	H15	UL, CSA, TÜV
RHEF1500-AP	—	—	1,000	5,000	H15	UL, CSA, TÜV
RUSBF						
6V						
RUSBF075	500	—	—	10,000	R75	UL, CSA, TÜV
RUSBF075-2	—	3,000	—	15,000	R75	UL, CSA, TÜV
RUSBF075-AP	—	—	2,000	10,000	R75	UL, CSA, TÜV
RUSBF120	500	—	—	10,000	R120	UL, CSA, TÜV
RUSBF120-2	—	3,000	—	15,000	R120	UL, CSA, TÜV
RUSBF120-AP	—	—	2,000	10,000	R120	UL, CSA, TÜV
RUSBF155	500	—	—	10,000	R155	UL, CSA, TÜV
RUSBF155-2	—	3,000	—	15,000	R155	UL, CSA, TÜV
RUSBF155-AP	—	—	2,000	10,000	R155	UL, CSA, TÜV

Agency Recognitions

UL	File # E74889
CSA	File # CA78165
TÜV	Certificate number available on request (per IEC 60730-1).

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R7 — Tape and Reel Specifications

RXEF and RKEF devices are available in tape and reel packaging per EIA468-B/IEC60286-2 standards.

Description	EIA Mark	Dimension (mm)	Tolerance
Carrier Tape Width	W	18	-0.5/+1.0
Hold-Down Tape Width	W ₄	11	Minimum
Top Distance between Tape Edges	W ₆	3	Maximum
Sprocket Hole Position	W ₅	9	-0.5/+0.75
Sprocket Hole Diameter	D ₀	4	± 0.2
Abscissa to Plane (Straight Lead) (RXEF110 To RXEF300, RKEF135 To RKEF500)	H	18.5	± 2.5
Abscissa to Plane (Kinked Lead) (RXEF010 To RXEF090, RKEF050 To RKEF110)	H ₀	16.0	± 0.5
Abscissa to Top (RXEF010 To RXEF090, RKEF050 To RKEF185)	H ₁	32.2	Maximum
Abscissa to Top* (RXEF110 To RXEF300, RKEF250 To RKEF500)	H ₁	47.5	Maximum
Overall Width with Lead Protrusion (RXEF010 To RXEF090, RKEF050 To RKEF185)	C ₁	43.2	Maximum
Overall Width with Lead Protrusion* (RXEF110 To RXEF300, RKEF250 To RKEF500)	C ₁	58	Maximum
Overall Width without Lead Protrusion (RXEF010 To RXEF090, RKEF050 To RKEF185)	C ₂	42.5	Maximum
Overall Width without Lead Protrusion* (RXEF110 To RXEF300, RKEF250 To RKEF500)	C ₂	57	Maximum
Lead Protrusion	L ₁	1.0	Maximum
Protrusion of Cut-Out	L	11.0	Maximum
Protrusion beyond Hold-down Tape	I ₂	Not Specified	—
Sprocket Hole Pitch	P ₀	12.7	± 0.3
Device Pitch (RXEF010 To RXEF090, RKEF050 To RKEF185)	—	12.7	± 0.3
Device Pitch (RXEF110 To RXEF300, RKEF250 To RKEF500)	—	25.4	± 0.61
Pitch Tolerance	—	20 Consecutive	± 1
Tape Thickness	T	0.9	Maximum
Overall Tape and Lead Thickness (RXEF010 To RXEF090, RKEF050 To RKEF185)	T ₁	1.5	Maximum
Overall Tape and Lead Thickness (RXEF110 To RXEF300, RKEF250 To RKEF500)	T ₁	2.3	Maximum
Splice Sprocket Hole Alignment	—	0	± 0.3
Body Lateral Deviation	Dh	0	± 1.0
Body Tape Plane Deviation	Dp	0	± 1.3
Ordinate to Adjacent Component Lead (RXEF010 To RXEF185, RKEF050 To RKEF300)	P ₁	3.81	± 0.7
Ordinate to Adjacent Component Lead (RXEF250 To RXEF300, RKEF375 To RKEF500)	P ₁	7.62	± 0.7
Lead Spacing* (RXEF010 To RXEF185, RKEF050 To RKEF300)	F	5.05	± 0.75
Lead Spacing* (RXEF250 To RXEF300, RKEF375 To RKEF500)	F	10.15	± 0.75
Reel Width (RXEF010 To RXEF090, RKEF050 To RKEF185)	W ₂	56.0	Maximum
Reel Width* (RXEF110 To RXEF300, RKEF250 To RKEF500)	W ₂	63.5	Maximum
Reel Diameter	A	370.0	Maximum
Space between Flanges* (RXEF010 To RXEF090, RKEF050 To RKEF185)	W ₁	48.00	Maximum
Space between Flanges* (RXEF110 To RXEF300, RKEF250 To RKEF500)	W ₁	55.00	Maximum
Arbor Hold Diameter	C	26.0	± 12.0
Core Diameter*	N	91.0	Maximum
Box	—	64/372/362	Maximum
Consecutive Missing Places	—	None	—
Empty Places per Reel	—	0.1%	Maximum

*Differs from EIA specification.

PolySwitch Resettable Devices

Radial-Leaded Devices

Table R7 — Tape and Reel Specifications

(Cont'd)

RUEF and RUSBF devices are available in tape and reel packaging per EIA468-B/IEC60286-2 standards.

Description	EIA Mark	Dimension (mm)	Tolerance
Carrier Tape Width	W	18	-0.5/+1.0
Hold-down Tape Width	W ₄	11	Minimum
Top Distance between Tape Edges	W ₆	3	Maximum
Sprocket Hole Position	W ₅	9	-0.5/+0.75
Sprocket Hole Diameter	D ₀	4	± 0.2
Abscissa to Plane (Straight Lead)* (RUEF300 to RUEF900)	H	18.5	± 2.5
Abscissa to Plane (Kinked Lead) (RUSBF075 to RUSBF250, RUEF090 to RUEF250)	H ₀	16.0	± 0.5
Abscissa to Top (RUSBF075 to RUSBF250, RUEF090 to RUEF300)	H ₁	32.2	Maximum
Abscissa to Top* (RUEF400 to RUEF900)	H ₁	45.0	Maximum
Overall Width with Lead Protrusion (RUSBF075 to RUSBF250, RUEF090 to RUEF300)	C ₁	43.2	Maximum
Overall Width with Lead Protrusion (RUEF400 To RUEF900)	C ₁	56	Maximum
Overall Width without Lead Protrusion (RUSBF075 to RUSBF250, RUEF090 to RUEF300)	C ₂	42.5	Maximum
Overall Width without Lead Protrusion (RUEF400 to RUEF900)	C ₂	56	Maximum
Lead Protrusion	L ₁	1.0	Maximum
Protrusion of Cut-out	L	11	Maximum
Protrusion beyond Hold-down Tape	I ₂	Not Specified	—
Sprocket Hole Pitch	P ₀	12.7	± 0.3
Device Pitch (RUSBF075 to RUSBF250, RUEF090 to RUEF300)	—	12.7	± 0.3
Device Pitch (RUEF400 to RUEF900)	—	25.4	± 0.6
Pitch Tolerance	—	20 Consecutive	± 1
Tape Thickness	T	0.9	Maximum
Overall Tape and Lead Thickness (RUSBF075 to RUSBF250, RUEF090 to RUEF50)	T ₁	1.5	Maximum
Overall Tape and Lead Thickness* (RUEF300 to RUEF900)	T ₁	2.3	Maximum
Splice Sprocket Hole Alignment	—	0	± 0.3
Body Lateral Deviation	Dh	0	± 1.0
Body Tape Plane Deviation	Dp	0	± 1.3
Ordinate to Adjacent Component Lead (RUSBF075 to RUSBF250, RUEF090 to RUEF300)	P ₁	3.81	± 0.7
Ordinate to Adjacent Component Lead (RUEF400 to RUEF900)	P ₁	7.62	± 0.7
Lead Spacing* (RUSBF075 to RUSBF250, RUEF090 to RUEF400)	F	5.05	± 0.75
Lead Spacing* (RUEF500 to RUEF900)	F	10.15	± 0.75
Reel Width (RUEF090 to RUEF400, RUSBF075 to RUSBF250)	W ₂	56.0	Maximum
Reel Width (RUEF500* to RUEF900)	W ₂	63.5	Maximum
Reel Diameter	A	370.0	Maximum
Space between Flanges* (RUEF090 to RUEF400, RUSBF075 to RUSBF250)	W ₁	48.0	Maximum
Space between Flanges* (RUEF500 to RUEF900)	W ₁	55.0	Maximum
Arbor Hold Diameter	C	26.0	± 12.0
Core Diameter*	N	91.0	Maximum
Box	—	64/372/362	Maximum
Consecutive Missing Places	—	None	—
Empty Places per Reel	—	0.1%	Maximum

*Differs from EIA specification.

Table R7 — Tape and Reel Specifications

(Cont'd)

RGEF and RHEF devices are available in tape and reel packaging per EIA468-B/IEC60286-2 standards.

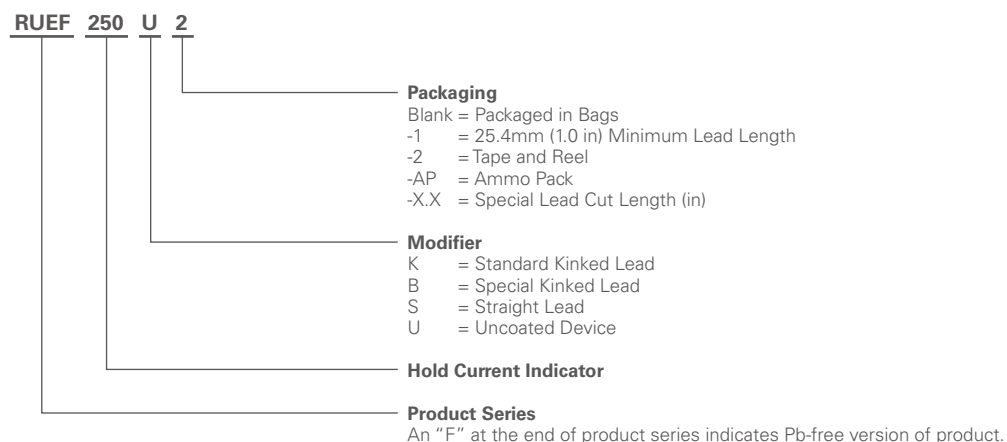
Description	EIA Mark	Dimension (mm)	Tolerance
Carrier Tape Width	W	18	-0.5/+1.0
Hold-Down Tape Width	W ₄	11	Minimum
Top Distance between Tape Edges	W ₆	3	Maximum
Sprocket Hole Position	W ₅	9	-0.5/+0.75
Sprocket Hole Diameter	D ₀	4	± 0.2
Abscissa to Plane (Straight Lead) (RGEF250 to RGEF1400)	H	18.5	± 2.5
Abscissa to Plane (Kinked Lead) (RHEF050 to RGEF1500)	H ₀	16.0	± 0.5
Abscissa to Top (RGEF250 to RGEF500, RGEF050 to RGEF450)	H ₁	32.2	Maximum
Abscissa to Top* (RGEF600 to RGEF1400, RHEF550 to RHEF1500)	H ₁	45.0	Maximum
Overall Width with Lead Protrusion (RGEF250 to RGEF600, RHEF050 to RHEF450)	C ₁	43.2	Maximum
Overall Width with Lead Protrusion (RGEF700 to RGEF1400, RHEF550 to RHEF1500)	C ₁	55	Maximum
Overall Width without Lead Protrusion (RGEF250 to RGEF600, RHEF050 to RHEF450)	C ₂	42.5	Maximum
Overall Width without Lead Protrusion (RGEF700 to RGEF1400, RHEF550 to RHEF1500)	C ₂	54	Maximum
Lead Protrusion	L ₁	1.0	Maximum
Protrusion of Cut-out	L	11	Maximum
Protrusion beyond Hold-down Tape	I ₂	Not Specified	—
Sprocket Hole Pitch	P ₀	12.7	± 0.3
Device Pitch (RGEF250 to RGEF700, RHEF050 to RHEF600)	—	25.4	± 0.61
Device Pitch (RGEF800 to RGEF1400, RHEF650 to RHEF1500)	—	25.4	± 0.6
Pitch Tolerance	—	20 Consecutive	± 1
Tape Thickness	T	0.9	Maximum
Overall Tape and Lead Thickness* (RGEF250 to RGEF1100, RHEF050 to RHEF1100)	T ₁	2.0	Maximum
Overall Tape and Lead Thickness* (RGEF1200 to RGEF1400, RHEF1300 to RHEF1500)	T ₁	2.3	Maximum
Splice Sprocket Hole Alignment	—	0	± 0.3
Body Lateral Deviation	Dh	0	± 1.0
Body Tape Plane Deviation	Dp	0	± 1.3
Ordinate to Adjacent Component Lead (RGEF250 to RGEF1100, RHEF050 to RHEF900)	P ₁	3.81	± 0.7
Ordinate to Adjacent Component Lead (RGEF1200 to RGEF1400, RHEF1000 to RHEF1500)	P ₁	7.62	± 0.7
Lead Spacing* (RGEF250 to RGEF1100, RHEF050 to RHEF900)	F	5.05	± 0.75
Lead Spacing* (RGEF1200 to RGEF1400, RHEF1000 to RHEF1500)	F	10.15	± 0.75
Reel Width (RGEF250 to RGEF600, RHEF050 to RHEF450)	W ₂	56.0	Maximum
Reel Width* (RGEF700 to RGEF1400 & RHEF550 to RHEF1500)	W ₂	63.5	Maximum
Reel Diameter	A	370.0	Maximum
Space between Flanges* (RGEF250 to RGEF600, RHEF050 to RHEF450)	W ₁	48.0	Maximum
Space between Flanges* (RGEF700 to RGEF400, RHEF550 to RHEF1500)	W ₁	55.0	Maximum
Arbor Hold Diameter	C	26.0	± 12.0
Core Diameter*	N	91.0	Maximum
Box	—	64/372/362	Maximum
Consecutive Missing Places	—	None	—
Empty Places per Reel	—	0.1 %	Maximum

*Differs from EIA specification.

PolySwitch Resettable Devices

Radial-Leaded Devices

Part Numbering System



Note: Kinked parts are recommended to control the height of the part on the PCB in non-auto PCB applications.



Warning :

- Users should independently evaluate the suitability of and test each product selected for their own application.
- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- These devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommodate device expansion.
- Operation in circuits with a large inductance can generate a circuit voltage (Ldi/dt) above the rated voltage of the device.

Notice:

Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

POLYSWITCH RESETTABLE DEVICES

Line-Voltage-Rated Devices

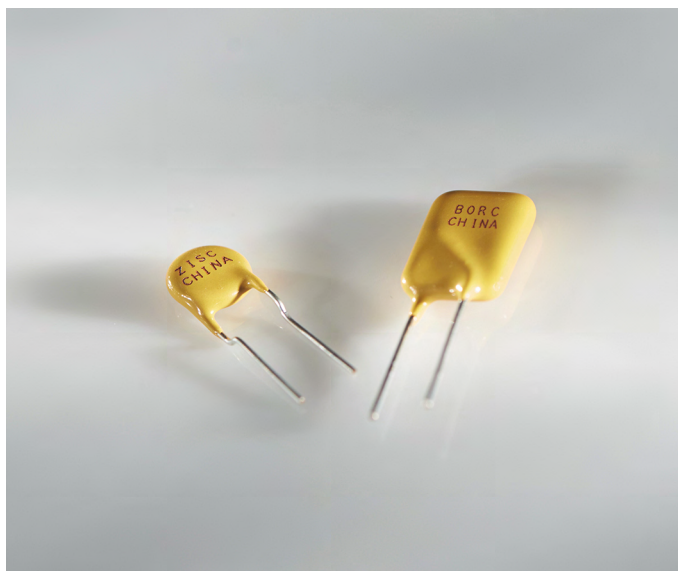
PolySwitch line-voltage-rated (LVR) devices help protect electric motors and transformers used in commercial and home appliances from damage caused by mechanical overloads, overheating, stall, lost neutral and other potentially harmful conditions.

The LVR line-voltage product line of polymeric positive temperature coefficient (PPTC) devices includes components that are rated for line voltages of 120V_{AC} and 240V_{AC}, for up to 2A of operating current at 20°C. They help protect against damage caused by both overcurrent surges and overtemperature faults. They also offer low resistance and are compatibly sized with fuse solutions.

Unlike traditional fuses, PolySwitch devices do not require replacement after a fault event. After power has been removed and the overcurrent condition eliminated, the circuit is restored to normal operating condition.

Compared to bimetal breakers, they offer greater flexibility, longer lifespan and lower electromagnetic interference (EMI).

The PolySwitch LVR devices' resettable functionality and latching attributes make them a reliable, cost-effective circuit protection solution for both intermittent- and continuous-operation motor applications. Their low resistance, fast time-to-trip, and low profile help circuit designers provide a safe and dependable product, comply with regulatory agency requirements and reduce warranty repair costs. LVR/LVB series are suitable for line-voltage applications up to a continuous operating voltage of 240V_{AC}/120V_{AC}. RoHS versions of all products are available.



BENEFITS

- Choice of many devices helps provide engineers with design flexibility
- Compatible with high-volume electronics assembly
- Assist in meeting regulatory requirements
- Higher voltage ratings allow use in new applications

FEATURES

- RoHS compliant
- Broadest range of radial-leaded resettable devices available in the industry
- Current ratings from 50mA to 2A
- Line voltage rating of 120V_{AC} and 240V_{AC}
- Agency recognition : UL, CSA, TÜV, CQC
- Fast time-to-trip
- Low resistance

APPLICATIONS

- Electromagnetic loads
- Game machines
- Industrial controls
- Lighting ballasts
- Loudspeakers
- Medical equipment
- Motors, fans and blowers
- POS equipment
- Satellite video receivers
- Security and fire alarm systems
- Test and measurement equipment
- Transformers
- USB hubs, ports and peripherals
- Intelligent appliance
- Robotic machine

PolySwitch Resettable Devices

Line-Voltage-Rated Devices

Table L1 — Product Series - Current Rating, Voltage Rating/Typical Resistance

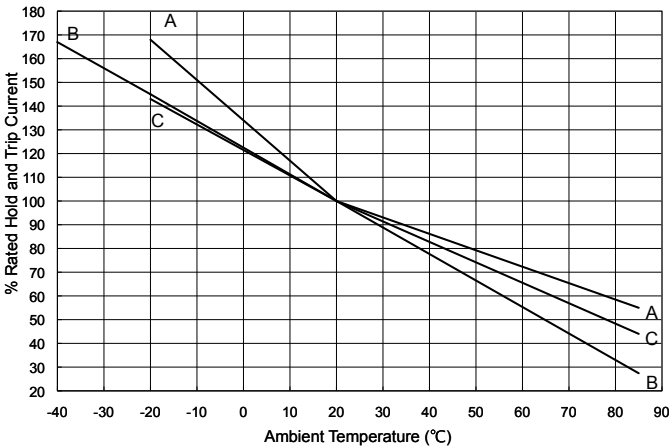
Voltage Rating	LVR 240V _{AC} / 120V _{AC}	LVB 240V _{AC}
Hold Current (A)		
0.050	25.00Ω	—
0.080	9.800Ω	—
0.120	4.800Ω	—
0.160	3.400Ω	—
0.250	1.700Ω	—
0.330	1.000Ω	—
0.400	0.800Ω	—
0.550	0.590Ω	—
0.750	0.400Ω	—
1.000	0.276Ω	—
1.250	0.209Ω	0.209Ω
1.350	—	—
2.000	0.110Ω	—

Table L2 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)]

Part	Maximum Ambient Temperature								
Number	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C
LVR									
LVR005N	0.08	0.06	0.05	0.05	0.04	0.04	0.03	0.03	0.02
LVR008N	0.12	0.10	0.08	0.08	0.07	0.06	0.05	0.04	0.03
LVR012	0.18	0.15	0.12	0.12	0.10	0.09	0.07	0.06	0.04
LVR016	0.24	0.20	0.16	0.16	0.13	0.11	0.10	0.08	0.05
LVR025	0.38	0.32	0.25	0.25	0.21	0.18	0.15	0.13	0.09
LVR033	0.50	0.42	0.33	0.33	0.27	0.23	0.20	0.17	0.11
LVR040	0.61	0.51	0.40	0.40	0.33	0.28	0.24	0.20	0.14
LVR055	0.80	0.68	0.55	0.54	0.46	0.40	0.35	0.29	0.22
LVR075	1.23	0.98	0.75	0.74	0.60	0.56	0.49	0.45	0.41
LVR100	1.65	1.30	1.00	0.94	0.80	0.75	0.65	0.60	0.55
LVR125	2.06	1.63	1.25	1.20	1.00	0.94	0.81	0.75	0.69
LVR200	3.30	2.60	2.00	1.97	1.60	1.50	1.30	1.20	1.10
LVR075-240	1.23	0.98	0.75	0.74	0.60	0.56	0.49	0.45	0.41
LVR100-240	1.65	1.30	1.00	0.94	0.80	0.75	0.65	0.60	0.55
LVR125-240	2.06	1.63	1.25	1.20	1.00	0.94	0.81	0.75	0.69
LVR200-240	3.30	2.60	2.00	1.97	1.60	1.50	1.30	1.20	1.10
LVB									
LVB125	2.09	1.81	1.53	1.25	1.19	0.99	0.86	0.73	0.41

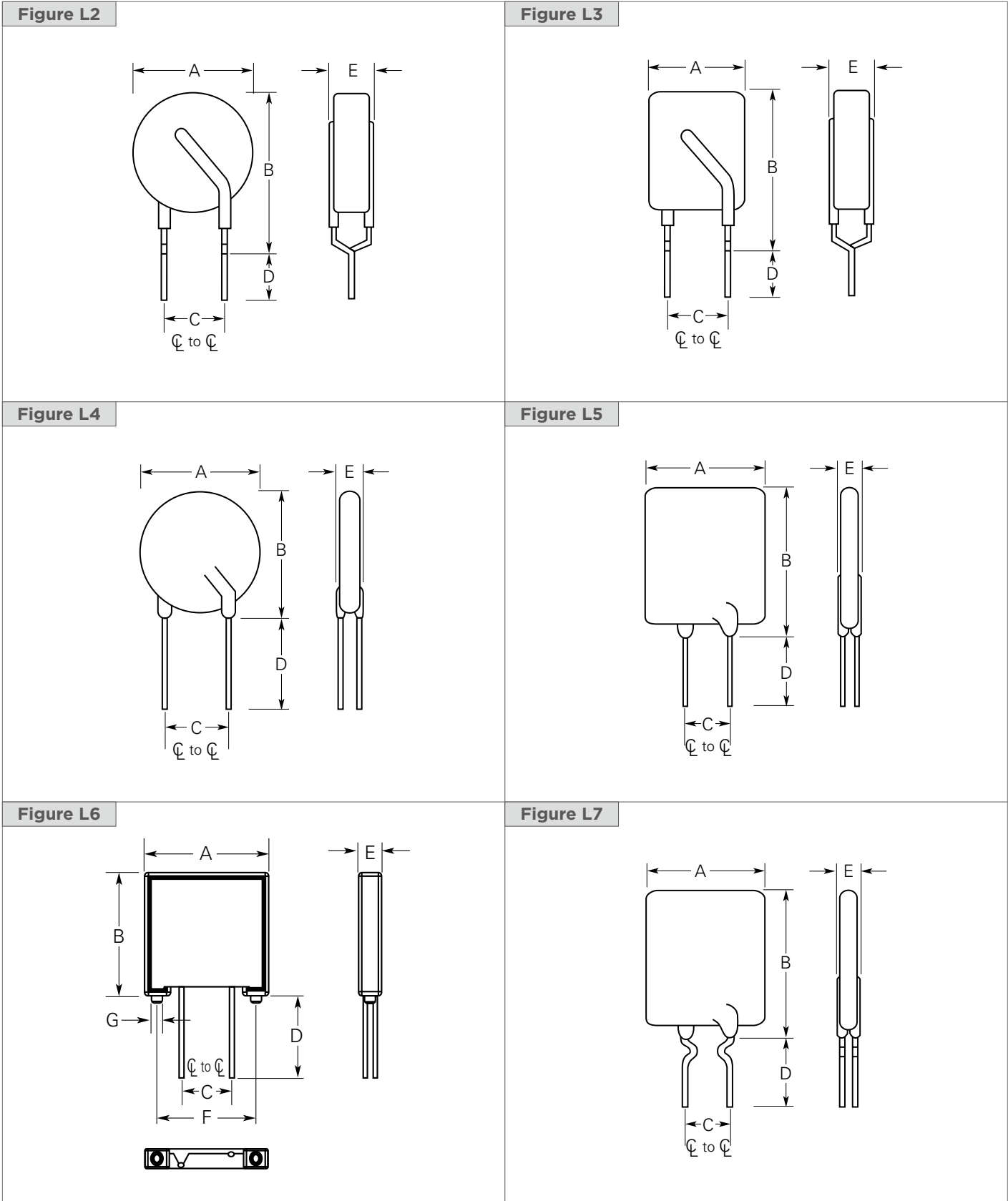
Figure L1 — Thermal Derating Curve

- A = LVR075-LVR200
- B = LVB125
- C = LVR005N-LVR055



PolySwitch Resettable Devices **Line-Voltage-Rated Devices**

Figures L2-L7 — Dimension Figures



PolySwitch Resettable Devices

Line-Voltage-Rated Devices

Table L4 — Dimensions and Weights - Millimeters (Inches)

Part Number	A		B		C		D		E		Figure	Device Mass(g) (Only for Reference)				
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max						
LVR																
LVR005NK	—	6.9 (0.27)	—	12.1 (0.48)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	4.6 (0.18)	L2	0.177				
LVR005NS	—	6.9 (0.27)	—	9.9 (0.39)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	4.6 (0.18)	L4	0.211				
LVR008NK	—	7.2 (0.28)	—	12.4 (0.49)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	4.6 (0.18)	L2	0.233				
LVR008NS	—	7.2 (0.28)	—	10.2 (0.40)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	4.6 (0.18)	L4	0.211				
LVR012K	—	8.3 (0.33)	—	12.9 (0.51)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L2	0.231				
LVR012S	—	8.3 (0.33)	—	10.7 (0.43)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L4	0.235				
LVR016K	—	9.9 (0.39)	—	13.8 (0.54)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L2	0.253				
LVR016S	—	9.9 (0.39)	—	12.5 (0.50)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L4	0.291				
LVR025K	—	9.6 (0.38)	—	18.8 (0.74)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L3	0.508				
LVR025S	—	9.6 (0.38)	—	17.4 (0.69)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L5	0.472				
LVR033K	—	11.4 (0.45)	—	19.0 (0.75)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L3	0.628				
LVR033S	—	11.4 (0.45)	—	16.5 (0.65)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L5	0.600				
LVR040K	—	11.5 (0.46)	—	20.9 (0.82)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L3	0.698				
LVR040S	—	11.5 (0.46)	—	19.5 (0.77)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	L5	0.688				
LVR055K	—	14.0 (0.55)	—	22.4 (0.88)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	4.1 (0.16)	L3	1.100				
LVR055S	—	14.0 (0.55)	—	21.7 (0.85)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	4.1 (0.16)	L5	1.060				
LVR075S	—	11.5 (0.45)	—	23.4 (0.92)	4.1 (0.16)	6.1 (0.24)	5.1 (0.20)	—	—	4.8 (0.19)	L5	1.088				
LVR100S	—	18.7 (0.74)	—	24.4 (0.96)	8.9 (0.35)	11.4 (0.45)	5.1 (0.20)	—	—	5.1 (0.20)	L4	1.345				
LVR125S	—	21.2 (0.84)	—	27.4 (1.08)	8.9 (0.35)	11.4 (0.45)	5.1 (0.20)	—	—	5.3 (0.21)	L4	1.800				
LVR200S	—	24.9 (0.98)	—	33.8 (1.33)	8.9 (0.35)	11.4 (0.45)	5.1 (0.20)	—	—	6.1 (0.24)	L5	2.777				
LVR075S-240	—	11.5 (0.45)	—	23.4 (0.92)	4.1 (0.16)	6.1 (0.24)	5.1 (0.20)	—	—	4.8 (0.19)	L5	1.088				
LVR100S-240	—	18.7 (0.74)	—	24.4 (0.96)	8.9 (0.35)	11.4 (0.45)	5.1 (0.20)	—	—	5.1 (0.20)	L4	1.345				
LVR125S-240	—	21.2 (0.84)	—	27.4 (1.08)	8.9 (0.35)	11.4 (0.45)	5.1 (0.20)	—	—	5.3 (0.21)	L4	1.800				
LVR200S-240	—	24.9 (0.98)	—	33.8 (1.33)	8.9 (0.35)	11.4 (0.45)	5.1 (0.20)	—	—	6.1 (0.24)	L5	2.777				
LVR075K-240	—	11.5 (0.45)	—	25.4 (1.00)	4.1 (0.16)	6.1 (0.24)	7.6 (0.30)	—	—	4.1 (0.16)	L3	1.088				
LVR100K-240	—	18.7 (0.74)	—	28.8 (1.13)	8.9 (0.35)	11.4 (0.45)	7.6 (0.30)	—	—	4.1 (0.16)	L2	1.345				
LVR125K-240	—	21.2 (0.84)	—	31.8 (1.25)	8.9 (0.35)	11.4 (0.45)	7.6 (0.30)	—	—	4.1 (0.16)	L2	1.800				
LVR200K-240	—	24.9 (0.98)	—	34.80 (1.37)	8.9 (0.35)	11.4 (0.45)	7.6 (0.30)	—	—	4.1 (0.16)	L7	2.777				
LVB																
LVB125	24.8 (0.98)	25.2 (.099)	26.8 (1.06)	27.2 (1.07)	8.9 (0.35)	11.4 (0.45)	5.1 (0.20)	—	4.2 (0.17)	4.6 (0.18)	20.0 (0.79)	20.3 (0.80)	— (0.80)	2.5	L6	1.653

PolySwitch Resettable Devices
Line-Voltage-Rated Devices

Figure L8 — Typical Time-to-Trip Curves at 20°C

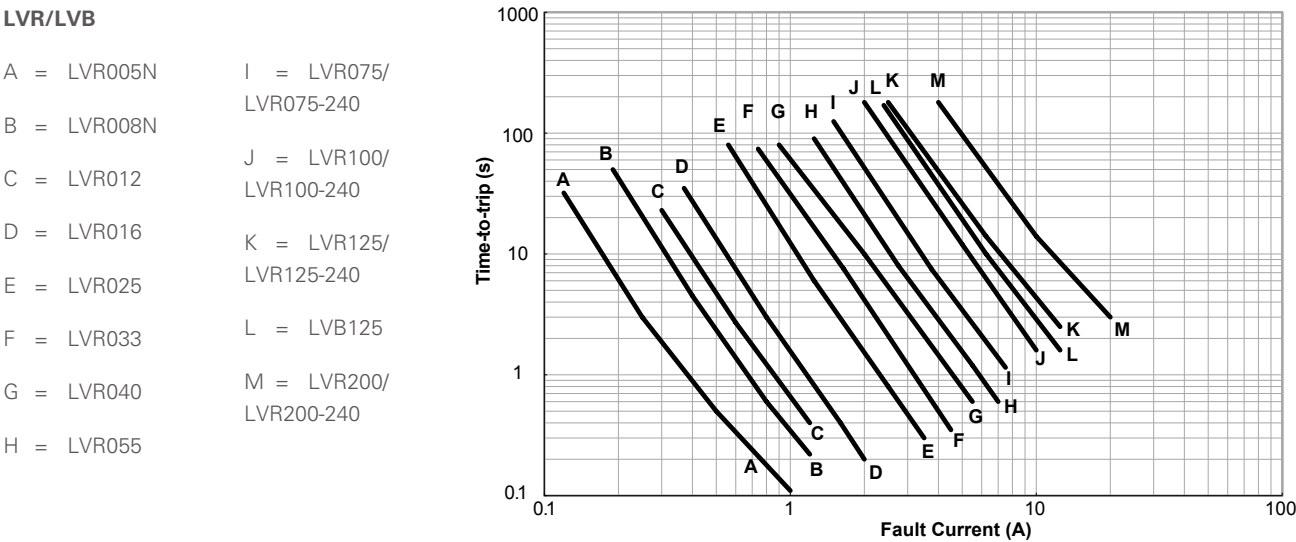


Table L5 — Physical Characteristics and Environmental Specifications

LVR/LVB		
Physical Characteristics		
Lead Material	LVR005N to LVR016	: Tin-plated Copper, (24AWG), ø0.51mm (0.020in)
	LVR025 to LVR040	: Tin-plated Copper, (22AWG), ø0.64mm (0.025in)
	LVR055 to LVR200	: Tin-plated Copper, (20AWG), ø0.81mm (0.032in)
	LVR075-240 to LVR200-240	: Tin-plated Copper, (20AWG), ø0.81mm (0.032in)
	LVB125	: Tin-plated Copper, (20AWG), ø0.81mm (0.032in)
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3	
Solder Heat Withstand	Per IEC-STD 68-2-20, Test Tb, Method 1A, Condition B, Can Withstand 10 s at 260°C ±5°C	
Insulating Material	LVR005N to LVR055	: Cured, Flame-retardant Epoxy Polymer, Meets UL 94V-0
	LVR075 to LVR200	: Cured, Flame-retardant Modified Silicone, Meets UL 94V-0
	LVR075-240 to LVR200-240	: Cured, Flame-retardant Epoxy Polymer, Meets UL 94V-0
	LVB125	: Glass Reinforced PBT, Meets UL 94V-0

Note: Devices are not intended to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±10%
	85°C, 1000 hrs	±10%
Humidity Aging	85°C, 85% RH, 1000 hrs	±20%
Thermal Shock	85°C, -40°C (10 Times)	±15%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

Agency Recognitions

UL	File # E74889
CSA	File # CA78165
TÜV	Certificate Number Available on Request (per IEC 60730-1).

PolySwitch Resettable Devices

Line-Voltage-Rated Devices

Table L6 — Packaging and Marking Information

Part	Bag	Tape and Reel	Ammo Pack	Standard Package	Part Marking	Agency Recognition
Number	Quantity	Quantity	Quantity	Quantity		
LVR/LVB						
LVR005NK	500	—	—	10,000	L005	UL, CSA, TÜV, CQC
LVR005NK-2	—	1,500	—	7,500	L005	UL, CSA, TÜV, CQC
LVR005NS	500	—	—	10,000	L005	UL, CSA, TÜV, CQC
LVR005NS-2	—	1,500	—	7,500	L005	UL, CSA, TÜV, CQC
LVR008NK	500	—	—	10,000	L008	UL, CSA, TÜV, CQC
LVR008NK-2	—	1,500	—	7,500	L008	UL, CSA, TÜV, CQC
LVR008NS	500	—	—	10,000	L008	UL, CSA, TÜV, CQC
LVR008NS-2	—	1,500	—	7,500	L008	UL, CSA, TÜV, CQC
LVR012K	500	—	—	10,000	L012	UL, CSA, TÜV, CQC
LVR012K-2	—	2,000	—	10,000	L012	UL, CSA, TÜV, CQC
LVR012S	500	—	—	10,000	L012	UL, CSA, TÜV, CQC
LVR012S-2	—	2,000	—	10,000	L012	UL, CSA, TÜV, CQC
LVR016K	500	—	—	10,000	L016	UL, CSA, TÜV, CQC
LVR016K-2	—	2,000	—	10,000	L016	UL, CSA, TÜV, CQC
LVR016S	500	—	—	10,000	L016	UL, CSA, TÜV, CQC
LVR016S-2	—	2,000	—	10,000	L016	UL, CSA, TÜV, CQC
LVR025K	500	—	—	10,000	L025	UL, CSA, TÜV, CQC
LVR025K-2	—	2,000	—	10,000	L025	UL, CSA, TÜV, CQC
LVR025S	500	—	—	10,000	L025	UL, CSA, TÜV, CQC
LVR025S-2	—	2,000	—	10,000	L025	UL, CSA, TÜV, CQC
LVR033K	500	—	—	10,000	L033	UL, CSA, TÜV, CQC
LVR033K-2	—	2,000	—	10,000	L033	UL, CSA, TÜV, CQC
LVR033S	500	—	—	10,000	L033	UL, CSA, TÜV, CQC
LVR033S-2	—	2,000	—	10,000	L033	UL, CSA, TÜV, CQC
LVR040K	500	—	—	10,000	L040	UL, CSA, TÜV, CQC
LVR040K-2	—	2,000	—	10,000	L040	UL, CSA, TÜV, CQC
LVR040S	500	—	—	10,000	L040	UL, CSA, TÜV, CQC
LVR040S-2	—	2,000	—	10,000	L040	UL, CSA, TÜV, CQC
LVR055K	500	—	—	10,000	L055	UL, CSA, TÜV, CQC
LVR055S	500	—	—	10,000	L055	UL, CSA, TÜV, CQC
LVR055S-2	—	1,000	—	5,000	L055	UL, CSA, TÜV, CQC
LVR075S	500	—	—	10,000	L075	UL, CSA, TÜV, CQC
LVR100S	250	—	—	5,000	L100	UL, CSA, TÜV, CQC
LVR125S	250	—	—	5,000	L125	UL, CSA, TÜV, CQC
LVR200S	250	—	—	5,000	L200	UL, CSA, TÜV, CQC
LVR075S-240	500	—	—	10,000	L075	UL, CSA, TÜV, CQC
LVR075S-240-2	—	1,000	—	5,000	L075	UL, CSA, TÜV, CQC
LVR075S-240-AP	—	—	1,000	5,000	L075	UL, CSA, TÜV, CQC
LVR100S-240	250	—	—	5,000	L100	UL, CSA, TÜV, CQC
LVR100S-240-2	—	1,000	—	5,000	L100	UL, CSA, TÜV, CQC
LVR100S-240-AP	—	—	1,000	5,000	L100	UL, CSA, TÜV, CQC
LVR125S-240	250	—	—	5,000	L125	UL, CSA, TÜV, CQC
LVR125S-240-2	—	1,000	—	5,000	L125	UL, CSA, TÜV, CQC
LVR125S-240-AP	—	—	1,000	5,000	L125	UL, CSA, TÜV, CQC
LVR200S-240	250	—	—	5,000	L200	UL, CSA, TÜV, CQC
LVR200S-240-2	—	1,000	—	5,000	L200	UL, CSA, TÜV, CQC
LVR200S-240-AP	—	—	1,000	5,000	L200	UL, CSA, TÜV, CQC
LVR075K-240	500	—	—	10,000	L075	UL, CSA, TÜV, CQC
LVR075K-240-2	—	1,000	—	5,000	L075	UL, CSA, TÜV, CQC
LVR075K-240-AP	—	—	1,000	5,000	L075	UL, CSA, TÜV, CQC
LVR100K-240	250	—	—	5,000	L100	UL, CSA, TÜV, CQC
LVR100K-240-2	—	1,000	—	5,000	L100	UL, CSA, TÜV, CQC
LVR100K-240-AP	—	—	1,000	5,000	L100	UL, CSA, TÜV, CQC
LVR125K-240	250	—	—	5,000	L125	UL, CSA, TÜV, CQC
LVR125K-240-2	—	1,000	—	5,000	L125	UL, CSA, TÜV, CQC
LVR125K-240-AP	—	—	1,000	5,000	L125	UL, CSA, TÜV, CQC
LVR200K-240	250	—	—	5,000	L200	UL, CSA, TÜV, CQC
LVR200K-240-2	—	1,000	—	5,000	L200	UL, CSA, TÜV, CQC
LVR200K-240-AP	—	—	1,000	5,000	L200	UL, CSA, TÜV, CQC
LVB125	250	—	—	5,000	B125	UL

PolySwitch Resettable Devices

Line-Voltage-Rated Devices

Table L7 — Tape and Reel Specifications

LVR devices are available in tape and reel packaging per EIA468-B/IEC60286-2 standards.

Description	EIA Mark	Dimension (mm)	Tolerance
Carrier Tape Width	W	18	-0.5/+1.0
Hold-down Tape Width	W ₄	11	Minimum
Top Distance between Tape Edges	W ₆	3	Maximum
Sprocket Hole Position	W ₅	9	-0.5/+0.75
Sprocket Hole Diameter	D ₀	4	± 0.2
Abscissa to Plane (Straight Lead) (LVR005N to LVR200)	H	18.5	± 2.5
Abscissa to Plane (Kinked Lead) (LVR005N to LVR055)	H ₀	16.0	± 0.5
Abscissa to Top (LVR005N to LVR016)	H ₁	32.2	Maximum
Abscissa to Top* (LVR025 to LVR200)	H ₁	45.0	Maximum
Overall Width with Lead Protrusion (LVR005N to LVR016)	C ₁	43.2	Maximum
Overall Width with Lead Protrusion (LVR025 to LVR200)	C ₁	56.0	Maximum
Overall Width without Lead Protrusion (LVR005N to LVR016)	C ₂	42.5	Maximum
Overall Width without Lead Protrusion (LVR025 to LVR200)	C ₂	56.0	Maximum
Lead Protrusion	L ₁	1.0	Maximum
Protrusion of Cut-out	L	11.0	Maximum
Protrusion beyond Hold-down Tape	I ₂	Not Specified	—
Sprocket Hole Pitch	P ₀	12.7	± 0.3
Device Pitch (LVR005N to LVR040)	—	12.7	± 0.3
Device Pitch (LVR055 to LVR200)	—	25.4	± 0.6
Pitch Tolerance	—	20 Consecutive	± 1
Tape Thickness	t	0.9	Maximum
Overall Tape and Lead Thickness (LVR005N to LVR040)	t ₁	1.5	Maximum
Overall Tape and Lead Thickness (LVR055 to LVR200)	t ₁	2.3	Maximum
Splice Sprocket Hole Alignment	—	0	± 0.3
Body Lateral Deviation	Dh	0	± 1.0
Body Tape Plane Deviation	Dp	0	± 1.3
Ordinate to Adjacent Component Lead	P ₁	3.81	± 0.7
Lead Spacing*	F	5.08	+0.75/-0.5
Reel Width (LVR005N to LVR040)	W ₂	56.0	Maximum
Reel Width* (LVR055 to LVR200)	W ₂	63.5	Maximum
Reel Diameter	a	370.0	Maximum
Space between Flanges* (LVR005N to LVR040)	W ₁	48.0	Maximum
Space between Flanges* (LVR055 to LVR200)	W ₁	55.0	Maximum
Arbor Hold Diameter	c	26.0	± 12.0
Core Diameter*	n	91.0	Maximum
Box	—	64/372/362	Maximum
Consecutive Missing Places	—	None	—
Empty Places per Reel	—	0.1%	Maximum

*Differs from EIA specification.

PolySwitch Resettable Devices
Line-Voltage-Rated Devices

Figure L9 — EIA Referenced Taped Component Dimensions

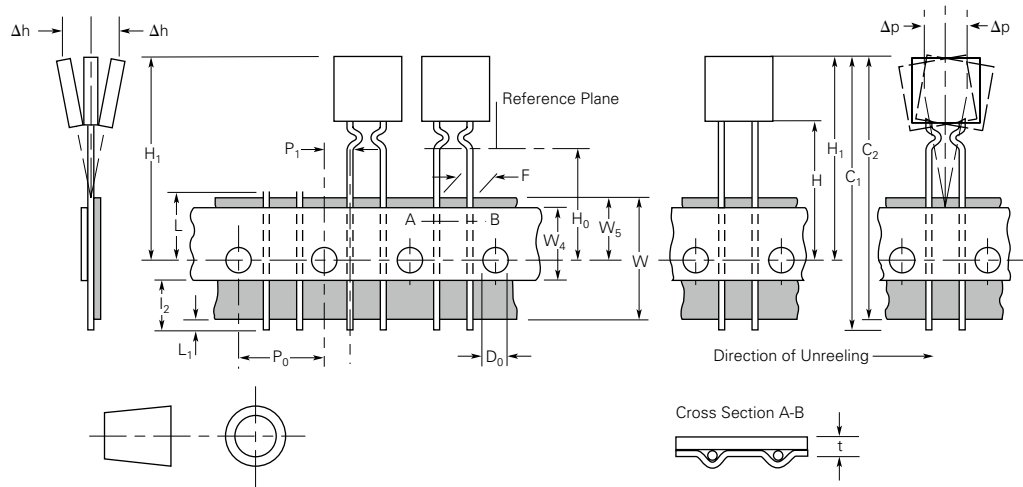
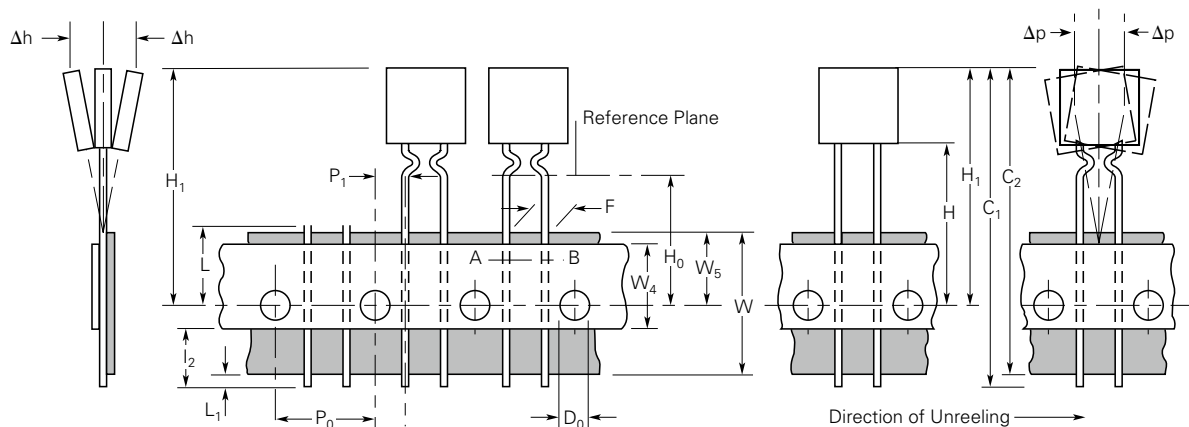


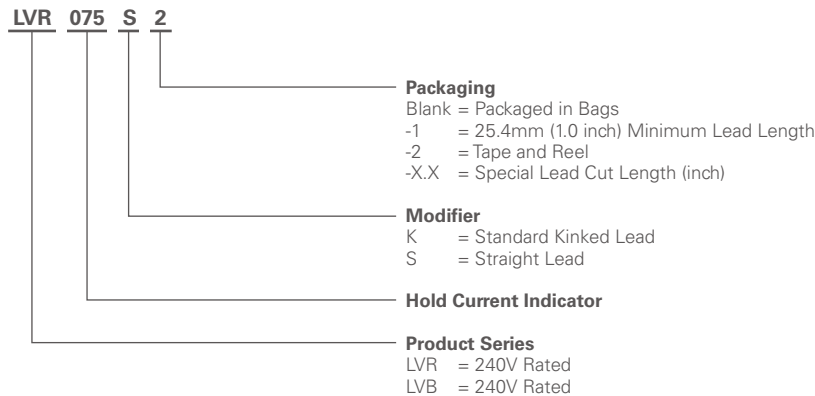
Figure L10 — EIA Referenced Reel Dimensions



PolySwitch Resettable Devices

Line-Voltage-Rated Devices

Part Numbering System



Warning : Application Limitations for the LVR Product Line

- Users should independently evaluate the suitability of and test each product selected for their own application.
- This product should not be used in an application where the maximum interrupt voltage or maximum interrupt current can be exceeded in a fault condition. Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- A PPTC device is not a fuse - it is a nonlinear thermistor that limits current. Under a fault condition all PPTC devices go into a high-resistance state but do not open circuit, so hazardous voltage may be present at PPTC locations.
- The devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- In most applications power must be removed and the fault condition cleared in order to reset a PPTC device; however under certain unusual conditions, a PPTC device may automatically reset. PPTC devices should not be used in an application where an automatic reset could create a safety hazard, such as garbage disposals and blenders. Appropriate qualification testing should be performed.
- It is the responsibility of the user to determine the need for back-up or failsafe protection to prevent damage that may occur in the event of abnormal function or failure of the PPTC device.
- Operation in circuits with a large inductance can generate a circuit voltage ($L di/dt$) above the rated voltage of a PPTC device. This product should not be used in an application where the maximum interrupt voltage or maximum interrupt current can be exceeded by inductive spikes.
- Devices are not recommended for reflow soldering.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, or mechanical procedures for electronic components.
- *PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommodate device expansion.
- *Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.

*Does not apply for LVB devices.

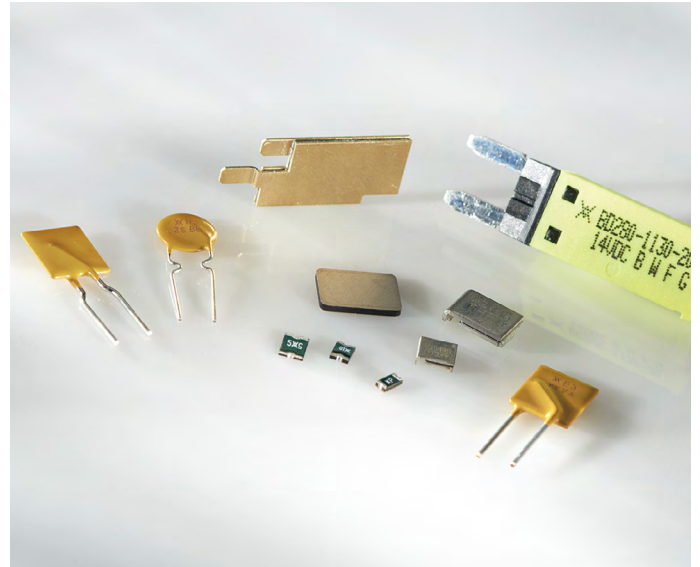
Notice:

Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

POLYSWITCH RESETTABLE DEVICES

Automotive Devices

We have provided PPTC resettable devices for the automotive industry for over 25 years. With the advent of TS16949 and our continued involvement in the automotive industry, Littelfuse PolySwitch team developed automotive-specific versions of PPTC devices (the nanoASMDC, microASMD, miniASMDC, AHS, ASMD, AHRF, AHEF, AGRF and BD families). These products are qualified and sold under the PS400 specification which is derived from AEC-Q200, the standard for electronic components used in the automotive industry. The key difference between these product families and other protection devices in our circuit protection product portfolio is the qualification process that is followed that includes a series of rigorous tests related to the automotive environment. As a result, they are characterized by specific additional values determined following automotive-related testing.



BENEFITS

- Expertise from the world's leading resettable overcurrent protection manufacturer
- High-quality products from the world's largest passive component manufacturer
- Worldwide team dedicated to support automotive applications
- Wide range of dedicated automotive surface-mount and radial-leaded resettable overcurrent devices
- High-performance transient voltage protection devices

FEATURES

- RoHS compliant
- Overcurrent and overvoltage circuit protection devices
- Resettable and single-use overcurrent devices
- Wide range of form factor and termination methods
- Products meet applicable automotive industry standards
- Devices compatible with high-volume electronics assembly

APPLICATIONS

- Motor and motor circuit protection including power door-locks, mirrors, lumbar pumps, seats, sunroofs and windows
- Electronic Control Unit (ECU) I/O protection
- Heating, Ventilation and Cooling (HVAC) motor and I/O protection
- Telematics, infotainment and navigations systems
- Liquid Crystal Display (LCD) back-light heaters
- Power and cigarette lighter outlets, plugs and adapter/chargers
- Powered networks and buses
- Air-flow detection and overcurrent protection in HVAC and cooling fan systems
- Stall detection in express window and sunroof circuits
- Resettable overcurrent protection for power distribution, electrical centers and junction boxes
- Wire downsizing
- Motor electromagnetic interference (EMI) suppression
- Electrostatic discharge (ESD) damage protection
- Load dump and other transient voltage protection

PolySwitch Resettable Devices

Automotive Devices

Table A1 — Product Series - Current Rating, Voltage Rating/Typical Resistance

Voltage Rating	AGRF 16V	AHRF 16V	AHRF 30V	AHEF 32V	AHS 16V	ASMD 16V	ASMD 30V	ASMD 33V	ASMD 60V	BD 14V	BD 16V
Hold Current (A)											
0.30	—	—	—	—	—	—	—	—	2.90Ω	—	—
0.50	—	—	0.565Ω	0.5650Ω	—	—	—	—	0.90Ω	—	—
0.70	—	—	0.385Ω	0.3850Ω	—	—	—	—	—	—	—
0.75	—	—	—	—	—	—	0.60Ω	—	—	—	—
0.80	—	—	—	—	0.250Ω	—	—	—	—	—	—
1.00	—	—	0.225Ω	0.2250Ω	—	—	0.30Ω	—	—	—	—
1.20	—	—	—	—	0.245Ω	—	—	—	—	—	—
1.25	—	—	—	—	—	0.160Ω	—	—	—	—	—
1.50	—	—	—	—	—	0.140Ω	—	0.149Ω	—	—	—
1.60	—	—	—	—	0.100Ω	—	—	—	—	—	—
1.85	—	—	—	—	—	0.079Ω	—	—	—	—	—
2.00	—	0.0565Ω	—	—	0.070Ω	0.090Ω	—	—	—	—	—
2.50	—	—	—	—	—	0.060Ω	—	—	—	—	—
3.00	—	0.0410Ω	—	0.0520Ω	0.050Ω	—	—	—	—	—	—
4.00	0.0300Ω	0.0305Ω	—	—	—	—	—	—	—	—	—
4.50	—	0.0290Ω	—	—	—	—	—	—	—	—	—
5.00	0.0192Ω	—	—	0.0200Ω	—	—	—	—	—	—	—
5.50	—	0.0190Ω	—	—	—	—	—	—	—	—	—
6.00	0.0145Ω	0.0180Ω	—	—	—	—	—	—	—	—	—
6.50	—	0.0140Ω	—	—	—	—	—	—	—	—	—
7.00	0.0105Ω	0.0126Ω	—	—	—	—	—	—	—	—	—
7.50	—	0.0120Ω	—	0.0120Ω	—	—	—	—	—	—	—
8.00	0.0086Ω	0.0104Ω	—	—	—	—	—	—	—	0.01150Ω	—
9.00	0.0070Ω	0.0100Ω	—	—	—	—	—	—	—	—	—
10.00	0.0056Ω	0.0083Ω	—	0.0083Ω	—	—	—	—	—	—	—
11.00	0.0050Ω	0.0069Ω	—	—	—	—	—	—	—	—	—
12.00	0.0046Ω	—	—	—	—	—	—	—	—	0.00600Ω	—
13.00	—	0.0055Ω	—	—	—	—	—	—	—	—	—
14.00	0.0040Ω	0.0050Ω	—	—	—	—	—	—	—	—	—
15.00	—	0.0050Ω	—	—	—	—	—	—	—	—	—
16.00	—	—	—	—	—	—	—	—	—	0.00365Ω	—
20.00	—	—	—	—	—	—	—	—	—	0.00285Ω	—
21.00	—	—	—	—	—	—	—	—	—	0.00260Ω	0.0030Ω

Voltage Rating	nanoASMD 48V	nanoASMD 24V	nanoASMD 16V	microASMD 30V	miniASMD 60V	miniASMD 30V	miniASMD 24V	miniASMD 16V
Hold Current (A)								
0.05	—	—	—	26.80Ω	—	—	—	—
0.10	—	—	—	8.55Ω	6.70Ω	—	—	—
0.12	3.95Ω	—	—	—	—	—	—	—
0.14	—	—	—	—	3.75Ω	—	—	—
0.16	3.05Ω	—	—	—	—	—	—	—
0.20	—	1.875Ω	—	—	—	1.950Ω	—	—
0.30	—	—	—	—	—	0.975Ω	—	—
0.35	—	—	0.90Ω	—	—	—	—	—
0.50	—	—	—	—	—	—	0.575Ω	—
0.75	—	—	—	—	—	—	0.190Ω	—
1.10	—	—	—	—	—	—	0.120Ω	0.1200Ω
1.25	—	—	—	—	—	—	—	0.0950Ω
1.50	—	—	—	—	—	—	0.080Ω	0.0750Ω
2.60	—	—	—	—	—	—	—	0.0325Ω

PolySwitch Resettable Devices

Automotive Devices

Table A2 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)]

Part Number	Maximum Ambient Temperature										
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
AGRF											
16V — Radial-leaded											
AGRF400	5.9	5.3	4.8	4.1	4.0	3.5	3.2	2.8	2.5	1.9	—
AGRF500	7.3	6.6	6.0	5.2	5.0	4.4	4.0	3.6	3.1	2.4	—
AGRF600	8.8	8.0	7.2	6.2	6.0	5.2	4.8	4.2	3.8	2.8	—
AGRF700	10.3	9.3	8.4	7.3	7.0	6.2	5.6	5.0	4.4	3.3	—
AGRF800	11.7	10.7	9.6	8.3	8.0	6.9	6.4	5.6	5.1	3.7	—
AGRF900	13.2	11.9	10.7	9.4	9.0	7.9	7.2	6.4	5.6	4.2	—
AGRF1000	14.7	13.3	12.0	10.3	10.0	8.7	8.0	7.0	6.3	4.7	—
AGRF1100	16.1	14.6	13.1	11.5	11.0	9.7	8.8	7.8	6.9	5.2	—
AGRF1200	17.6	16.0	14.4	12.4	12.0	10.4	9.6	8.4	7.6	5.6	—
AGRF1400	20.5	18.7	16.8	14.5	14.0	12.1	11.2	9.8	8.9	6.5	—
AHRF (High Temperature)											
30V — Radial-leaded											
AHRF050	0.7	0.6	0.6	0.5	0.5	0.4	0.4	0.4	0.3	0.3	0.1
AHRF070	1.0	0.9	0.8	0.7	0.7	0.6	0.6	0.5	0.5	0.4	0.2
AHRF100	1.4	1.2	1.1	1.0	1.0	0.9	0.8	0.7	0.7	0.6	0.2
AHRF (High Temperature)											
16V — Radial-leaded											
AHRF200	2.7	2.5	2.3	2.1	2.0	1.8	1.6	1.5	1.3	1.1	0.5
AHRF300	4.1	3.7	3.4	3.1	3.0	2.7	2.4	2.2	2.0	1.7	0.7
AHRF400	5.6	5.1	4.7	4.2	4.0	3.6	3.3	3.0	2.7	2.3	1.0
AHRF450	6.1	5.6	5.1	4.6	4.5	4.0	3.6	3.3	3.0	2.5	1.1
AHRF550	7.5	6.9	6.2	5.7	5.5	4.9	4.4	4.0	3.7	3.1	1.4
AHRF600	8.2	7.5	6.8	6.2	6.0	5.3	4.9	4.4	4.0	3.3	1.5
AHRF650	8.8	8.1	7.4	6.7	6.5	5.7	5.3	4.8	4.3	3.6	1.6
AHRF700	9.5	8.7	8.0	7.2	7.0	6.2	5.6	5.2	4.7	3.9	1.7
AHRF750	10.2	9.4	8.6	7.7	7.5	6.6	6.1	5.6	5.0	4.1	1.9
AHRF800	10.9	10.0	9.1	8.2	8.0	7.1	6.4	5.9	5.3	4.4	2.0
AHRF900	12.2	11.2	10.2	9.3	9.0	8.0	7.2	6.6	6.0	5.0	2.2
AHRF1000	13.6	12.5	11.4	10.3	10.0	8.8	8.1	7.4	6.6	5.5	2.5
AHRF1100	14.9	13.7	12.5	11.3	11.0	9.7	8.8	8.1	7.3	6.1	2.7
AHRF1300	17.7	16.3	14.8	13.4	13.0	11.4	10.5	9.6	8.6	7.2	3.3
AHRF1400	19.0	17.5	15.9	14.4	14.0	12.4	11.2	10.3	9.3	7.8	3.5
AHRF1500	20.4	18.8	17.1	15.5	15.0	13.2	12.1	11.1	9.9	8.3	3.8
AHEF (High Temperature)											
32V — Radial-leaded											
AHEF050	0.7	0.6	0.60	0.5	0.5	0.4	0.400	0.40	0.30	0.300	0.1
AHEF070	1.0	0.9	0.80	0.7	0.7	0.6	0.600	0.50	0.50	0.400	0.2
AHEF100	1.4	1.2	1.10	1.0	1.0	0.9	0.800	0.70	0.70	0.600	0.2
AHEF300	4.1	3.8	3.42	3.1	3.0	2.7	2.430	2.22	1.98	1.650	0.6
AHEF500	6.8	6.3	5.70	5.2	5.0	4.5	4.050	3.70	3.30	2.750	1.0
AHEF750	10.2	9.4	8.55	7.7	7.5	6.7	6.075	5.55	4.95	4.125	1.5
AHEF1000	13.6	12.5	11.40	10.3	10.0	8.9	8.100	7.40	6.60	5.500	2.0
AHS (High Temperature)											
16V — Surface-mount											
AHS080-2018	1.20	1.04	0.90	0.8	0.77	0.68	0.62	0.60	0.53	0.46	0.26
AHS120	1.72	1.54	1.36	1.2	1.14	1.01	0.92	0.83	0.74	0.61	0.25
AHS160	2.15	1.96	1.78	1.6	1.55	1.42	1.33	1.24	1.15	1.01	0.64
AHS200	2.90	2.50	2.20	2.0	1.94	1.80	1.75	1.70	1.40	1.18	0.67
AHS300	4.20	3.80	3.70	3.0	2.92	2.63	2.44	2.10	2.00	1.76	1.00

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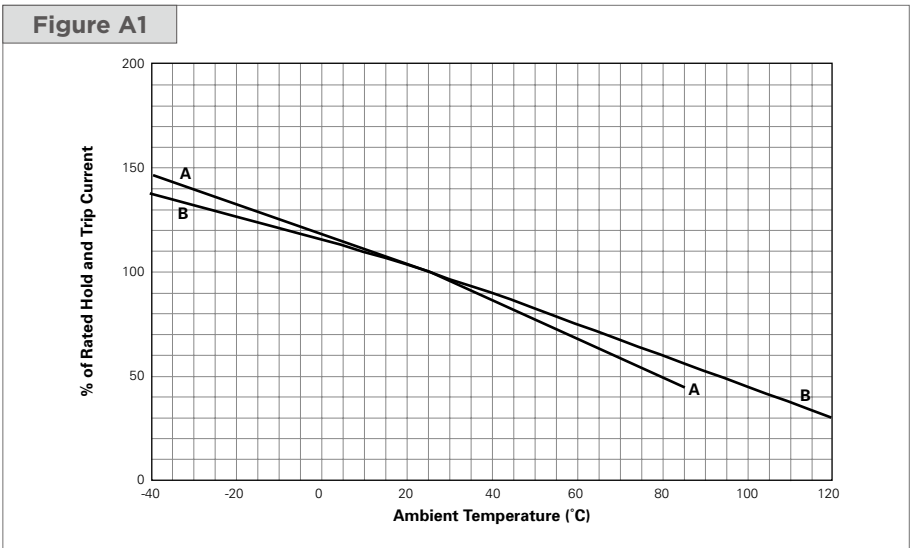
Automotive Devices

Table A2 — Thermal Derating [Hold Current (A) at Ambient Temperature (°C)] (Cont'd)

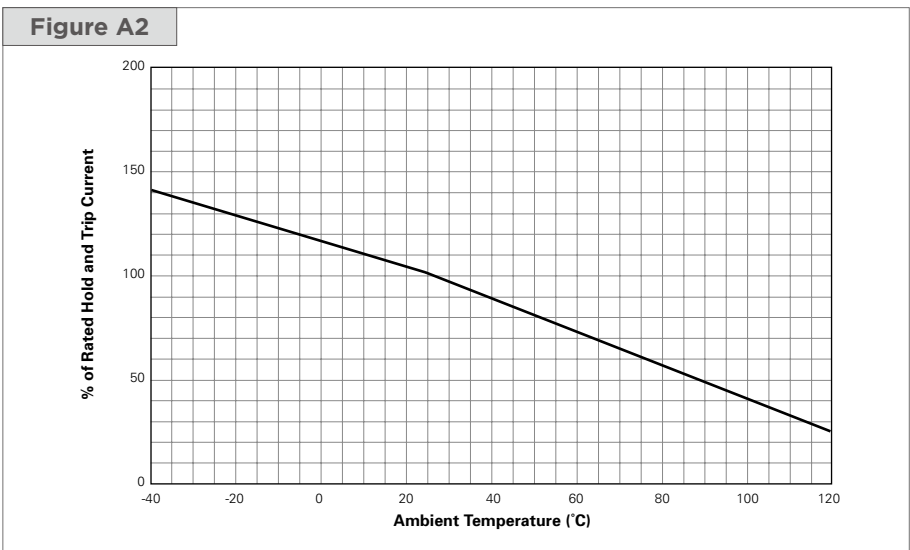
Part Number	Maximum Ambient Temperature										
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
ASMD											
16-60V — Surface-mount											
ASMD030F	0.35	0.31	0.27	0.23	0.22	0.19	0.17	0.15	0.13	0.11	—
ASMD050F	0.59	0.53	0.46	0.39	0.37	0.33	0.29	0.26	0.23	0.18	—
ASMD075F	0.91	0.81	0.71	0.60	0.58	0.50	0.45	0.40	0.35	0.28	—
ASMD100F	1.37	1.22	1.06	0.90	0.86	0.76	0.68	0.60	0.52	0.41	—
NEW ASMD125F	1.58	1.40	1.23	1.04	1.00	0.87	0.78	0.70	0.60	0.48	—
ASMD150F	1.93	1.70	1.50	1.27	1.22	1.07	0.95	0.85	0.74	0.58	—
ASMD150F/33	1.96	1.73	1.50	1.26	1.20	1.03	0.91	0.80	0.68	0.51	—
ASMD185F	2.93	2.58	2.30	1.93	1.85	1.62	1.44	1.30	1.12	0.88	—
ASMD200F	2.63	2.34	2.04	1.73	1.66	1.45	1.30	1.16	1.00	0.80	—
ASMD250F	3.00	2.66	2.32	1.97	1.89	1.65	1.48	1.32	1.14	0.91	—
nanoASMD											
16-48V — Surface-mount											
nanoASMD012F	0.20	0.17	0.15	0.13	0.12	0.11	0.10	0.09	0.08	0.07	—
nanoASMD016F	0.21	0.20	0.18	0.16	0.16	0.14	0.13	0.12	0.11	0.09	—
nanoASMD020F	0.34	0.30	0.26	0.22	0.20	0.17	0.15	0.13	0.11	0.08	—
nanoASMD035F	0.58	0.51	0.44	0.38	0.35	0.31	0.28	0.24	0.21	0.16	—
microASMD											
30V — Surface-mount											
microASMD005F	0.08	0.07	0.06	0.05	0.05	0.04	0.04	0.03	0.03	0.02	—
microASMD010F	0.15	0.13	0.12	0.10	0.10	0.09	0.08	0.06	0.06	0.05	—
miniASMD											
16-60V — Surface-mount											
miniASMD010F	0.17	0.15	0.13	0.11	0.10	0.09	0.08	0.07	0.06	0.04	—
miniASMD014F	0.23	0.20	0.17	0.14	0.13	0.11	0.10	0.09	0.07	0.05	—
miniASMD020F	0.30	0.27	0.23	0.20	0.19	0.17	0.15	0.13	0.12	0.09	—
miniASMD030F	0.49	0.44	0.39	0.32	0.30	0.27	0.24	0.22	0.18	0.14	—
miniASMD050F	0.59	0.57	0.55	0.50	0.48	0.45	0.43	0.35	0.30	0.23	—
miniASMD075F/24	1.50	1.25	1.00	0.75	0.73	0.65	0.60	0.55	0.50	0.43	—
miniASMD110F/16	1.68	1.49	1.30	1.10	1.05	0.92	0.83	0.75	0.64	0.50	—
miniASMD110F/24	2.00	1.70	1.40	1.10	1.06	0.95	0.88	0.80	0.73	0.61	—
miniASMD125F/16	2.00	1.69	1.47	1.25	1.17	1.03	0.92	0.90	0.69	0.53	—
miniASMD150F/16	2.40	2.10	1.80	1.50	1.44	1.25	1.13	1.00	0.88	0.69	—
miniASMD150F/24	2.10	1.90	1.70	1.50	1.44	1.25	1.13	1.00	0.88	0.69	—
miniASMD260F/16	3.50	3.20	3.00	2.60	2.53	2.30	2.15	2.00	1.85	1.63	—
BD											
14-16V — Bladed Device											
BD280-1130-10/16	12.4	11.0	9.7	8.3	8.0	7.0	6.3	5.6	5.0	4.0	1.8
BD280-1130-15/16	17.4	15.7	14.1	12.4	12.0	10.8	9.9	9.1	8.3	7.0	2.6
BD280-1130-20/16	24.0	21.6	19.1	16.6	16.0	14.1	12.9	11.7	10.4	8.6	3.5
BD280-1927-25/16-W	32.0	28.3	24.6	20.9	20.0	17.2	15.4	13.5	11.7	8.9	4.4
BD280-1927-30/16-W	34.1	30.1	26.0	22.0	21.0	18.0	16.0	14.0	11.9	9.1	4.6
BD540-30	34.1	30.1	26.0	22.0	21.0	18.0	16.0	14.0	11.9	9.1	4.6

Figures A1-A4 — Thermal Derating Curves

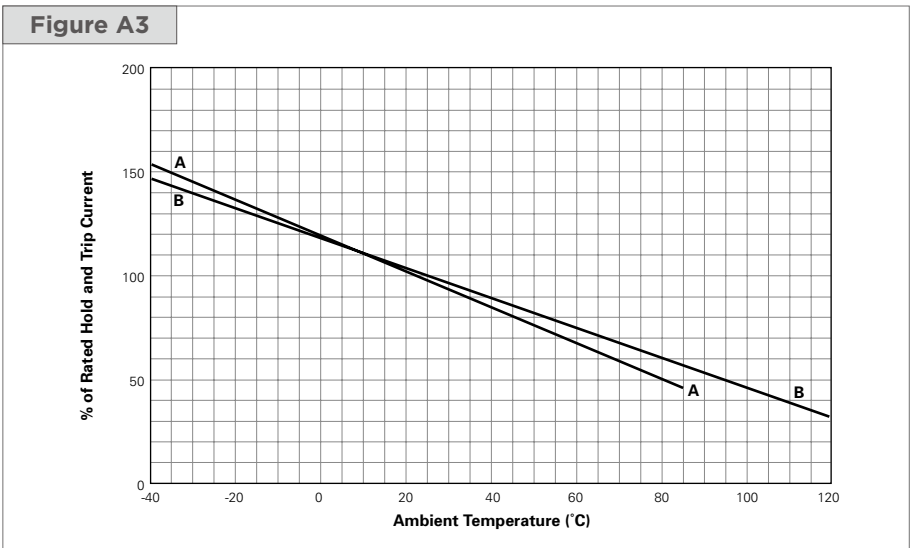
A = AGRF
B = AHRF



AHEF



A = ASMD, nanoASMD,
microASMD, miniASMD
B = AHS



BD

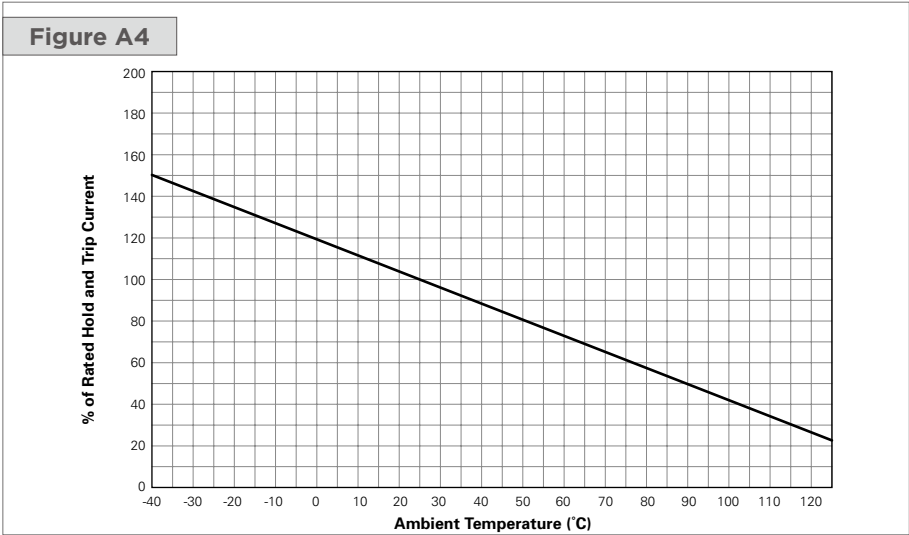


Table A3 — Electrical Characteristics

Part	$I_H(A)@$	$I_H(A)@$	I_T	V_{MAX}	I_{MAX}	$P_{D Typ}$	Max. Time-to-trip		R_{MIN}	R_{1MAX}	R_{aMAX}	Figure for
Number	R_{1MAX}	R_{aMAX}	(A)	(V_{DC})	(A)	(W)	(A)	(s)	(Ω)	(Ω)	(Ω)	Dimensions
AGRF												
16V — Radial-leaded												
AGRF400	4.0	3.0	7.6	16	100	2.5	20.0	2.0	0.0186	0.0610	0.0850	A5, A8, A9
AGRF500	5.0	4.3	9.4	16	100	2.7	25.0	2.5	0.0140	0.0340	0.0480	A5, A8, A9
AGRF600	6.0	5.3	10.7	16	100	2.8	30.0	3.5	0.0095	0.0280	0.0320	A5, A8, A9
AGRF700	7.0	6.5	13.2	16	100	3.0	35.0	4.0	0.0066	0.0200	0.0220	A5, A8, A9
AGRF800	8.0	7.6	15.0	16	100	3.2	40.0	5.5	0.0049	0.0175	0.0181	A5, A8, A9
AGRF900	9.0	8.6	16.5	16	100	3.4	45.0	6.0	0.0041	0.0135	0.0140	A5, A8, A9
AGRF1000	10.0	9.6	18.5	16	100	3.6	50.0	7.0	0.0034	0.0102	0.0106	A5, A8, A9
AGRF1100	11.0	10.5	20.3	16	100	3.7	55.0	7.5	0.0033	0.0089	0.0093	A5, A8, A9
AGRF1200	12.0	11.5	22.1	16	100	4.2	60.0	8.0	0.0030	0.0086	0.0091	A5, A8, A9
AGRF1400	14.0	13.0	27.3	16	100	4.6	70.0	9.0	0.0022	0.0064	0.0067	A5, A8, A9
AHRF (High Temperature)												
30V — Radial-leaded												
AHRF050	0.5	0.5	1.0	30	40	0.9	2.5	3.0	0.3500	1.100	1.100	A8, A9, A11
AHRF070	0.7	0.7	1.4	30	40	1.4	3.5	3.2	0.2300	0.800	0.800	A5, A8, A9
AHRF100	1.0	1.0	1.9	30	40	1.4	5.0	6.2	0.1500	0.430	0.430	A8, A9, A10
AHRF (High Temperature)												
16V — Radial-leaded												
AHRF200	2.0	2.0	3.8	16	100	1.4	10.0	4.8	0.0390	0.1100	0.1100	A8, A9, A10
AHRF300	3.0	3.0	6.5	16	100	3.0	15.0	5.0	0.0290	0.0790	0.0790	A5, A8, A9
AHRF400	4.0	4.0	7.4	16	100	3.3	20.0	5.0	0.0210	0.0600	0.0600	A5, A8, A9
AHRF450	4.5	4.5	8.7	16	100	3.6	22.5	4.0	0.0170	0.0540	0.0540	A5, A8, A9
AHRF550	5.5	5.5	10.0	16	100	3.5	27.5	6.0	0.0130	0.0370	0.0370	A5, A8, A9
AHRF600	6.0	6.0	12.0	16	100	4.1	30.0	6.5	0.0100	0.0320	0.0320	A5, A8, A9
AHRF650	6.5	6.5	13.7	16	100	4.3	32.5	7.0	0.0090	0.0260	0.0260	A5, A8, A9
AHRF700	7.0	7.0	13.1	16	100	4.0	35.0	7.0	0.0087	0.0250	0.0250	A5, A8, A9
AHRF750	7.5	7.5	14.8	16	100	4.5	37.5	8.0	0.0074	0.0220	0.0220	A5, A8, A9
AHRF800	8.0	8.0	15.0	16	100	4.2	40.0	8.0	0.0072	0.0200	0.0200	A5, A8, A9
AHRF900	9.0	9.0	18.5	16	100	5.0	45.0	11.5	0.0061	0.0170	0.0170	A5, A8, A9
AHRF1000	10.0	10.0	20.5	16	100	5.3	50.0	10.5	0.0051	0.0150	0.0150	A5, A8, A9
AHRF1100	11.0	11.0	21.2	16	100	5.5	55.0	11.0	0.0048	0.0130	0.0130	A5, A8, A9
AHRF1300	13.0	13.0	27.0	16	100	6.9	65.0	15.0	0.0034	0.0100	0.0100	A5, A8, A9
AHRF1400	14.0	14.0	28.3	16	100	6.9	70.0	15.5	0.0029	0.0090	0.0090	A5, A8, A9
AHRF1500	15.0	15.0	33.0	16	100	7.0	75.0	20.0	0.0027	0.0092	0.0092	A5, A8, A9

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Table A3 — Electrical Characteristics

(Cont'd)

Part Number	I_H (A)@ R_{1MAX}	I_H (A)@ R_{2MAX}	I_T (A)	V_{MAX} (V_{DC})	I_{MAX} (A)	P_{DTP} (W)	Max. Time-to-trip		R_{MIN} (Ω)	R_{1MAX} (Ω)	R_{2MAX} (Ω)	Figure for Dimensions	
							(A)	(s)					
AHEF (High Temperature)													
32V — Radial-leaded													
AHEF050	0.5	0.5	1.0	32	100	0.9	2.5	3.0	0.3500	1.100	1.100	A8, A9, A10	
AHEF070	0.7	0.7	1.4	32	100	1.4	3.5	3.2	0.2300	0.800	0.800	A8, A9, A11	
AHEF100	1.0	1.0	1.9	32	100	1.4	5.0	6.2	0.1500	0.430	0.430	A8, A9, A10	
AHEF300	3.0	3.0	6.0	32	100	3.2	15.0	5.0	0.0350	0.110	0.110	A8, A9, A12	
AHEF500	5.0	5.0	10.0	32	100	5.3	25.0	9.0	0.0150	0.040	0.040	A8, A9, A12	
AHEF750	7.5	7.5	15.0	32	100	6.5	37.5	13.0	0.0074	0.023	0.023	A8, A9, A12	
AHEF1000	10.0	10.0	20.0	32	100	7.0	50.0	15.0	0.0060	0.016	0.016	A8, A9, A12	
AHS (High Temperature)													
16V — Surface-mount													
AHS080-2018	0.80	0.80	2.00	16	70	1.5	8.0	9.0	0.130	0.550	0.550	A6	
AHS120	1.20	1.20	2.30	16	50	2.2	8.0	2.0	0.150	0.340	0.340	A7	
AHS160	1.60	1.60	3.20	16	70	2.2	8.0	15.0	0.050	0.150	0.150	A7	
AHS200	2.00	2.00	4.00	16	70	2.3	8.0	13.4	0.050	0.140	0.140	A7	
AHS300	3.00	3.00	6.00	16	70	3.0	15.0	8.0	0.024	0.083	0.083	A7	
ASMD													
16-60V — Surface-mount													
ASMD030F	0.23	0.23	0.59	60	10	1.1	1.15	12.0	0.980	4.800	4.800	A7	
ASMD050F	0.37	0.37	0.98	60	10	1.7	1.95	20.0	0.290	1.400	1.400	A7	
ASMD075F	0.60	0.60	1.48	30	40	1.1	3.00	20.0	0.290	1.000	1.000	A7	
ASMD100F	0.90	0.90	2.16	30	40	1.1	4.50	20.0	0.098	0.480	0.480	A7	
ASMD125F	1.04	1.04	2.46	16	40	1.1	5.20	20.0	0.057	0.250	0.250	A7	
ASMD150F	1.27	1.27	2.95	16	40	1.2	6.35	25.0	0.049	0.250	0.250	A7	
ASMD150F/33	1.20	1.20	2.88	33	40	1.9	6.00	14.0	0.068	0.230	0.230	A7	
ASMD185F	1.85	1.85	3.70	16	40	1.5	9.25	11.3	0.032	0.126	0.126	A7	
ASMD200F	1.73	1.73	3.93	16	40	1.2	8.65	30.0	0.050	0.120	0.120	A7	
ASMD250F	1.97	1.97	5.00	16	40	1.2	9.85	30.0	0.035	0.085	0.085	A7	
nanoASMD													
16-48V — Surface-mount													
nanoASMD012F	0.12	0.12	0.39	48	10	0.5	1.0	0.2	1.40	6.50	6.50	A15	
nanoASMD016F	0.16	0.16	0.45	48	10	0.5	1.0	0.3	1.10	5.00	5.00	A15	
nanoASMD020F	0.20	0.20	0.42	24	100	0.6	8.0	0.1	0.65	3.10	3.10	A15	
nanoASMD035F	0.35	0.75	0.75	16	20	0.6	3.5	0.1	0.45	1.35	1.35	A15	
microASMD													
30V — Surface-mount													
microASMD005F	0.05	0.05	0.15	30	10	1.0	0.25	1.5	3.6	50.0	50.0	A15	
microASMD010F	0.10	0.10	0.25	30	10	0.8	0.50	1.0	2.1	15.0	15.0	A15	
miniASMD													
16-60V — Surface-mount													
miniASMD010F	0.10	0.10	0.30	60	40	0.75	0.5	5.000	0.700	12.70	12.70	A15	
miniASMD014F	0.14	0.14	0.28	60	10	0.75	8.0	0.008	1.500	6.00	6.00	A15	
miniASMD020F	0.20	0.20	0.40	30	10	0.80	8.0	0.020	0.600	3.30	3.30	A15	
miniASMD030F	0.30	0.30	0.60	30	40	0.80	8.0	0.100	0.200	1.75	1.75	A15	
miniASMD050F	0.50	0.50	1.00	24	100	0.80	8.0	0.150	0.150	1.00	1.00	A15	
miniASMD075F/24	0.75	0.75	1.50	24	40	0.80	8.0	0.300	0.090	0.29	0.29	A15	
miniASMD110F/16	1.10	1.10	2.20	16	100	0.80	8.0	0.300	0.060	0.18	0.18	A15	
miniASMD110F/24	1.10	1.10	2.20	24	20	0.80	8.0	0.500	0.060	0.18	0.18	A15	
miniASMD125F/16													

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Table A3 — Electrical Characteristics

(Cont'd)

Part Number	$I_H(A)@$	$I_H(A)@$	I_T (A)	V_{MAX} (V _{DC})	I_{MAX} (A)	$P_{D Typ}$ (W)	Max. Time-to-trip		R_{MIN} (Ω)	R_{1MAX} (Ω)	R_{2MAX} (Ω)	Figure for Dimensions								
	R_{1MAX}	R_{2MAX}					(A)	(s)												
BD																				
14V — Bladed Device																				
BD280-1130-10/16	8	8	13	14	100	4.4	40	8	0.0095	0.0185	0.0185	A13								
BD280-1130-15/16	12	12	20	14	100	4.5	60	8	0.0050	0.0070	0.0070	A13								
BD280-1130-20/16	16	16	26	14	100	5.2	80	10	0.0028	0.0064	0.0064	A13								
BD280-1927-25/16-W	20	20	32	14	100	6.0	100	13	0.0024	0.0042	0.0042	A14								
BD280-1927-30/16-W	21	21	38	14	100	6.2	120	13	0.0021	0.0043	0.0043	A14								
BD																				
16V — Bladed Device																				
BD540-30	21	21	40	16	100	6	120	13	0.0016	0.0044	0.0044	A16								

Notes:

I_H : Hold current: maximum current device will pass without interruption in 25°C, unless otherwise specified (20°C for ASMD).

I_T : Trip current: minimum current that will switch the device from low-resistance to high-resistance in 25°C still air, unless otherwise specified.

V_{MAX} : Maximum voltage device can withstand without damage at rated current.

I_{MAX} : Maximum fault current device can withstand without damage at rated voltage.

P_D : Power dissipated from device when in the tripped state in 25°C still air, unless otherwise specified.

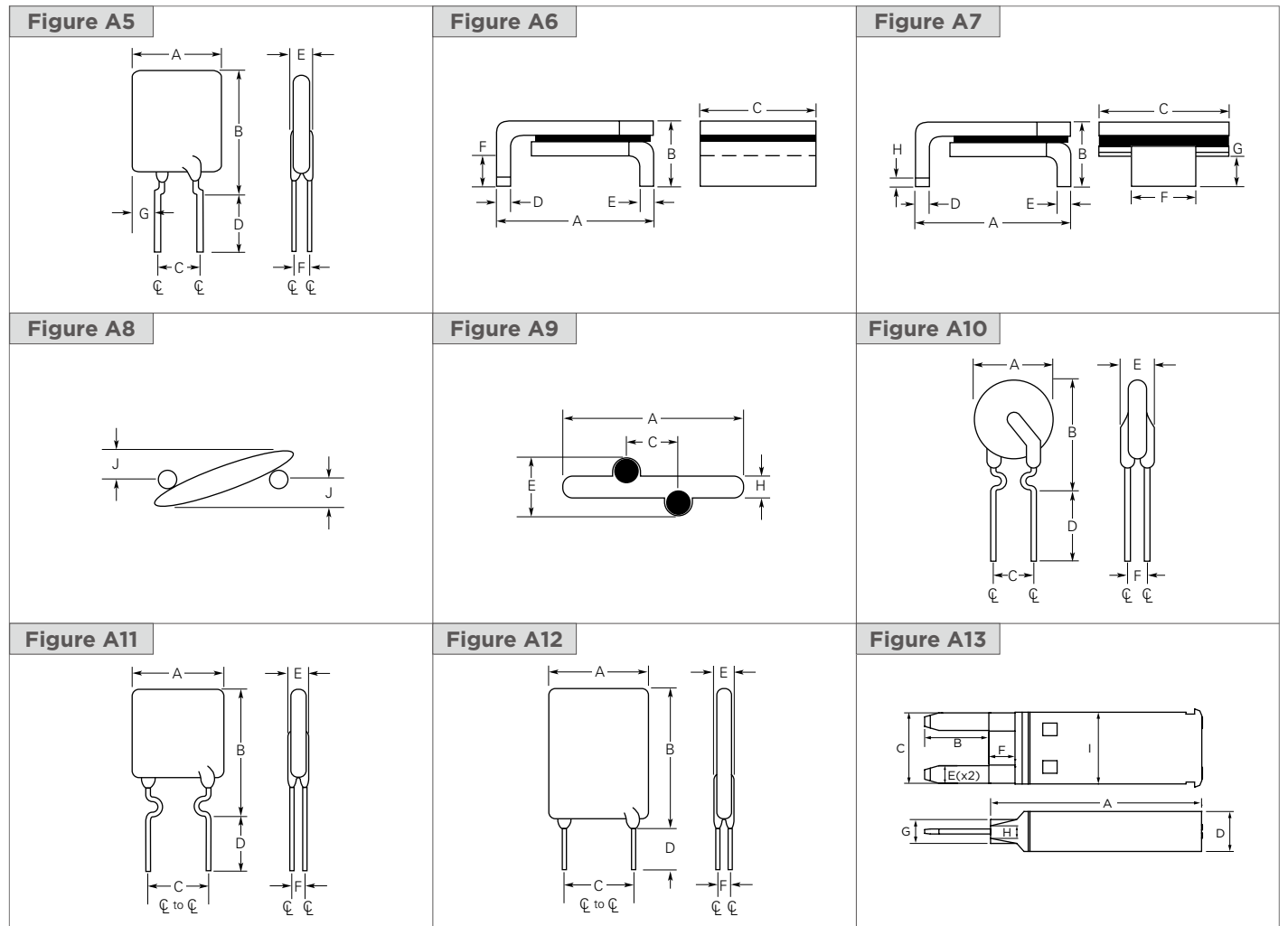
R_{MIN} : Minimum resistance of device as supplied at 25°C, unless otherwise specified.

R_{1MAX} : Maximum resistance of device when measured one hour post reflow (surface-mount device) or one hour post trip (radial-leaded device) at 25°C unless otherwise specified.

R_{2MAX} : Maximum functional resistance of device after being subjected to the stresses described in PS400 at 25°C, unless otherwise specified.

R_{2MIN} : Minimum functional resistance of device after being subjected to the stresses described in PS400 at 25°C, unless otherwise specified.

Figures A5-A16 — Dimension Figures



PolySwitch Resettable Devices

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Figures A5-A16 — Dimension Figures

(Cont'd)

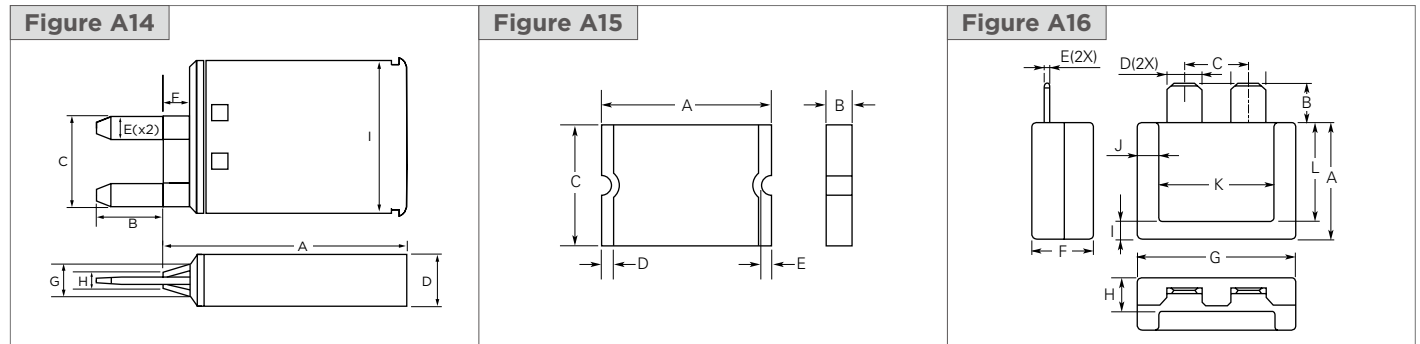


Table A4 — Dimensions in Millimeters and (Inches)

Part Number	A		B		C		D		E		F		G		H	J	Figure	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Typ	Max		
AGRF																		
16V — Radial-leaded																		
AGRF400	—	8.9 (0.350)	—	14.1 (0.56)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.15)	—	—	3.10 (0.120)	1.24 (0.049)	1.4 (0.06)	A5, A8, A9	
AGRF500	—	10.4 (0.410)	—	15.6 (0.61)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	3.94 (0.155)	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AGRF600	—	10.7 (0.420)	—	18.4 (0.73)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	4.07 (0.160)	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AGRF700	—	11.2 (0.440)	—	21.0 (0.73)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	4.49 (0.177)	1.24 (0.049)	1.7 (0.07)	A5, A8, A9	
AGRF800	—	12.7 (0.500)	—	22.2 (0.88)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	5.08 (0.200)	1.24 (0.049)	1.8 (0.07)	A5, A8, A9	
AGRF900	—	14.0 (0.550)	—	23.0 (0.91)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	5.69 (0.224)	1.24 (0.049)	2.0 (0.08)	A5, A8, A9	
AGRF1000	—	16.51 (0.650)	—	25.7 (1.01)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	6.96 (0.274)	1.24 (0.049)	2.0 (0.08)	A5, A8, A9	
AGRF1100	—	17.5 (0.690)	—	26.5 (1.04)	4.3 (0.17)	5.8 (0.20)	7.6 (0.3)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	7.47 (0.294)	1.24 (0.049)	2.4 (0.09)	A5, A8, A9	
AGRF1200	—	17.5 (0.690)	—	28.8 (1.14)	9.4 (0.37)	10.9 (0.43)	7.6 (0.3)	—	—	3.5 (								

PolySwitch Resettable Devices

Automotive Devices

Table A4 — Dimensions in Millimeters and (Inches)

(Cont'd)

Part Number	A		B		C		D		E		F		G		H	J	Figure	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Typ	Max		
AHRF (High Temperature)																		
16V — Radial-leaded																		
AHRF200	—	9.4 (0.37)	—	14.4 (0.57)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	1.24 (0.049)	1.6 (0.06)	A8, A9, A10	
AHRF300	—	8.8 (0.35)	—	13.8 (0.55)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF400	—	10.0 (0.39)	—	15.0 (0.59)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF450	—	10.4 (0.41)	—	15.6 (0.61)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	3.94 (0.155)	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF550	—	11.2 (0.44)	—	18.9 (0.74)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF600	—	11.2 (0.44)	—	21.0 (0.73)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	4.49 (0.177)	1.24 (0.049)	1.7 (0.07)	A5, A8, A9	
AHRF650	—	12.7 (0.50)	—	22.2 (0.88)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	5.08 (0.200)	1.24 (0.049)	1.8 (0.07)	A5, A8, A9	
AHRF700	—	14.0 (0.55)	—	21.9 (0.86)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF750	—	14.0 (0.55)	—	23.5 (0.93)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	5.69 (0.224)	1.24 (0.049)	2.0 (0.08)	A5, A8, A9	
AHRF800	—	16.5 (0.65)	—	22.5 (0.88)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF900	—	16.5 (0.65)	—	25.7 (1.01)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	—	—	A5, A8, A9	
AHRF1000	—	17.5 (0.69)	—	26.5 (1.04)	9.4 (0.37)	10.9 (0.43)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	7.47 (0.294)	1.24 (0.049)	1.5 (0.06)	A5, A8, A9	
AHRF1100	—	21.0 (0.83)	—	26.1 (1.03)	9.4 (0.37)	10.9 (0.43)	7.6 (0.30)	—	—	3.0 (0.12)	1.2 (0.05)	—	—	—	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF1300	—	23.5 (0.925)	—	28.7 (1.13)	9.4 (0.37)	10.9 (0.43)	7.6 (0.30)	—	—	3.5 (0.14)	1.4 (0.06)	—	—	7.82 (0.308)	1.45 (0.057)	1.9 (0.08)	A5, A8, A9	
AHRF1400	—	23.5 (0.93)	—	28.7 (1.13)	9.4 (0.37)	10.9 (0.43)	7.6 (0.30)	—	—	3.6 (0.14)	1.4 (0.06)	—	—	—	1.24 (0.049)	1.6 (0.06)	A5, A8, A9	
AHRF1500	—	23.5 (0.93)	—	28.7 (1.13)	9.4 (0.37)	10.9 (0.43)	7.6 (0.30)	—	—	3.5 (0.14)	1.4 (0.06)	—	—	7.82 (0.308)	—	—	A5, A8, A9	
AHEF (High Temperature)																		
32V — Radial-leaded																		
AHEF050	—	7.4 (0.29)	—	12.7 (0.50)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.3 (0.13)	—	—	—	—	—	—	A8, A9, A10	
AHEF070	—	6.9 (0.27)	—	10.8 (0.43)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	—	—	—	—	—	—	A8, A9, A11	
AHEF100	—	9.7 (0.38)	—	13.6 (0.54)	4.3 (0.17)	5.8 (0.23)	7.6 (0.30)	—	—	3.0 (0.12)	—	—	—	—	—	—	A8, A9, A10	
AHEF300	—	10.2 (0.40)	—	15.5 (0.61)	4.32 (0.17)	5.84 (0.23)	7.6 (0.30)	—	—	3.8 (0.15)	—	—	—	—	—	—	A8, A9, A12	
AHEF500	—	14.0 (0.55)	—	24.1 (0.95)	4.3 (0.17)	5.8 (0.23)	11.5 (0.45)	—	—	3.8 (0.15)	—	—	—	—	—	—	A8, A9, A12	
AHEF750	—	21.1 (0.83)	—	24.9 (0.98)	9.4 (0.37)	10.9 (0.43)	7.6 (0.30)	—	—	3.8 (0.15)	—	—						

PolySwitch Resettable Devices

Automotive Devices

Table A4 — Dimensions in Millimeters and (Inches)

(Cont'd)

Part Number	A		B		C		D		E		F		G		H		Figure	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
AHS (High Temperature)																		
16V — Surface-mount																		
AHS080-2018	4.72 (0.186)	5.44 (0.214)	—	1.52 (0.060)	4.22 (0.166)	4.93 (0.194)	0.25 (0.010)	0.36 (0.014)	0.25 (0.010)	0.36 (0.014)	0.30 (0.012)	0.46 (0.018)	—	—	—	—	A6	
AHS120	6.73 (0.265)	7.98 (0.314)	—	3.00 (0.118)	4.8 (0.19)	5.44 (0.214)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	2.16 (0.085)	2.41 (0.095)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
AHS160	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.24)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
AHS200	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.240)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
AHS300	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.240)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD																		
16-60V — Surface-mount																		
ASMD030F	6.73 (0.265)	7.98 (0.314)	—	3.18 (0.125)	4.8 (0.19)	5.44 (0.214)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	2.16 (0.085)	2.41 (0.095)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD050F	6.73 (0.265)	7.98 (0.314)	—	3.18 (0.125)	4.8 (0.19)	5.44 (0.214)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	2.16 (0.085)	2.41 (0.095)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD075F	6.73 (0.265)	7.98 (0.314)	—	3.18 (0.125)	4.8 (0.19)	5.44 (0.214)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	2.16 (0.085)	2.41 (0.095)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD100F	6.73 (0.265)	7.98 (0.314)	—	3.00 (0.118)	4.8 (0.19)	5.44 (0.214)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	2.16 (0.085)	2.41 (0.095)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD125F	6.73 (0.265)	7.98 (0.314)	—	3.00 (0.118)	4.8 (0.19)	5.44 (0.214)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	2.16 (0.085)	2.41 (0.095)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD150F	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.24)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD150F/33	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.24)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD185F	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.24)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD200F	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.24)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
ASMD250F	8.00 (0.315)	9.40 (0.370)	—	3.00 (0.118)	6.0 (0.24)	6.71 (0.264)	0.56 (0.022)	0.71 (0.028)	0.56 (0.022)	0.71 (0.028)	3.68 (0.145)	3.94 (0.155)	0.66 (0.026)	1.37 (0.054)	0.43 (0.017)	—	A7	
nanoASMD																		

PolySwitch Resettable Devices
Automotive Devices

Table A4 — Dimensions in Millimeters and (Inches) (Cont'd)

Part Number	A		B		C		D		E		Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
miniASMDC 16-60V — Surface-mount											
miniASMDC010F	4.37	4.73	0.635	0.89	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.186)	(0.025)	(0.035)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC014F	4.37	4.73	0.635	0.89	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.186)	(0.025)	(0.035)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC020F	4.37	4.73	0.635	0.89	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.186)	(0.025)	(0.035)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC030F	4.37	4.73	0.635	0.89	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.186)	(0.025)	(0.035)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC050F	4.37	4.73	0.38	0.62	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.186)	(0.015)	(0.025)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC075F/24	4.37	4.83	0.81	1.46	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.190)	(0.032)	(0.057)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC110F/16	4.37	4.83	0.28	0.48	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.190)	(0.011)	(0.019)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC110F/24	4.37	4.83	0.81	1.46	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.190)	(0.032)	(0.057)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC125F/16	4.37	4.83	0.28	0.48	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.190)	(0.011)	(0.019)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC150F/16	4.37	4.83	0.28	0.48	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.190)	(0.011)	(0.019)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC150F/24	4.37	4.83	1.00	1.94	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.190)	(0.040)	(0.077)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	
miniASMDC260F/16	4.37	4.83	1.02	1.52	3.07	3.41	0.25	0.95	0.20	—	A15
	(0.172)	(0.190)	(0.042)	(0.060)	(0.121)	(0.134)	(0.010)	(0.040)	(0.008)	—	

Part Number	A		B		C		D		E(x2)		F		G		H		I		Figure
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
BD 14V — Bladed Device																			
BD280-1130-10/16	29.50	30.10	8.70	9.30	10.75	11.25	6.05	6.65	2.55	3.05	3.30	3.90	3.40	4.00	1.70	2.30	10.90	11.50	A13
	(1.173)	(1.185)	(0.343)	(0.366)	(0.423)	(0.443)	(0.238)	(0.262)	(0.100)	(0.120)	(0.130)	(0.154)	(0.134)	(0.157)	(0.067)	(0.091)	(0.429)	(0.453)	
BD280-1130-15/16	29.50	30.10	8.70	9.30	10.75	11.25	6.05	6.65	2.55	3.05	3.30	3.90	3.40	4.00	1.70	2.30	10.90	11.50	A13
	(1.173)	(1.185)	(0.343)	(0.366)	(0.423)	(0.443)	(0.238)	(0.262)	(0.100)	(0.120)	(0.130)	(0.154)	(0.134)	(0.157)	(0.067)	(0.091)	(0.429)	(0.453)	
BD280-1130-20/16	29.50	30.10	8.70	9.30	10.75	11.25	6.05	6.65	2.55	3.05	3.30	3.90	3.40						

PolySwitch Resettable Devices

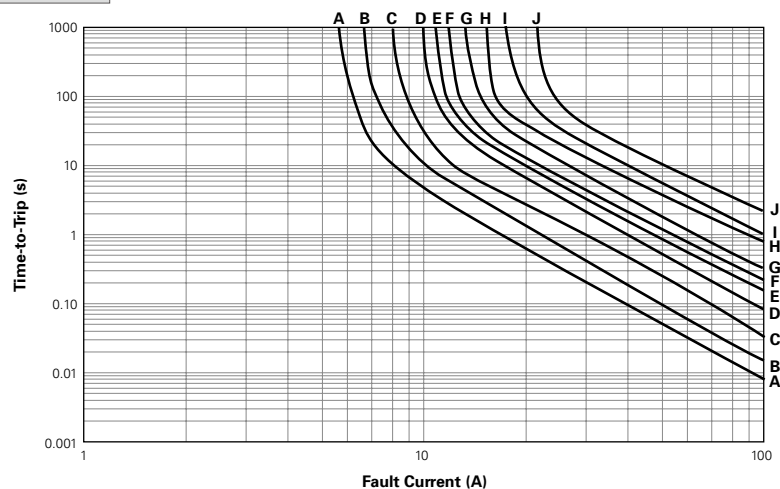
Automotive Devices

Figures A17-A26 — Typical Time-to-Trip at 25°C

AGRF

A = AGRF400	F = AGRF900
B = AGRF500	G = AGRF1000
C = AGRF600	H = AGRF1100
D = AGRF700	I = AGRF1200
E = AGRF800	J = AGRF1400

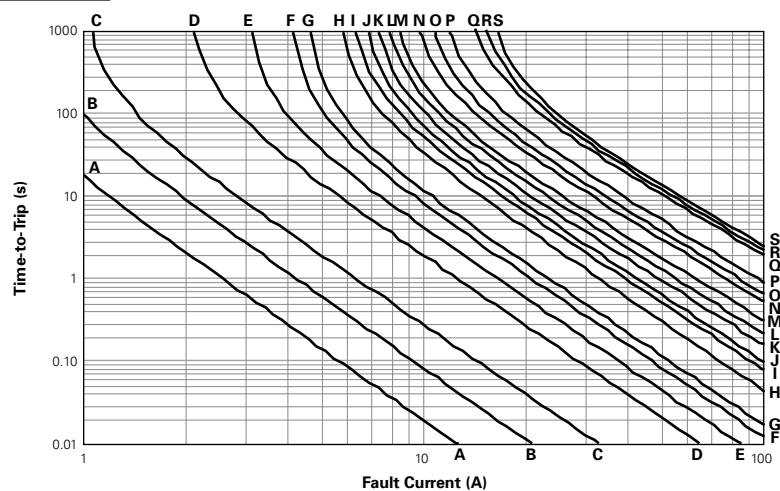
Figure A17



AHRF

A = AHRF050	K = AHRF700
B = AHRF070	L = AHRF750
C = AHRF100	M = AHRF800
D = AHRF200	N = AHRF900
E = AHRF300	O = AHRF1000
F = AHRF400	P = AHRF1100
G = AHRF450	Q = AHRF1300
H = AHRF550	R = AHRF1400
I = AHRF600	S = AHRF1500
J = AHRF650	

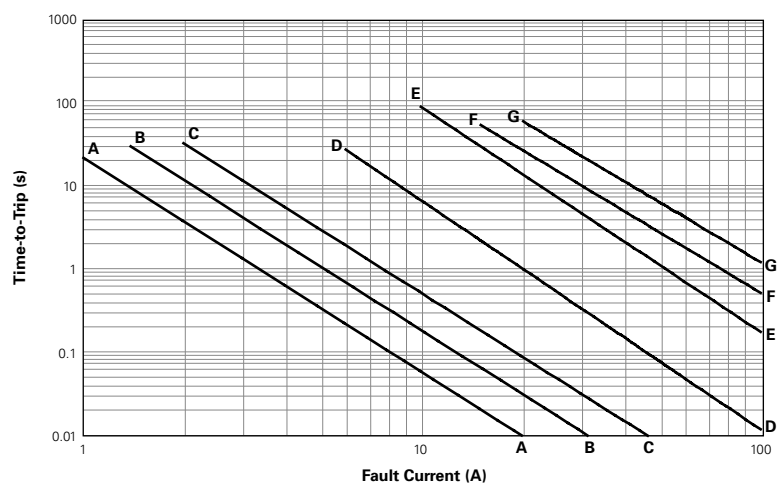
Figure A18



AHEF

A = AHEF050
B = AHEF070
C = AHEF100
D = AHEF300
E = AHEF500
F = AHEF750
G = AHEF1000

Figure A19



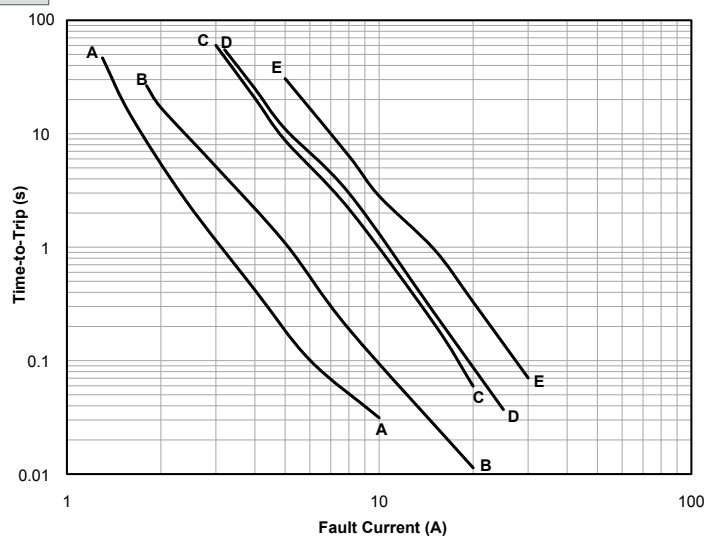
Figures A17-A26 — Typical Time-to-Trip at 25°C

(Cont'd)

AHS

- A = AHS080-2018
- B = AHS120
- C = AHS160
- D = AHS200
- E = AHS300

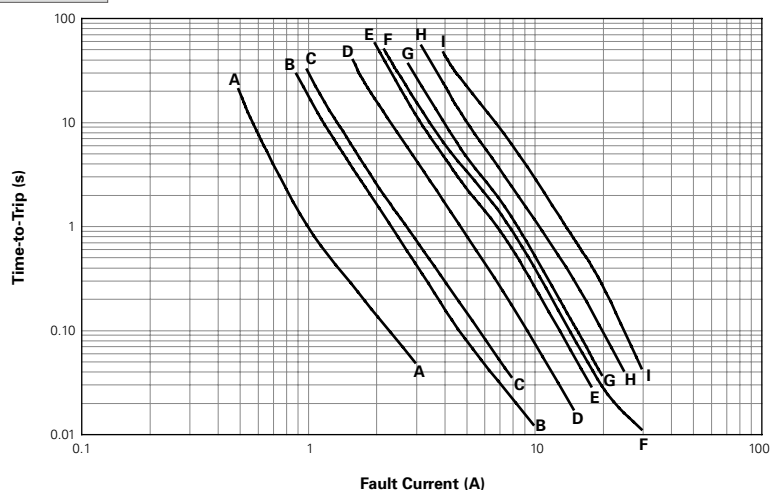
Figure A20



ASMD

- A = ASMD030F
- B = ASMD050F
- C = ASMD075F
- D = ASMD100F
- E = ASMD125F
- F = ASMD150F, ASMD150F/33
- G = ASMD185F
- H = ASMD200F
- I = ASMD250F

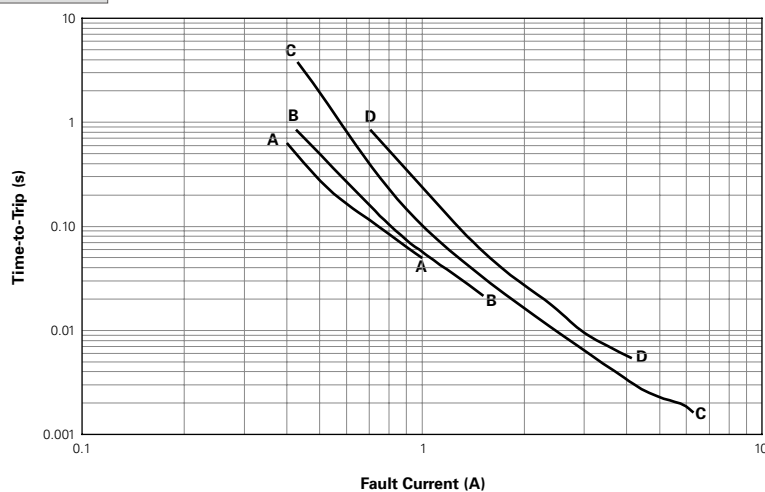
Figure A21



nanoASMDC

- A = nanoASMDC012F
- B = nanoASMDC016F
- C = nanoASMDC020F
- D = nanoASMDC035F

Figure A22

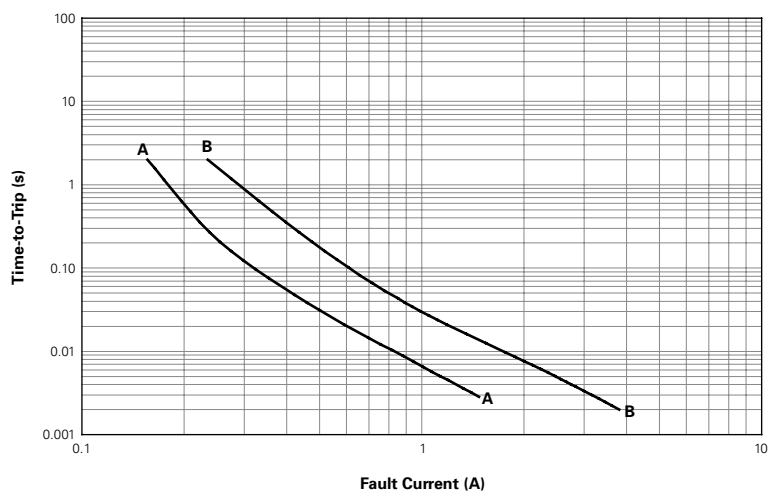


microASMD

A = microASMD005F

B = microASMD010F

Figure A23



miniASMDC

A = miniASMDC010F, miniASMDC014F

B = miniASMDC020F

C = miniASMDC030F

D = miniASMDC050F

E = miniASMDC075F/24

F = miniASMDC110F/16

G = miniASMDC110F/24

H = miniASMDC125F/16

I = miniASMDC150F/16

J = miniASMDC150F/24

K = miniASMDC260F/16

Figure A24

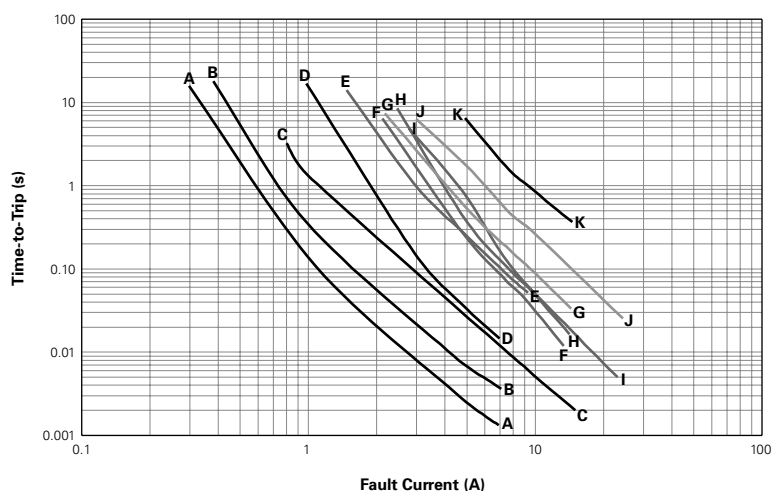
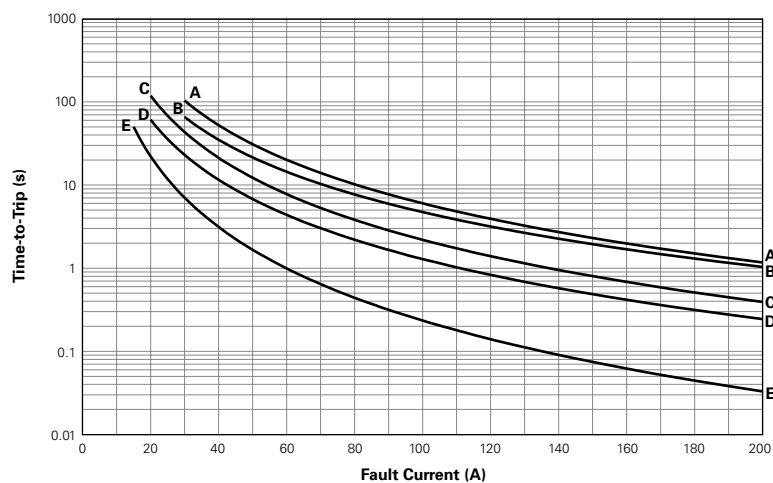


Figure A25



BD

A = BD30A

B = BD25A

C = BD20A

D = BD15A

E = BD10A

Figures A17-A26 — Typical Time-to-Trip at 25°C

(Cont'd)

BD
A = BD540-30

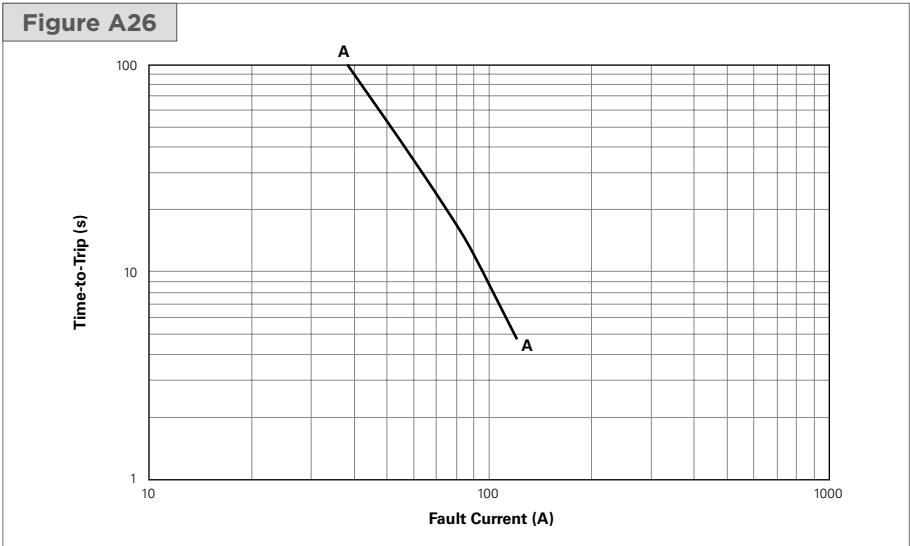


Table A5 — Physical Characteristics and Environmental Specifications

AGRF	
Physical Characteristics	
Lead Material	AGRF400 to AGRF1100 : Tin-plated Copper, 0.52mm ² (20AWG) ø 0.8 mm/0.032in AGRF1200 to AGRF1400: Tin-plated Copper, 0.82mm ² (18AWG) ø 1.0mm/0.040in
Soldering Characteristics	Solderability per ANSI/J-STD-002 Category 3
Solder Heat Withstand	AGRF400 : per IEC68-2-20 Test Tb, Method 1A, Condition A: Can Withstand 5 s at 260°C ± 5°C AGRF500-AGRF1400 : per IEC68-2-20 Test Tb, Method 1A, Condition B: Can Withstand 10 s at 260°C ± 5°C
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0
Operation Temperature	-40°C~85°C

Note: See PS400 for other physical characteristics.
Devices are not intended to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%
Thermal Shock	85°C, -40°C (10 Times)	±5%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

Note: See PS400 for other environmental specifications.

Table A5 — Physical Characteristics and Environmental Specifications

(Cont'd)

AHRF	
Physical Characteristics	
Lead material	AHRF050 to AHRF200 : Tin-plated Copper-clad Steel, 0.205mm ² (24 AWG), ø 0.51mm/0.020in AHRF300 to AHRF1100 : Tin-plated Copper 0.52mm ² (20 AWG), ø 0.81mm/0.032in AHRF1300 to AHRF1500: Tin-plated Copper 0.82mm ² (18 AWG), ø 1.0mm/0.04in
Soldering Characteristics	Solderability per ANSI/J-STD 002 Category 3
Solder Heat Withstand	Per IEC 68-2-20, Test Tb, Method 1A, Condition B; Can Withstand 10 s at 260°C ± 5°C
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0 Requirements
Operation Temperature	-40°C~125°C

Note: See PS400 for other physical characteristics.

Devices are not intended to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%
Thermal Shock	125°C, -40°C (10 Times)	±5%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

Note: See PS400 for other environmental specifications.

AHEF	
Physical Characteristics	
Lead Material	AHEF050 to AHEF100: Tin-plated Copper-clad Steel, 0.205mm ² (24 AWG), ø 0.51mm/0.020in. AHEF300 to AHEF750: Tin-plated Copper 0.52mm ² (20 AWG), ø 0.81mm/0.032in AHEF1000: Tin-plated Copper 0.82mm ² (18 AWG), ø 1.0mm/0.04in
Soldering Characteristics	Solderability per ANSI/J-STD 002 Category 3
Solder Heat Withstand	Per IEC 68-2-20, Test Tb, Method 1A, Condition B; Can Withstand 10 s at 260°C ± 5°C
Insulating Material	Cured, Flame-retardant Epoxy Polymer; Meets UL 94V-0 Requirements
Operation Temperature	-40°C~125°C

Note: See PS400 for other physical characteristics.

Devices are not intended to be placed through a reflow process.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±5%
	85°C, 1000 hrs	±5%
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%
Thermal Shock	125°C, -40°C (10 Times)	±5%
Solvent Resistance	MIL-STD-202, Method 215F	No Change

Note: See PS400 for other environmental specifications.

Table A5 — Physical Characteristics and Environmental Specifications

(Cont'd)

AHS	
Physical Characteristics	
Lead Material	Tin-plated Brass to MIL-T-10727B
Soldering Characteristics	Solderability per ANSI-J-STD-002 Category 1
Solder Heat Withstand	Per IEC-STD 68-2-20, Test Tb, Section 5, Method 1A
Flammability	Per IEC 695-2-2 Needle Flame Test for 20 s
Operation Temperature	-40°C~125°C

Note: See PS400 for other physical characteristics.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	70°C, 1000 hrs	±3% Typical
	85°C, 1000 hrs	±5% Typical
Humidity Aging	85°C, 85% RH, 1000 hrs	±1.2% Typical
Thermal Shock	125°C, -40°C (20 Times)	-33% Typical
Solvent Resistance	Freon	No Change
	Trichloroethane	No Change
	Hydrocarbons	No Change

Note: See PS400 for other environmental specifications.

ASMD	
Physical Characteristics	
Terminal Pad Material	98%+ Tin-plated Brass
Soldering Characteristics	Solderability per ANSI-J-STD-002 Category 1
Solder Heat Withstand	Per IEC-STD 68-2-20, Test Tb, Section 5, Method 1A
Flammability Resistance	Per IEC 695-2-2 Needle Flame Test for 20 s
Recommended Storage Conditions	40°C max, 70% RH max; Devices May Not Meet Specified Ratings if Storage Conditions are Exceeded
Operation Temperature	-40°C~85°C

Note: See PS400 for other physical characteristics.

Environmental Specifications		
Test	Conditions	Resistance Change
Passive Aging	60°C, 1000 hrs	±3% Typical
	85°C, 1000 hrs	±5% Typical
Humidity Aging	85°C, 85% RH, 100 hrs	±1.2% Typical
Thermal Shock	85°C, -40°C (20 Times)	-33% Typical
	125°C, -55°C (10 Times)	-33% Typical
Solvent Resistance	Freon	No Change
	Trichloroethane	No Change
	Hydrocarbons	No Change

Note: See PS400 for other environmental specifications.

Table A5 — Physical Characteristics and Environmental Specifications

(Cont'd)

nanoASMDC/microASMD/miniASMDC				
Physical Characteristics				
Terminal Pad Material	100% Matte Tin with Nickel Underplate			
Soldering Characteristics	Solderability per ANSI-J-STD-002 Category 3			
Solder Heat Withstand	Per IEC-STD 68-2-20, Test Tb, Section 5, Method 1A			
Flammability Resistance	Per IEC 695-2-2 Needle Flame Test for 20 s			
Recommended Storage Conditions	40°C max, 70% RH max; Devices May Not Meet Specified Ratings if Storage Conditions are Exceeded			
Operation Temperature	-40°C~85°C			
Note: See PS400 for other physical characteristics.				
Environmental Specifications				
Test	Conditions	Resistance Change		
Passive Aging	60°C, 1000 hrs	±3% Typical		
	85°C, 1000 hrs	±5% Typical		
Humidity Aging	85°C, 85% RH, 100 hrs	±1.2% Typical		
Thermal Shock	85°C, -40°C (20 Times)	-33% Typical		
	125°C, -55°C (10 Times)	-33% Typical		
Solvent Resistance	Freon	No Change		
	Trichloroethane	No Change		
	Hydrocarbons	No Change		
Note: See PS400 for other environmental specifications.				
BD				
Physical Characteristics				
Lead Material	Brass H65, Thickness: 0.8mm, Tin Plating Thickness: 5µm			
Soldering Characteristics	NA			
Solder Heat Withstand	NA			
Insulating Material	Colored PBT, Meets UL94V-0 Requirements			
Operation Temperature	-40°C~125°C			
Note: See PS400 for other physical characteristics.				
Environmental Specifications				
Test	Conditions	Resistance Change		
Passive Aging	85°C, 1000 hrs	±5%		
Humidity Aging	85°C, 85% RH, 1000 hrs	±5%		
	85°C, 85% RH (with 10% I _{HOLD}), 500 hrs	±5%		
Thermal Shock	85°C to -40°C (5 Times)	Meet SCD		
Solvent Resistance	MIL-STD-202, Method 215F	No Change		
Note: See PS400 for other environmental specifications.				

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Table A6 — Packaging and Marking Information

Part Number	Bag Quantity	Tape and Reel Quantity	Ammo Pack Quantity	Standard Package Quantity	Part Marking	Agency Recognition
AGRF Radial-leaded						
AGRF400	500	—	—	10,000	G4	*
AGRF400-2	—	2,500	—	12,500	G4	*
AGRF400-AP	—	—	2,000	10,000	G4	*
AGRF500	500	—	—	10,000	G5	*
AGRF500-2	—	2,000	—	10,000	G5	*
AGRF500-AP	—	—	2,000	10,000	G5	*
AGRF600	500	—	—	10,000	G6	*
AGRF600-2	—	2,000	—	10,000	G6	*
AGRF600-AP	—	—	2,000	10,000	G6	*
AGRF700	500	—	—	10,000	G7	*
AGRF700-2	—	1,500	—	7,500	G7	*
AGRF700-AP	—	—	1,500	7,500	G7	*
AGRF800	500	—	—	10,000	G8	*
AGRF800-2	—	1,500	—	7,500	G8	*
AGRF800-AP	—	—	1,500	7,500	G8	*
AGRF900	500	—	—	10,000	G9	*
AGRF900-2	—	1,000	—	5,000	G9	*
AGRF900-AP	—	—	1,000	5,000	G9	*
AGRF1000	250	—	—	5,000	G10	*
AGRF1000-2	—	1,000	—	5,000	G10	*
AGRF1000-AP	—	—	1,000	5,000	G10	*
AGRF1100	250	—	—	5,000	G11	*
AGRF1100-2	—	1,000	—	5,000	G11	*
AGRF1100-AP	—	—	1,000	5,000	G11	*
AGRF1200	250	—	—	5,000	G12	*
AGRF1200-2	—	1,000	—	5,		

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Table A6 — Packaging and Marking Information

(Cont'd)

Part Number	Bag Quantity	Tape and Reel Quantity	Ammo Pack Quantity	Standard Package Quantity	Part Marking	Agency Recognition
AHRF (High Temperature) Radial-leaded						
AHRF450	500	—	—	10,000	H4.5	*
AHRF450-2	—	1,500	—	7,500	H4.5	*
AHRF450-AP	—	—	1,500	7,500	H4.5	*
AHRF550	500	—	—	10,000	H5.5	*
AHRF550-2	—	2,000	—	10,000	H5.5	*
AHRF550-AP	—	—	2,000	10,000	H5.5	*
AHRF600	500	—	—	10,000	H6	*
AHRF600-2	—	2,000	—	10,000	H6	*
AHRF600-AP	—	—	2,000	10,000	H6	*
AHRF650	500	—	—	10,000	H6.5	*
AHRF650-2	—	1,500	—	7,500	H6.5	*
AHRF650-AP	—	—	1,500	7,500	H6.5	*
AHRF700	500	—	—	10,000	H7	*
AHRF700-2	—	1,500	—	7,500	H7	*
AHRF700-AP	—	—	1,500	7,500	H7	*
A						

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Table A6 — Packaging and Marking Information

(Cont'd)

Part Number	Tape and Reel Quantity	Standard Package Quantity	Part Marking	Recommended Pad Layouts [mm(in)] See Figure A27			Agency Recognition				
				Dimension A (Min*/Nom)	Dimension B (Nom)	Dimension C (Nom)					
AHS (High Temperature)											
Surface-mount											
AHS080-2018	4,000	20,000	H08	4.6 (0.18)	1.5 (0.06)	3.4 (0.134)	*				
AHS120	2,000	10,000	H12	3.1 (0.12)	2.3 (0.09)	5.1 (0.201)	*				
AHS160	1,500	7,500	160	4.6 (0.18)	2.3 (0.09)	6.1 (0.240)	*				
AHS200	1,500	7,500	H200	4.6 (0.18)							

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Figure A27 — Recommended Pad Layout

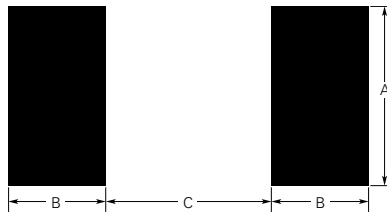


Table A7 — Tape and Reel Specifications for AGRF/AHRF/AHEF Devices

AGRF, AHRF and AHEF devices are available in tape and reel packaging per EIA468-B/IEC286-2 and EIA 481-2 standards.

Description	EIA Mark	Dimension (mm)	Tolerance
Carrier Tape Width	W	18.0	-0.5/+1.0
Hold Down Tape Width	W ₄	11.0	Minimum
Top Distance between Tape Edges	W ₆	3.0	Maximum
Sprocket Hole Position	W ₅	9.0	-0.5/+0.75
Sprocket Hole Diameter	D ₀	4.0	±0.2
Abscissa to Plane (Straight Lead) (AHEF300 to AHEF1000)	H	20.3	±0.5
Abscissa to Plane (Kinked Lead) (AGRF400 to AGRF1400, AHRF050 to AHRF1500, AHEF050 to AHEF100)	H ₀	16.0	±0.5
Abscissa to Top (AGRF40			

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Figure A28 — EIA Referenced Taped Component Dimensions for AGRF/AHRF/AHEF Devices

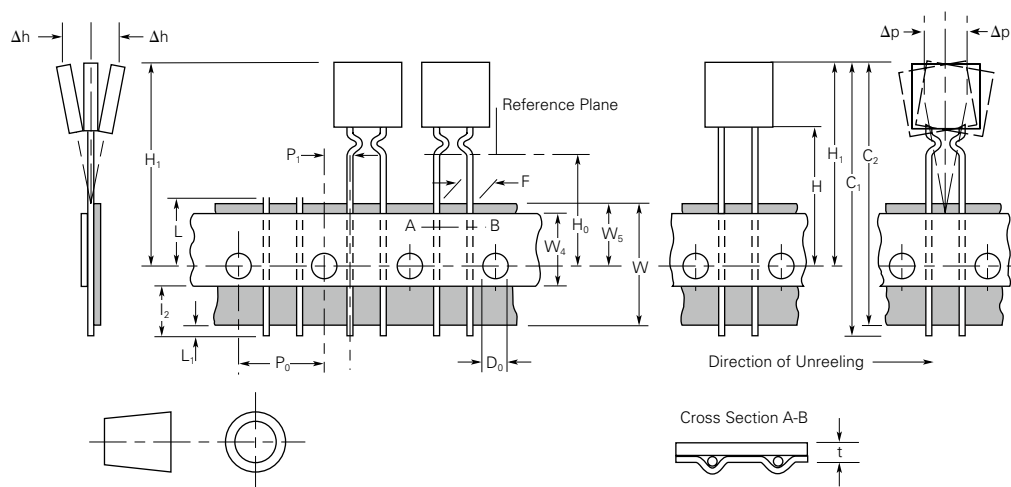


Figure A29 — EIA Referenced Reel Dimensions for AGRF/AHRF/AHEF Devices

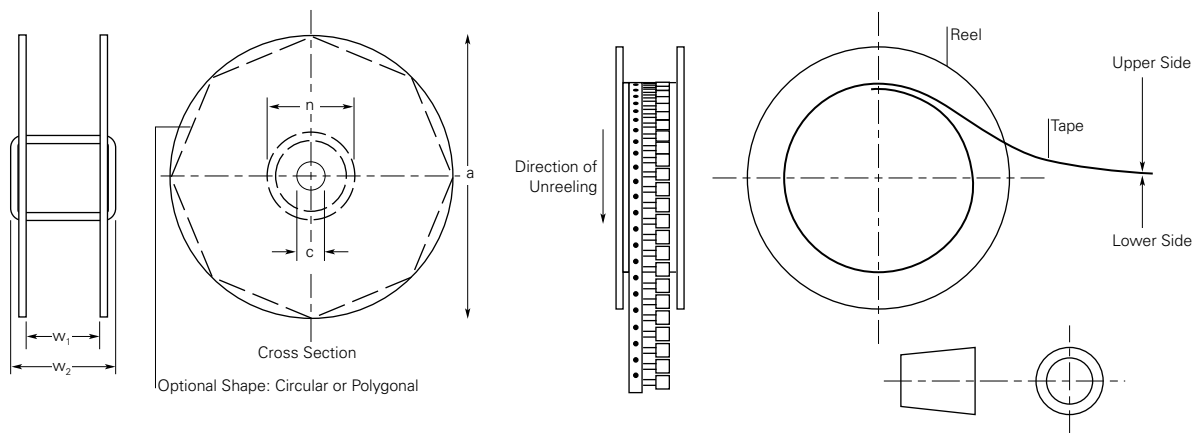


Table A8 — Tape and Reel Specifications for AHS

